

**Workshop on Diamond and Diamond-Like-Carbon Films
for the Transportation Industry**

Argonne National Laboratory
Argonne, IL

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Tribology Program
Office of Transportation Materials
Office of Transportation Technologies
Conservation and Renewable Energy
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and

Argonne National Laboratory

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ABSTRACT

Numerous applications exist in advanced transportation systems as well as in numerous manufacturing processes that would benefit from the superior tribological properties of diamond, diamond-like-carbon and cubic boron nitride coatings. The superior hardness of these coatings make them ideal candidates as protective coatings to reduce adhesive, abrasive and erosive wear in advanced diesel engines, gas turbines and spark-ignited engines and in machining and manufacturing tools as well. The high thermal conductivity of diamond also makes it desirable for thermal management not only in tribological applications but also in high-power electronic devices and possibly large braking systems.

A workshop has been recently held at Argonne National Laboratory entitled "Diamond and Diamond-Like-Carbon Films for Transportation Applications" which was attended by 85 scientists and engineers including top people involved in the basic technology of these films and also representatives from many US industrial companies. A working group on applications endorsed 18 different applications for these films in the transportation area alone. With this strong indication of industrial support, we envision a second workshop to address applications in the US manufacturing industry. It is anticipated that industrial expenditures will exceed \$3000K per year and will result in numerous CRADAs between National Labs and US companies.

1.0 EXECUTIVE SUMMARY

Problem Definition: Numerous applications exist in advanced transportation systems as well as in numerous manufacturing processes that would benefit from the superior tribological properties of diamond, diamond-like-carbon and cubic boron nitride coatings. The superior hardness of these coatings make them ideal candidates as protective coatings to reduce adhesive, abrasive and erosive wear in advanced diesel engines, gas turbines and spark-ignited engines and in machining and manufacturing tools as well. The high thermal conductivity of diamond also makes it desirable for thermal management not only in tribological applications but also in high-power electronic devices and possibly large braking systems.

Objectives: The program envisioned to follow from this Workshop will focus on transferring technologies for depositing these films to advanced engine components (e.g. diesel injectors, piston rings, cylinder liners, bearings, valve stems, etc.). A critical issue in this process will be to establish the proper conditions for depositing smooth, adherent films on a number of substrates at low deposition temperatures, and to evaluate their performance under simulated and prototypical conditions.

Potential Industrial Participation: A workshop has been recently held at Argonne National Laboratory entitled "Diamond and Diamond-Like-Carbon Films for Transportation Applications" which was attended by 85 scientists and engineers including top people involved in the basic technology of these films and also representatives from many US industrial companies. A working group on applications endorsed 18 different applications for these films in the transportation area alone. With this strong indication of industrial support, we envision a second workshop to address applications in the US manufacturing industry. It is anticipated that industrial expenditures will exceed \$3000K per year and will result in numerous CRADAs between National Labs and US companies. This initiative fits beautifully into the planning of the Presidential Initiative entitled "Advanced Materials and Processing Program" (AMPP) and some cooperative funding from that source is possible.

Technical Approach: Working with already-identified companies and further ones to result from the new workshop on manufacturing applications, cooperative programs will be established with industrial partners. Areas of application strongly endorsed by a working panel on applications to the transportation sector are:

1. Valve guide/stem wear at high temperatures in developmental low-heat-rejection engines.
2. Piston ring/bore tribosystem improvements to decrease wear, oil consumption and emissions for gasoline, diesel and alternative fuels.
3. Increased load-carrying capacity for gears and bearings (including journal bearings as temperatures rise in sump and loads increase due to higher cylinder and injection pressures) in spark-ignited/diesel engines and vehicular drive trains, including continuously variable transmissions (CVTs) as well as in manufacturing.

4. Electric fuel pumps and fuel-pump gears, to reduce wear and corrosion, especially when used with low-viscosity alternative fuels such as methanol.
5. Applications of diamond and DLC films require improved modeling of wear mechanisms as well as adhesion processes and improved analytical methods for extending the results of lab-bench tests to actual operating conditions.
6. Improved resistance to wear-in ("beat-in") and scuffing of fuel-injector plungers for diesel and especially for new alternative fuels in diesel and spark-ignited engines. Erosion-corrosion of injector spray holes must also be reduced to conserve fuel and decrease emissions.
7. Improvements in rolling-contact-fatigue (RCF) life of cams and cam-roller followers for both valves and injectors, which would also reduce emissions. Needs exist in both diesel, spark and gas-turbine engines.
8. Improvements in self-lubrication and scuffing resistance of new light-weight materials for automotive applications, e.g., Al block engine/cylinder bore surface, valve-train components, transmission case "hot spots" and air conditioning compressor hardware.
9. Improvements in wear life of ferrous and non-ferrous die materials for medium-volume applications in engine manufacture.
10. Diamond or DLC sensors for temperature, force and chemical conditions, along with associated packaging systems needed for harsh transportation-related environments, especially as temperatures continue to increase.
11. Improved abrasion/erosion resistance of compressor blades/stator vanes in gas turbines and turbochargers, where small amounts of wear result in drastic efficiency losses.
12. Improved abrasion resistance of windows on aircraft and automobiles.
13. Improved power-management capabilities for electric-powered vehicles and power transmissions, leading to extended vehicle range and improved safety/reliability/performance.
14. Improved thermal management to decrease thermal fatigue from hot spots in combustion chambers, especially in cylinder heads.
15. Improved machine/cutting tools for advanced materials, e.g., composites, ceramics.
16. Improved thermal management for heavy-duty trucks and aircraft braking systems, which is currently a critical problem area.

17. New lubricants may need to be developed for compatibility with diamond and/or DLC materials used in engines, transmissions, gears, etc.
18. Improved seals for many areas of application.

It must be strongly emphasized that if programs are undertaken with respect to any of these identified problem areas, applied work must be coupled with projects to improve our understanding and capabilities with respect to deposition techniques, film properties and characterization techniques. Working panels provided specific guidance for required parallel efforts in all three of these categories.

2.0 INTRODUCTION.

2.1 HISTORY OF THE TRIBOLOGY PROGRAM.

The Department of Energy (DOE) established the Energy Conversion and Utilization Technologies (ECUT) Program in FY 1980 with the mission of conducting generic, long-term, high-risk, applied research and exploratory development in energy conversion and utilization in areas pertaining to energy conservation, which private enterprise will not or cannot pursue. The Tribology Program of ECUT was formed in the fall of 1983. In April 1990, the Assistant Secretary for Conservation and Renewable Energy conducted a reorganization and placed the Tribology Program under the Office of Transportation Materials (OTM) in the Office of Transportation Technologies (OTT). The ECUT program was already heavily oriented to transportation needs and that emphasis continues and is further enhanced in the current program plans.

The current program is mainly intended to support researchers in industry, academia and government to explore ideas or concepts aimed at specific applications to bring them to a stage where private industry or other government programs can carry them into more advanced technology and engineering development. Its goals are to (1) establish feasibility of concepts that significantly reduce energy consumption in transportation systems, (2) carry out exploratory development on novel or innovative concepts for advanced transportation systems, (3) evaluate new concepts for improved efficiency or alternative-fuel use in advanced engines and (4) expand the technology base necessary for development of improvements in advanced transportation systems. The program attempts to be a bridge between basic research and large-scale technology and engineering development in the transportation sector.

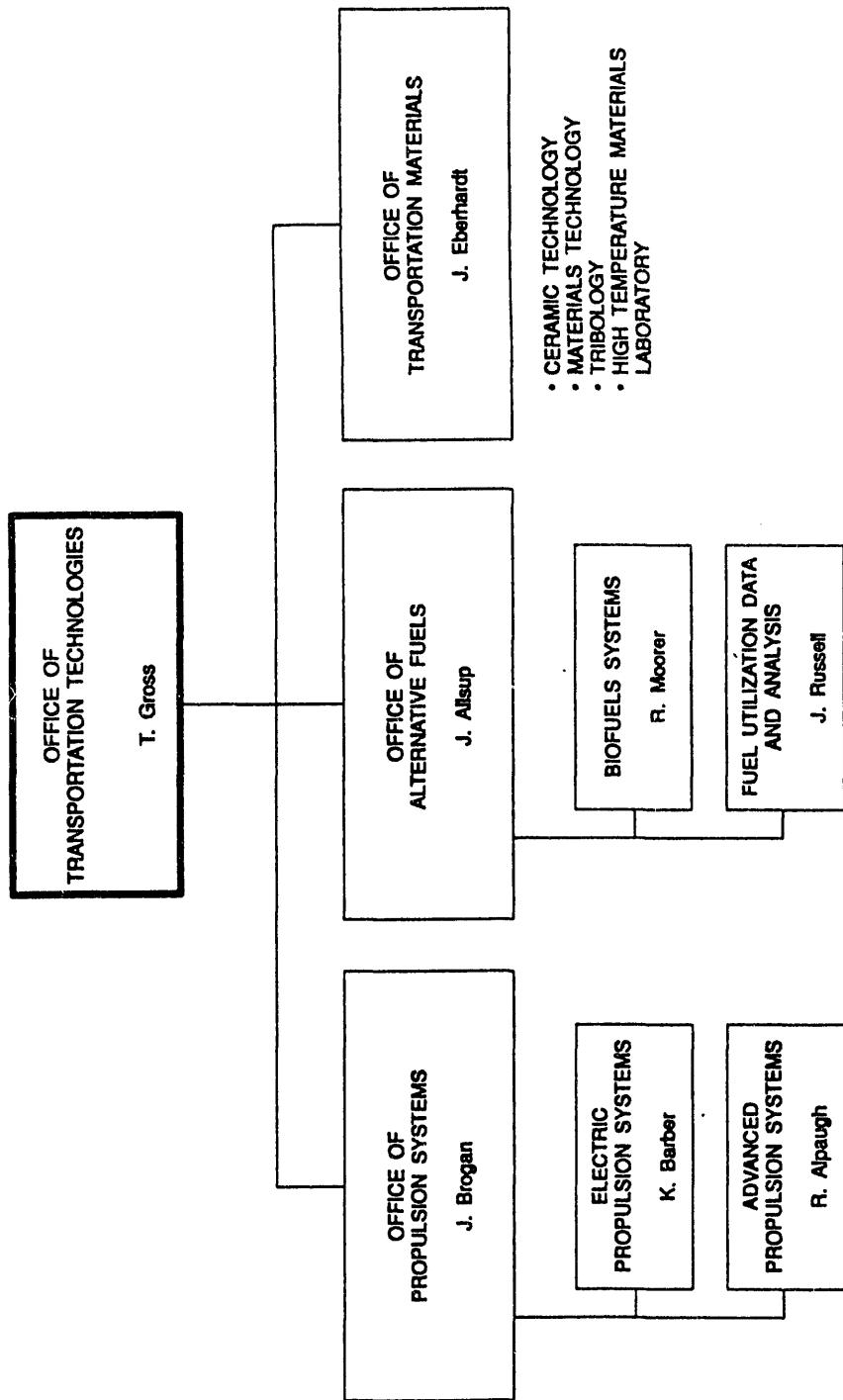
2.2 OFFICE OF TRANSPORTATION TECHNOLOGY (OTT).

MISSION. The OTT is charged with long-term, high risk, and potentially high-payoff research and development of promising transportation technologies that are unlikely to be undertaken by the private sector alone. OTT activities are designed to develop an advanced technology base within the U.S. transportation industry for future manufacture of more energy-efficient, fuel-flexible and environmentally sound transportation systems. OTT operations are focused in three areas: advanced automotive propulsion systems including gas turbines, low-heat-rejection diesel, and electric-vehicle technologies; advanced-materials development and tribology research; and research, development, demonstration, test, and evaluation (including field testing in fleet operations) of alternative fuels.

OTT's research objectives focus on the two largest segments of the transportation sector: (1) automobiles and light-duty trucks and vans and (2) heavy-duty trucks and buses. Roughly, 64% of all the transportation petroleum consumed in the United States is pumped into automobiles and light-duty trucks and vans. Heavy-duty trucks and buses consume another 15%. By focusing research and development (R&D) efforts in these two areas, even small gains in efficiency can produce large payback for the taxpayers' funding dollar. A 10% reduction in gasoline consumption in the U.S. automobile and light-duty-truck fleet, attainable in the near term through increased efficiency, could accumulatively save the owners of new vehicles billions of dollars.

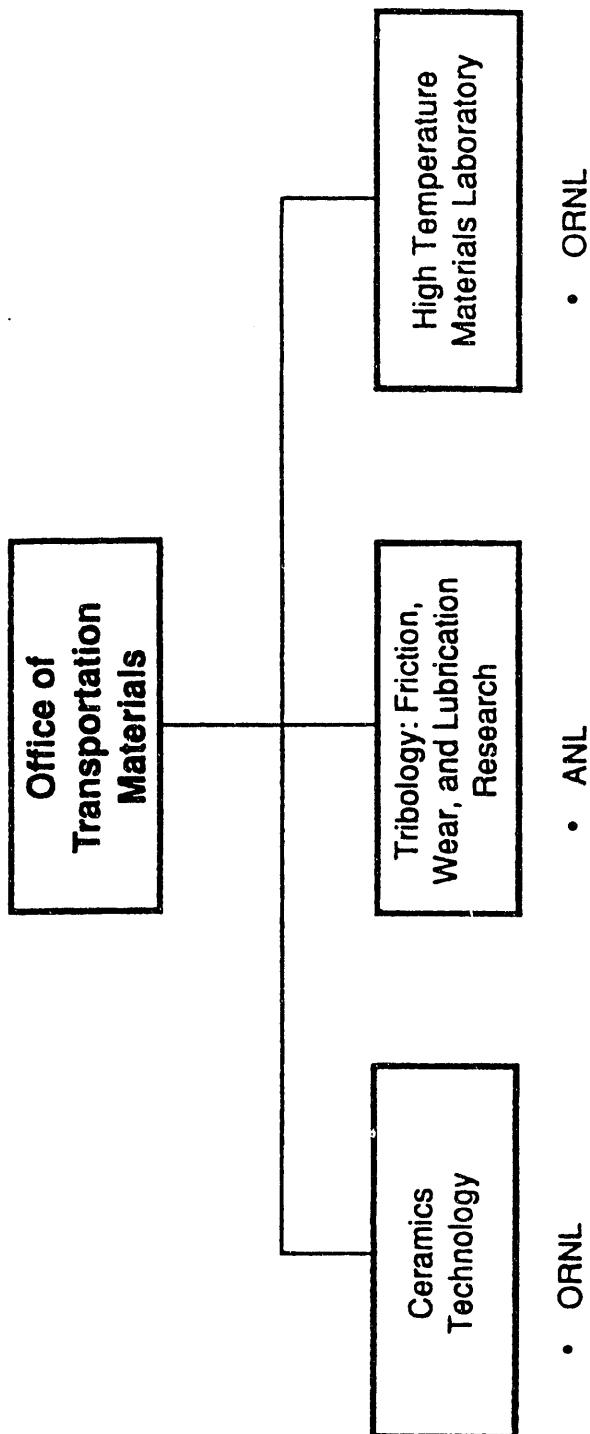
Office of Transportation Materials

Organization of the Office of Transportation Technologies



Office of Transportation Materials

Current Program Structure of OTM



OTT works closely with the Department of Transportation (DOT), the General Services Administration (GSA), and the Environmental Protection Agency (EPA) to ensure that legislatively mandated goals regarding alternative fuels, reduced emissions, and clean air are met.

OTT is structured to reflect the end-user orientation of DOE's Conservation and Renewable Energy organization and to effect timely technology transfer to industry. Three units comprise the office: (1) the Office of Alternative Fuels, which includes Bio-fuels Systems Division and the Fuel Utilization Data and Analysis Division; (2) the Office of Propulsion Systems, which includes the Electric and Hybrid Propulsion Division and the Advanced Propulsion Division; and (3) the Office of Transportation Materials. The synergism of the research conducted under the three units of OTT, as well as that carried out by investigators from other government agencies, industry and universities, holds promise for resolving our nation's transportation problems. A diagram of the organizational structure of OTT is found in Figure 1.

2.3 OFFICE OF TRANSPORTATION MATERIALS (OTM).

MISSION. The mission of the OTM is to develop an industrial base in advanced transportation-related materials and associated materials processing. The objective is to enable the development and engineering of energy-efficient transportation systems that will make possible the transition of the U.S. transportation sector from near-total dependence on petroleum to alternative fuels and electricity.

The current structure of the OTM, Figure 2, includes the Ceramics Technology for Advanced Heat Engines Program, the High Temperature Materials Laboratory and the Tribology Program which is the basis of this planning document.

In pursuit of its mission the OTM Program seeks to accomplish the following goals:

1. Understand and improve techniques, processes and materials necessary to the solution of specific problems associated with the efficiency limits and the multi-fuel-use capability of advanced transportation systems and components.
2. Monitor and evaluate advances in basic scientific research for applicability to transportation systems.
3. Conduct exploratory development of novel or innovative concepts.
4. Establish the feasibility of concepts having the potential to reduce energy consumption significantly.
5. Ensure a continual flow of information on conservation-related technical advances in the transportation sector to private industry.

Mainly, OTM supports research and exploratory development on a specific concept or idea at the laboratory or bench scale in order to bring it to a stage where it might be carried into more advanced technology and engineering development funded by private industry or

other government programs. The program encourages cooperative research between industry and government laboratories, with an emphasis on heavy industrial involvement and leadership.

2.4 TRIBOLOGY PROGRAM

MISSION. The mission of the OTM Tribology Program is to provide the base technology to enable savings in annual U.S. energy consumption through tribological advances in the transportation sector. These energy savings may be achieved directly or through savings of embodied energy or enhanced productivity. This mission is carried out in a manner so as to reduce the significant limitations in the operation of existing and advanced tribological systems which have to operate in severe environments such as high temperatures, high speeds, high loads, corrosive gases/liquids and combinations thereof. The program works closely with U.S. industry to determine current and future needs for advances of tribological systems for transportation applications and to facilitate the transfer of the new technologies which are developed in this program. Continual coordination and information interchange is maintained with the various other government-sponsored tribology programs.

The DOE-OTM Tribology Program Manager is Dr. Joseph M. Perez. The technical project direction is under the leadership of Argonne National Laboratory (ANL). The Tribology Project Manager at ANL is Dr. Fred A. Nichols. The organizational structure for the Tribology Project is shown in Figure 3.

The science and technology of tribology can play a critical role in raising the level of U.S. competitiveness in world markets. Research and engineering studies in tribology can help to decrease the estimated \$100 billion annual energy and material losses in the manufacturing, metalworking, transportation and utility sectors by identifying the causes of friction and wear and devising and implementing methods to reduce these losses. Studies have shown that a major portion of these potential savings resides in the transportation sector where the emphasis of this program lies.

A major barrier to these advances in tribological technology, however, is the lack of effective communication of new research results and of the best state-of-the-art technologies. The complex, interdisciplinary research required to understand and eliminate tribological losses involves scientists and engineers from many very diverse areas of expertise who report their research results in journals and at meetings specialized to their individual discipline. Such compilations of results and techniques are being generated at ever-increasing rates. Nevertheless, progress in tribology is hindered by the relative inaccessibility of information on these advances. It has been estimated that a significant fraction of these tribological losses could be saved simply by better technology transfer.

Additional savings in energy, as well as significant increases in the efficiency and reliability of tribological components and systems, could be achieved if it were possible to optimize their performance and increase their operating lifetimes through the use of realistic design and analysis methods. The need for adequate models and codes becomes

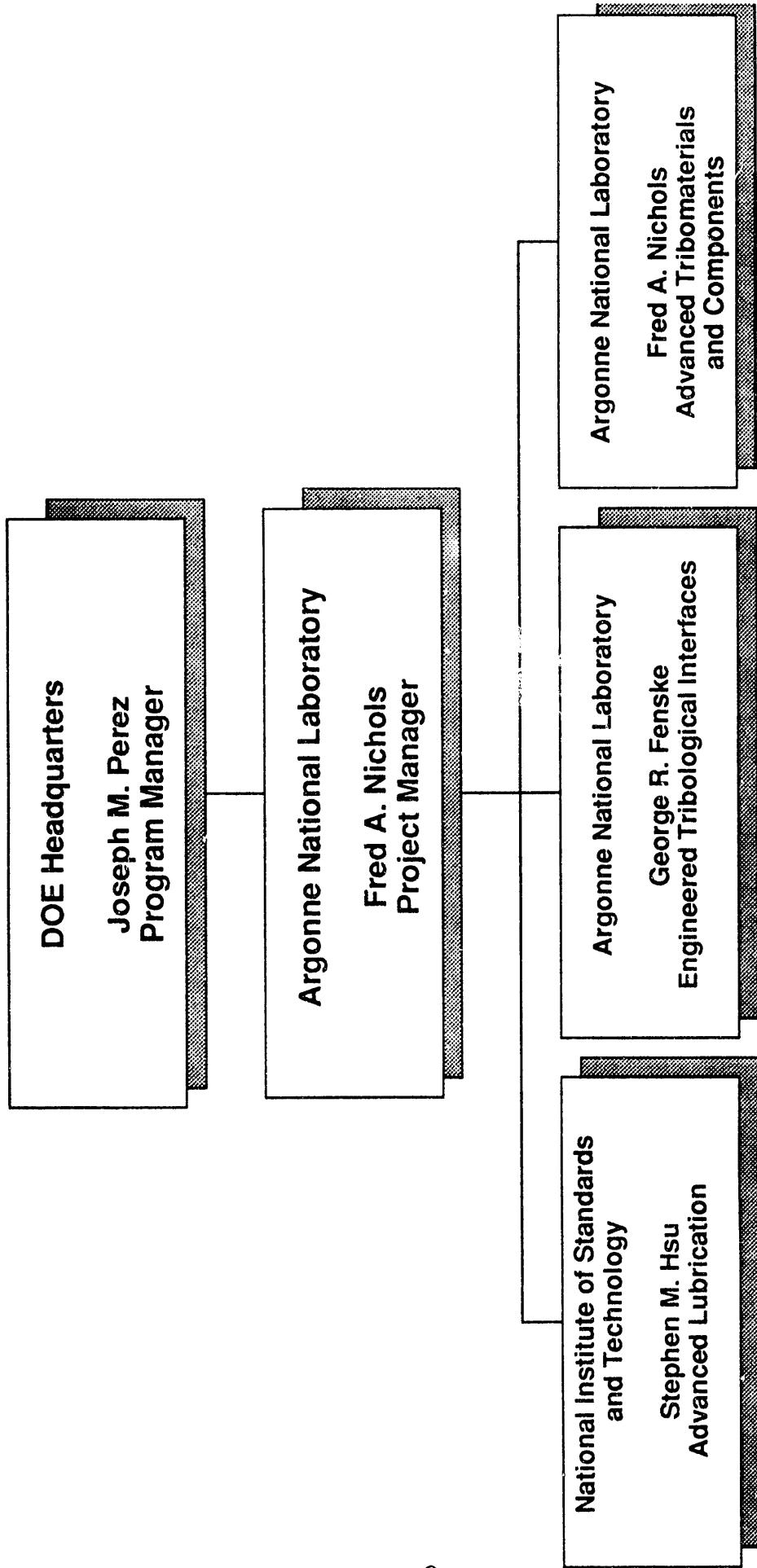


Fig. 3.

even more urgent as the operating conditions become more severe (e.g., high temperature, high loads, corrosive atmospheres, etc.).

2.5 CURRENT TASK AREAS.

The current major task areas of the tribology program are Advanced Lubrication, Engineered Tribological Interfaces and Advanced Tribomaterials and Components:

The Advanced Lubrication task area includes experimental and theoretical investigations of lubrication phenomena and the development of improved or novel lubricants and lubricant-delivery systems for current and advanced transportation systems.

The Engineered Tribological Interfaces task area includes research and development on advanced coating processes to modify the microstructure and chemical composition of near-surface regions in order to improve their friction and wear properties for use in advanced transportation systems.

The Advanced Tribomaterials and Components task area encompasses two subtasks: tribomaterials evaluation, which assesses the potential of newly developed materials for transportation applications; and tribocomponents, which includes transportation-system component models, design-tool development, and the dissemination of tribology information to U.S. transportation industry.

Project Management encompasses the administrative and managerial duties of planning, including assessments of application areas with significant tribological energy losses and opportunities for tribological advances in the transportation sector; program implementation, including the review of proposals, organization and conduct of Requests for Proposals (RFP) and/or Research Opportunity Announcements (ROA), advice on selection of R&D projects and the issuing of subcontracts, grants and purchase orders; monitoring of project activities (site visits, phone contacts and review of reports); reporting (bi-monthly and semi-annual reports as well as special formal and information reports) and information interchange.

3.0 WORKSHOP PLENARY LECTURES

Diamond and Diamond-Like Films for Transportation Applications

Workshop Overview

Joseph M. Perez
Tribology Program Manager
Office of Transportation Materials
Conservation and Renewable Energy

February 4 & 5, 1992

Argonne, Illinois

Office of Transportation Materials

Tribology Program

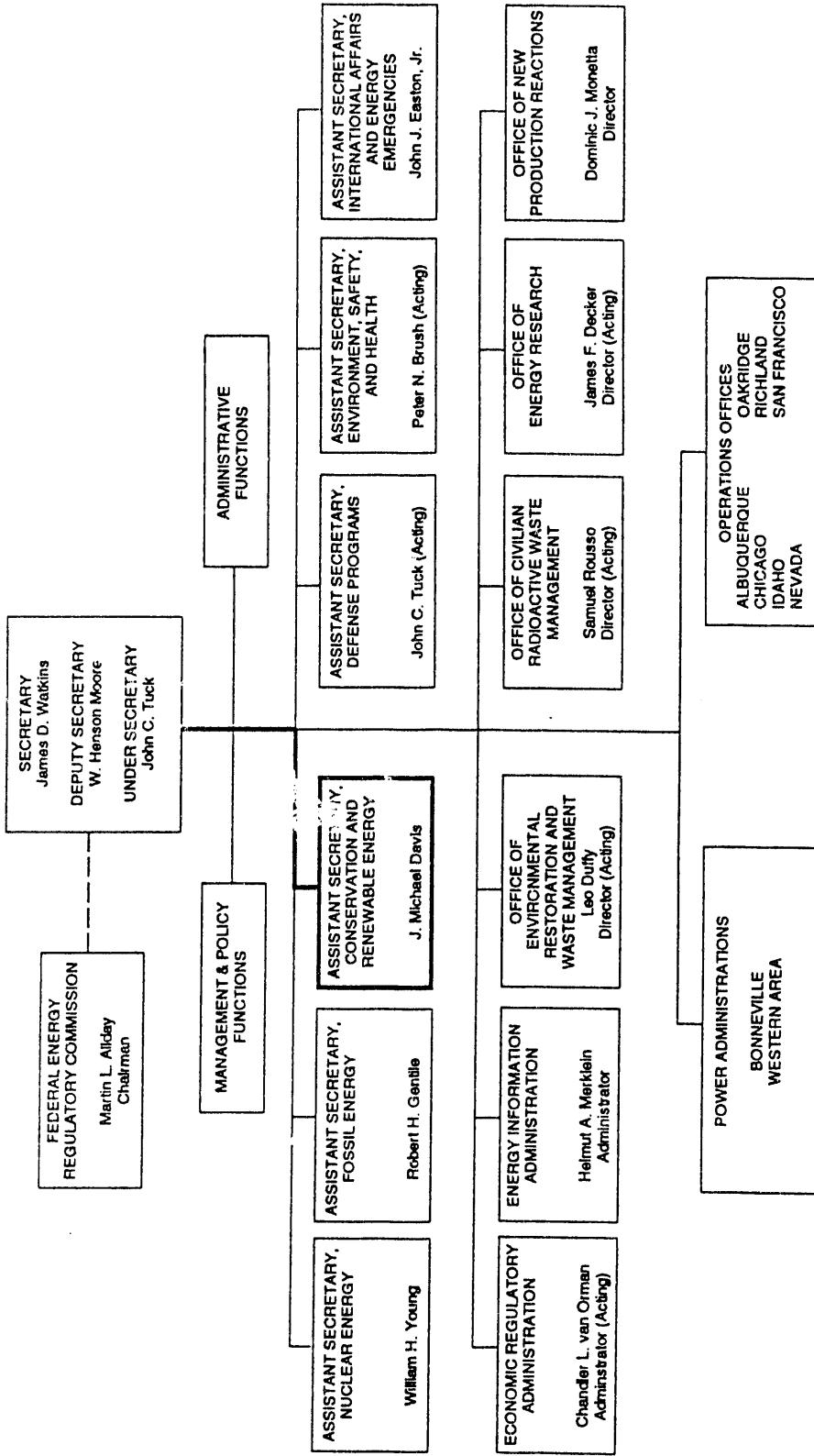
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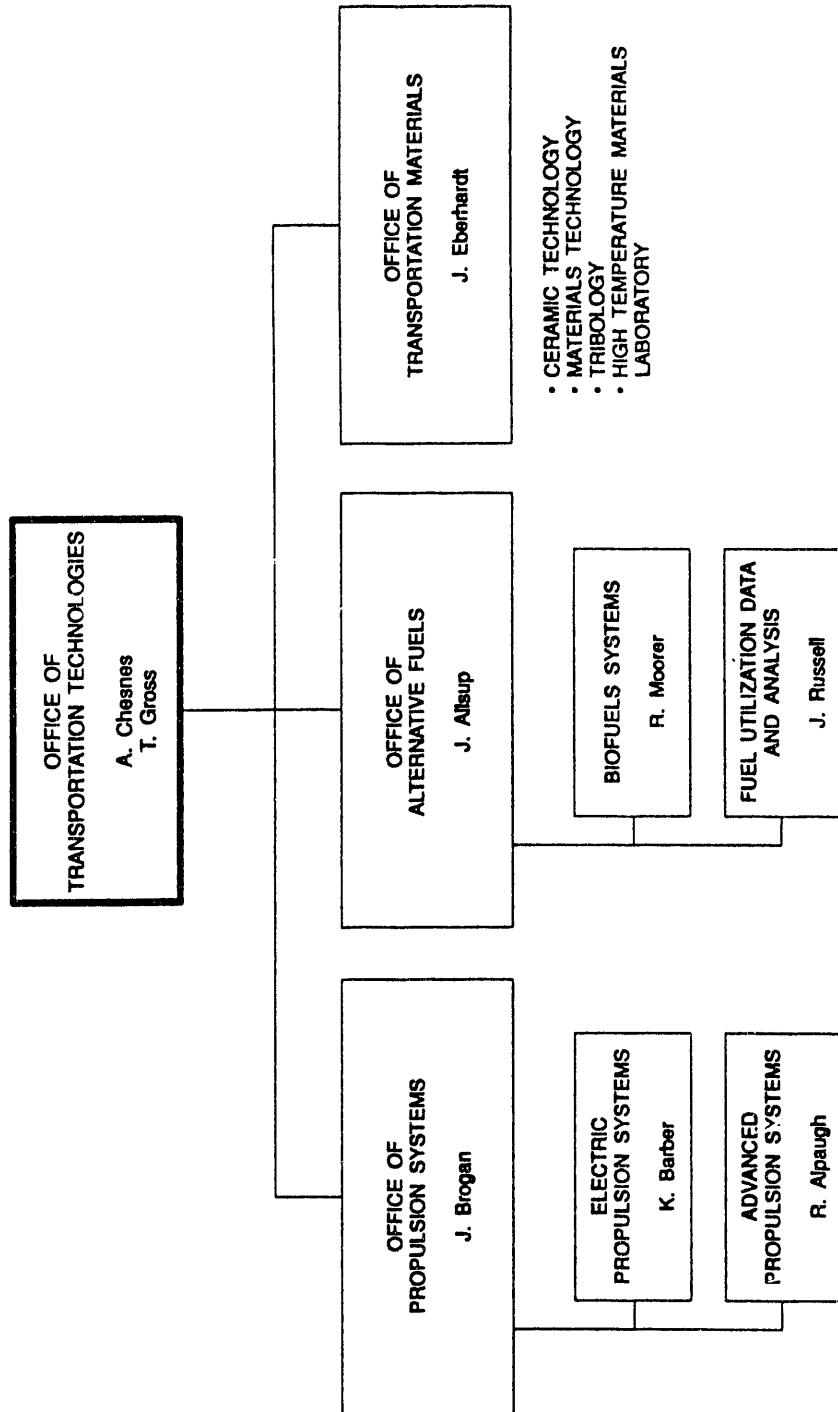
Office of Transportation Materials

THE DEPARTMENT OF ENERGY



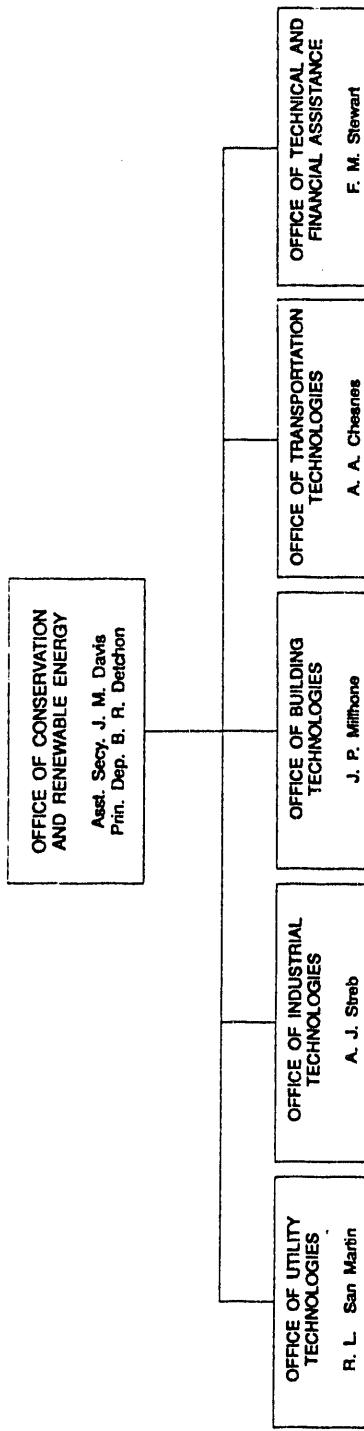
Office of Transportation Materials

Organization of the Office of Transportation Technologies



Office of Transportation Materials

Organization of the Office of Conservation and Renewable Energy



Office of Transportation Materials

Materials Development Program

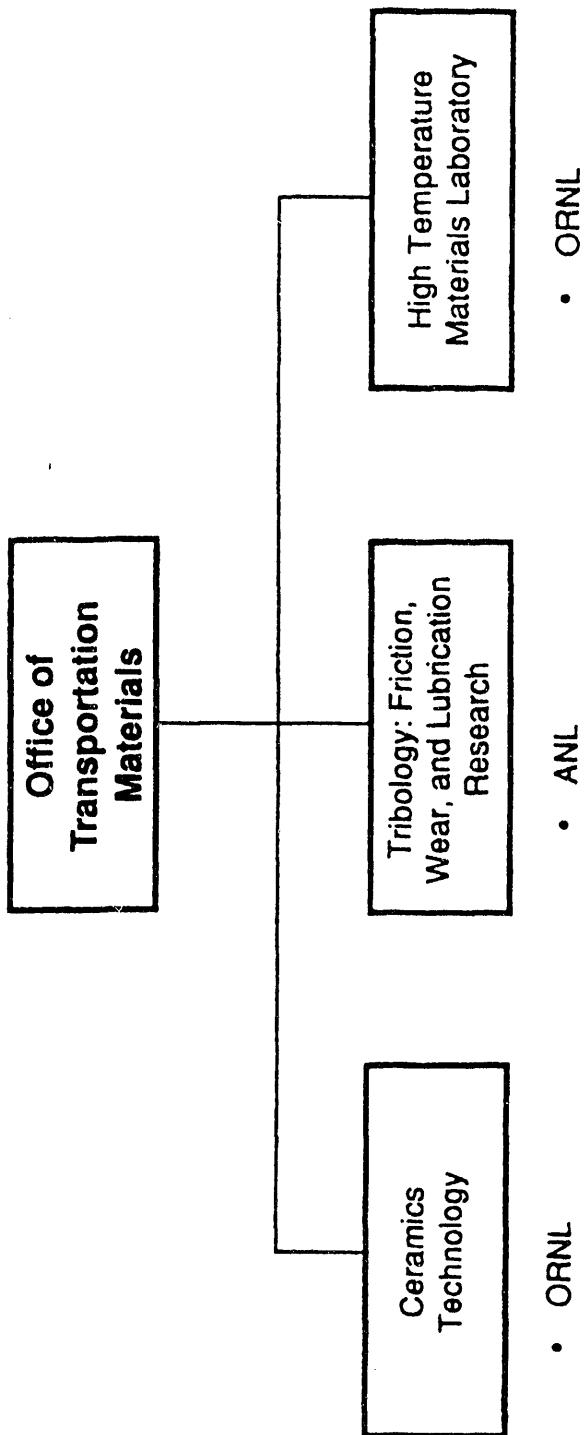
Origin - DOE / CE Reorganization April 1990

- **Action**

- **The Office of Transportation Materials (OTM) was created to provide a centralized materials development support to the programs of the Office of Transportation Technologies**

Office of Transportation Materials

Current Program Structure of OTM



Office of Transportation Materials

Role and Mission

Office of Transportation Materials

Mission

- Develop an industrial technology base in advanced transportation-related materials and associated materials processing
- Enable development and engineering of energy-efficient transportation systems that will make possible the transition of the U.S. transportation sector from near total dependence on petroleum to alternative fuels and electricity

Office of Transportation Materials

The Office of Transportation Materials is developing a comprehensive R&D program which seeks to extend throughout the transportation sector of the economy the benefits of modern materials science and engineering.

- **Materials technology enables components and systems to achieve their design performance capabilities.**
- **Improved materials of all types (metals, metal matrix composites, intermetallics, polymers, polymer matrix composites and ceramics) can be exploited so that their inherently superior properties can make the largest contribution to:**
 - improving energy efficiency;
 - reducing environmental degradation; and
 - utilizing alternative fuels all at the lowest cost possible.

Office of Transportation Materials

Materials R&D

Focus is on Materials Properties

Materials is a key "enabling technology"



Performance of a system or component depends on materials properties



Materials properties (high temperature strength, corrosion resistance, cycle fatigue, creep strength, fracture toughness, etc.) are determined by composition and microstructure of a material



Structure (microstructure and/or molecular in the case of polymers) is determined by how a material is processed



Processing is a major contributor to materials cost

Office of Transportation Materials

Tribology Program

Procurement Plan for FY 1992

Task Area: 1.0 Extreme Environment Lubrication

Task Area: 2.0 Engineered Tribology Interfaces

Task Area: 3.0 Tribology by design

Office of Transportation Materials

Tribology Program

DOE-ECUT Tribology Program:

Long-range,
High risk,
Basic research

DOE-OTM Tribology Program:

Shorter-term,
Industry relevant

Office of Transportation Materials

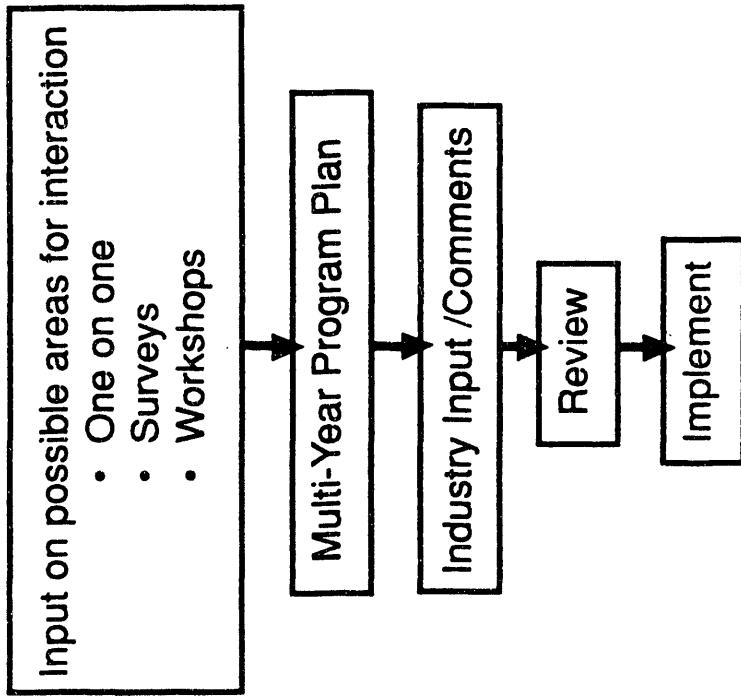
Tribology Program

Purpose

To obtain industry input on program in Tribology / Advanced Lubricants areas of interest.

Office of Transportation Materials

Tribology Program Approach



Office of Transportation Materials

Tribology Program

Objective

Identify opportunities for cost effective application of diamond and diamond-like carbon (DLC) in transportation systems.

Office of Transportation Materials

Tribology Program

Approach

- Current Status Overview (Speakers)
- Work Sessions - Panels
 - Define needs
 - Identify barriers
 - Potential benefits
- Panel Chairmen
- ANL Summary

Office of Transportation Materials

Tribology Program

Panels

Comparative Evaluation of Deposition Technologies

George Fenske, ANL

Properties of Diamond and Diamond-Like-Carbon Films

Peter Blau, ORNL

Characterization

Robert Erck, ANL

Applications to Transportation

Fred Nichols, ANL

Office of Transportation Materials

Tribology Program

Goals

- Improve competitiveness
- Reduce energy dependence
- Environmentally friendly

Acknowledgments

Fred Nichols and staff (ANL)

Ted Vojnovich and Jim Eberhardt (USDOE)

Denise Moores for outstanding arrangements

DIAMOND FILMS: HISTORICAL PERSPECTIVE

Russell Messier

The Pennsylvania State University
Materials Research Laboratory
University Park, PA 16802

Presentation at: Diamond Films Workshop
Department of Energy
Argonne National Laboratory
February 4-5, 1992

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graph TD
    A[CVD  
PYROLYSIS OF CH4  
AND OTHER HYDROCARBONS] --> B[DIAMOND FILMS  
& MICROCRYSTALS]
    A --> C[ELECTRICAL ION BEAM  
DISCHARGE  
PLASMA IN  
HYDROCARBON GAS]
    A --> D[HYDROGENATED  
DIAMOND-LIKE FILMS]
    C --> E[DIAMOND-LIKE FILMS]
    D --> E
    E --> F[VARIED SP2/3 RATIO]
    F --> G[VARIED SP2/3 RATIO]
    G --> H[HYBRIDE  
METHODS]
  
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1911 BOLTON IN GERMANY

1954 HIGH PRESSURE at GE

1955 BRIDGEMAN

1958 EVERSOLE of U.C.
HOMOEPIТАХY

1955
SCHMELLENMEIER
DC DISCHARGE

1971 AISENBERG
& CHABOT

C 967 ANGUS DERJAGUIN
 O 1973 at CWR MOSCOW
 N 1976
 C 75 BENZ
 E 1975 ATOMIC
 T HYDROGEN
 R H° SUPEREQ.
 A MICROCRYSTALS
 T
 I
 O 1981 H°
 N 1982 MATSUMOTO & SETAKA
 W FILAMENT * MICROWAVE PLASMA

1976 HOLLAND
in OJHA
in GB
RF in BUTANE
1983 KOIDL +...
in WEST GERMANY
RF in BENZENE

1976 SPENCER+.
1979 WIESSMANTAL E
1979 SOKOŁOWSKI P
1982 BANKS NASA

1984 1985 MATSUMOTO
P₁₀ RF PLASMA IN MIXTURE 1% CH₄ IN H₂

Synthetic Diamonds



Their recent production was the culmination of a hundred years of attempts, some of which were claimed to be successful. An account of these efforts and the thermodynamic laws defining the problem

by P. W. Bridgman

Now that the problem of synthesizing diamond has at last been solved, it is perhaps of interest to survey some of the highlights of the history of this long endeavor. The attempts to solve this glittering problem have revealed the whole human spectrum: those engaged in it have ranged from first-rate scientists to downright muckers and charlatans. There has been no little wishful thinking and self-deception, not

unmixed with avarice. The project has generated an extensive literature in technical journals and many accounts in the popular press, based on rumors later proved unsubstantial. Many amateurs have done their own unpublished thinking about the subject. I suppose that over the last 25 years an average of two or three people a year have come into my office, offering to share the secret and the profit of making diamonds in return

for my constructing the apparatus and reducing the idea to practice. The problem has got into the thriller literature, and I have often encountered the belief that the successful solver of this problem would be in danger of his life from the Diamond Syndicate.

The beginning of a foundation for scientific attack on the problem was laid in 1797 when the Englishman Smithson Tennant showed that diamond is a form of elementary carbon. This may be proved by burning a pure diamond in an atmosphere of pure oxygen: it burns to carbon dioxide without any residue. The common crystalline form of carbon, of course, is graphite. Diamond has a density of 3.51 against 2.25 for graphite. Modern X-ray analysis has disclosed the structural differences between them. Diamond crystallizes in a cubic system with each atom symmetrically surrounded by four others, all at the same distance and arranged at the corners of a regular tetrahedron. Graphite crystallizes in the hexagonal system: the atoms are arranged in layers; within each layer the pattern is not greatly different from the arrangement in diamond, but the layers are separated by comparatively large intervals. It is to this that graphite owes its lubricating properties, for the layers can slip over one another under the action of weak mechanical forces.

Paradoxically, although diamond is very dense and is the hardest substance known, its atoms are not packed in the closest possible geometrical arrangement. It would be much denser if each atom were surrounded by 12 other equidistant atoms instead of only four.

Willard Gibbs's work in thermodynamics at the turn of the 19th century made it possible to say theoretically under what conditions carbon



DIAMONDS made in the General Electric Research Laboratory are enlarged about seven diameters. They were grown by H. P. Bovenkamp in the press depicted on the opposite page.

take the form of diamond in preference to graphite. Gibbs's studies made clear that graphite could not turn into diamond unless the "thermodynamic potential" of diamond was less than that of graphite. The thermodynamic potential plays for chemical reactions a role closely analogous to the ordinary potential of mechanics. Just as a weight falls from a higher to a lower position because its potential is less near the earth, so a chemical reaction tends to run in the direction in which its thermodynamic potential becomes less—or, expressing the rule more rigorously, a chemical reaction can run only in the direction in which its thermodynamic potential decreases.

Gibbs showed how to calculate the thermodynamic potential in terms of the specific heat, the thermal expansion and other measurable properties of materials. It appeared probable at the time, and later it became a certainty, that the thermodynamic potential of graphite is lower than that of diamond—which is another way of saying that under ordinary conditions graphite is thermodynamically the more stable form. It follows that if any transformation is to take place at all at ordinary temperatures and pressures, it is from diamond to graphite.

But there is a catch when it comes to using these considerations to predict what will happen. For although we can tell when a transformation can run, we cannot tell when it will run. Although diamond has thermodynamic permission to transform itself into graphite under ordinary conditions, it has no mandate to do so. (Thermodynamic stability is not the same as mechanical stability.) Everyone knows that diamonds do not spontaneously change to graphite, and my wife has worn her engagement ring these many years with no solicitude on that score.

The mathematical expression for the thermodynamic potential showed that if the pressure could be raised high enough, graphite would receive thermodynamic permission to transform, even at ordinary temperatures, to diamond. This pressure was calculated to be about 20,000 atmospheres. But here again permission does not mean that the reaction will inevitably run.

Just as we cannot say that graphite will change to diamond if only it has thermodynamic permission, so also we cannot say that when a carbon compound decomposes, or when carbon is precipitated from a solution, the form of carbon that separates will be the form thermodynamically preferred. We know from the thermodynamic potential that

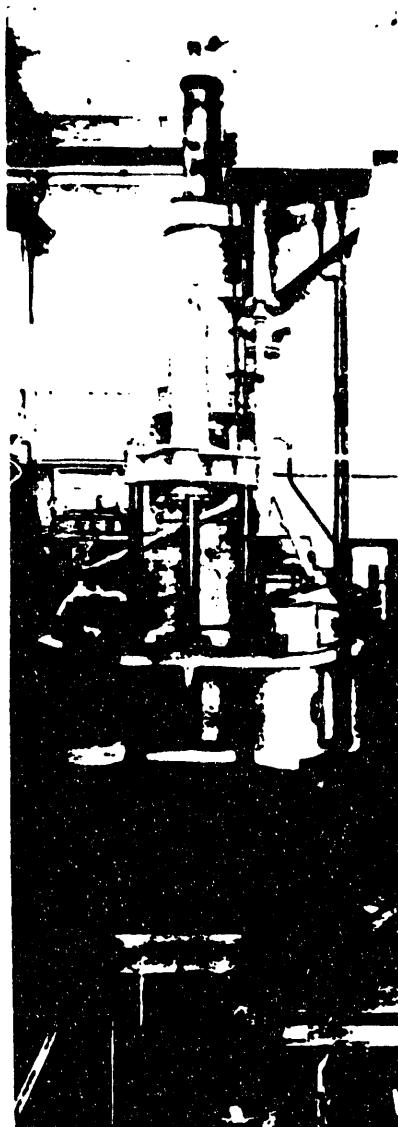
graphite is ordinarily the preferred form, but this does not enable us to say that the actual precipitate will be graphite and not diamond. As a matter of fact, there are many known instances in which an element's unstable form, corresponding to diamond, separates from a solidifying liquid or solution in preference to the more stable form.

The possibility that diamond may be formed as an unstable phase under conditions where "nascent" (uncombined) carbon is liberated makes it impossible to rule out the chance of an accidental success. Thus I could never say to the hopeful amateur who walked into my office: "Your process certainly will not work." I could only say this when he proposed to transform graphite directly into diamond under thermodynamically impossible conditions. The aforementioned possibility has been one of the bogeys in the whole situation. Many geologists and mineralogists have been of the opinion that diamond is formed in nature under unstable conditions, which would mean that it might be a matter of anybody's lucky guess to find the proper conditions.

None of the sophistications we have considered entered into the early attempts to make diamonds. Many of those who made the attempt were guided simply by the fact that diamond is more dense than graphite, which naturally suggested the possibility that it might be formed by subjecting carbon to great pressure. There were then no means of producing anything like the 20,000 atmospheres later calculated to be necessary, but claims of success were numerous nonetheless.

One of the earliest and still most discussed attempts was by a Scot, J. B. Hannay, in 1880. He mixed hydrocarbons, "bone oil" and lithium, sealed the mixture in a wrought-iron tube and heated it to redness in a forge. All but three of 80 tubes exploded. (The pressure in the tubes could not have been more than one or two thousand atmospheres.) In the residue of the unexploded tubes it was said that diamonds of density 3.5 were found. The claim was accepted at its face value and reported in the London Times by N. Story-Maskelyne. Subsequent attempts by a number of experimenters failed, however, to reproduce Hannay's results.

The matter was reopened in 1943 by the discovery in a forgotten corner of the British Museum of a small exhibit labeled "Hannay's Diamonds." These were analyzed with X-rays by F. A. Bannister



HYDRAULIC PRESS in which the diamonds were grown is capable of exerting a force of 1,000 tons. The pressure chambers are located below the floor level (bottom).

and Kathleen Lonsdale, and found to be certainly diamonds, and of a somewhat rare type at that. On the theory that it was unlikely that diamonds fraudulently inserted would be of this rare type, Bannister and Mrs. Lonsdale argued that Hannay's claim was probably genuine. But there was also contrary evidence, in particular, as pointed out by Lord Rayleigh, some known instances of bad faith on Hannay's part. It seems to be the present consensus that Hannay was a fraud. Mrs. Lonsdale recently told me that she now also inclines to that view.

Perhaps the best known experiments of all are those of the Frenchman Henri Moissan, made in the 1890s when he was

metal halide melt, obtaining feltable titanium dioxide fibers, and levitating the feltable titanium dioxide fibers from the metal halide melt.

1,698,184

METHOD FOR PRODUCTION OF MAGNESIUM HYDROIDE

John P. Powell, Kennesaw, Georgia; E. Fugle, Newark, and Theodore L. Maytag, Tennessee, N.Y., assignors to Ohio Matchless Chemical Corporation, No Drawing, Filed Aug. 31, 1958, Ser. No. 762,380
2 Claims. (CL 23—269)

1. In the production of magnesium hydride by reacting magnesium metal and molecular hydrogen, the step of introducing into the reaction mixture consisting essentially of magnesium metal and hydrogen a catalytic amount of a compound of the class RXX' wherein R is an aliphatic hydrocarbon radical containing from 1 to 3 carbon atoms, X is selected from the group consisting of chlorine, bromine, and iodine and X' is selected from the group consisting of chlorine, bromine, iodine and hydrogen.

1,698,185

PROCESS FOR PRODUCING BORON TRICHLORIDE

Sheldon L. Clark, Kennesaw, and Theodore L. Maytag, Tennessee, N.Y., assignors to Ohio Matchless Chemical Corporation, a corporation of Virginia
No Drawing, Filed Feb. 14, 1958, Ser. No. 715,474
2 Claims. (CL 23—269)

1. A process for the production of boron trichloride which comprises pyrolyzing diborane in a first reaction zone under conditions providing products including a mixture of boron hydrides higher than decaborane, separating the mixture of boron hydrides higher than decaborane from the other pyrolysis products, separately reacting the mixture of boron hydrides higher than decaborane in a second reaction zone at a temperature within the range from about 30° to 350° C. with a gas stream consisting essentially of chlorine, and recovering boron trichloride from the reaction product.

1,698,186

MANUFACTURE OF HYDROGEN PEROXIDE
Donald F. Krebs, Buffalo, and Leonard R. Durkin, Grand Island, N.Y., assignors to FMC Corporation, a corporation of Delaware
No Drawing, Filed May 16, 1958, Ser. No. 735,675
2 Claims. (CL 23—367)

1. In the production of hydrogen peroxide by the alternate reduction and oxidation of an alkylated aniline-quinone as the working material carried in solution and wherein the working material is hydrogenated by passage through a fixed particulate catalyst bed of a noble metal catalyst deposited as a surface coating upon an inert solid carrier, the improvement comprising such inert carrier being within the range of 4 mesh to 60 mesh and having a surface area of less than five square meters per gram and a pore volume as to pores of less than 800° A. of less than 0.03 cc. per gram.

1,698,187

SYNTHESIS OF DIAMONDS

William G. Edwards, Kennesaw, N.Y., assignor to Union Carbide Corporation, a corporation of New York
No Drawing, Filed July 21, 1958, Ser. No. 750,309
8 Claims. (CL 23—269.4)

1. A solid-gas contacting process for growing diamond on diamond seed crystal; contacting said diamond seed crystal solely with a gas selected from the group consisting of carbon monoxide and mixtures of carbon dioxide and carbon monoxide at temperatures between about 800° C. and about 1600° C. and pressures above about 20 atmospheres.

1,698,188

SYNTHESIS OF DIAMONDS

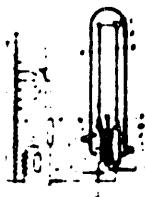
William G. Edwards, Kennesaw, N.Y., assignor to Union Carbide Corporation, a corporation of New York
No Drawing, Original application July 23, 1957, Ser. No. 750,309. Divided and this application Nov. 24, 1958, Ser. No. 154,838
9 Claims. (CL 23—269.4)

1. A process for growing diamond on diamond seed crystal which comprises providing diamond seed crystal; contacting said diamond seed crystal with a gas which is at least partially decomposable to a free methyl radical at temperatures between about 800° C. and about 1600° C. and pressures at which the partial pressure of the gas decomposable to a free methyl radical is low than about 75 millimeters of mercury.

1,698,189

MANUFACTURE OF SEMICONDUCTOR SUBSTANCES OF HIGH PURITY, PARTICULARLY ELECTRICALLY CONDUCTIVE SUBSTANCES

Mark L. Johnson and Robert G. Johnson, Indianapolis, and John W. Johnson, Indianapolis, assignors to Bell Telephone Laboratories, Inc., New York, N.Y.
No Drawing, Filed June 1, 1958, Ser. No. 735,676
2 Claims. (CL 23—269.4)



5. A method of producing an electric semiconductor of high purity, comprising contacting the peripheral surface of an elongated carrier body of the same material as the semiconductor with a gas comprising a chemical compound of the material, the carrier body being heated by passing an electric current through the elongated body lengthwise thereof, the heating being to a temperature sufficiently high to cause chemical conversion of the chemical compound to said material and deposition of the latter on the lengthwise extending peripheral surface of the carrier body, stretching the enlarged body, in a crevice-free zone-pulling process, by pulling an end region thereof in a direction away from the opposite end region while making a zone of limited longitudinal dimension by heating means having no contact with said zone, the molten zone being caused to be displaced longitudinally with respect to the body during the pulling, whereby an elongated section of reduced cross-section is produced in the body, contacting at least part of the reduced section, employed as heated elongated carrier body, with a gaseous chemical compound of the said material to enlarge said piece by deposition of the material thereon.

1,698,190

METHOD OF CHEMICAL TREATMENT OF OILS
Walter P. Schaeffer, Indianapolis, Indiana, and Francis P. Hartigan, Indianapolis, Indiana, assignors to Shell Oil Company, New York, N.Y., a corporation of Delaware
No Drawing, Filed Apr. 26, 1958, Ser. No. 24,628
2 Claims. (CL 23—269)

1. A method of determining the saponification number of mineral oils which are subject to carbonization with

1968

Growth of Diamond Seed Crystals by Vapor Deposition

JOHN C. ANGUS, HERBERT A. WILL,* AND WAYNE S. STANKO

Case Western Reserve University, Cleveland, Ohio

(Received 30 November 1967)

Carbon was deposited on virgin, natural diamond powder from methane gas at 1050°C and 0.3 Torr. The deposits were identified as new diamond by chemical analysis, chemical etching, density measurements, x-ray and electron diffraction, microwave absorption, electron spin resonance, and visual observations. The crystalline quality of the new diamond layers has not been established; it could range from polycrystalline material with a large number of defects to true epitaxial layers.

I. INTRODUCTION

The history of diamond synthesis is long and colorful and relatively familiar.¹ Most efforts were directed at transforming carbonaceous material to diamonds at high pressures where diamond is the thermodynamically stable phase. These efforts were successful in 1955.²

It is less well known that there have been a number of serious, independent proposals for growing diamond at low pressures. Among those discussing the possibility were Bridgman,³ Ubbelohde and Lewis,⁴ Suits,⁵ Lander and Morrison,⁶ and Angus.⁷ In addition, claims of successful low-pressure syntheses were made by Brinkman⁸ and Evernote,⁹ the latter being the more relevant for the present work. All of the proposed processes involve deposition of carbon onto a diamond seed crystal at pressures where diamond is thermodynamically unstable with respect to graphite.

In the light of this history it is remarkable that the question has received so little serious attention. In this paper we present evidence conclusively demonstrating that diamond crystals can be grown at sub-atmospheric pressures.

II. DISCUSSION OF METHOD

The tendency to discuss diamond synthesis in the terms of equilibrium thermodynamics can obscure the fact that kinetic factors may provide the possibility of diamond synthesis in a temperature-pressure regime where diamond is actually thermodynamically unstable with respect to graphite. For example, there is a

significant activation barrier impeding the spontaneous transformation of diamond to graphite. In fact, the rate of spontaneous transformation does not become significant until 1300°C. Also the mobility of carbon atoms on clean diamond surfaces at 1000°C is quite high.¹⁰

These considerations show that a diamond seed crystal might be expected to grow if placed in an environment supersaturated with respect to carbon at temperatures ranging from 1000°C to 1300°C. A competing process will, of course, be the spontaneous nucleation of new graphite crystals from the supersaturated vapor phase. (This is not to be confused with the spontaneous transformation of the diamond substrate into graphite). It can be expected that the rate of homogeneous nucleation of graphite in the vapor phase will be small because of the surface free-energy barrier to nucleation predicted by conventional nucleation theory. Heterogeneous nucleation of graphite on the diamond seed crystals cannot be avoided, but the mobile carbon atoms on the diamond surface may be more likely to attach themselves to the diamond crystal rather than to form new graphite nuclei.

Graphite has a lower Gibbs free energy (chemical potential) than diamond. Therefore, if the atmosphere above the crystal is supersaturated with respect to diamond, then it will be even more supersaturated with respect to graphite. This means that the possibility of nucleating graphite can never be eliminated but it is expected that the probability will be low because of the factors listed above.

In this paper we report on the growth of natural, virgin diamond powder by vapor deposition at sub-atmospheric pressures. Our experiments show that new diamond is formed. The crystalline quality of the new diamond has not been established, however.

III. EXPERIMENTAL METHOD

A. Deposition and Cleaning Procedures

A gas phase supersaturated with carbon was provided by the thermal decomposition of methane gas at pressures ranging from 0.15 to 458 Torr and tem-

* Present address: NASA, Lewis Laboratories, Cleveland, Ohio.

¹ P. W. Bridgman, *Sci. Am.* 193, 42 (1955).

² F. P. Bundy, H. T. Hall, H. M. Strong, and R. H. Wentorf, *Nature* 176, 51 (1955).

³ A. R. Ubbelohde and F. A. Lewis, *Graphite and Its Crystalline Compounds* (Oxford University Press, London, 1960), p. 62.

⁴ C. G. Suits, *The Synthesis of Diamond—A Case History in Modern Science*, A paper presented before the American Chemical Society, Rochester, New York, Nov. 3, 1960. Reference is made to an unpublished report by R. A. Oriani and W. A. Rocco.

⁵ J. J. Lander and J. Morrison, *Surface Sci.* 4, 241 (1966).

⁶ J. C. Angus, *Synthesis of Diamonds*, unpublished report, Nov., 1961.

⁷ J. A. Brinkman, U.S. patent No. 3,142,539, July 28, 1964.

⁸ W. G. Evernote, Canadian patent No. 628,567, October 3, 1961.

АКАДЕМИЯ НАУК СССР

Ордена Трудового Красного Знамени

Институт физической химии

DERYAGIN FEDOSEEV GROWTH OF DIAMOND POCET ALIMAZA and GRAPHITA GRAPHITE ИЗ ГАЗОВОЙ ФАЗЫ from GAS

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Москва

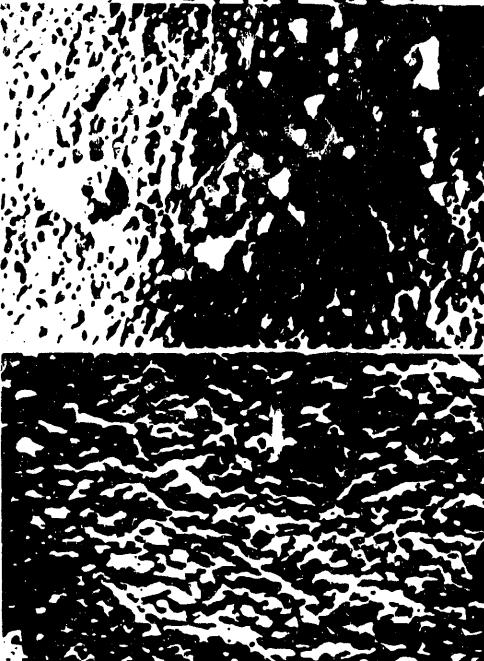
PIUS & VINCENZO

4. ЭПИТАКИТАСИЕ АЛМАЗНЫЕ ПЛЕНИКИ И ИНТЕРФИДНЫЕ КРИСТАЛЛЫ

HYPOTHETICAL SOLVENT

Когда же здесь от китайской земли перекинут известные гравюры, то, быть может, в связи с повышением на них второго критического звена, то есть частотности, либо это не может произойти, то есть частотность не вырастет и поэтому гладко выходит из земли и попадает на террасу, размытую вступившим в землю потоком, и впадает в реку, и на нее, таким образом, попадают китайские гравюры.

ATOMIC HYDROGEN: I. CATALYTIC & P.



Таким образом, несмотря на начинаящуюся кристаллизацию, ядро граней равно расщепляется, между ядрами оставаясь зернистым, и в среднее время между первыми двумя падающими кристаллами ядро расщепляется на южное и северное ядра. Размеры ядер неизменны, но различия в размерах кристаллов в разных группах ядер неизменны, например уменьшения в южной группе в 1,5 раза. В то же время случаи полного кристалла не являются.

На разных стадиях кристаллизации из газа заметно проявляется эффект декорирования, т.е. экзогенное развитие структуры поверхности реального кристалла. На рис. 54 показаны катализированные выращивания азотом поверхности затравочного кристалла алмаза на начальной стадии кристаллизации. При температуре роста кристаллов отдельные островки ячейки размываются (рис. 54, a), которые затем, сливаясь, образуют сплошной фронт кристаллизации (рис. 54, б).
На рис. 55 показана скорость роста алмаза, полученная из изотопных измерений. Скорость роста алмаза, выращиваемого из газа, зависит от температуры, давления и концентрации газа.

SELECTIVE GASIFICATION OF GRAPHITE



Рис. 14. Акустическая картина изображения в виде звуков в диапазоне 0-1000 Гц в зависимости от времени (0-1000 мкс).

2. ELECTRICAL DISCHARGE 3. W FILAMENT

существует **двойство**. Как было показано в предыдущей главе, разбавление углеродсодержащего газа во градиенте сильно уменьшает скорость роста графита, но почти не отражается на скорости роста лимита. Таким образом, если вводится CO , то графит при давлении 10^3 атм и температуре $1000^{\circ}C$ [45]. Однако можно предположить, что на графит действует именно атомарный водород. При температуре $1050^{\circ}C$ концентрация молекулярного водорода концентрация **атомарного водорода** во 10^2 раза величине пропорциональна корню квадратному из общего излучения. Поэтому для газификации используют высокие давления. Стакко и **Барбера** [66] или с помощью **атомарного водорода** [67] считают разбавленное **атомарное** водородом.

Совместное в одном реакторе двух процессов — роста зерен (и графита) из углеродсодержащего газа и катализитического получения атомарного водорода в непосредственной близости от загрязненного чоком кристалла алмаза — позволило авторам (см. статью Н. Д. Поповской) получить и исследовать структуру (построить кристаллическую модель) алмазных пленок.

Структурные исследования, проводимые с помощью дифракции электронов, подтверждают следующую картину роста. Первоначально растет один совершенно чистый монокристалл (рис. 36, а), затем его структура удаляется на передний монокристаллических участках растет поликристаллический алмаз (см. рис. 36, б). На следующей стадии растет как алмаз, так и графит. Примеси алмаза сохраняют монокристаллическую структуру, что видно по ярким ямочкам, которые часто бывают двойными вследствие наследования двойниковой структуры кристалла-затравки. Далее растет поликристаллический алмаз совместно с графитом в якорных пазах, ракит (см. рис. 36, в). Ниже приведены результаты расчета в "заданных" значениях температурных распределений на стадии, соответствующей рис. 36, г.

	C_{max} , Å	1.06	1.27	1.075	1.457	1.414	1.723	1.53	1.24	1.257
C_{max} , Å	1.06	1.27	1.075	1.457	1.414	1.723	1.53	1.24	1.257	
C_{max} , Å	1.06	1.27	1.075	1.457	1.414	1.723	1.53	1.24	1.257	

Некоторые свойства стекловидных эпите克斯иальных плёнок изучены в работе 1901. Микротвердость стекловидных плёнок изменяется в зависимости от времени термической обработки плёнок на приборе ГИМТ-3. Глубина залегания составляет 1 мкм. Измерения величины микротвердости проводятся в диапазоне 1500 ± 100 кг/мм², что соответствует диапазону для предела прочности.

Зависимость состава пленки по данным микрорентгеноспектрального анализа, проведенного на приборе МС-45 (Макет), отвечает соотношению углерод: 99,5 \pm 1,5%. Плотность слоя синтетического керамика определялась по користи фотографии для трех образцов, полученных в рабочей зоне: 1,9 \pm 0,4 г/см³. Поверхность предварительно

VAPOR GROWTH OF DIAMOND ON DIAMOND AND OTHER SURFACES

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Institute of Physical Chemistry, Academy of Sciences of the USSR, Moscow, USSR

It is shown that diamond crystallization by chemical vapor deposition should preferably be carried out at reduced pressures. Selective growth of diamond is ensured by introducing atomic hydrogen into the crystallization zone: this suppresses crystallization of graphite. The growth rate of homoepitaxial diamond films reached $1 \mu\text{m/h}$ at 1000°C ; film properties were identical to those of bulk crystals. The lattice parameter in boron-doped films ($\sim 0.1 \text{ at. \%}$) decreased by 0.0019 \AA ; the film and substrate parameters coincide at dopant concentrations of $\sim 1 \text{ at. \%}$, and the semiconductor diamond film intergrows with the substrate *without stress*. Diamond crystals up to several tens of microns in thickness were grown also on non-diamond substrates. At large supersaturation, the crystal habit is octahedral and at low supersaturation, it is cubic. The linear growth rate is constant at the early stages of crystal growth but then it diminishes to a level typical for the homoepitaxial growth of diamond films.

1. Introduction

The unique combination of excellent mechanical, physical, and chemical properties of diamond has been the driving force for the development of new and cheaper methods of synthesis. Different fields of diamond applications both in research and industry can be satisfied only by essentially different techniques of crystallization. For instance, the unique electrical and thermal properties of diamond, as a high-temperature semiconductor, can be fully developed only under the following strictly controlled conditions of synthesis: layered structures are grown, consisting of alternating dielectric and semiconducting single crystalline diamond films, with thickness of the order of one micron each. Such conditions can be obtained by means of vapor growth techniques at reduced pressure, that is in the region of metastability of diamond. Research in this direction [1, 2] began almost at the same time as the well-known work on diamond synthesis at ultrahigh pressures.

2. Physical and chemical crystallization

The simplest process of diamond crystallization is the sublimation of graphite and subsequent condensation of the carbon vapor on the

surface of the diamond seed crystal. The material is transferred to the growing crystal due to the temperature gradient between the source and the substrate [3]. Although this process is, in principle, possible, in practice it is inhibited by a number of factors:

(1) According to LEED data [4], the diamond surface retains the bulk structure up to temperatures $\sim 1300^\circ\text{C}$ (in vacuum). At such temperatures the equilibrium carbon vapor pressure over the diamond phase is almost twice [3] that over graphite [5], and reaches $\sim 1 \times 10^{-13} \text{ Torr}$. An acceptable growth rate (about $1 \mu\text{m/h}$) requires that the carbon vapor pressure over diamond phase exceed 10^{-11} Torr . Hence, the sublimation growth of diamond at such rates requires supersaturation $\sim 10^7$ which obviously entails high defect density in the overgrowth. In addition, the probability of nucleation and growth of the graphite phase which is stable at low pressures, will also be considerable at such high supersaturations [6].

(2) The composition of carbon vapor over graphite shows a predominance of C_2 -type molecules [5] with multiple bonds between carbon atoms; this factor inhibits incorporation of carbon units into the diamond lattice.

(3) Finally, even single carbon atoms in the ground (non-excited) state are bivalent, so that about 96 kcal/g-atom has to be expended to

when the crystallization temperature decreases and the partial pressure of the component comprising the crystallized material increases. In the synthesis techniques that we have chosen, the supersaturation is a function of both the pressure of hydrocarbons, and of the partial pressure of atomic hydrogen. The latter changes the concentration of the hydrocarbon complexes adsorbed on the substrate, by interacting with hydrocarbons in the gas phase and on the surface. Hence, the atomic hydrogen not only maintains selectivity of the process but also affects the growth rate, thus having the role of an active participant in the diamond crystallization.

3. Diamond growth on diamond surfaces

Substrate temperature is one of the factors which determines the rate of the process and the structure of the deposit. Diamond layers grown on single crystals at 600°C are polycrystalline with grain size of 15 to 20 Å [15]. However, high-perfection single-crystalline layers were obtained on the {110} face of natural diamond at 750°C; this is confirmed by electron diffraction (fig. 1) which shows a well-pronounced system of

Kikuchi lines. As the temperature is increased further, the growth rate of homoepitaxial film increases (activation energy of the order of 25 kcal/mole) and reaches a maximum at $\sim 1100^{\circ}\text{C}$. Further increase in temperature results in reduction of the growth rate and in deterioration of the structure of the diamond layers, so that HEED analysis reveals graphite inclusions

Cathodoluminescence [17] and X-ray topography [16] have demonstrated that void-type growth defects produce stresses in homoepitaxial diamond films. As the crystallization temperature is lowered from 1100 to 800°C, the stress in the film increases by a factor of approximately three. When the stresses in the substrate-film system exceed a certain threshold, lattice discontinuities and microtwin lamellae are formed in the film [18]. At the same time, ESR studies show that the film contains broken C-C bonds. Stresses produced during growth and high rates of crystallization may result in deterioration in the morphology of the diamond deposit (fig. 2) and in a gradual transformation from a single-crystalline film into a polycrystalline one. The diamond layers were characterized (using SIMS) by a comparatively high purity [19]; the impurity content was found to be approximately the same as in natural single crystals. One exception is

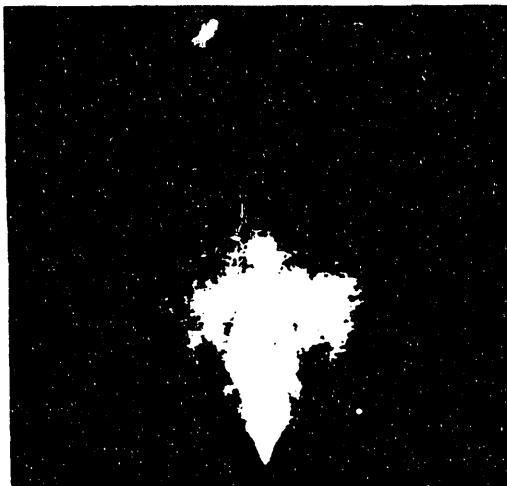


Fig. 1. Electron diffraction pattern ($E = 65\text{ keV}$) of a diamond film $0.8\text{ }\mu\text{m}$ thick, grown on {110} face of a natural diamond crystal at a growth rate $\sim 0.4\text{ }\mu\text{m}/\text{hour}$.

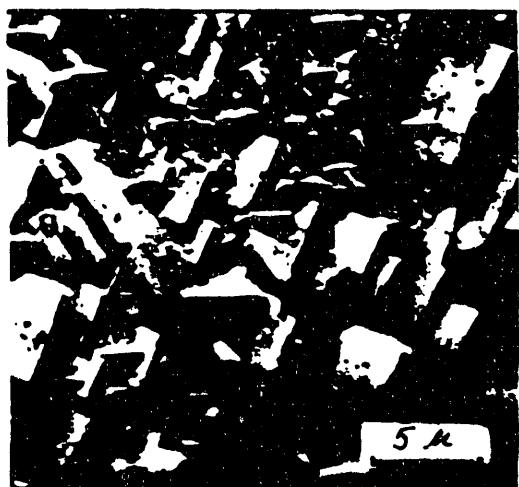


Fig. 2. Diamond layer $\sim 4\text{ }\mu\text{m}$ thick, grown at a rate of $\sim 2\text{ }\mu\text{m}/\text{hour}$ on {111} face of a natural crystal.

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DIAMOND ON DIAMOND

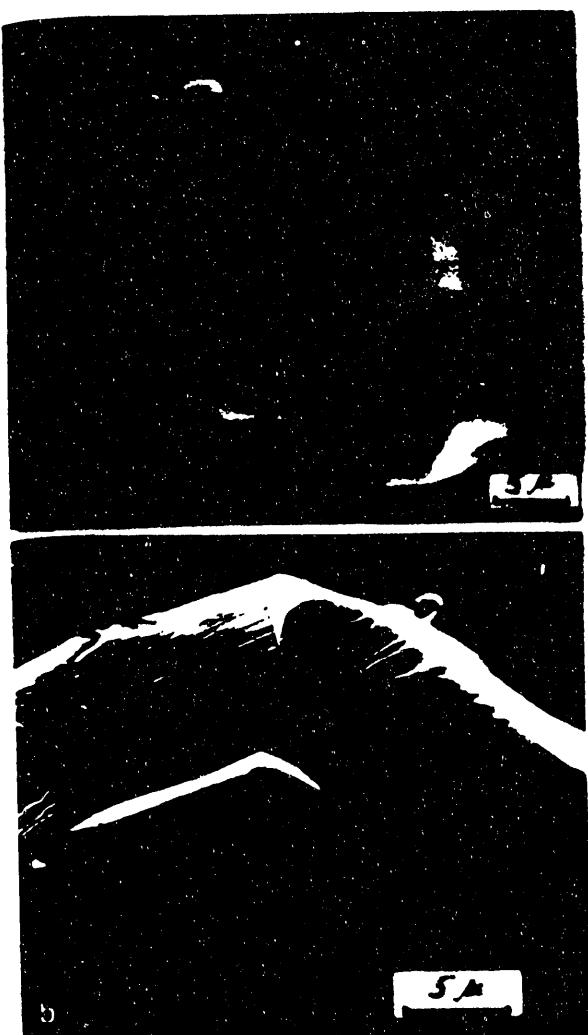


Fig. 4. Growth twinning on (a) {111}, and (b) {100}, faces.

of a polycrystalline copper specimen annealed in hydrogen (fig. 5a). After a certain growth time the specimens were extracted from the reactor, photographed in a scanning electron microscope, and then returned to the reactor. A conducting gold layer was not found necessary to obtain an image when applying a scanning electron microscope to photograph diamond crystals, having sizes up to $50 \mu\text{m}$, that were grown on a conducting substrate.

Figs. 5b and 5c show the same area of the copper substrate as that in fig. 5a, after 15 and 30 min of growth. Crystals spontaneously nucleated on the substrate surface are seen to

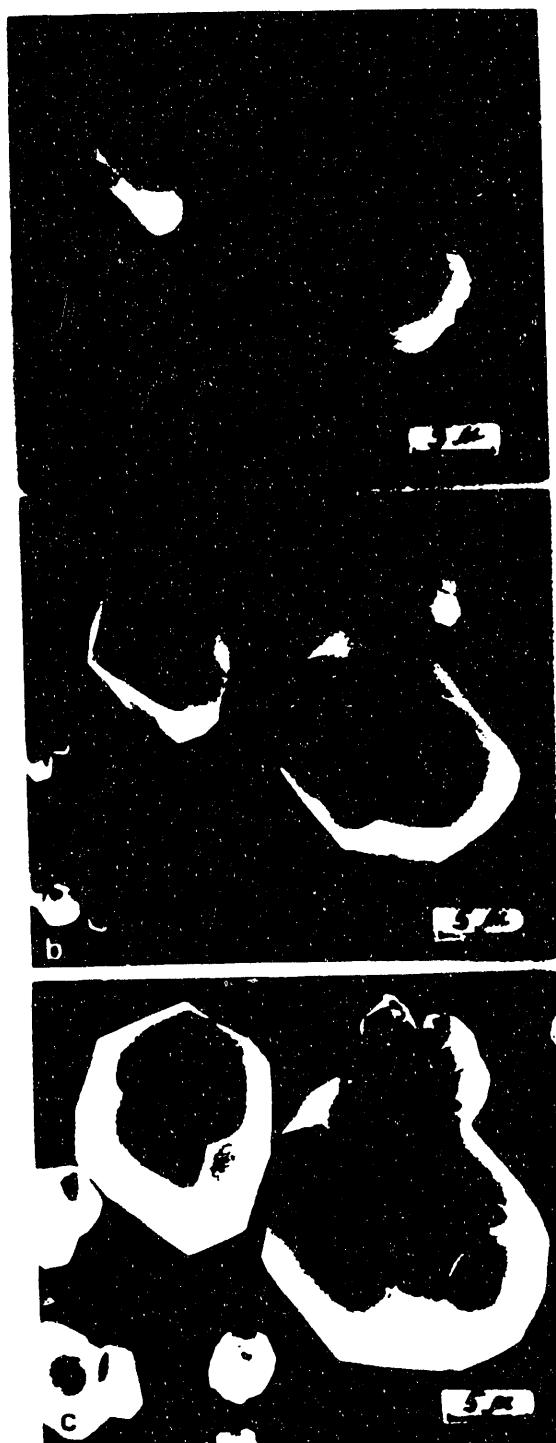


Fig. 5. Growth of diamond crystals on copper substrate: (a) area of substrate with two rounded-shape diamond seed crystals. (b) and (c) same area after 15 and 30 min of crystallization, respectively.

Vapor Deposition of Diamond Particles from Methane

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Microcrystalline diamond has been formed on silicon or molybdenum substrates by vapor deposition from a gaseous mixture of methane and hydrogen. Cube-octahedral or multiply-twinned crystals were obtained. The structure of the deposits was identified by electron diffraction and Raman scattering.

The considerable effort that has been devoted to the synthesis of diamond has been motivated by the unique combination of properties exhibited by this material. These properties include great hardness, high thermal conductivity, high electrical resistivity, optical transparency and semiconductivity induced by impurity doping. Besides high pressure techniques, currently used for commercial production of diamond, attempts have been made to make diamond by chemical vapor deposition (CVD),¹⁻³⁾ ion-beam techniques,⁴⁻⁶⁾ and plasma-induced vapor deposition.⁷⁻¹⁰⁾ The carbon films obtained by these techniques are often termed diamondlike, since they show, to some extent, properties similar to those of diamond. Unambiguous identification of the structure of these films, however, is difficult owing to the amorphous nature of the films or the appearance of forbidden reflections and of reflections from structures other than diamond in electron diffraction.^{3,6,8,9)}

On the other hand, Deryagin et al.¹¹⁾ reported that octahedral or cubo-octahedral diamond crystals can be grown on non-diamond substrates such as copper and gold by chemical transport in a closed system. Recently, a more detailed account of the growth features, characterization and possible growth mechanism has been given by Spitsyn et al.¹²⁾ Diamond crystals were grown on diamond, silicon, tungsten and molybdenum at growth rates of up to 5 $\mu\text{m}/\text{h}$. The importance of the role played by atomic hydrogen was pointed out, but the details of the deposition technique were not given. In this paper, we report that diamond crystals can also be grown on non-diamond substrates by CVD in a flow-system.

Deposition was carried out by passing a mixture of gaseous methane and hydrogen through a deposition chamber, in which a tungsten filament was mounted near the substrate, as shown in Fig. 1. Silicon wafers or molybdenum plates were used as the substrates. Observations by SEM were made with the deposits obtained under the following conditions: methane concentration, ca. 1 vol %; total gas pressure, 10-100 Torr; flowrate, ca. 10 ml/min; temperature of deposition chamber, 800-1000°C; filament temperature, ca. 2000°C. The temperature of the deposition chamber was measured by a thermocouple in contact with the silicon substrate holder, as shown in Fig. 1.

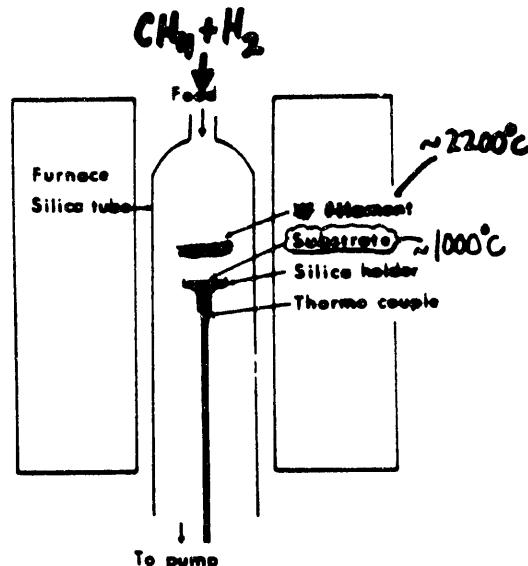


Fig. 1. Schematic diagram of deposition chamber.

be higher than the temperature measured by the thermocouple as a result of radiation from the filament.

After deposition runs of 3 hours' duration, diamond particles up to 3 μm were formed as shown in Fig. 2(a). There appeared to be little difference in the growth characteristics between silicon and molybdenum substrates. Multiply-twinned crystals as well as cubo-octahedral crystals were observed. The microstructures resemble that observed with crystals deposited by chemical transport in a closed system.^{11,12)} Film-like regions are also formed by the contact of crystals, as Fig. 2(c) shows. The density of nucleation appears to depend strongly on the substrate conditions, and preferential growth along scratches or edges was often seen.

The structures of the deposits were identified by reflection electron diffraction. As Fig. 3 shows, spotted rings were observed; the pattern consists of diffraction spots from more than a hundred particles. As Table I shows, the d -values obtained from the diffraction rings are in good agreement with the reported values for cubic diamond except that the 222 double diffraction ring appears in the diffraction pattern.

Raman scattering of the deposits was also observed as support for the structural identification. The spectra were recorded at room temperature using a Spex Raman

SEM
MORPHOL.

Fig. 2. Scanning electron micrographs of diamond deposited on silicon. (a) Diamond particles deposited at 790°C (micrograph taken by tilting substrate). (b) Film-like region formed at 890°C.

Table I. Comparison of observed interlayer spacings with reported values.

Observed	Reported (ASTM 6-675, Diamond)			
d (Å)	I	d (Å)	I/I_0	hkl
2.06	s	2.06	100	111
1.26	r	1.261	25	220
1.08	s	1.0754	16	311
1.03	w	—	—	222
0.89 ₃	w	0.8916	8	400
0.81 ₈	m	0.8182	16	331
0.727	m	0.7280 ^a	—	422
0.685	m	0.6864 ^a	—	511, 333
0.633	w	0.6305 ^a	—	440
0.603	m	0.6029 ^a	—	531

^a Calculated from the reported value of $a_0 = 3.5667$ Å.

1401 spectrometer with a back-scattering geometry. The 488.0 or 514.5 nm lines of an argon ion laser or the 441.6 nm line of an He-Cd laser were used for excitation. In

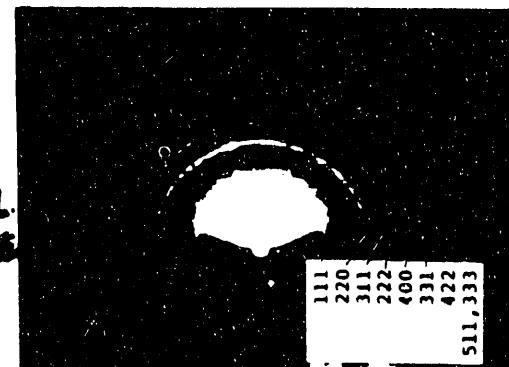


Fig. 3. Reflection electron diffraction of diamond particles deposited on silicon.

the Raman-shift range of 300–2500 cm⁻¹, the spectra consist of Raman peaks due to diamond as well as to the substrate, and background due to weak luminescence, as Fig. 4 shows. Raman scattering from the amorphous

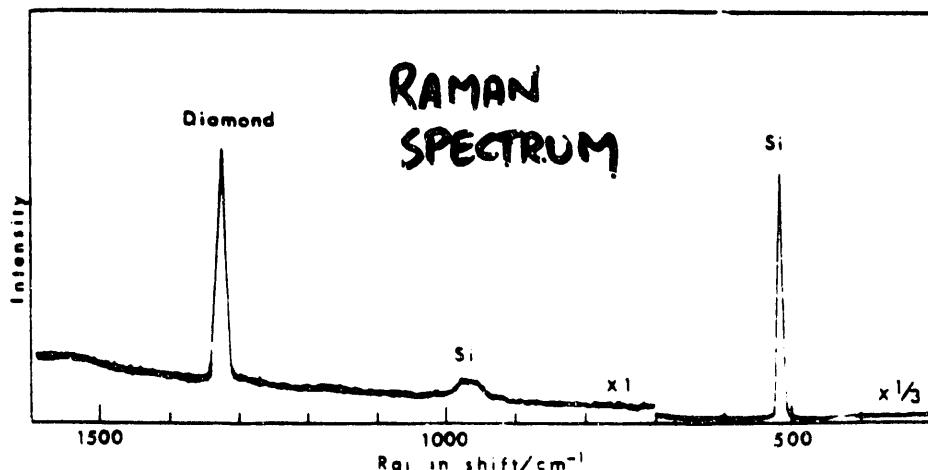


Fig. 4. Raman spectrum of as-grown specimen on silicon substrate. 441.6 nm line of He-Cd laser was used for excitation.

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That's Fit to Print"

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COURSE RECORD: Yannick Noah of France, above, setting a course record in the women's Mercedes Mile on Fifth Avenue yesterday. Jean-Louis Cottet of Spain, left, won the men's race. See Page 5.

The New York Times/Joe Vitello

New Era of Technology Seen In Diamond-Coating Process

By MALCOLM W. BROWNE

Scientists have discovered a way of coating objects with thin films of synthetic diamond, an achievement that they believe has opened a new era for electronics, optics, machine tools, chemical processing and military technology.

Experts said that diamond-coating processes would be cheap enough, moreover, to mass diamond film as a common manufacturing method. Although many diamond films will be no more visible to the unaided eye than coatings of transparent lacquer, they will radically improve the quality of the objects they coat.

Long-wearing tools and bearings coated with diamond film and powerful new optical systems for sensitive instruments, communications and weapon systems are just some of the many intended applications. Others are scratch-proof lenses and windows, ultra-high-fidelity diamond loudspeakers and a new generation of high-speed solid-state devices impervious to the radiation of nuclear blasts. Diamond coatings could improve a range of devices extending from the most advanced rocket engines to humble raster blasters, experts say.

Impact on Society

Some scientists suggest that diamond film could have an impact on society comparable to that of the advent of cheap aluminum after the invention of the electric arc-heat process 100 years ago.

Developments in recent months have been so rapid and dramatic that a wide cross-section of American industry and the Pentagon's Strategic Defense Initiative

have organized defense against intercontinental missiles, have joined the drive to exploit diamond coatings.

Scientists at Pennsylvania State University are among the leaders in diamond-film research, and Penn State held a conference in Philadelphia to inform American industry of the latest developments and possibilities.

Soviet and Japanese Advances

Some of the biggest news came from abroad. The Soviet Union has succeeded in developing diamond films more than one millimeter thick, and next year, Sumitomo Electric Industries of Japan is expected to begin producing the world's first diamond computer chips.

Representatives of more than 40 companies, including many of the

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G.O.P. MAY DO WELL IN VOTE FOR HOUSE, EXPERTS FORECAST

They See Democratic Gains as
Being Much Smaller Than
History Would Suggest

By E. J. BROWN Jr.
Special to The New York Times

WASHINGTON, Sept. 13 — While national attention has focused on the elections that will determine which party controls the Senate, political leaders say the Republican Party, remarkably, is likely to avoid any serious losses in the House of Representatives this year.

Experts from both parties agree that the Democrats will maintain control of the House but that their chances for dramatic gains are minimal. The analysts are speaking instead of the Democrats' picking up 10 to 15 seats, much less than has often been the case when one party has controlled the White House for six years. The average shift has been 40 seats in the last three elections held at such a time: 1974, 1980 and 1984.

Both sides caution that dramatically bad economic news, such as a continuation of this week's slide in the stock market, could alter the picture substantially.

"I thought we were at pretty good shape in October of 1982," said Joseph Gaynor, executive director of the National Republican Congressional Committee. But when the national unemployment rate rose to over 10 percent in mid-October of that year, Republicans could cite it as a reason for their losses, while the Democrats could say they had received unfavorable news about 10 states of where they were when President Reagan was first elected in 1980.

"We've been in the ring six years with the heavyweight champ and we only lost 10 seats," said Harold D. Pinter, executive director of the Democratic Congressional Campaign Committee. "That's not much of a sign."

As for the Republicans, Mr. Gaynor said, "We've been in the ring six years with the heavyweight champ and we only lost 10 seats," said Harold D. Pinter, executive director of the Democratic Congressional Campaign Committee. "That's not much of a sign."

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Anatoly Daniloff and his wife, Ruth, in Moscow yesterday.

Associated Press

Soviet Says a C.I.A. Station Chief Passed On Instructions to Daniloff

By PHILIP TALBMAN

Special to The New York Times

MOSCOW, Sept. 13 — The Soviet Union presented new espionage charges against an American correspondent today and said the United States was holding East-West relations hostage to the case.

The charges were presented by Gen. F. Gerasimov, Foreign Ministry spokesman, at a news briefing. He said the Soviet Government had "irrefutable" evidence that the correspondent, Anatoly Daniloff, chief of the Central Intelligence Agency, had spied for the United States.

The Soviet Government's press agency, Tass, in reporting Mr. Gerasimov's briefing, identified Mr. Daniloff as Moscow station chief of the Central Intelligence Agency.

Jaroslav Verner, a spokesman for the United States Embassy, denied the charges.

Mr. Daniloff, who was released from jail last month, has been held in custody pending trial, told The Associated Press that he "would not dignify the charges by commenting on them."

Earlier, in a written statement read by his wife, Ruth, he said, "I have no official or secret relationship with any intelligence agency."

The custody arrangement under which Mr. Daniloff was released from jail also involved the release in New York of Gennadi P. Zalikarov, a Soviet employee of the United Nations, who faces espionage charges in the United States.

Mr. Daniloff, who is free to move about Moscow but must check in with

Continued on Page 14, Column 1

Why Stocks Fall Anxiety, With

By LEONARD

The precipitous stock market drop on the New York Stock Exchange

Diamanter av sumpgas!

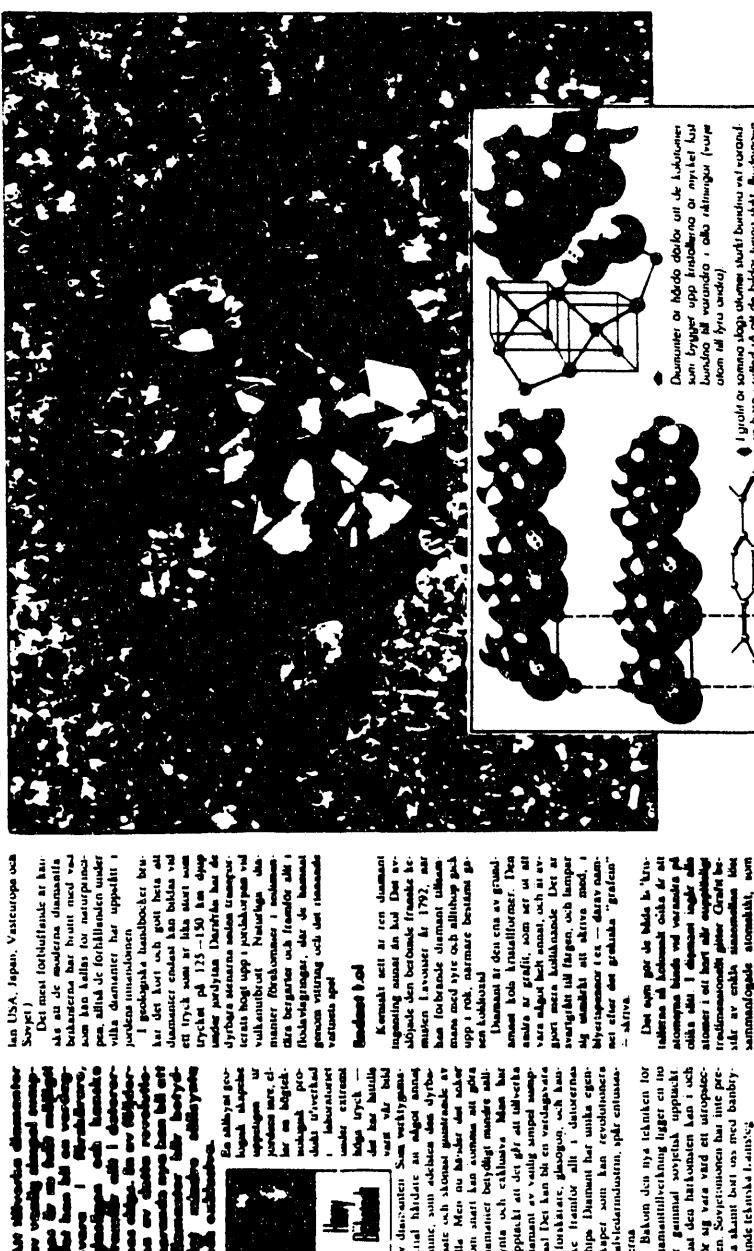
an USA, Japan, West Europe and Soviet Union.

Be salutary for
high hepatic
ulcers.

manier: flexibler in Wahrnehmung, aber ziemlich unbeständig. Pferde sind sehr auf die Bergwelt und Freiräume abgestimmt. Pferde sind überwiegend herbivore Tiere, die die humanen preisigen Weitungen nicht von menschlichen Spuren trennen können.

enhet **Kost och skof**
När nödskiften fortuna (11.000
öster) er utridt ringerbland av en
kombination av hand-
delskost och skof. (eller) publicitetskost
och handelskost. Självförturerna i hand-
elsskiften är dock inom gränserna, men
handelskosterna är höga och utrida-
bland. Därför kan man i handels-
kosterna se en del av nödskiften.

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kosterna se en del av nödskiften.



U.S. HISTORY DIAMOND VAPOR GROWTH

[at practical rates]

pre-1985

Results. Little Belief!

1985

Cautious Belief.

1986

Belief! Cautious Acceptance.

1987

We're Behind! \Rightarrow START!

1988

We're all in for the long-haul.



Soviets On Cutting Edge Of Earth's Diamond Age

By MICHAEL WOODS

Times Staff Writer

MOSCOW — Historians who chronicle human progress in terms of new materials that change society will never know who fashioned the first stone tools that ushered in the Stone Age, or exactly which inspired individuals deserve credit for the Bronze Age or the Iron Age.

But if scientists' expectations prove correct, the founders of the next such era — the Diamond Age — will be easily identifiable.

They are working in a modest laboratory at the huge Institute for Physical Chemistry here, trying to perfect a process for coating materials with a thin film of gem-quality diamond, the hardest material known to man.

"A diamond age," Dr. Boris Deryagin ~~sighed~~ ~~smiled~~. His thumb and forefinger ~~softly~~ ~~firmly~~ caressed a small wafer of material coated with diamond in the process that he and Dimitri Fedoseyev invented a decade ago.

"Yes, maybe so."

Although they published a de-

tailed report on the process in 1977, scientists around the world ignored it — for reasons that are unclear.

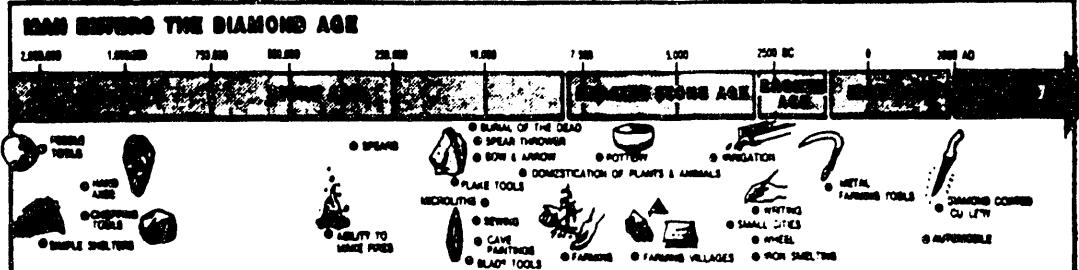
Shrouded In Mystery

Dr. Victor Spitsyn, director of the institute and a member of the prestigious Academy of Sciences of the USSR, shrugged his shoulders in bewilderment when asked why it has taken the scientific community so long to recognize the implications of the process. Dr. Spitsyn also has participated in the diamond-film research.

During the last year, Drs. Spitsyn, Deryagin, and Fedoseyev have become folk heroes of materials science, the effort to develop stronger and more economical materials for use in industrial and consumer products. Their names are becoming widely known in a number of other fields where diamond films can be used. Scientists believe that the three are prime candidates for a Nobel Prize.

Indeed, some predict that thin-film diamond technology will have a

THE
TOLEDO
BLADE



— Illustration by Larry Correia

broad impact on society than any other technological achievement since 1885 — the year of the invention of the process that made aluminum widely available.

That process, developed by Charles Hall and Paul Heroux, transformed aluminum from a semiprecious metal that sold for more than 77 an ounce into a common metal that cost less than 2 cents a pound by 1910.

Dr. Deryagin questions whether diamond films will be used as extensively in consumer products as aluminum is. But he predicted "a great expansion" in mankind's exploitation of the unique properties of diamond. It is the hardest and most chemically inert material on earth, giving it the ability to cut all other materials and resist attack by chemicals.

It also conducts heat better than silver, copper, and other metals. Unlike those metals, it does not conduct electricity, but acts as an excellent electrical insulator. Those properties give diamond numerous potential applications in electronics, where heat dissipation is a major factor limiting how tightly transistors can be packed together on printed circuit boards.

Dr. Deryagin said that diamond films could be used on everything from knives and industrial cutting tools that remain sharp indefinitely to a new generation of computers and other electronics products.

Films Extremely Thin

The films are extremely thin, perhaps only 0.00001 inch thick.

Scores of industrial firms are trying to develop products that would

use diamond coatings. Dr. Deryagin pointed out that the Japanese have taken the lead in transforming the Soviet Union's basic research on diamond films into technology with the potential for producing "enormous profit."

The Japanese reportedly are developing numerous products, including diamond-coated stereo speakers, scratch-proof airplane windows and camera lenses, and diamond-coated computer chips that dissipate heat very rapidly.

Dr. Spitsyn suggested that cooperation between U.S. and Soviet scientists might be one way of preventing the Japanese from dominating diamond-film technology, just as they have dominated other forms of advanced technology.

Turn to Page 4, Col. 2

Soviets On Cutting Edge

Continued from First Page

He and his associates acknowledged that diamond-film technology has military applications. The American Star Wars program, for example, has become a major financier of diamond-film research because of its potential for improving the performance of lasers and other optical devices.

U.S.-Soviet Cooperation

But Dr. Spitsen indicated that there could be U.S.-Soviet cooperation on nonmilitary aspects of thin-film diamond technology.

American scientists speculate that the initial 1977 Soviet report on diamond films was ignored because the technology for depositing the films appeared so simple that it was barely believable.

Scientists knew that manufacture of synthetic diamonds, first achieved in the United States in 1954, required extremely high temperatures and pressures. Synthetic diamonds are made from carbon that has been subjected to enormous pressures and ultra-high temperatures.

The Soviet process, in contrast, is simple, inexpensive, and uses lower temperatures and pressures. It uses methane, a common gas that is the major component of natural gas,

and microwaves similar to those used in ovens.

Electrically Charged Gas

Each molecule of methane consists of one atom of carbon and four atoms of hydrogen. In the diamond-film process, microwaves are used to heat methane, separating the carbon from the hydrogen atoms, and forming an electrically charged gas known as a plasma.

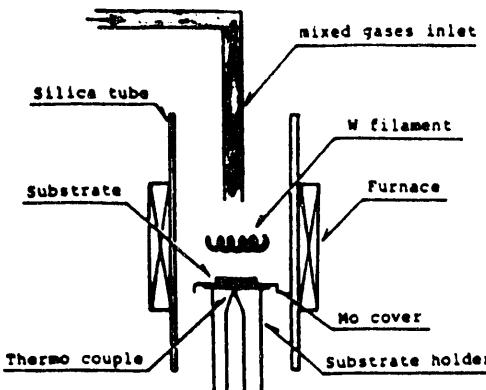
When the plasma comes into contact with an object, carbon atoms accumulate on its surface in the specific crystalline form of diamond.

The Soviet apparatus now is able to deposit about 4 micrometers of diamond an hour, Dr. Fedoseyev said. That rate should be adequate for most purposes, he added. One micrometer is about 0.000039 inch.

Dr. Fedoseyev said the Soviets are capable of depositing two distinct kinds of films, one consisting of ordinary diamond, and another of a diamond-like material that a translator termed "diamond slag."

All three of the Soviet scientists cited many pleasant encounters with American scientists. Dr. Spitsen expressed the hope that political differences would not hinder scientific cooperation between the United States and the USSR.

ALL
HYDROCARBON GASES
MAKE DIAMOND \approx SAME



Heated Filament
CVD

Fig. 1. Schematic diagram of thermal CVD apparatus.

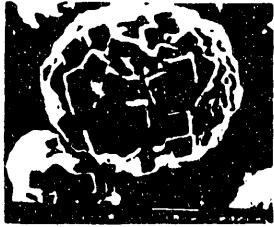
Table I. Organic compounds for diamond synthesis in this study.

methyl alcohol	CH_3OH
ethyl alcohol	$\text{C}_2\text{H}_5\text{OH}$
isopropyl alcohol	$(\text{CH}_3)_2\text{CHOH}$
2-methyl-2-propanol	$(\text{CH}_3)_2\text{COH}$
acetone	CH_3COCH_3
isopropyl ether	$(\text{CH}_3)_2\text{CH}_2\text{O}$
diethyl ether	$\text{C}_2\text{H}_5\text{OC}_2\text{H}_5$
methyl acetate	$\text{CH}_3\text{COOCH}_3$
acetaldehyde	CH_3CHO
trimethylamine	$(\text{CH}_3)_3\text{N}$

← Vodka, Sake
← Nail Polish Remover

From Y. Hirose and Y. Terasawa
Jpn. JAP 25, L519 (1986)

March 29 '88
The Journal, Shimbun



DIMEN ガスバーナーと
シリコン基材で

切削工具に応用

高畠は、おおむね「おおむね」といふのが特徴である。

「アーヴィングの死」

現在、最大の時は一時間が
経て、タイヤであることを確認
した。
これが威力を發揮するものと見
られる。

動産賃料原留久保ひぐち
同区瑞光二丁目・大隅二丁目
に住む七人。いずれも一軒

東湖集

（一）（二）（三）（四）（五）

2回以上売買 16%

都
区
取
部
引

民間企業同士が67%

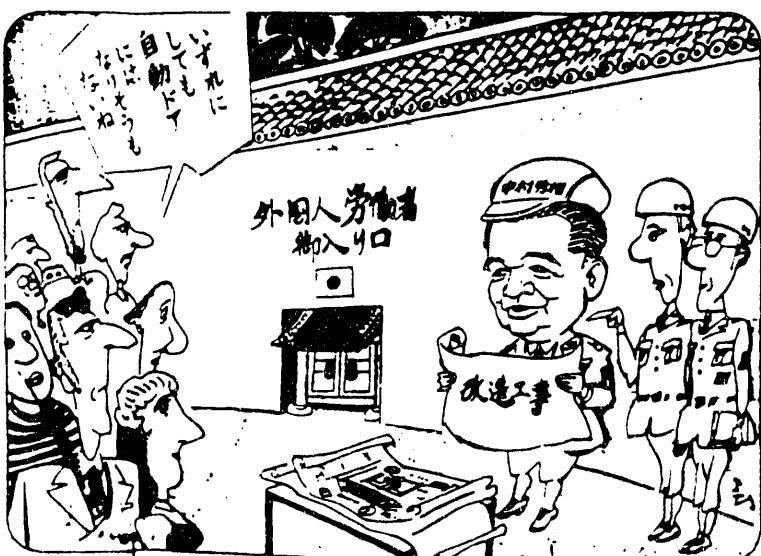
61年、都白書

職住近接を促進

建築規制の見直し訪問

新幹線公審 調整委が初の調停へ 大阪市民の申請を受理

九時以降の運転中止を規定
が設置したテレビ受信用共
アンテナの設置費用約三五



いよいよ「ナンモン」に取り組む 玄野 圭一

translated by M. Suzuki
April 3, '88

You can make diamond easily!

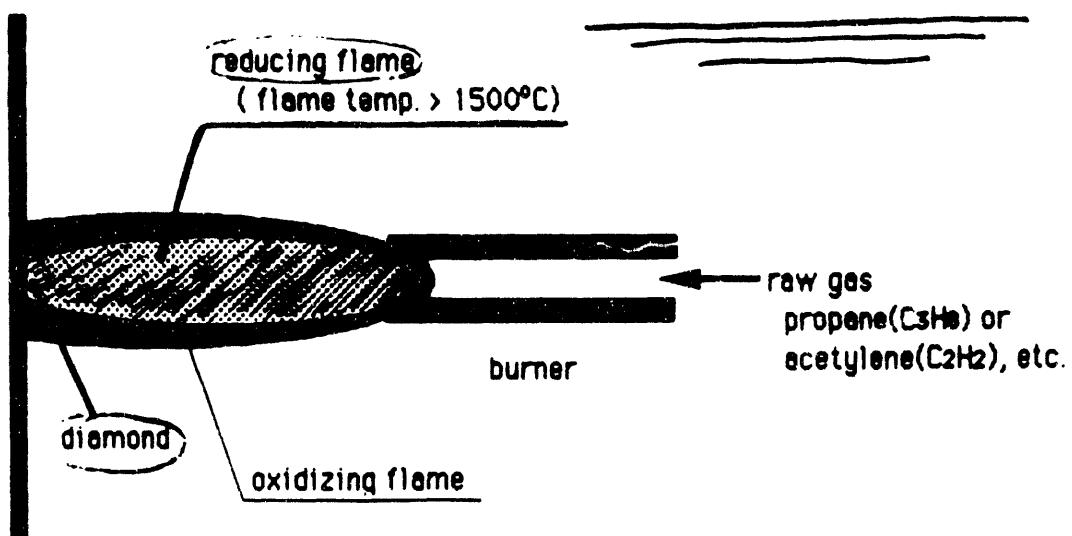
(The Yomiuri Shimbun* March 29, '88, P2)

Dr. Hirose, an associate professor of Nippon ~~Wagyu~~ University, developed a much easier way to synthesize diamond than ever reported. This method works in the air, so it doesn't need a vacuum pump or vessel. As shown in the below figure, the flame ejected from the burner deposits diamond particles on a silicon substrate which temperature is held between 600°C and 900°C. The key point is to use a reducing flame which temperature is above 1500°C. XRD and Raman spectrum identify the particles as diamond. So far, the biggest particle grown for an hour has 200 micron diameter size. This new process seems to be suitable for coating on cutting tools or curved surfaces rather than for making diamond semiconductor.

Dr. Hirose will give a presentation about this work at 35th Applied Physics Seminar today.

Si substrate
(600°C < temp. < 900°C)

Acetylene Torch
in Air

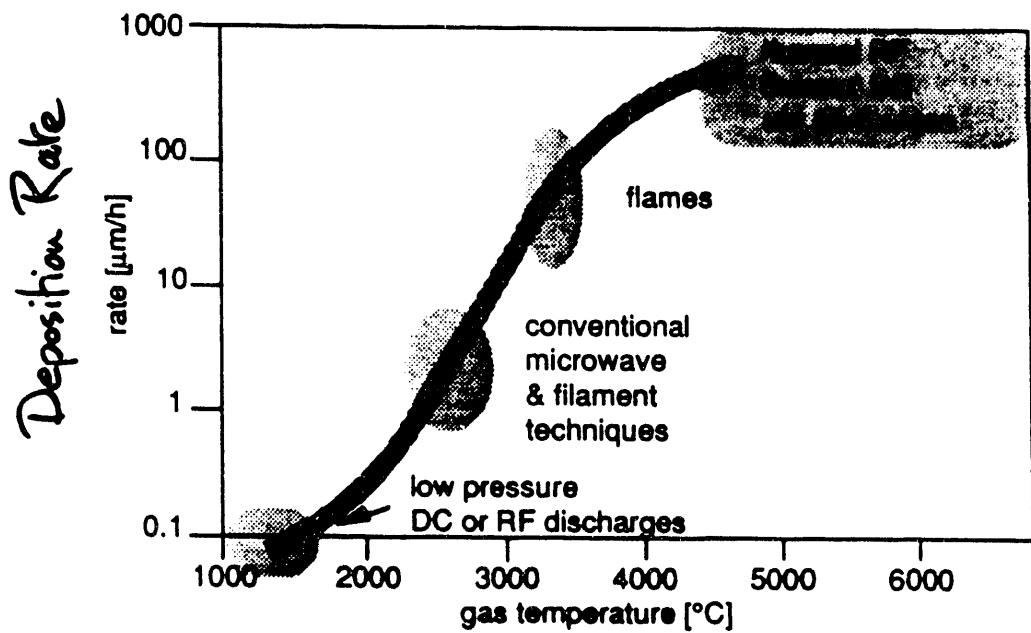


at an atmospheric pressure, in the air

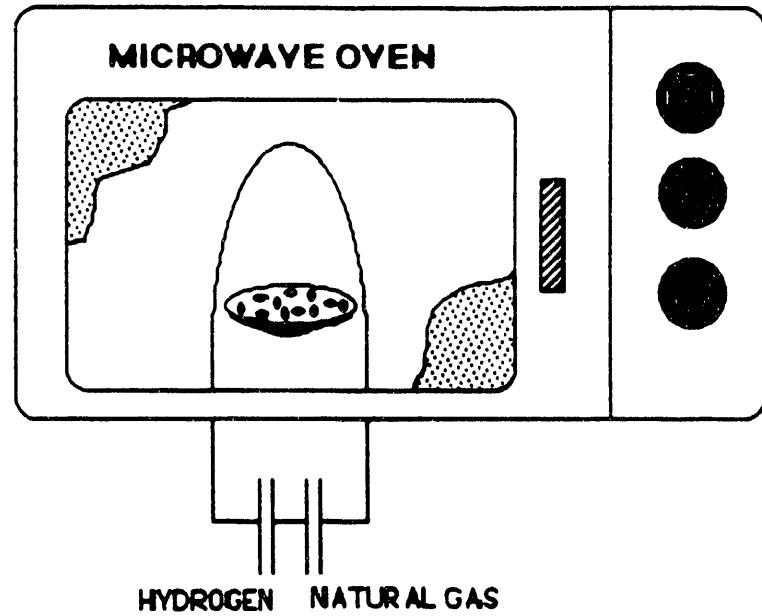
A Schematic Image of the New Process

*The Yomiuri Shimbun is one of three big Japanese newspapers.

Gas Temperature vs. Diamond Deposition Rate

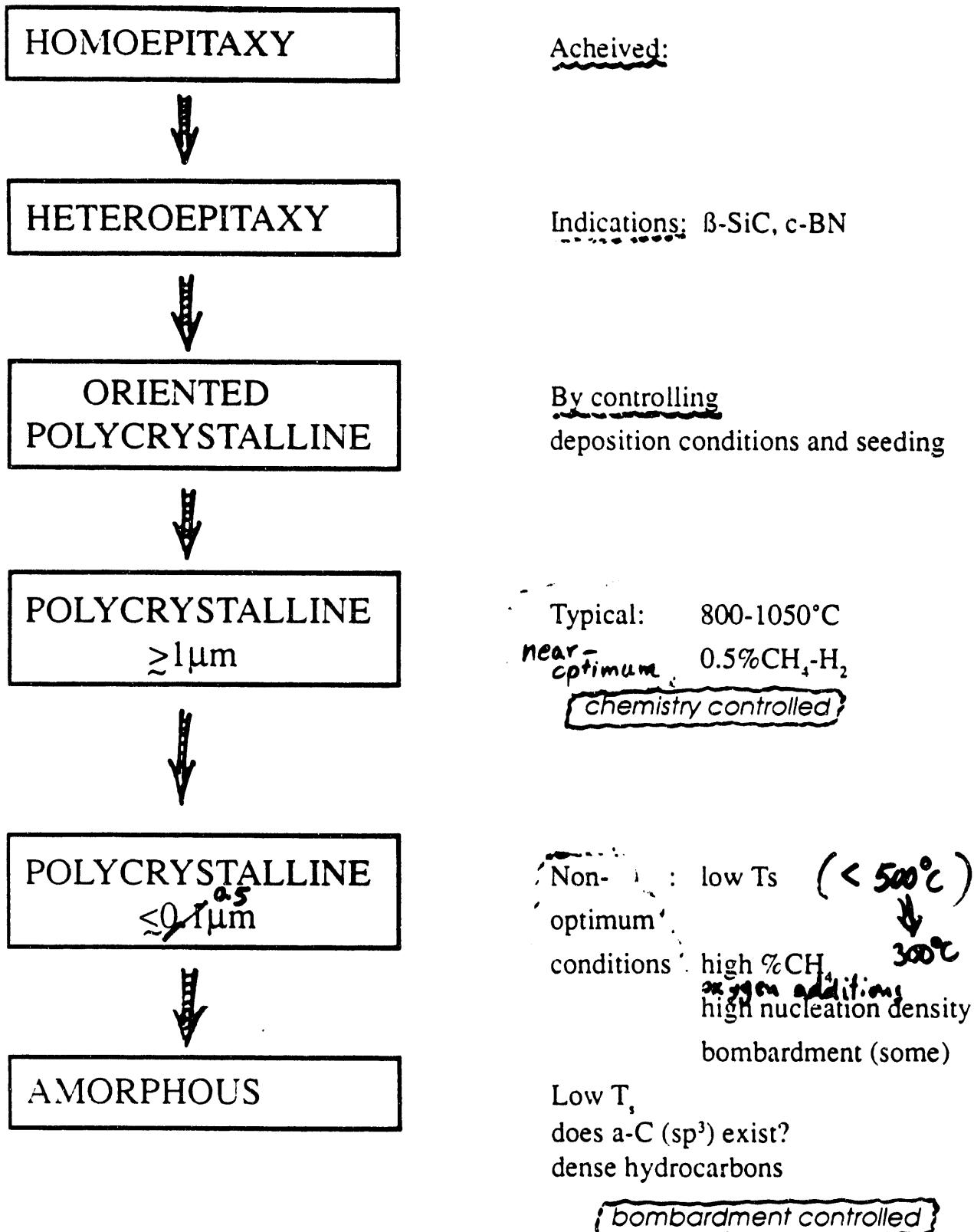


from Bachmann and Lydtin
MRS Symp. Proc. 165 (1989)

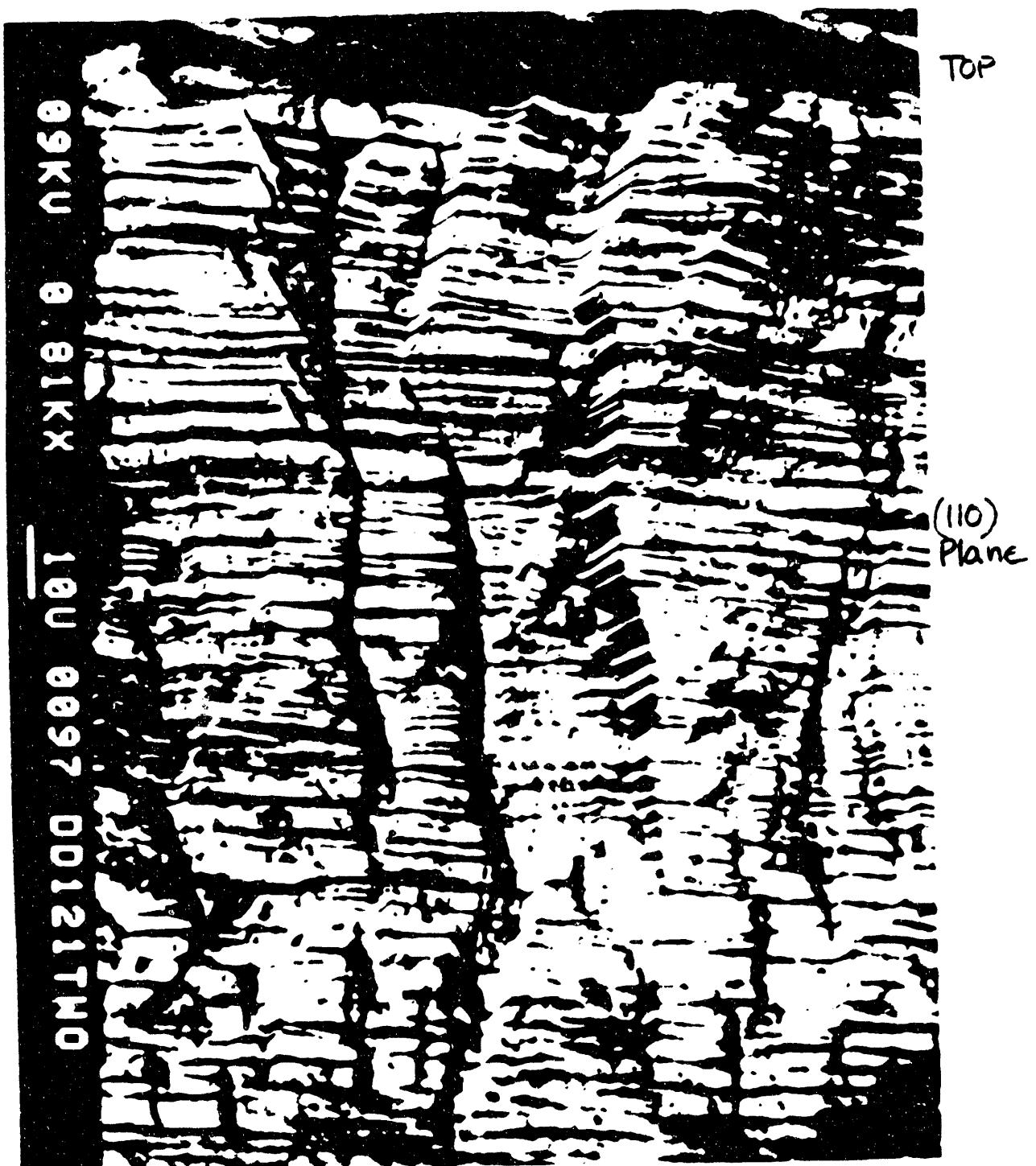


GE Process !
1986

DIAMOND \longleftrightarrow DIAMOND-LIKE



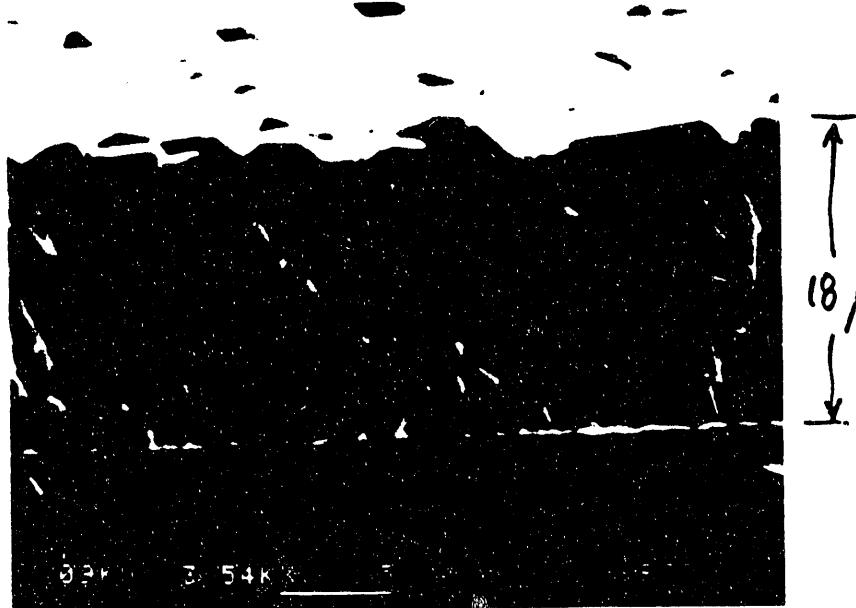
HOMOEPITAXIAL DIAMOND



A. RADZIAN & T. BADZIAN

Diamond on Silicon

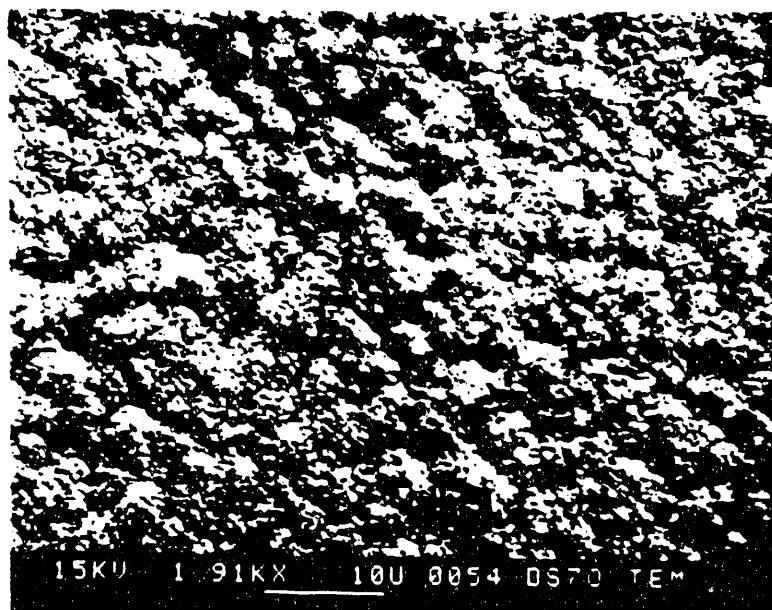
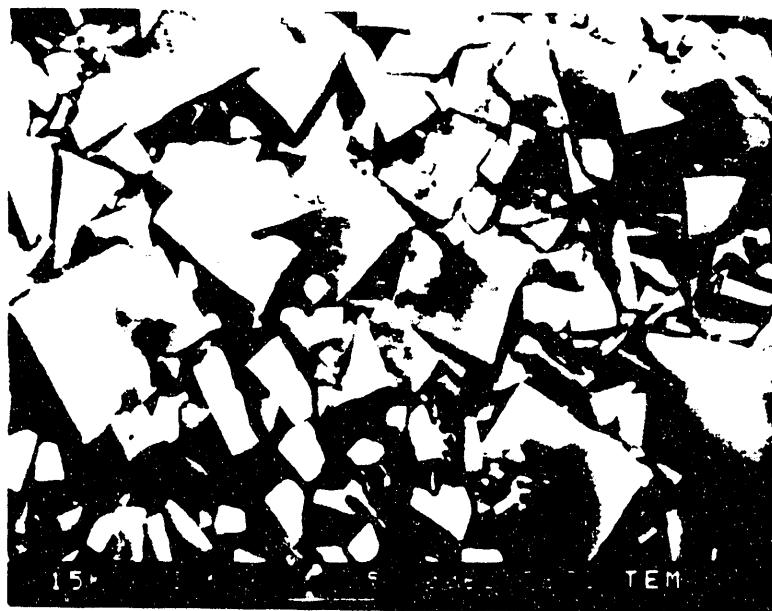
980°C
80 Torr
0.4% $\text{CH}_4 - \text{H}_2$



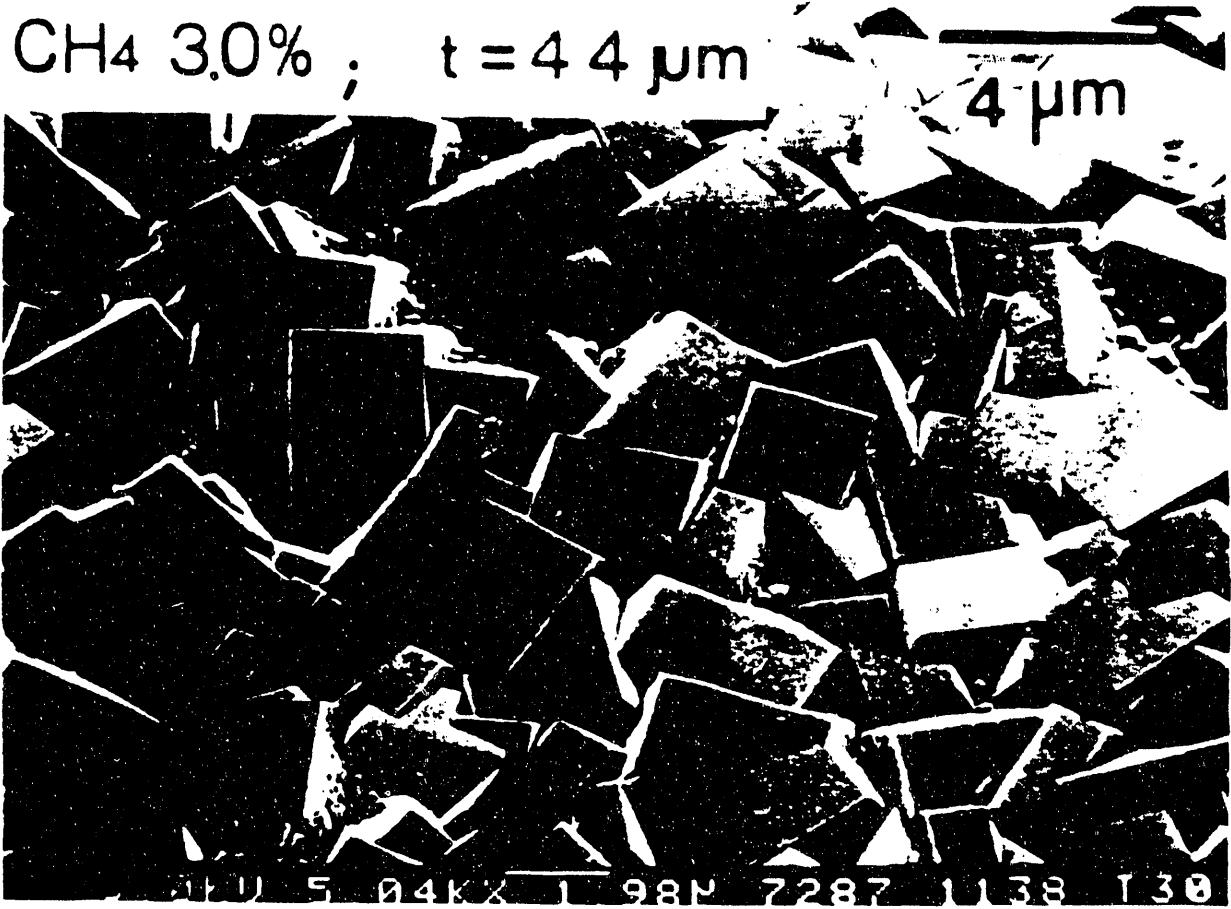
A.R. Badzian and T. Badzian
MCVD

Diamond on Si

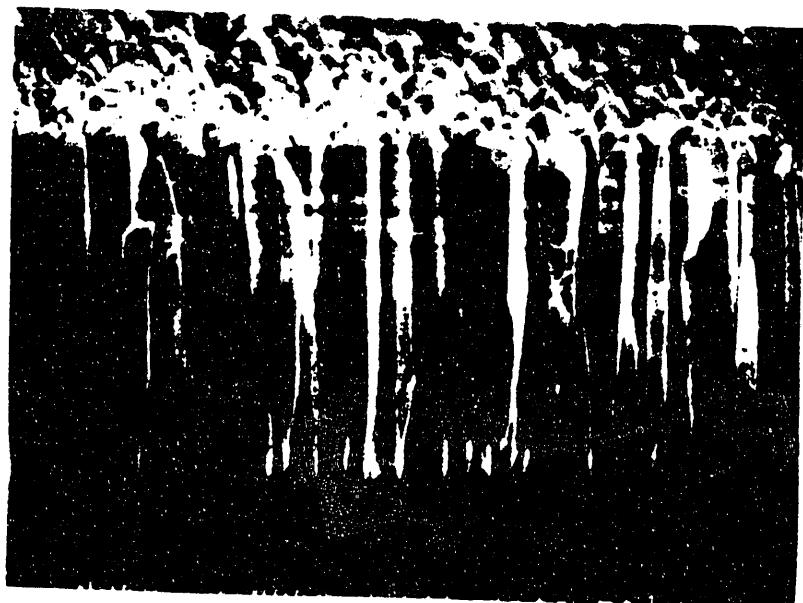
MPACVD



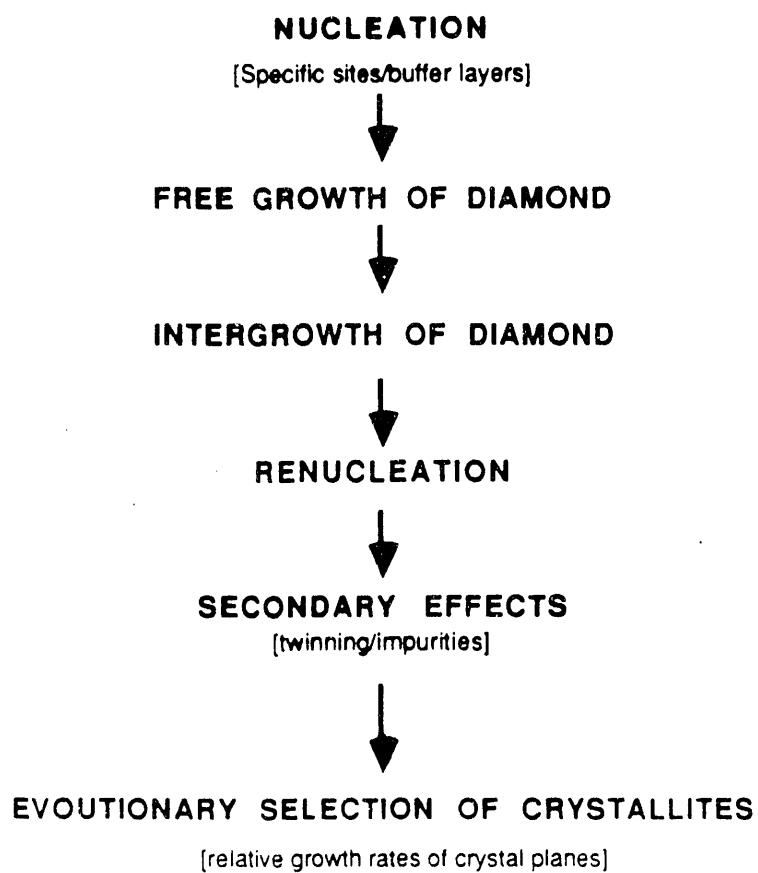
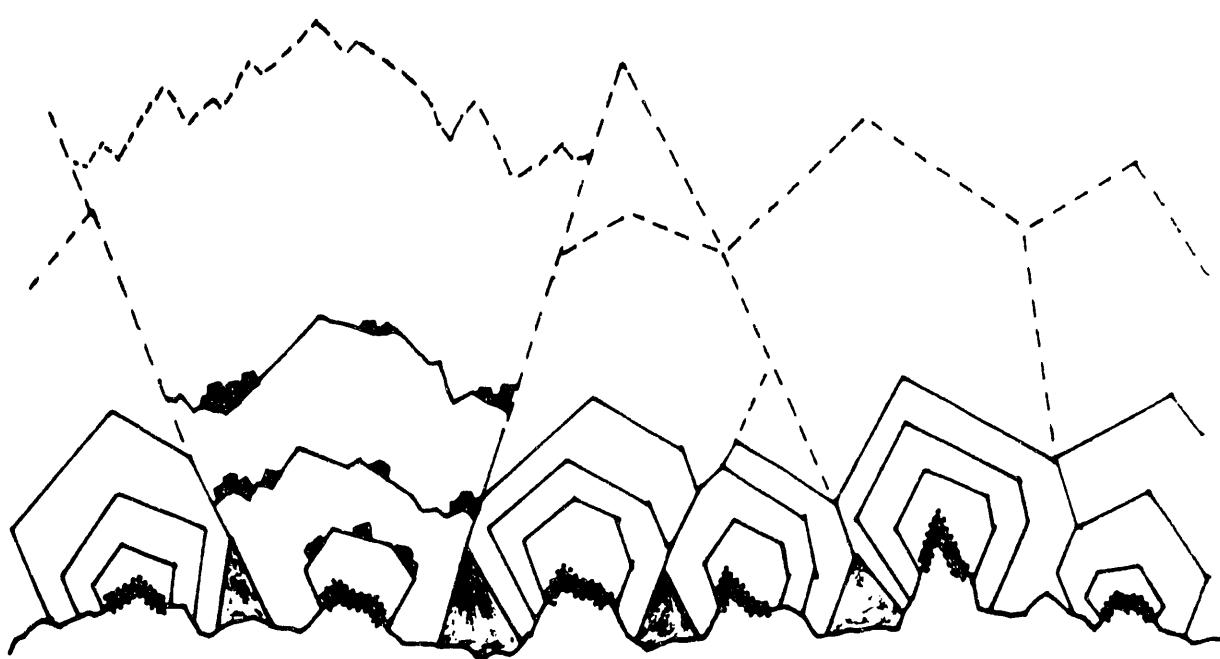
A. BADZIAN & T. BADZIAN



from Y. Sato (NIRIM)



from Y. Sato (NIRIM)



PREFERENTIAL ORIENTATION

Windischmann (MPACVD)	{111}	800°C	~1%CH ₄ (low growth rate)
	{110}	@ high T and %CH ₄	
zarker (MPACVD)	{110}	~650°C	~1 μm/hr
Wild (HFCVD + MPACVD)	{110}	~900°C	1.5%CH ₄ twinning on {111}
Narayan (dc plasma)	{110}		"
Shibata (MPACVD)	{110}		
Yamada (HFCVD)	{110}	at lower T _s (~600°C)	
zato (MPACVD)	{100}	850°C	3-4%CH ₄ low defects
Teng (MPACVD)	{100}		
Lausing (HFCVD)	{100}	950°C	
	{110}	900°C	
Kaee (HFCVD biased)	{100}	Similar Conditions	SF and MT near grain boundaries
	{111}		SF and MT distributed throughout

DIAMOND PROBLEM AREAS

- High Quality
- Large Area Heteroepitaxy
- Adhesion
- Nucleation \Rightarrow Nucleation Density \Rightarrow Morphology
- Crystallite Size \Rightarrow Surface Roughness
(Polishing required \rightarrow mechanical ; chemical)
- Post-Deposition Processing
(Surface Polishing, Laser Cutting, Defect Annealing)
- n-type dopant

UNIQUE ASPECTS OF DIAMOND SiT

- C is Smallest Group IV Element
 - ↓
 - Diamond has largest atom number density
 - ↓
 - Large # of Unique Properties
- Diamond Technology \Rightarrow Metastable Material
 - can defects be reduced \leftarrow during prep \Rightarrow post-dep
 - stable to high T's
- New Approach to Materials Synthesis
 - can it be generalized (eg. cBN) or is it unique to carbon chemistry?
- New Deposition Methods
 - MPACVD
 - HFCVD
 - Combustion Flames
 - Thermal Plasmas

ニューダイヤモンドフォーラムの活動状況

佐藤純一

1. はじめに——ニューダイヤモンドとは

ダイヤモンドが、古く古代エジプトの時代からその高貴な輝きをもって人類の装飾品として最高の地位を獲得し現在にまで維持していることは周知のとおりである。

一方、ダイヤモンドが最高の硬さを有することも古くから知られていたよう、聖書にも石材をダイヤモンドで加工したことが記されており、加工工具材料としての利用についても装飾に劣らず古い歴史をもっていることも驚くべきことである。

以来、ダイヤモンドそのものを始めとして各種の貴石、非常に難削材あるいは高精度を要する加工にダイヤモンドが工具材料として用いられてきたが、いずれも天然のダイヤモンドであって、資源的制約から利用範囲は特殊なものに限られざるを得なかった。

ダイヤモンドの成因は、従来より地球物理学者の興味を引くテーマとして研究されているが、一方、これを人工的に製造して上記の資源的制約を越えるための努力が超高压技術の専門家達によって行われてきたのも周知のとおりである。

ダイヤモンドが工業材料として広く利用される道を開いたのは、

1955年の米国ゼネラルエレクトリック(GE)社の静水圧法によるダイヤモンド合成の成功である。これ以後、ダイヤモンド砥石を中心とした利用が飛躍的に増大し、現在、ダイヤモンド工具は売上高で年間700億円以上、伸び率で年15~20%になっている。

更に最近、大粒ダイヤモンドの静水圧法による製造、気相法による膜状ダイヤモンドの製造が可能になり、硬さを生かした切削・研削工具、耐摩耗工具への応用のみならず、ダイヤモンドの化学的、熱的、光学的、電子的な特性に注目したより広い機能材料としての応用の可能

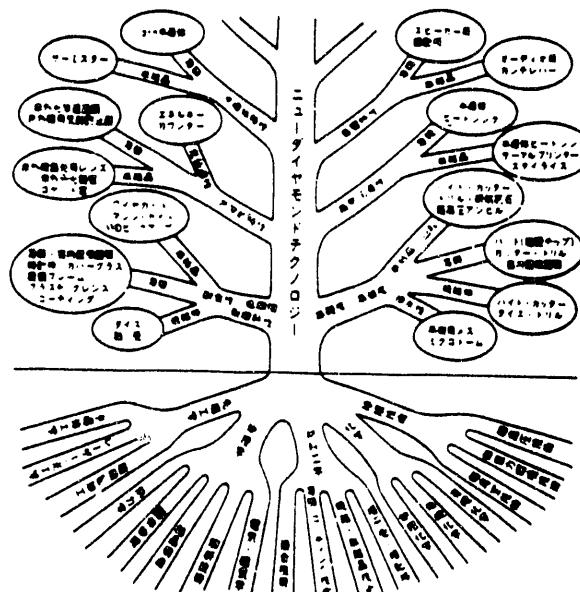


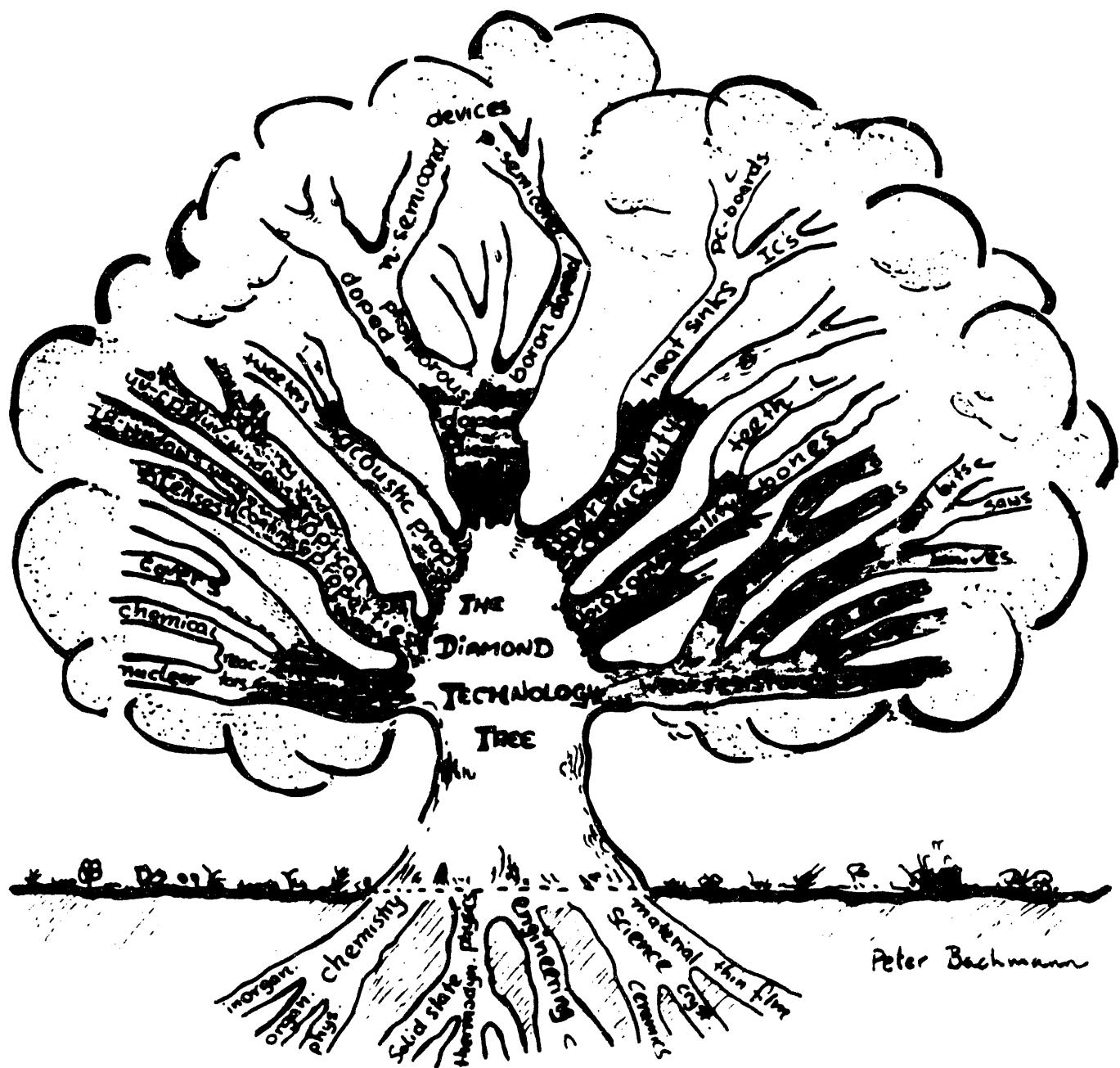
図1 ニューダイヤモンドテクノロジーの基礎と発展
通商産業省ファインセラミックス室「ファインセラミックス産業の現状及び展望」(昭和61年4月)

Junichi SATO (Showa Denko K.K.) Activities of New Diamond Forum

セラミックス 21 (1986) No. 11

1386

The basic development of new diamond tech
written by MITI, fine ceramic section,
now and then.



the "diamond technology" tree

PROPERTIES

Property	Material	Silicon	GaAs	Diamond
optical band gap [eV]		1.1	1.4	5.5
hole mobility [cm ² /V sec]		600	400	1600
electron mobility [cm ² /V sec]		1500	8500	1900
breakdown voltage [V/ cm]		5×10^6	6×10^6	1×10^7
electron velocity at high fields [V / sec]		1×10^7	1×10^7	2.7×10^7
dielectric constant		11	12.5	5.5
resistivity [Ω cm]		10^3	10^8	$>10^{12}$
thermal conductivity [W / cm ² K]		1.45	0.46	20
thermal expansion coefficient [!/K]		2.6×10^{-6}	5.9×10^{-6}	1.1×10^{-6}
refractive index			3.4	2.4
Vickers hardness [kg / mm ²]		1 000	600	10 000
sound propagation velocity [m/ sec]				18 500
elasticity [N/ m ²]				1.2×10^{12}
density [g / cm ³]				3.5
melting point [°C]		1420	1238	N/A

DIAMOND SCIENCE AND TECHNOLOGY

UNIQUE PROPERTIES

1. HARDEST MATERIAL KNOWN, 9000 KG/MM²
 2. HIGHEST VELOCITY (LONG 18000 M/SEC)
 3. HIGHEST THERMAL CONDUCTIVITY, 20 W/CM°C +?
 4. MOST TRANSPARENT IN I-R, 225 NM-FAR IR
 5. HIGHEST HOLE MOBILITY 1600 CM²/V-SEC, HIGHEST KEYES FIGURE OF MERIT
 6. LOWEST FRICTION AMONG LOW-WEAR
 7. EXTREME CHEMICAL STABILITY
1. ABRASIVES, CUTTING TOOLS, SURGICAL KNIVES
 2. ACOUSTICS, SPEAKERS TO SAW DEVICES
 3. THERMAL MANAGEMENT, DENSE IC
 4. OPTICS (IR, VISIBLE)
 5. NEW ELECTRONICS
 6. TRIBOLOGY (BALL BEARINGS TO DIESELS)
 7. CORROSION PROTECTION

APPLICATIONS

- Mechanical

- Cutting tools
- Knives medical wood cutting
- bearings
- optical scanners
- nozzles
- eyelets
- high T, sliding seals
- abrasives

- Chemical

- BioCOMPATIBILITY

- Optical

- X-Ray windows
- X-Ray Litho Masks
- High Power Laser Mirrors
- UV windows
- IR windows

- Thermal

- Dense IC packaging
- TAB Bonding
- Laser Diodes
- High Power electronics

- Passive Electronics

- Thermistors

- Active Electronics / Optoelectronics

- Schottky Diodes
- MESFET and MOSFET Transistors
- Electro luminescent light Emitters

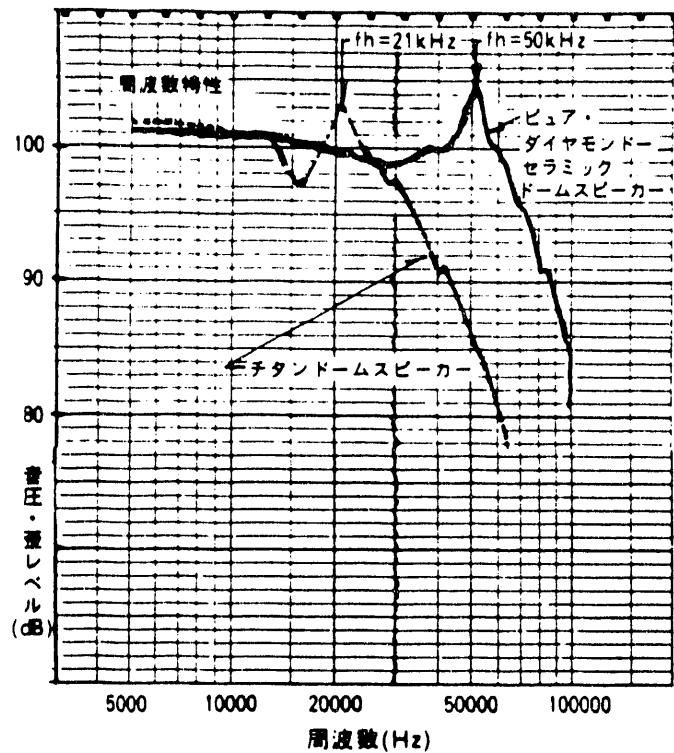


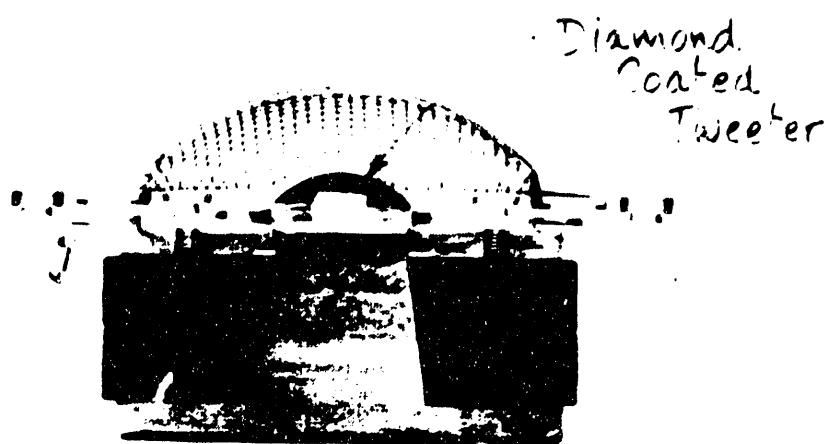
図8 直径25mm ピュア・ダイヤモンドーセラミックスドーム試作ツィーダの特性

SX-1000

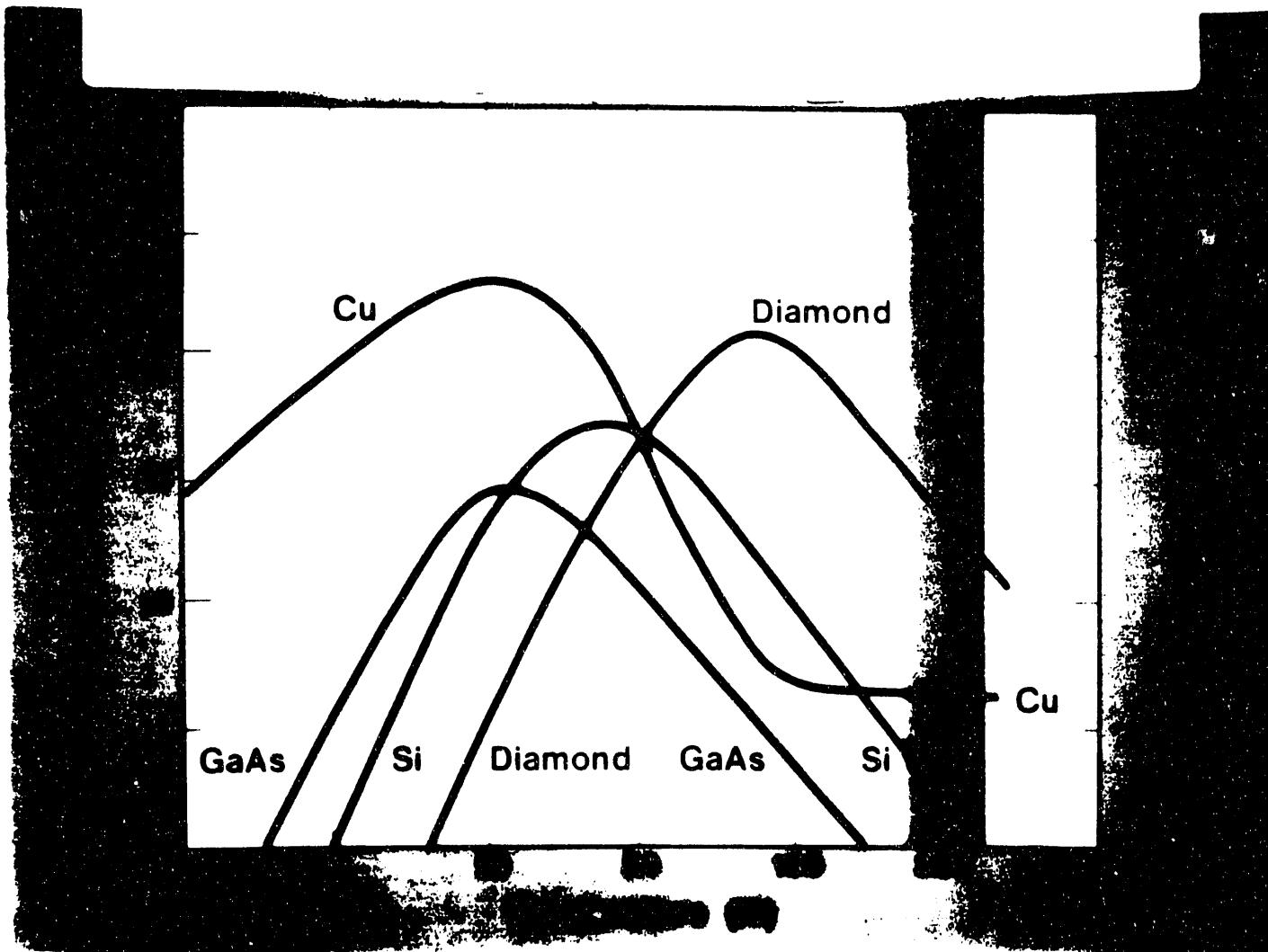
"Component of the year" of 1987

Stereo Sound

Japanese audio magazine

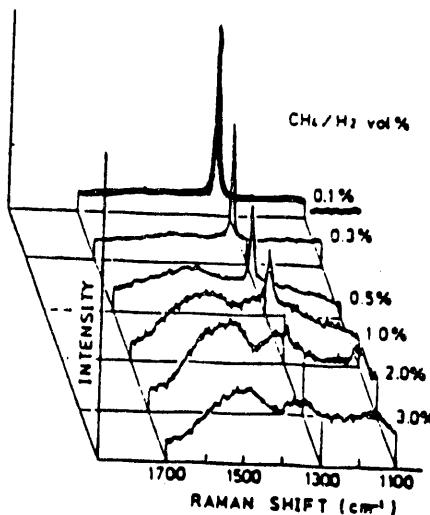


THERMAL CONDUCTIVITY

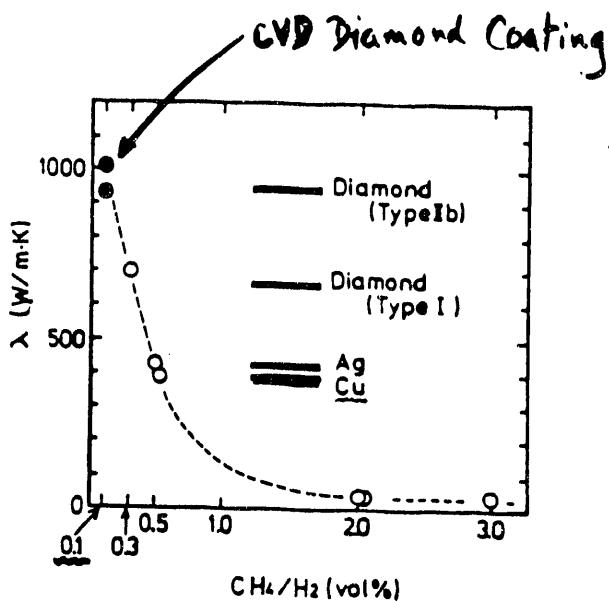


from Mike Geis

Thermal Conductivity



Raman spectra of diamond films for different methane concentrations.



Thermal conductivity of diamond films for different methane concentrations.

Ono, Baba, Funamoto, and Nishikawa
 Jpn. JAP (1986)
 MPACVD

THERMAL CONDUCTIVITY

Crystallite Size Dependence

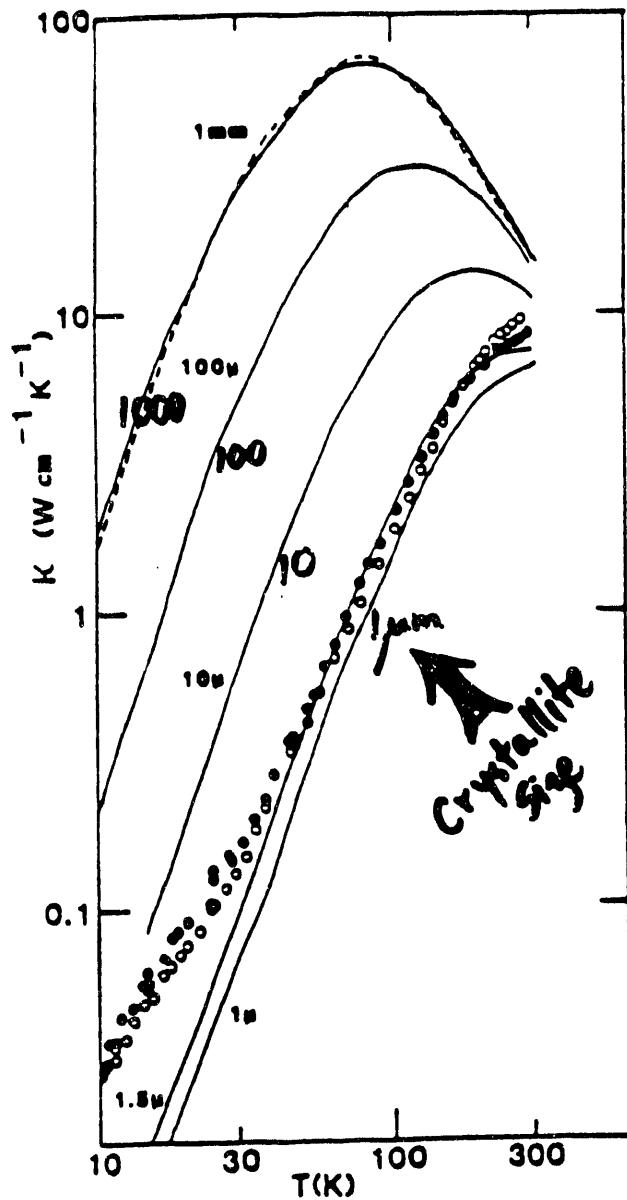


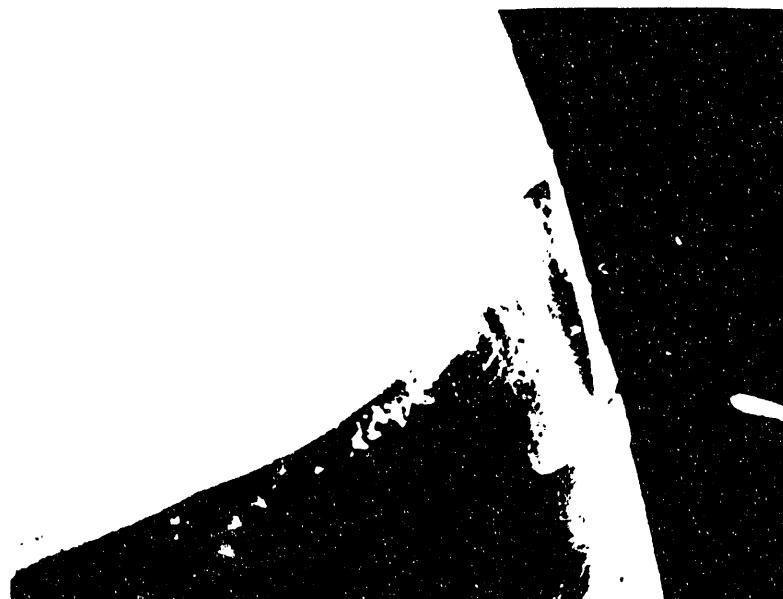
FIG. 3. Thermal conductivity of two diamond films (open circles: DT-13; full circles: DT-15). Bold lines are fits using different crystallite sizes L . Dashed line indicates data of Berman, Foster, and Ziman (Ref. 3) on a single crystal of lateral dimension of 1.1 mm.

Morelli, Bootz, and Perry

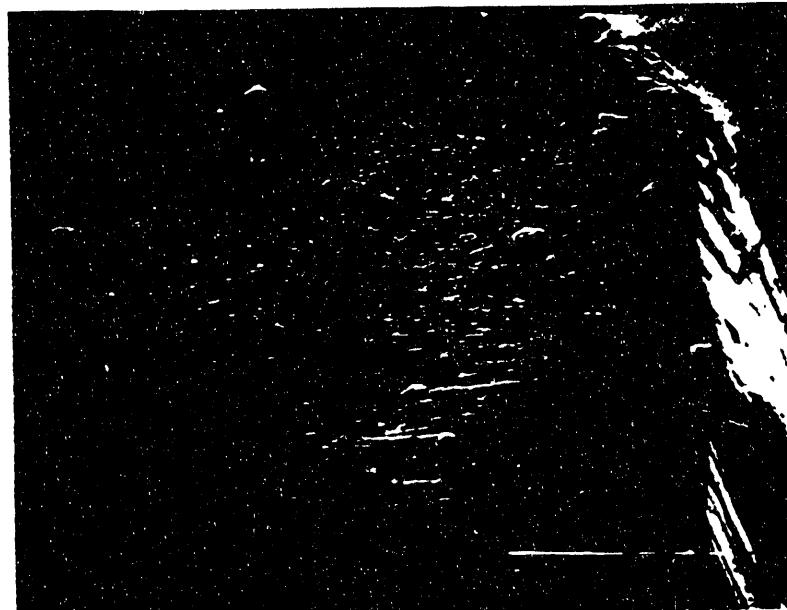
3064

J. Appl. Phys. 64, 3063- (1988)

DIAMOND COATINGS
ON
SIALON CERAMIC
CUTTING TOOLS



Upcut
edge



flank wear
~5 μm
diamond
coating

{ AL. 390 (16-18% Si)
1500 ft/min. 5000
0.0051" / rev feed
0.020" depth.

from Bill Drawl

HEAT DIFFUSERS

10mm

20 ~~mm~~

→ ←

1um



DC plasma torch deposition

Koshino (1988)
[Fujitsu]

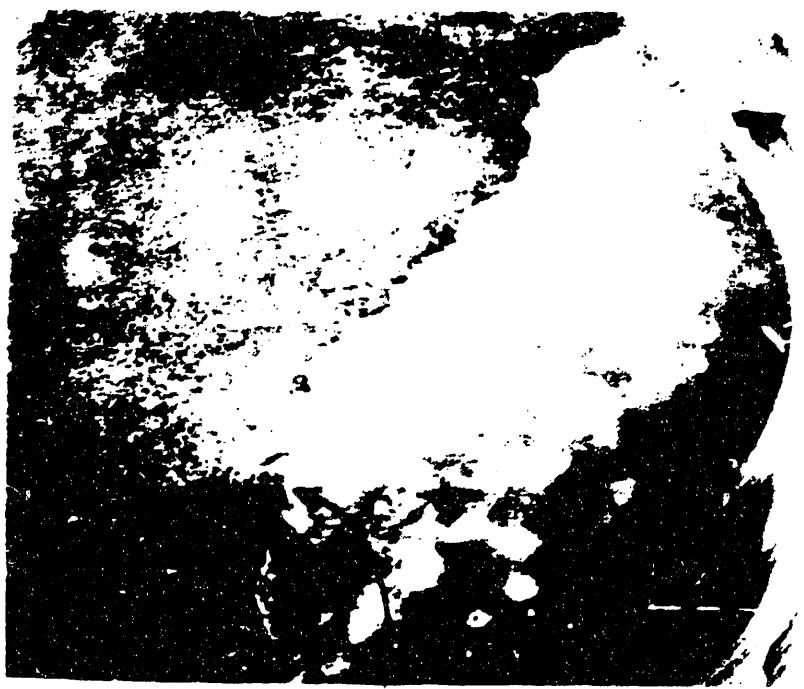
• Metal Build-up

[M-3-R3]



• Some
Shiny
Area

[M-3-R4]



Adhesion
Failure

from
Bill Draw!

X-Ray Lithography

TABLE III

MATERIALS FOR X-RAY MASK SUBSTRATES

	μm	$\text{W}/\text{cm}^2\text{K}$	10^{-6}	Kg/mm^2	$10^{12}\text{dyne}/\text{cm}^2$			
	$t_{50\%}$	κ	α	Kn.H	UTS	Y.M.	O.T.	FM
Si	5.5	1.6	2.3	800	.007*	1.3	Poor	1
Si_3N_4	2.3	0.2	1.8	2200	.05	3.36	Good	0.54
B_4C	6	4.9	2.9	2750	.0015	3.9	Unk.	2.7
BN	3.8	0.8	2.9	2500	.10	1.8	Good	5.42
B	7.5	0.65	4.2	2900	.023	4.5	Unk.	7.6
SiC	3.6	0.41	2.3	2540	.20	3.8	Good	10.6
C(Diam.)	3.0	6.55	1.2	8000	.02	11.2	Good	37

Figure
of
Merit

* Maximum measured value

$$FM_{\text{max}} = t^{2/3} \times (\kappa \times \alpha) \times UTS \times Y.M.$$

$$FM = FM_{\text{max}} / FM_{\text{Si}}$$

- $t_{50\%}$: Thickness for 50% x-ray transmission at 8.33 Å
- κ : Thermal Conductivity
- α : Thermal Expansion
- Kn.H: Knoop Hardness
- UTS: Ultimate Tensile Strength
- Y.M.: Young's Modulus
- O.T.: Relative Optical Transparency
- FM: Figure of Merit

TABLE III

from J.R. Maldonado
J. Electrachem Soc.
(1990)

Table I

Comparison of X-Ray Mask Materials Based on Optical Transparency

and Mechanical Stiffness Factor

Material	t_0 , thickness [μm]	Stiffness Factor [GPa- μm]
Polyimide	> 5	43
Mylar	> 5	42
Ti	Opaque	---
Be	Opaque	---
Si	1	181
BN	3	330
SiO_2	5	444
Al_2O_3	1	448
Si_3N_4	6	728
SiC	3	1,590
Diamond	2	2,340

t_0 is the thickness required for 50% transmission at 632.8 nm.

from H.Windischmann (1991)

Properties of Semiconductive Materials

Properties	Diamond	Si	GaAs	SiC
Band gap (eV)	5.5	1.1	1.4	3.0
Carrier mobility (cm ² /V.sec)				
Electron	1,800	1,500	8,500	400
Hole	1,600	600	400	50
Dielectric constant	5.5	11.8	10.9	10
Thermal conductivity (W/cm K)	20	1.5	0.5	5
Absorption edge (μm)	0.2	1.4	1.1	0.4

TECHNOLOGY/COMMERCIALIZATION

- Products are beginning to appear which take advantage of diamond's excellent:
 - mechanical properties
 - thermal properties
 - optical properties
- Electronic properties/applications seem to be the least developed and have the most commercial potential \Rightarrow New Japan MITI Program #45M
- Companies are continuing to make commitments to manufacturing
- Most hard coating companies have significant efforts

Sandvik Coromant	Sumitomo Electric
Norton	GTE Valenite
Kennametal	Toshiba Tungaloy
GE	Asahi Diamond
Mitsubishi Metal	

- Joint Ventures
 - GE / Asahi Diamond
 - Norton / Sandvik, etc.
 - Kennametal / Idemitsu Petrochemical
 - Diamonex / Seiko

DIAMOND SiT

PUSH

- Replace HPHT Diamond Powder Manufacture
- Replace PDC's (Polycrystalline Diamond Compacts)
- Replace other Coatings

DIAMOND S+T

PULL

● ENABLING TECHNOLOGY

- Unique Aspects / Properties of CVD Diamond
- New Specific Applications
- New Generic Technology Impacts

for example :

Transportation

- advanced heat engines
- higher reliability
- lower friction → lower energy
- decrease pollution
- economical machining of non-ferrous metals
- sensors in hostile locations

Manufacturing

- low wear
 - low friction
 - higher system reliability
- better performance
 - better quality

Energy Production

etc.

● CREATING NEW INTEREST IN NEW/OLD RELATED MATERIALS

DIAMOND IS AN ENABLING TECHNOLOGY

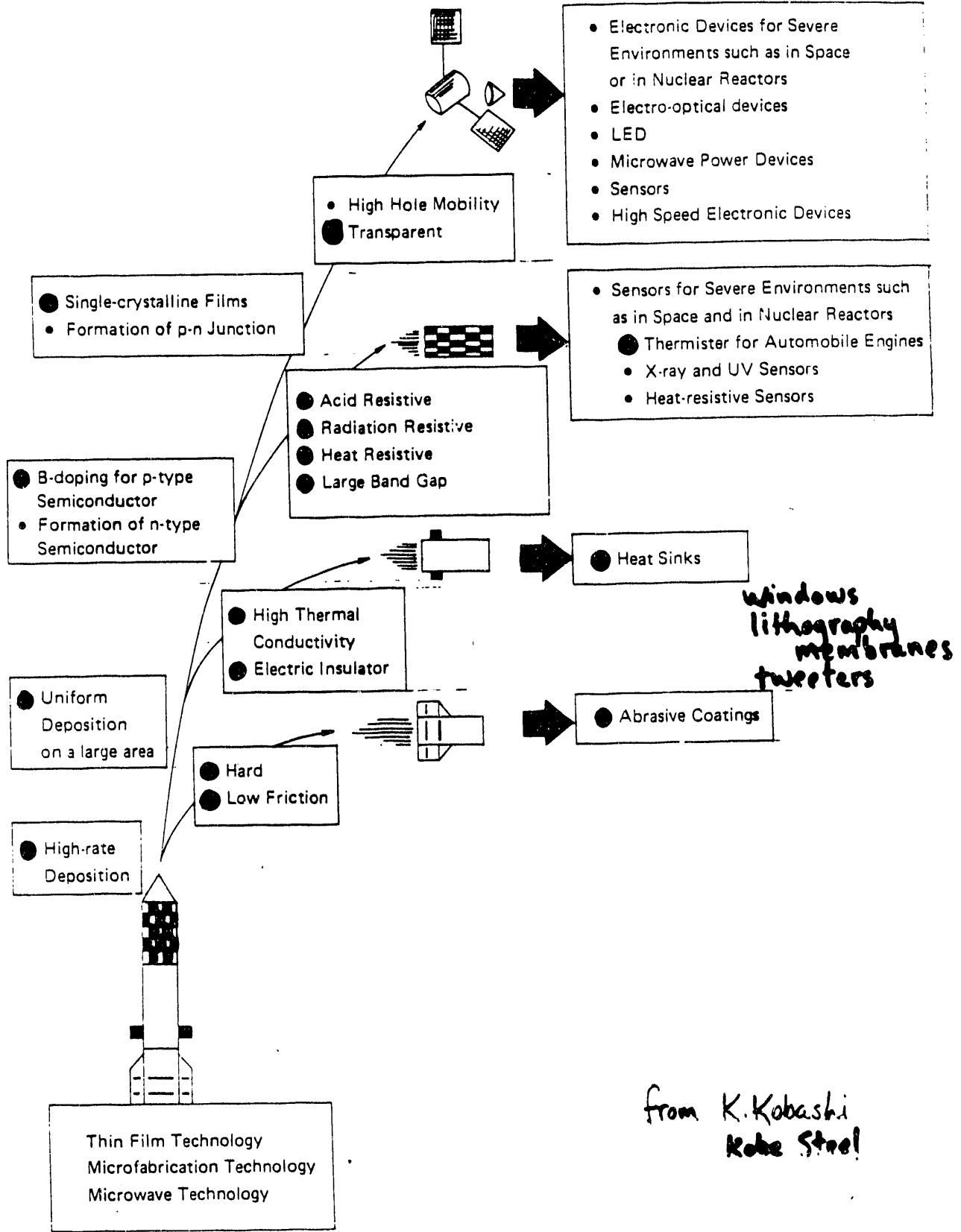
- X-RAY MASKS MADE OF DIAMOND WILL ENABLE THE PRODUCTION OF LARGER SCALE INTEGRATED CIRCUITS.
- LUBRICATION-FREE DIAMOND BEARING/JOURNAL SURFACES WILL ENABLE USE IN DEMAND ENVIRONMENTS WHERE LUBRICANTS EVAPORATE.
- SOLID STATE MICROWAVE AND MILLIMETER WAVE DIAMOND AMPLIFIERS WILL REPLACE VACUUM TUBE DEVICES (AND THEIR BUILT-IN WEAR-OUT MECHANISMS).
- DIAMOND THERMAL SPREADERS WILL ENABLE COMPUTER CHIPS TO BE PACKAGED 6 TIMES CLOSER TOGETHER WITH COMMENSURATE SPEED, VOLUME AND WEIGHT IMPROVEMENTS.
- DIAMOND AND ITS HIGH ACOUSTIC "G" WILL ENABLE FAR MORE COMMUNICATIONS/DATA CHANNELS PER UNIT SPECTRUM.
- DIAMOND CUTTING TOOLS WILL ENABLE A MUCH MORE AGGRESSIVE USE OF ALUMINUM IN THE AUTOMOBILE AND RELATED INDUSTRIES.
- DIAMOND OPTICS WILL ENABLE PORTABILITY OF FELS.

STATUS OF PRODUCT DEVELOPMENT

1. ACOUSTIC IN SONY SPEAKERS.
2. DIAMOND COATED CUTTING TOOLS.
3. FUJITSU HEAT SINKS.
4. X-RAY LITHOGRAPHY MASKS. ↑
DONE |
5. X-RAY WINDOWS.
6. GRIT FOR GRINDING WHEELS. ~~~~ |
7. ELECTRONIC PACKAGING. SOON |
8. CORROSION PROTECTION. ↑
9. FRICTION REDUCTION.
10. OPTICAL COATINGS AND WINDOWS.

R&D on CVD DIAMONDS

KOBELCO
Trademark of Kobe Steel, Ltd.



from K.Kobashi
Kobe Steel

CURRENT STATUS OF CVD DIAMOND

SCIENCE

- Progress is being made
- Basic and Applied Science needed
(the more questions answered, the more posed)

TECHNOLOGY

- Companies are beginning to make major and long term commitments
- Products are beginning to appear

GENERAL

- We're in for the long-haul!

PENNSTATE



University Park
Campus

CVD Diamond - Fundamental Phenomena

WALTER A. YARBROUGH

Materials Research Laboratory
The Pennsylvania State University
University Park, PA 16802

Department of Energy Workshop
Argonne National Laboratory
4-5 February 1992

Graphite/Diamond Equilibrium

$$dG = Vdp - SdT$$

$$\left(\frac{\partial(\Delta G)}{\partial p} \right)_T = \Delta V$$

$$\left(\frac{\partial(\Delta G)}{\partial T} \right)_p = -\Delta S$$

For diamond:

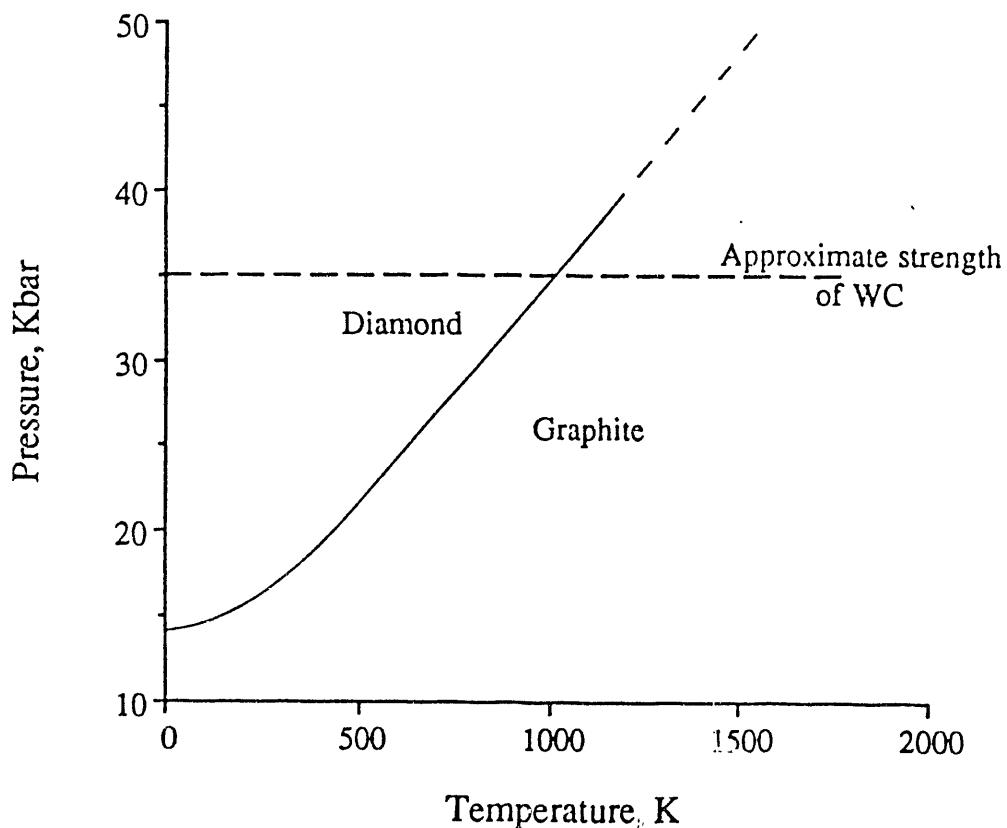
$$\bar{V} = 3.42 \text{ cm}^3 \text{ mol}^{-1}$$

$$\bar{S} = 2.38 \text{ J mol}^{-1} \text{ K}^{-1}$$

For graphite:

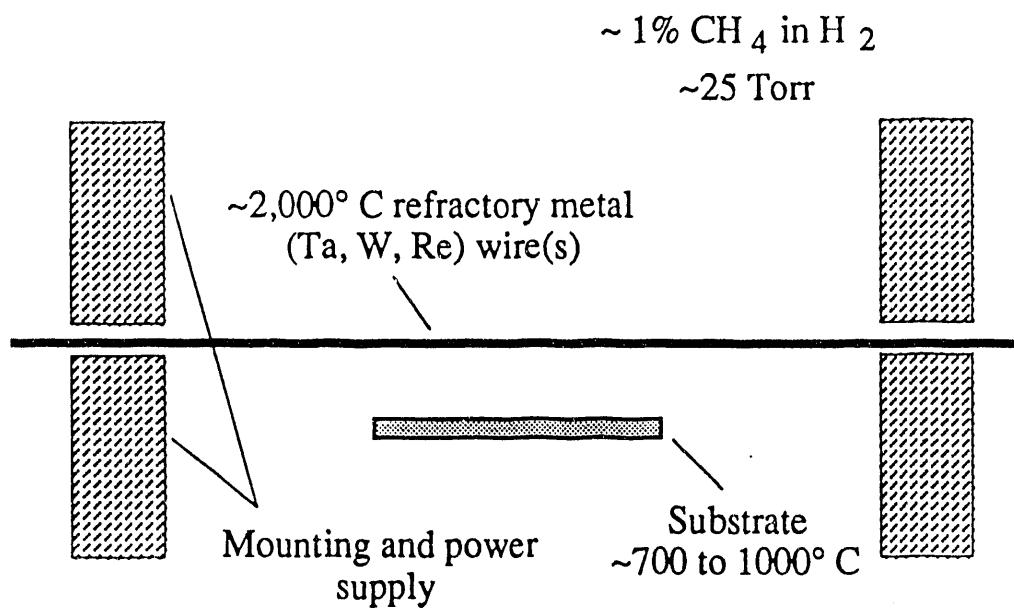
$$\bar{V} = 5.34 \text{ cm}^3 \text{ mol}^{-1}$$

$$\bar{S} = 5.74 \text{ J mol}^{-1} \text{ K}^{-1}$$

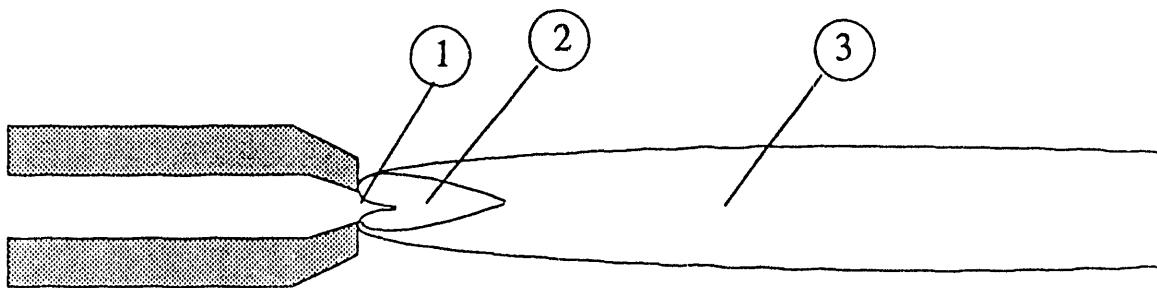


After: J. Bassett, *J. Phys. Radium*, 10, 217 (1939).

Hot Filament Assisted CVD

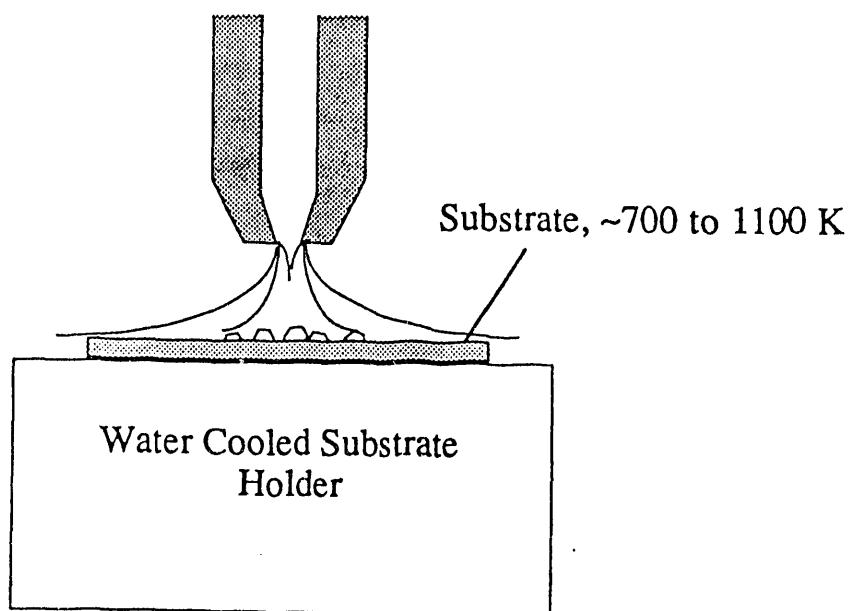


Combustion Synthesis of Diamond

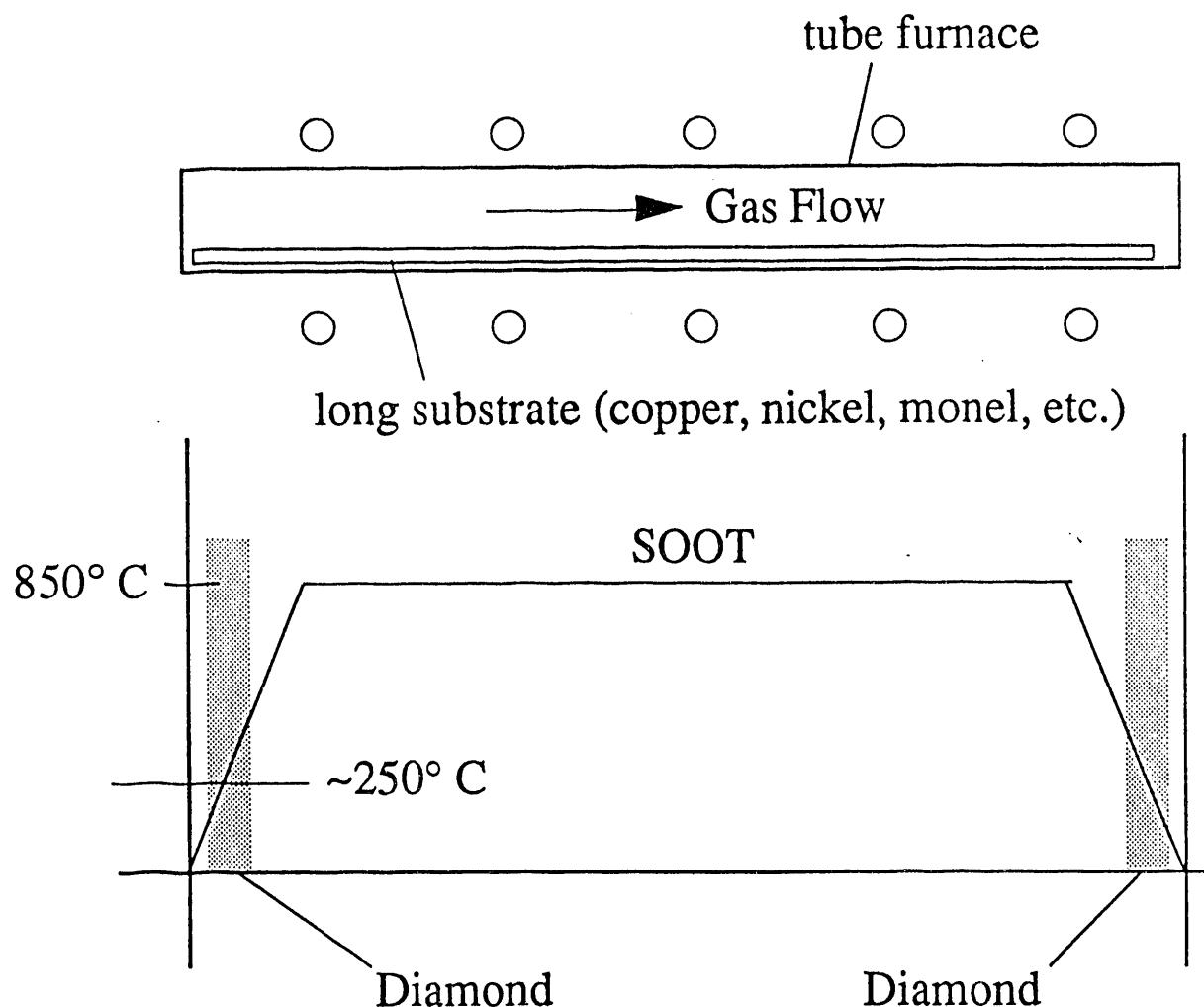


Various "zones" in an oxyacetylene brazing torch (~1:1 O/C or less)

1. Transparent, colorless. Preheat zone. Premixed gas at high velocity is heated to combustion.
2. Bright incandescent white. Primary combustion. Premixed acetylene and oxygen burns to produce primarily CO and H₂. Adiabatic combustion temperature (1:1 C₂H₂ - O₂) 3300 K. Much H₂ expected to be atomic. Diamond growth observed here.
3. Blue, transparent. Secondary combustion. Combustion of the CO and H₂ produced in primary combustion in the surrounding air.



Deposition of Diamond from Fluorocarbons



Observations

- * Diamond can be grown without hydrogen
$$\text{CS}_2 + 6 \text{ F}_2 \rightarrow \text{C}_{(\text{dia})} + 2\text{SF}_6$$
- * Methane, fluorine, hydrogen mixtures work.
- * Some oxygen important - best results with alcohols, ketones, etc.
- * Carbon furnace best - less metal halide.
- * Temperature control in hot zone important
- * Temperature gradient may be important

Why Diamond ?

(and not graphite, or lonsdaleite, or glassy carbon, or cliftonite, etc.)

Critical Observations

Diamond can be grown on diamond by simple hydrocarbon decomposition, i.e. without atomic hydrogen.

BUT only in small amounts - graphite nucleates eventually - then graphite growth dominates.

W. G. Eversole, "Synthesis of Diamond," U. S. Pat. no. 3,030,188, April 17, 1962.
John C. Angus, H. A. Will and W. S. Stanko, *J. Appl. Phys.*, 39, 2915 (1968).

If diamond and graphite both are present in "excess" atomic hydrogen: graphite decreases - diamond increases. *Diamond is nucleated and grown on graphite.*

H. B. Vakil, 1989.

Kinetic Theory:

Competitive Growth Model -

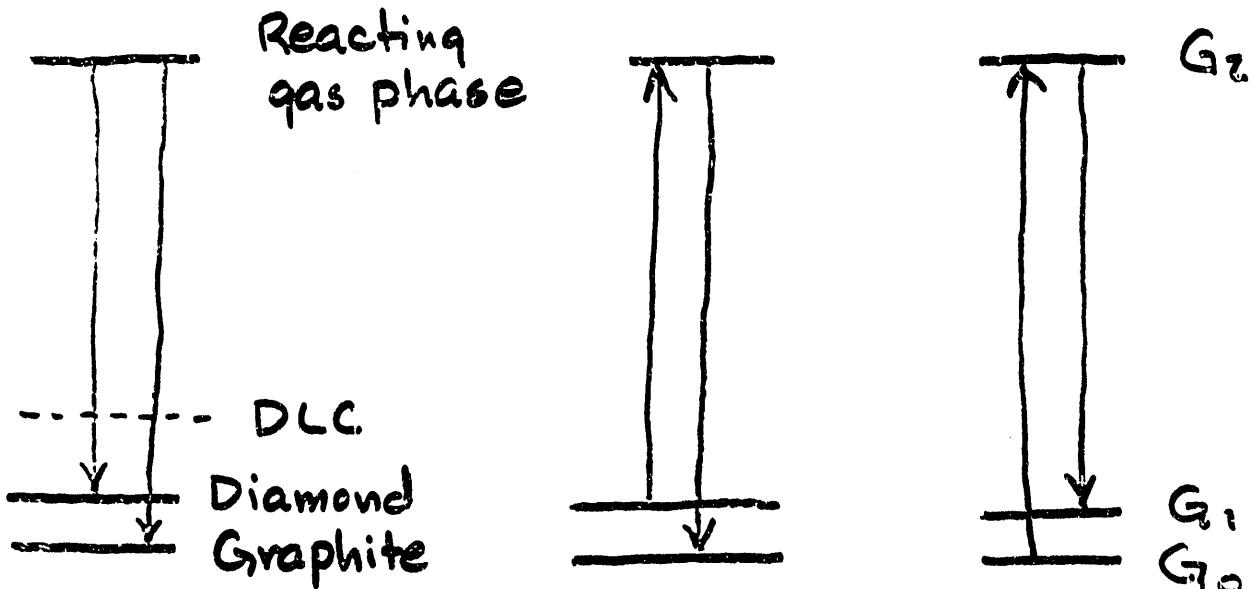
Graphite is "etched" or gasified faster than diamond, hence diamond persists.

- B. V. Derjaguin and D. V. Fedoseev, *Growth of Diamond and Graphite from the Gas Phase*, Nauka, Moscow (1977). (in Russian)
- B. V. Spitsyn, L. L. Bouilov and B. V. Derjaguin, *J. Crystal Growth*, 52, 219 (1981).

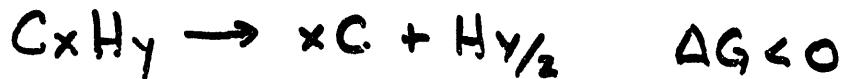
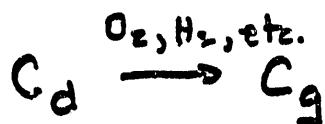
If equilibrium calculations are modified to include an enhanced etching of graphite by atomic hydrogen then the first solid obtained is diamond.

- M. Sommer, K. Mui and F. W. Smith, "Thermodynamic Analysis of the Chemical Vapor Deposition of Diamond Films," *Solid State Comm.*, 69 (7), 775 (1989).

What is the synthetic Paradigm?



Bridgman,
Eversole, etc.



$$\Delta G > 0$$

$$\Delta G \ll 0$$

Questions

Simultaneous gasification of graphite and deposition of diamond appears to violate second law.

Growth Surface Stabilization:

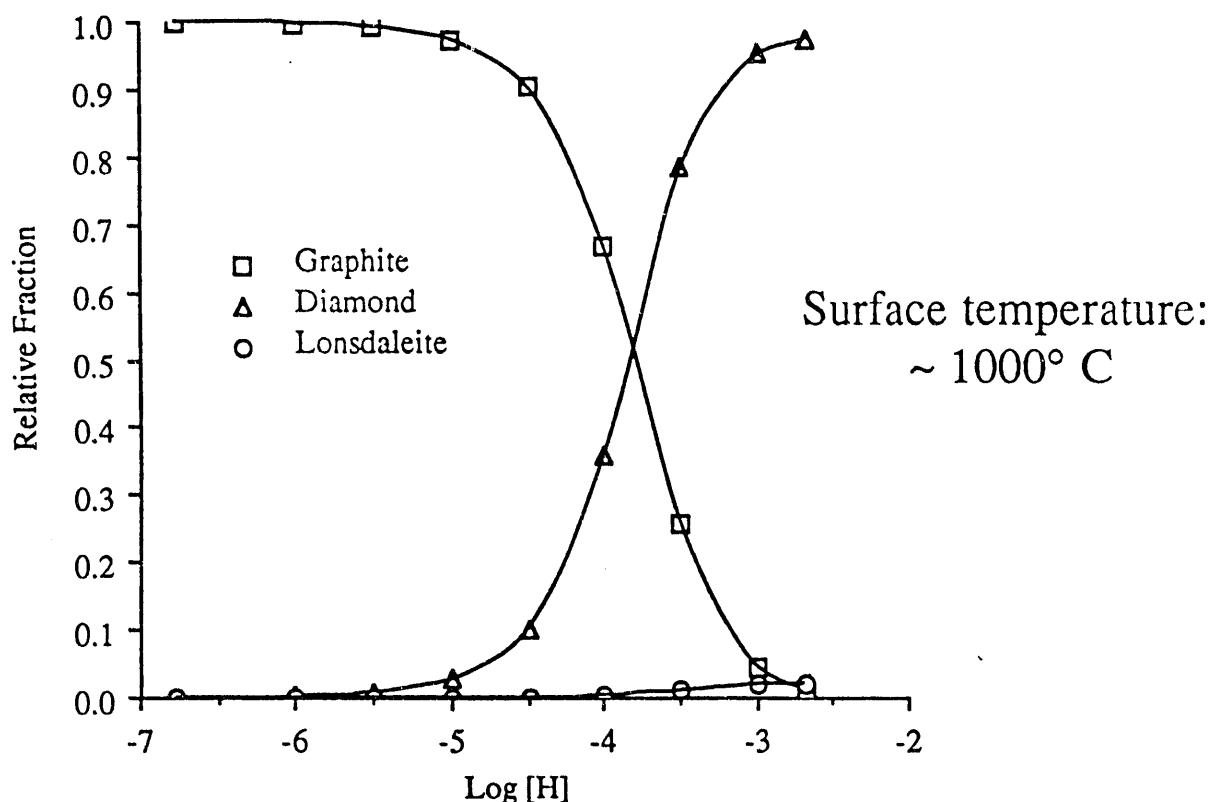
Stabilization by Hydrogen -

Hydrogenated diamond surface is stable relative to hydrogenated graphite.

Atomic hydrogen maintains surface hydrogenation at high temperature and low pressure.

- R. Roy, R. Messier and K. E. Spear, *Microwave Plasma Synthesis of Diamonds and Diamond Coatings*, Final Technical Report, ONR Contract N00014-84-K-0749, January, 1986.
- B. B. Pate, *Surface Science*, 165, 83 (1986).
- K. E. Spear, *Earth and Miner. Sci.*, The Pennsylvania State University, 46(4), 53-59 (1987).
- W. A. Yarbrough, "Thermodynamics and the CVD of Diamond," *Diamond, Silicon Carbide and Related Wide Band Gap Semiconductors*, J. T. Glass, et. al., eds., MRS Proceedings, Vol. 162, Pittsburgh, PA (1990), pp. 75-84.

Variation of Predicted Phase with Atomic Hydrogen Partial Pressure



At thermostatic equilibrium: For filament at 2000°C (50 Torr):

$$\text{Log } [\text{H}^\circ] = -6.78$$

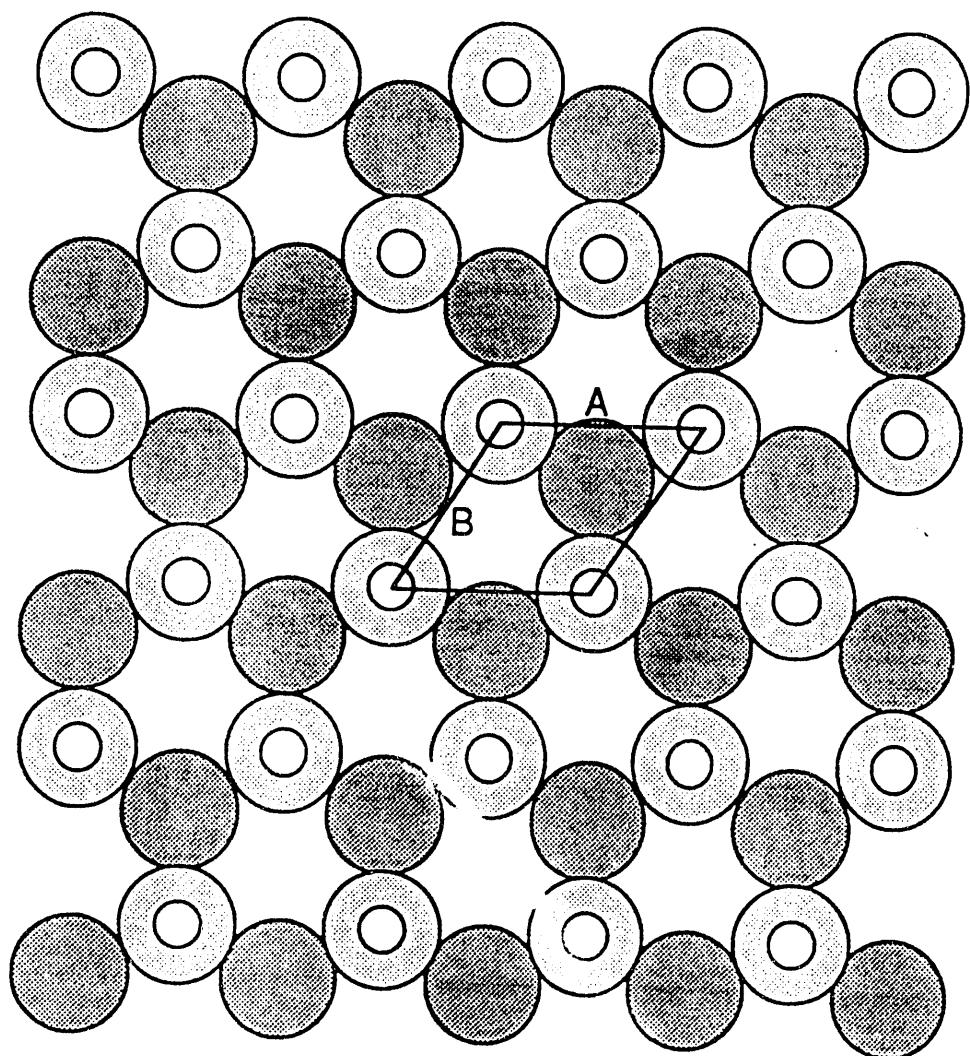
Graphite is predicted

$$\text{Log } [\text{H}^\circ] = -2.68$$

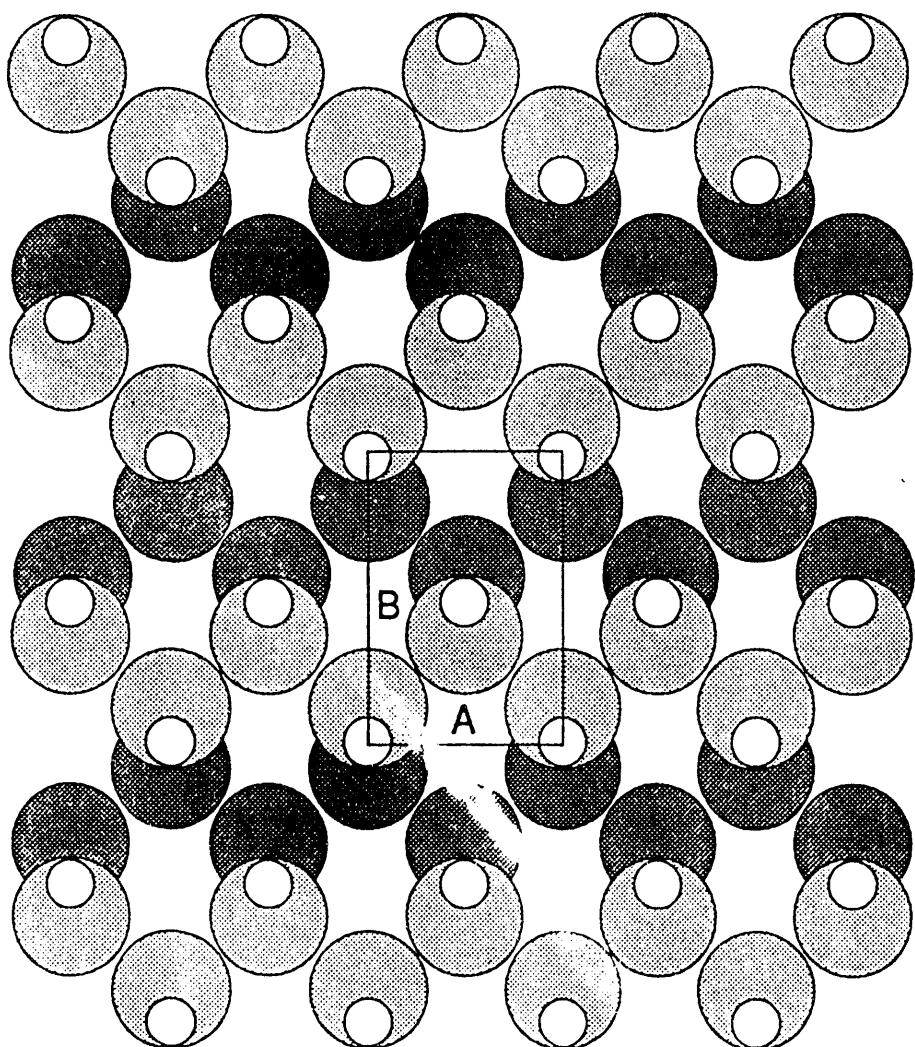
Diamond is predicted

Graphitic defects and twinning/stacking faults (polytypes or diamond - lonsdaleite crystalline solutions) possible.

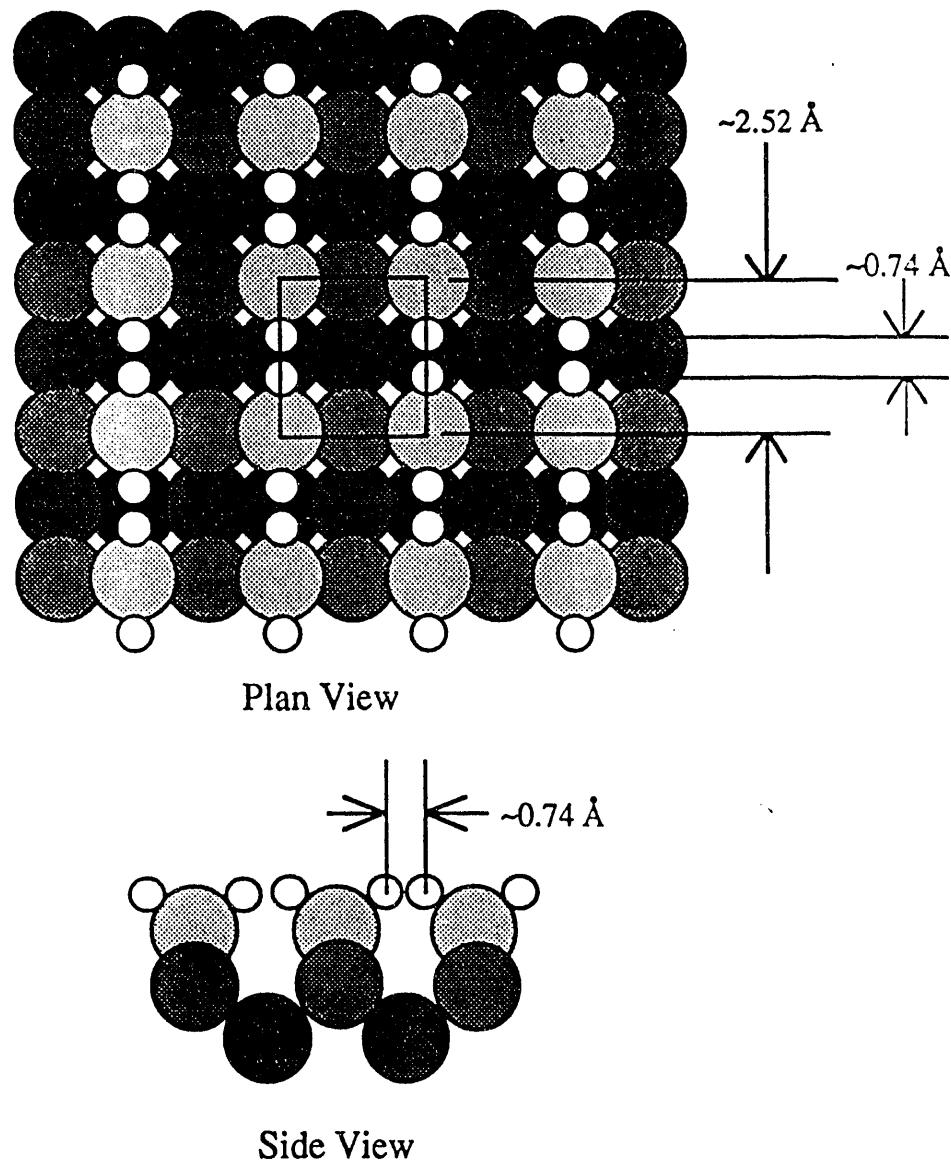
Hydrogenated, Unreconstructed (111) Surface of Diamond



Hydrogenated, Unreconstructed (110) Surface of Diamond



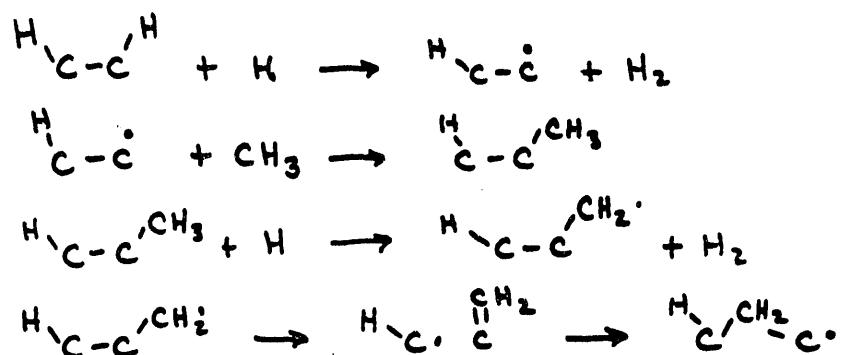
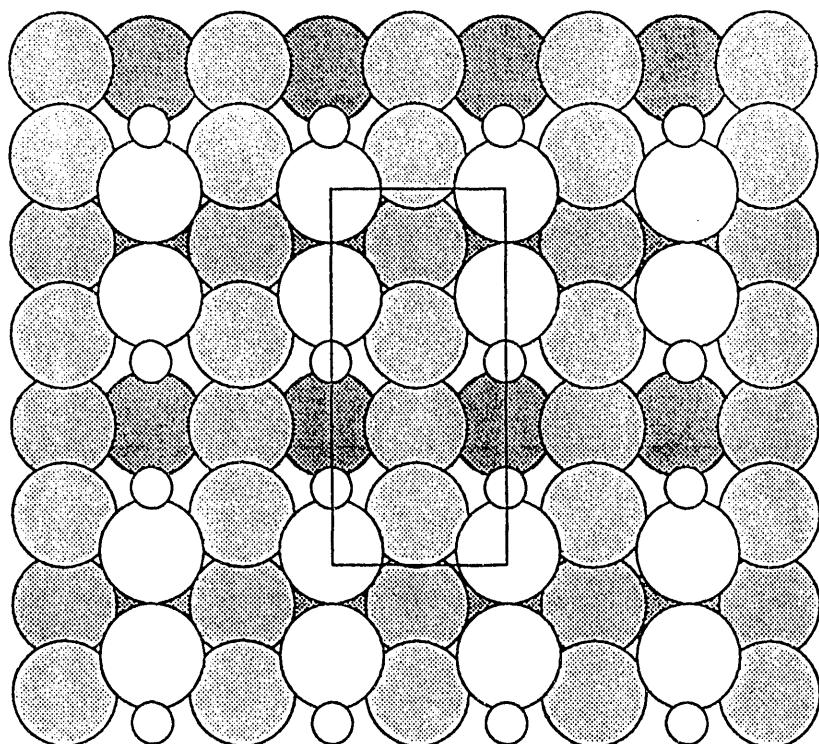
Hydrogenated, Unreconstructed (100) Surface



Using Lennard-Jones Potentials with $A = 31.4 \text{ \AA}^6$ and $B = 2.97 \times 10^3 \text{ \AA}^{12}$ kcal/mole, $\Delta H = \sim 0.7 \times 10^4 \text{ kcal/mole}$!
Simple hydrocarbon (cyclooctane) model, $\Delta H \sim 2.5 \text{ kcal/mole}$
Molecular mechanical modeling, $\Delta H \sim 40 \text{ kcal/mole}$
(Yang and D'Evelyn, 1991)

See: W. A. Yarbrough, in *Diamond, Silicon Carbide and Related Wide Band Gap Semiconductors*, pp. 75-84, MRS Proc., Vol. 162, Pittsburgh, PA (1990).
A. V. Hamza, et al., *Surf. Sci.*, 237, 35 (1990).
S. J. Harris, *Appl. Phys. Lett.*, 56 (23), 2298 (1990).

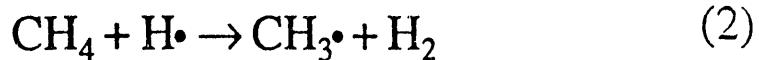
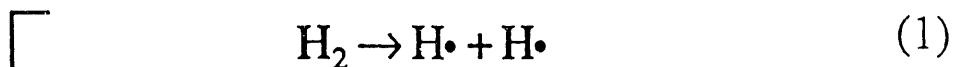
Hydrogenated, Reconstructed (100) Surface of Diamond



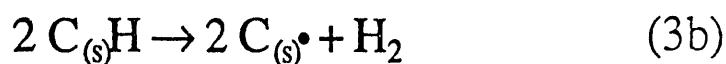
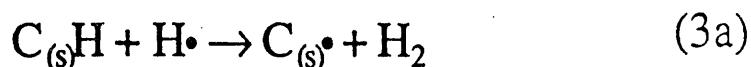
B. Garrison (Penn State)
 & D. Brenner (NRL), 1991

A Methyl Radical Mechanism

Gas Phase
Activation



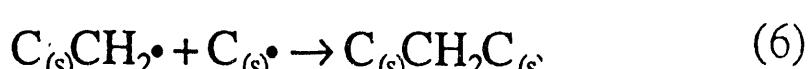
Surface
Activation



Addition

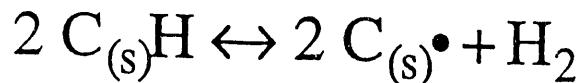


Incorporation



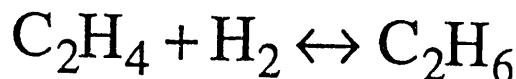
Unresolved Questions

Kinetic modeling, to date, treats diamond surface as large hydrocarbon. How good is this assumption?



Is it possible? important?

For simple hydrocarbons - not likely - forbidden by orbital symmetry rules, hence



does not happen.

Do reactive sites (radicals?) diffuse on the diamond surface?

Can carbon species ($\text{R}-\text{CH}_3$, $\text{R}=\text{CH}_2$, etc.) diffuse on diamond?

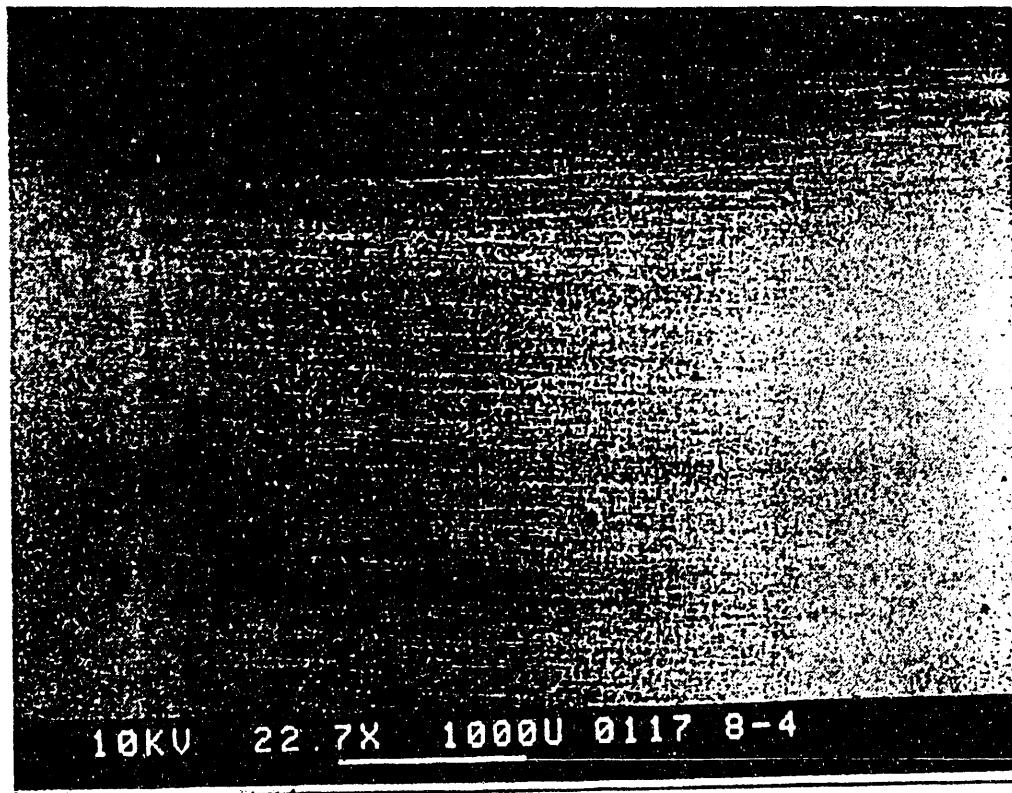
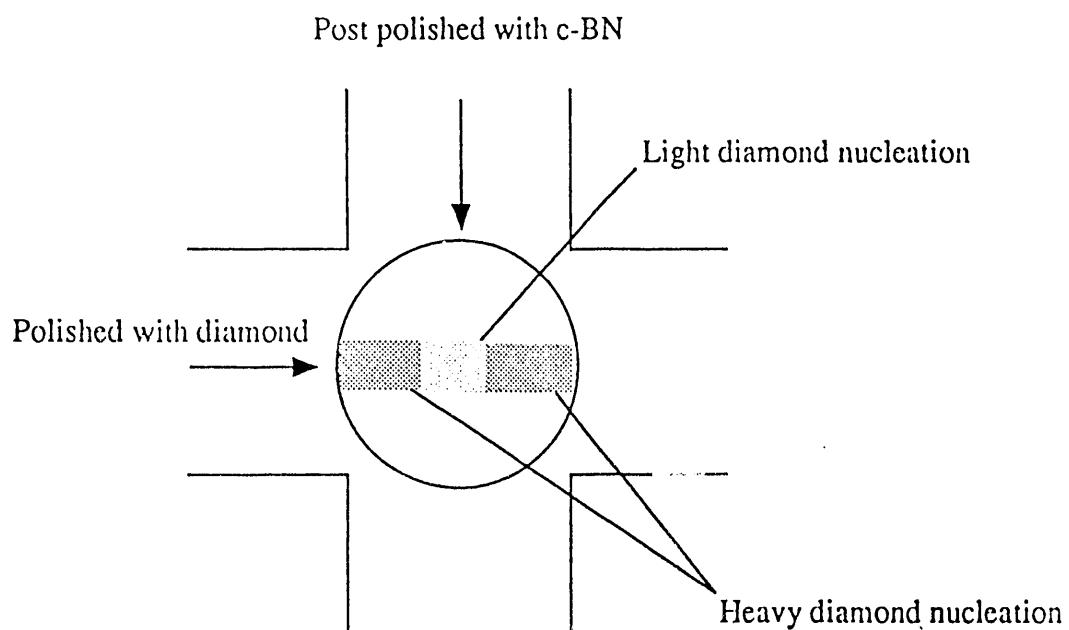
Dissociative chemisorption of H_2 on diamond is known at low temperature.

Y. Ishikawa, et al., in *The Chemistry and Physics of Carbon*, P. L. Walker and P. A. Thrower, eds., Vol. 12, (Marcel Dekker, New York, 1975), pp. 39-108.

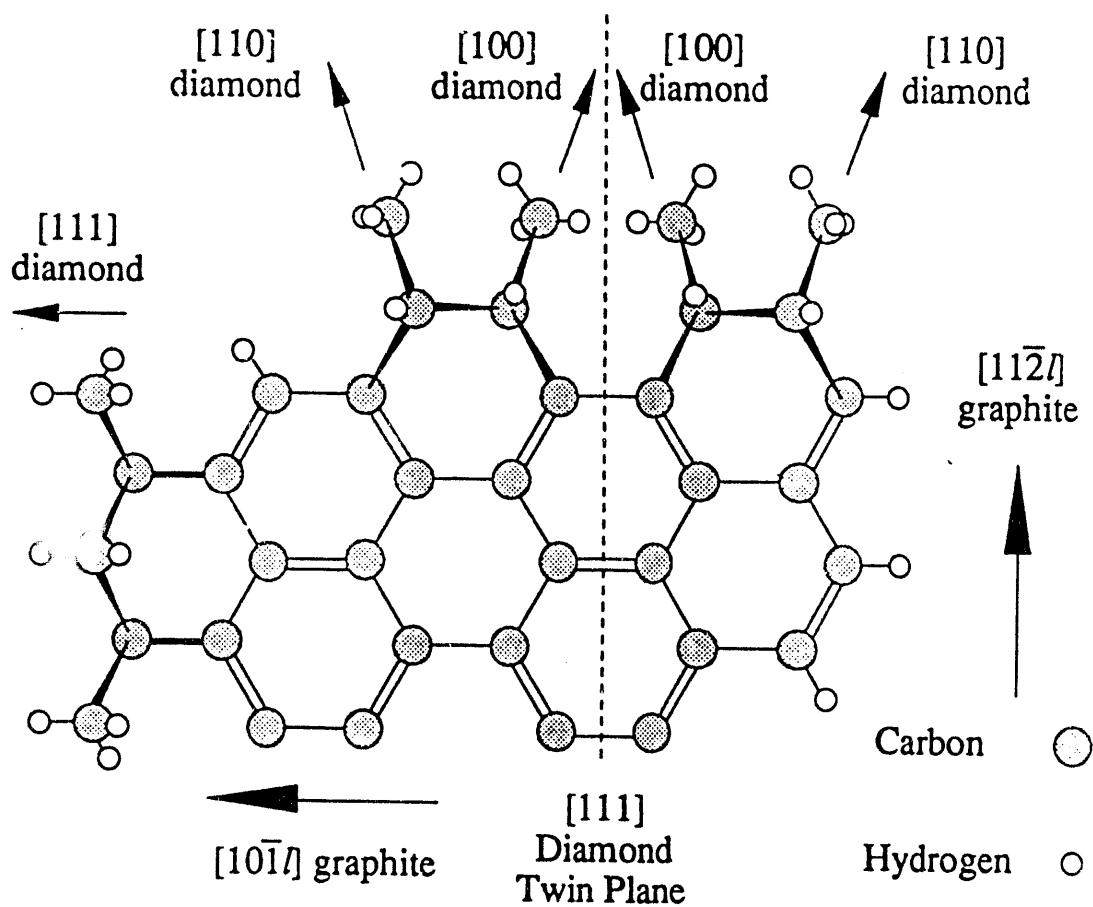
(111) diamond surface loses hydrogen at low pressure and high temperature.

If associative desorption does not happen - what is the mechanism?

Polishing to enhance diamond nucleation

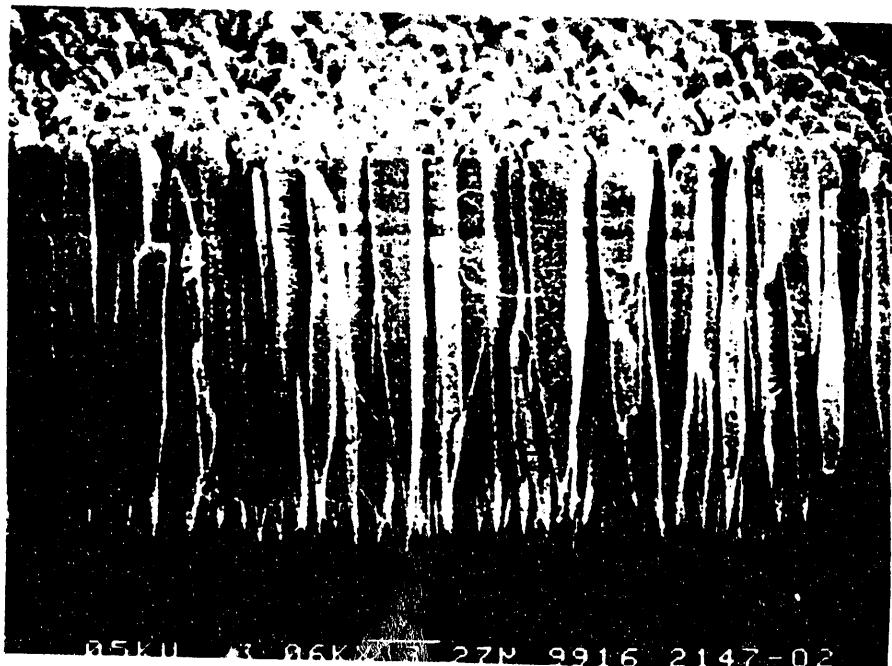


Nucleation of Diamond on Graphite





0.5KU 10.1KX 990n 9914 2147-02



0.5KU 3.8KX 27N 9916 2147-02

Y. SATO, C. HATA and M. KAMO, "Formation
and Structural Features of Needle-like
Diamond"

from Y. Sato (NIRIM)

1st International Symp. New Diamond Science & Technology
Tokyo, Japan Oct. 24-26, 1988

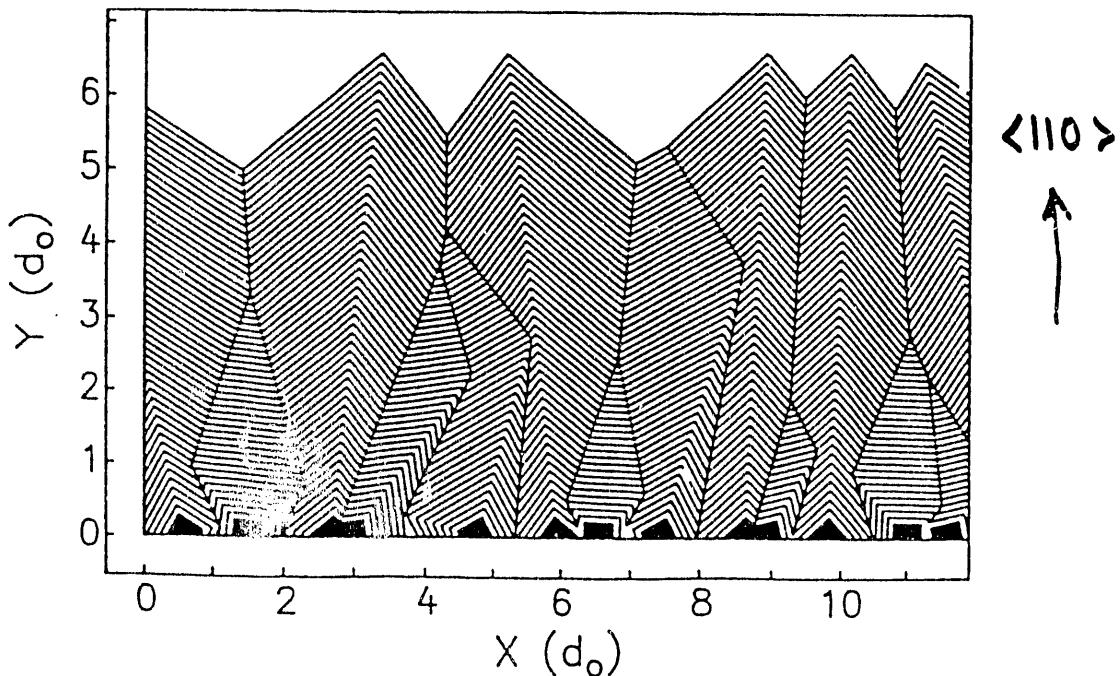


Fig. 6. Computer simulation of the growth of a polycrystalline film. The X and Y axis are normalized with respect to the mean nuclei distance d_o .

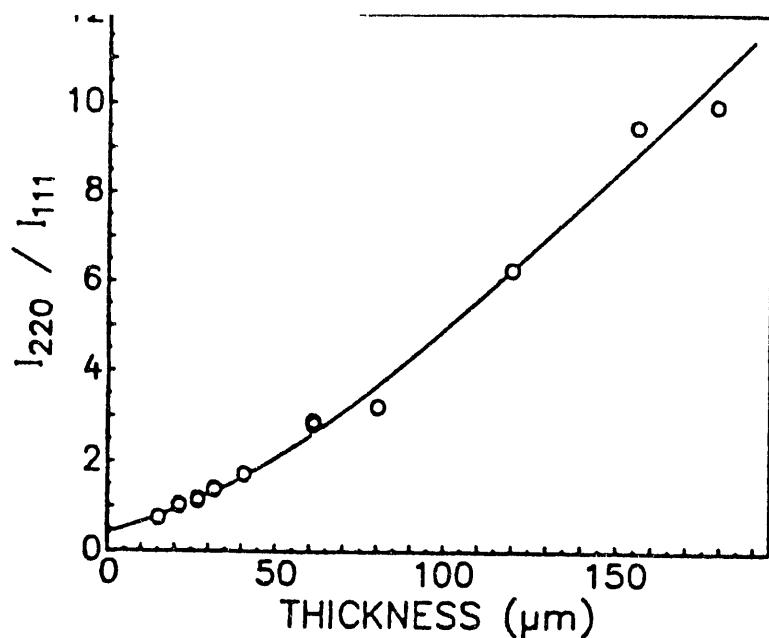
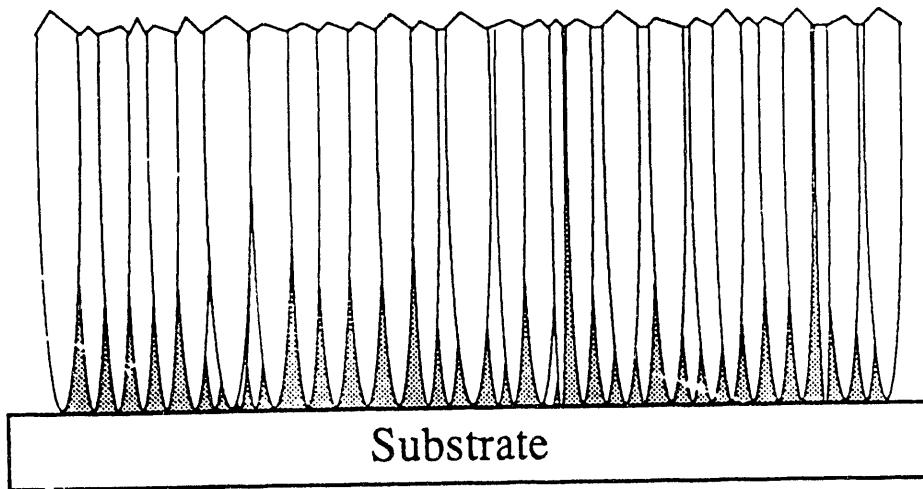


FIG. 5. Intensity ratio of the 220 peak to the 111 peak as a function thickness.

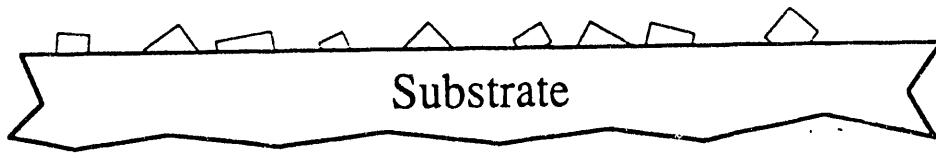
Modeling of Texture Development in Polycrystalline Films

Ch. Wild, N. Herres and P. Koidl, "Texture Formation in Polycrystalline Diamond Films," *J. Appl. Phys.*, **68** (3), 973-978 (1990).

Model for Microstructural Development



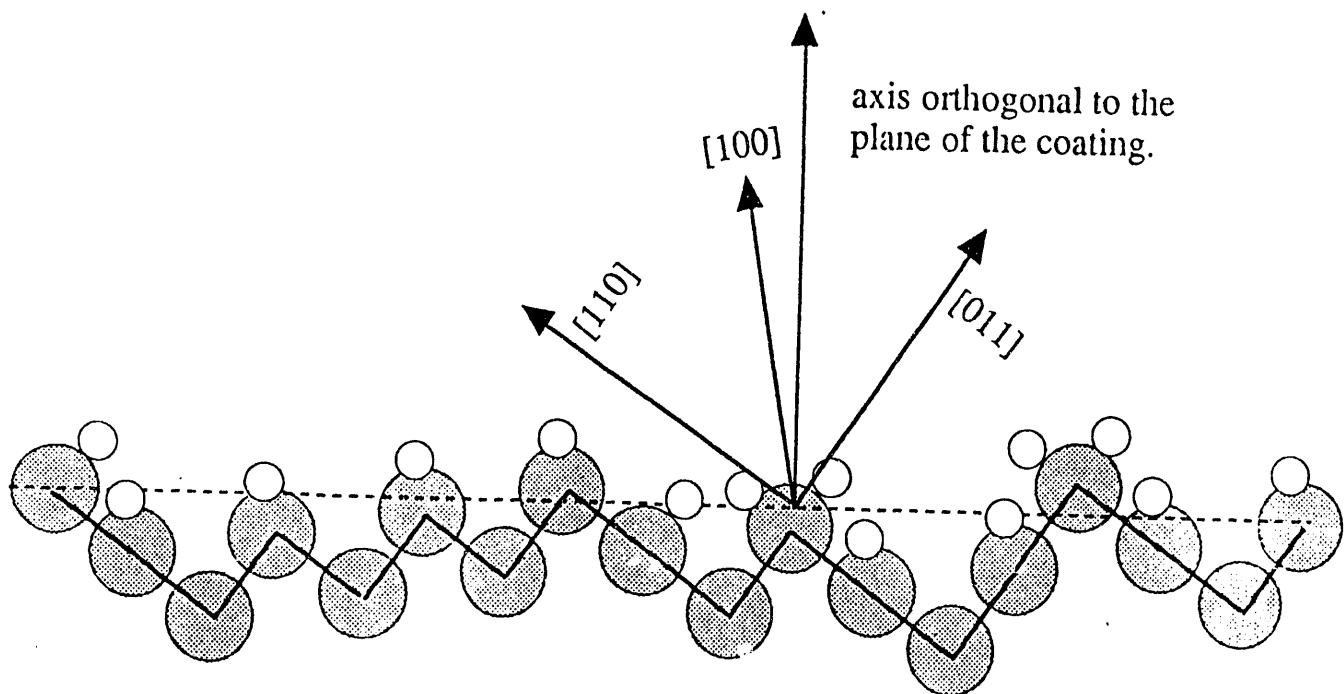
(a)



(b)

A schematic illustrating the uniaxial growth of polycrystalline layers. Nucleation occurs at discrete sites on the substrate and these nuclei may be randomly oriented with respect to their crystallographic axes as illustrated in (b) above. As growth continues, those crystals which are favorably oriented, i. e. have their dominant growth axis aligned more or less normal to the substrate, will begin to dominate and upon continued growth the film or layer will begin to exhibit this crystallographic texture. Impurities and voids may be intergranularly entrained, the shaded regions in (a), leading to greater perfection with continued growth.

Possibility for a vicinal $<100>$ Texture



FOR VICINAL $<100>$ TEXTURE SEE :

E. D. SPRECHT, R. E. CAUSING, AND L. HEATHERLY
J. MATER. RES., 5 (11), 2351 (1990).

Requirement for Elastic Isotropy in Cubic Materials

$$\frac{2c_{44}}{c_{11} - c_{12}} = 1$$

Values for diamond

from: M. H. Grimsditch and A. K. Ramdas, *Phys. Rev.*, B11, 3139 (1975)

$$c_{11} = 10.76, \quad c_{12} = 1.25, \quad c_{44} = 5.77 \quad \times 10^{11} \text{ Nm}^{-2}$$

or

$$\frac{2c_{44}}{c_{11} - c_{12}} = 1.21 \text{ for diamond}$$

Conclusion: Diamond is elastically anisotropic.

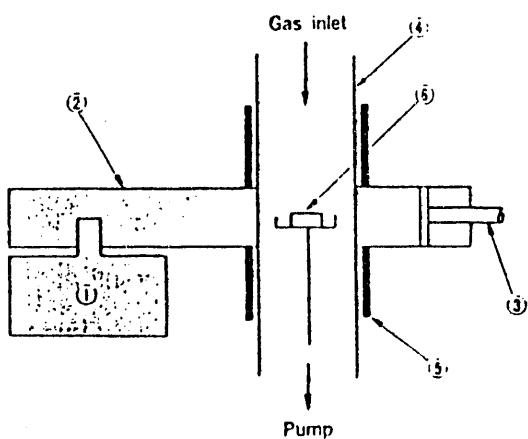


Fig. 4 Schematic diagram for synthesis equipment of microwave plasma CVD method. (1) magnetron (2.45 GHz), (2) wave guide, (3) plunger, (4) quartz tube, (5) sleeve, (6) substrate.

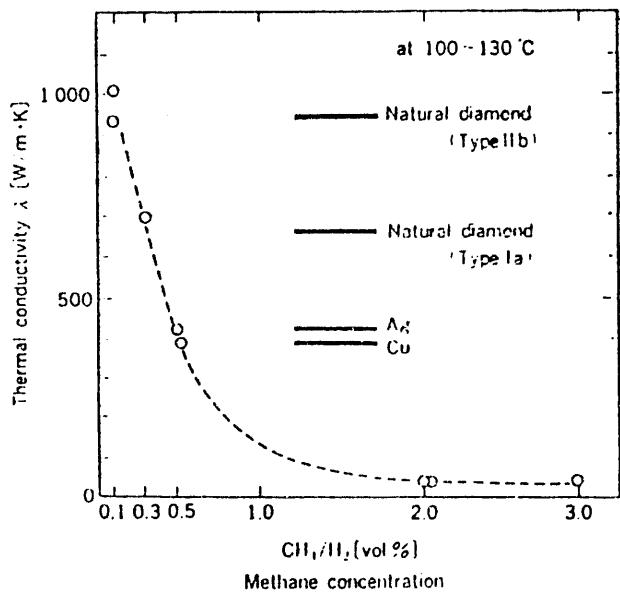


Fig. 5 Thermal conductivity of diamond films for different methane concentrations.

Table 1 Deposition condition of diamond films.

Method	MicroWave Plasma CVD
Reaction gas	CH ₄ +H ₂
CH ₄ concentration(CH ₄ /H ₂)	0.1~3.0 vol%
Total gas pressure	4kPa
Flow rate	300SCCM
Microwave power(2.45GHz)	500W
Temperature(on sub.)	~800 C
Substrate	Si(100)
Substrate dimensions	30×5×0.6mm
Thickness of diamond films	7~30/ μ m

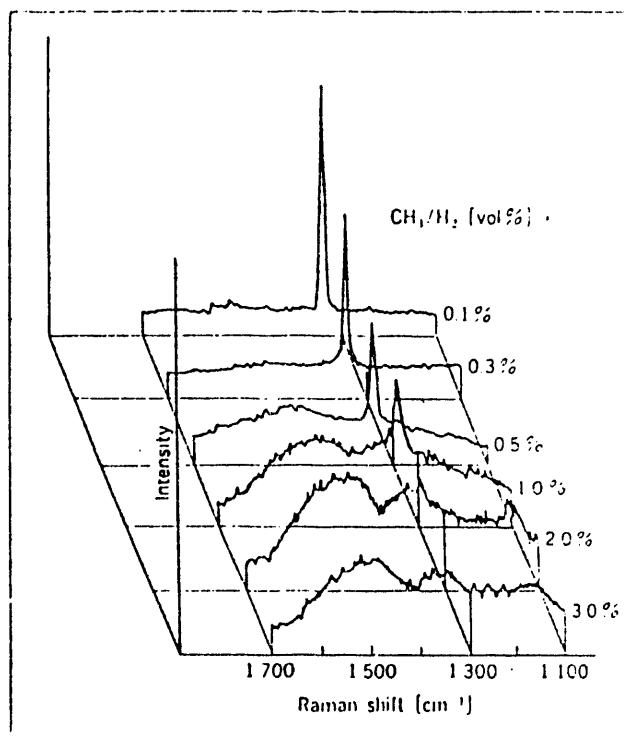
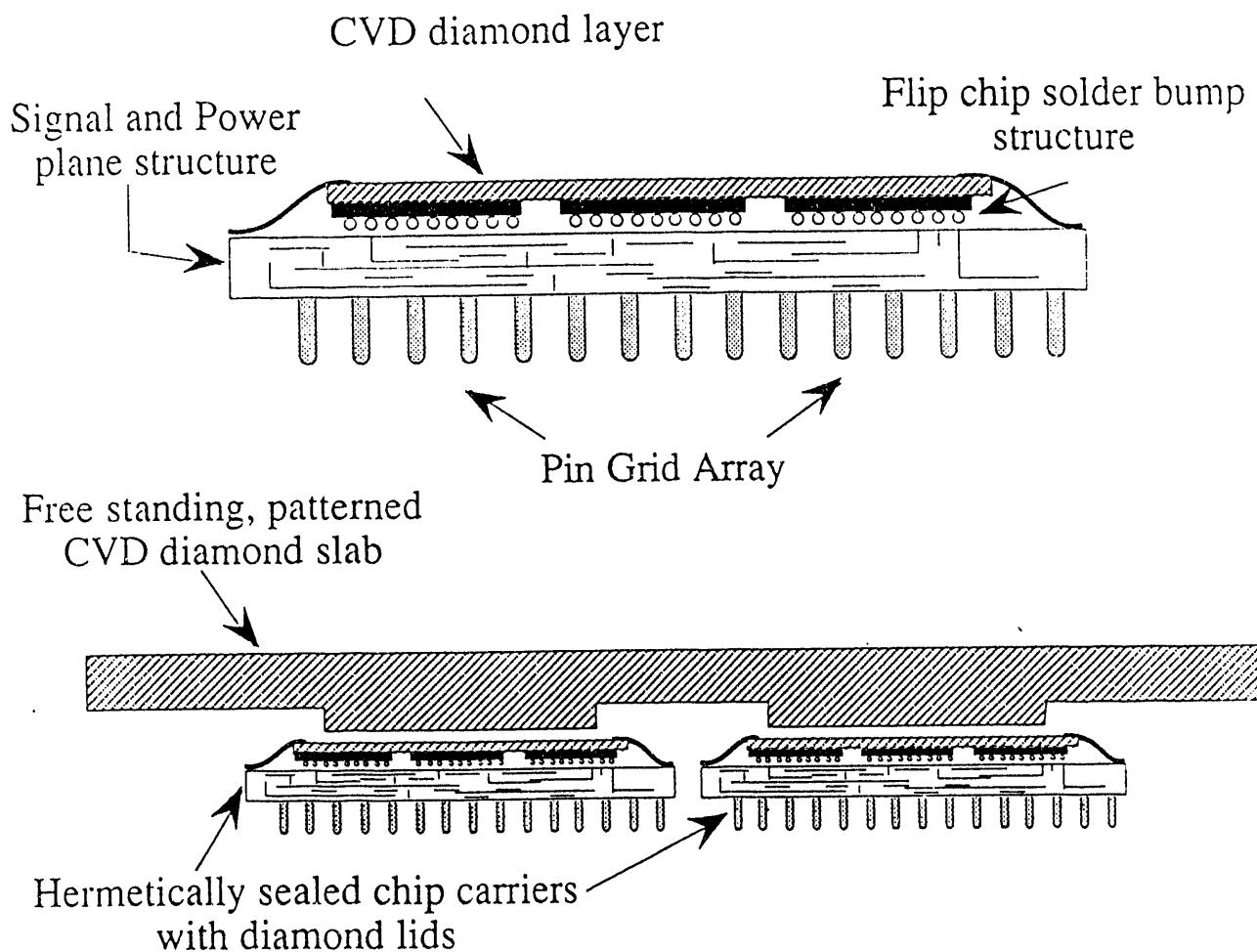


Fig. 6 Raman spectra of diamond films for different methane concentrations.

A. Nishikawa, "Measurement for Thermal Conductivity of Diamond Films," *New Diamond 1990*, Japan New Diamond Forum, through Ohmsha, Ltd., Tokyo, Japan.

Chip Carrier Possibilities



Notes:

1. Thermal "grease" at chip and carrier or carrier and board levels - expansion mismatch no problem.
2. Signal/power plane structure/materials optimized for expansion and permittivity at carrier and board levels. No need to consider κ_T
3. Uniform operating temperature - reduced connection fatigue.

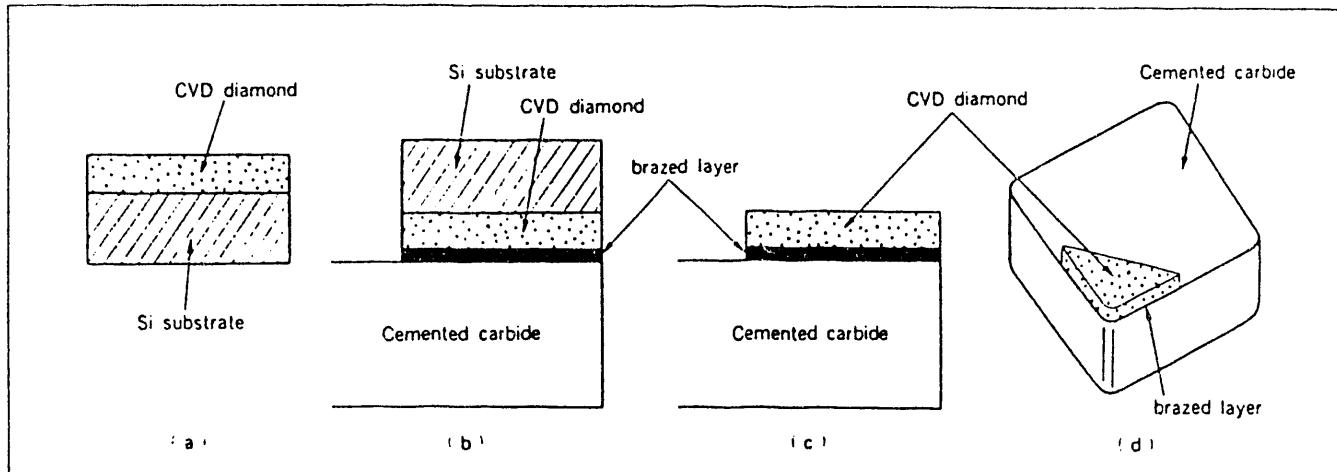


Fig. 2 Manufacturing method for a CVD poly-crystalline diamond tool.

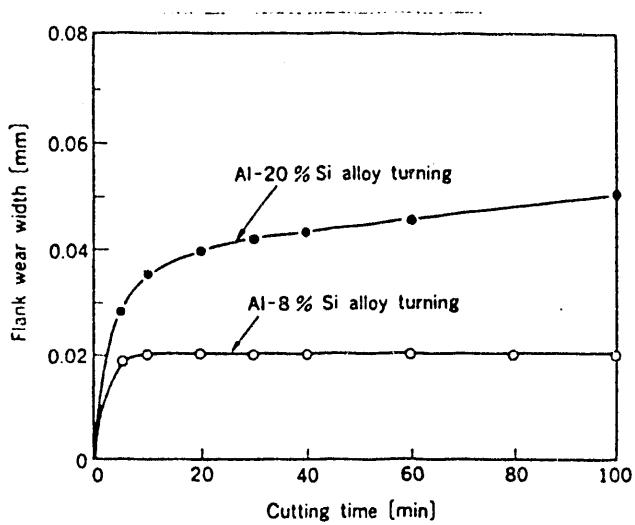


Fig. 4 Flank wear curve diagram of CVD poly-crystalline diamond tips in Al-8%Si and Al-20%Si alloy turning.

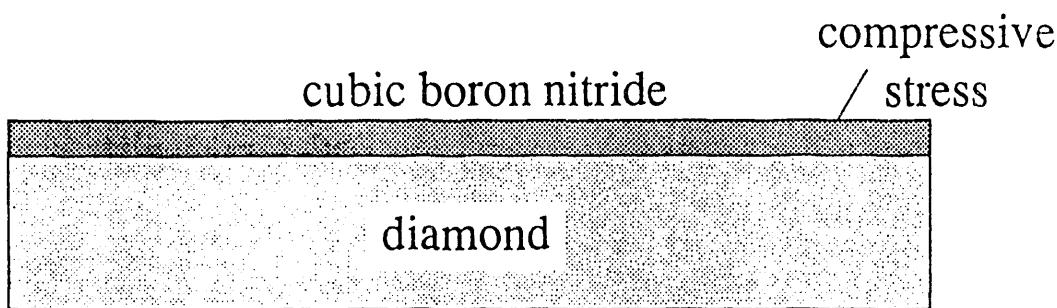
Brazed Diamond Cutting Tool and its performance

Asahi Industrial Diamond Co., Ltd.
Osaka, Japan

F. Okuzumi, "Gaseous Phase Synthesis Poly-crystalline Diamond Tool," *New Diamond 1990*, Japan New Diamond Forum, Ohmsha, Ltd., Tokyo, 1990.

Future Possibilities

- * Composite designs, e.g. consider



- * Passivation of diamond surface.
 - Oxidation resistance
 - Graphitization/reaction/dissolution
- * "Classical" CVD a possibility
 - Methyl fluoride work confirmed

Comparative Evaluation of CVD Diamond Technologies

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Abstract

Chemical vapor deposition (CVD) of diamonds occurs from hydrogen-hydrocarbon gas mixtures in the presence of atomic hydrogen at subatmospheric pressures. Most CVD methods are based on different means of generating and transporting atomic hydrogen in a particular system. Evaluation of these different techniques involves their capital costs, material costs, energy costs, labor costs and the type and quality of diamond that they produce. Currently, there is no universal agreement on which is the best technique and technique selection has been largely driven by the professional background of the user as well as the particular application of interest.

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Ia CRITERIA FOR EVALUATION

Four different factors should be considered in evaluating a process for the low-pressure deposition of diamond. The first factor is the basic process potential. This potential includes the maximum rate of diamond growth, the ability to deposit on flat surfaces as well as three-dimensional surfaces, the maximum area or volume of deposition, the maximum diamond thickness achievable, the uniformity of the deposition and the adaptability of the process to manufacturing. The latter criterion includes the process "ruggedness", its reproducibility from run to run and its technical sophistication.

Once a process satisfies the basic process potential, the costs of the process must be calculated. These costs include the capital cost based either on the physical life of the equipment or, more realistically at this point in diamond research, on the time to technological obsolescence. A second cost is the energy costs to run the process. Energy costs put most CVD processes above a dollar per carat and eliminate many of the applications described in the popular press. Another cost is labor. This cost tends to be low with simple processes and high with technically sophisticated processes. Cost for consumable materials such as gases, electrodes and filaments vary considerably from process to process. Some high-rate diamond deposition processes fail this criterion. Finally, the research and development costs must be amortized in the product costs or the organization spending these startup costs will fail. Certain processes

that require large amounts of R&D spending to launch are really uneconomical. However, if these costs are covered by a third party, ie the government, who is not subject to the discipline of the market place, these costs can be ignored.

The third general set of criteria that must be considered are application dependent criteria. These include: 1) the deposition temperature, eg, coating plastic with diamond requires a very low deposition temperature; 2) the required substrate composition, eg, coating stellite valves that contain cobalt that catalyzes the conversion of diamond to graphite necessitates operating under special conditions that not every process is capable of; 3) substrate cooling, eg, most high-deposition rate processes require forced water cooling of the substrate which is not possible with some applications; 4) substrate size and shape, eg, this may not be compatible with a particular process; 5) high adhesive bonding strength of diamond to substrate, eg, some processes are better at making a good bond with the substrate than others; 6) low adhesive bonding strength of diamond to the substrate, eg, some applications require free-standing diamond films where a low adhesive bonding strength to the substrate is needed to remove the diamond from the substrate without damaging it.

The last set of general criteria is the diamond quality produced by a particular process. Diamond quality includes its toughness, wear resistance, electrical breakdown strength, electrical resistivity, transparency to IR and visible light, thermal conductivity, grain size, grain size distribution, preferred grain orientation and the intrinsic stress grown into the film. End users may have demanding specifications that were not anticipated when a process was being developed and that are not achievable by the process. Diamond quality will gradually emerge as the principal arbiter of the "best process" in the coming years.

The selection of the best deposition method is a difficult, time-consuming, expensive and semi-empirical process. Currently, many of the questions arising from the above criteria are unanswerable from information in the public literature and choices must be based on intuition and best guesses. In the following discussion, we can only begin to examine the selection problem.

Ib. BRIEF HISTORY OF LOW-PRESSURE DIAMOND SYNTHESIS

For many years the metastable growth rate of diamond at low pressures was very small and diamond substrates were required to obtain any diamond at all. These processes were of scientific interest only because the cost of diamond produced by them greatly exceeded the cost of either natural diamond or synthetic diamond formed at high pressures. Most low-pressure methods stemmed from the work of Eversole[1] who alternatively exposed diamond substrates to a hydrocarbon gas and then hydrogen at high temperatures and low pressures[1-3]. Under these conditions, the hydrocarbon was pyrolyzed to form a mixture of diamond and graphite and then hydrogen was used to etch the graphite away. This cycle (Reactions 1 and 2) was repeated over and over again until the diamond deposit grew to the desired thickness.



In the late 1970's, an important invention changed this cyclic CVD (Chemical Vapor Deposition) process to a continuous one, increased the diamond growth rate by orders of magnitude, eliminated the need for diamond substrates and made the process technologically significant[4]. This new process[5] is shown in Reaction 3.



The key idea was the addition of atomic hydrogen to the reaction by Boris Spitsyn and his coworkers[5] following a suggestion by Prof John Angus of Case Western Reserve. Atomic hydrogen has many important roles in CVD diamond growth. These roles have been recently summarized and will not be covered here[6]. A large number of CVD methods based on the process of Reaction 3 have been developed over the last decade. Most methods are basically

just different ways of generating[7] the atomic hydrogen required in Reaction 3.

II CVD DIAMOND DEPOSITION PROCESSES

IIA HOT FILAMENT PROCESS

Langmuir first reported the dissociation of molecular hydrogen on a hot tungsten filament in the early 1900's [8-11]. This method has also been used to make atomic hydrogen in CVD diamond growth. Typically, a hot filament is heated to a temperature range of 1950-2300 Centigrade in the presence of molecular hydrogen and 1-2% hydrocarbon[11-13] as shown in Fig 1.. The molecular hydrogen adsorbs on the surface of the metal filament and dissociates into two atomic hydrogens that subsequently pass back into the surrounding gas (Fig 2).



In addition, many other reactions[14,15] take place on the filament involving the hydrocarbon. The concentration of atomic hydrogen and other hydrocarbon species around the filament have been directly measured[16,17]. A general conclusion of these experiments is that thermodynamic equilibrium calculations give a reasonable guide to the type and number of species that are actually present. The rate of deposition is dependent only on the *carbon* concentration in the gas and is independent of the type of hydrocarbon gas used.

There are some constraints on the electrically conductive refractory materials that can be used for atomic-hydrogen filaments. First, the melting point of the material must be higher than the operating temperature of the filament. Secondly, the binary eutectic temperature of carbon and the filament material must exceed the filament operating temperature to prevent the melting and breakage of the filament. This latter requirement makes molybdenum filaments marginal since a hot spot on a Mo filament may take it above the Mo-C eutectic temperature of 2200 C and cause the filament to melt and fail before the Mo filament is fully carburized.

While a carbon filament satisfies the melting-point and eutectic-point requirements, it does not produce CVD diamond

because atomic hydrogen that forms on a carbon filament reacts with the carbon and releases a hydrocarbon species into the gas rather than atomic hydrogen. Without atomic hydrogen at the substrate, graphite is deposited instead of diamond. The failure of carbon filaments to produce diamond[18] suggests that the atomic hydrogen does not form in the hot gas surrounding the filament but actually forms on the filament surface[9-11] where it can react with the filament material.

Of the remaining electrically conductive refractory materials, tungsten, tantalum and rhenium have been used to produce CVD diamond . Rhenium is usually not considered because it is 100 times as expensive as tantalum or tungsten. Both tantalum and tungsten react with the hydrocarbon in the gas to form carbides. Thus, the tungsten and tantalum filaments quoted in the literature are really tungsten carbide and tantalum carbide filaments. It is interesting to note that W_2C is a commonly used catalyst material in gaseous hydrocarbon chemistry. However, experiments that have compared the difference in diamond growth rates between tungsten or tantalum carbide filaments show no special catalytic effect for tungsten carbide[19]. Of course, the rate of diamond growth may not be controlled by the production of atomic hydrogen or carbon radicals on the filament surface but may instead be limited by some other process. Filament carburization can have a catalytic effect on the diamond nucleation rate by increasing the electron emission from the filament because of the lower work function of the carbide[20]. Electron bombardment of the substrate is known to increase the diamond nucleation rate.

Carburization is a two stage process with M_2C forming first followed by MC where M is one of the refractory metals(Fig 3). Under typical hot-filament CVD diamond growth, M_2C forms in all cases. However, MC does not always form because the activity coefficient of carbon is too small[21] under some conditions of CVD diamond growth. Since the carbides of tantalum and tungsten have a molar volume that is 40-70% larger than the molar volume of the metal from which they were formed, the filaments swell, crack, bend, distort and embrittle as inward radial carburization proceeds. Because carburization occurs most rapidly along grain boundaries where carbon mobility is the highest, cracking usually follows the grain boundary patterns of the original metal filament. Carburization significantly decreases the grain size of the wire. This reduction in grain size can lead to superplastic deformation under some some

conditions. Carburization and cracking increase the electrical resistance of the filament[20] so the current and voltage must be monitored and changed to keep a constant filament temperature. To avoid filament carburization, Aikyo and Kondo introduced the hydrocarbon downstream from the hot filament[22]. Diamond was successfully deposited and the filament life and the quality of the diamond film was improved. Unfortunately, the diamond deposition rate was decreased.

A disadvantage of the filament process is that a filament is a *remote* source of atomic hydrogen. During the transport of atomic hydrogen from the filament to the substrate, a considerable fraction is lost through trimolecular collision between two atomic hydrogens and a third gas molecule[23]:



where H is atomic hydrogen and M represents a gas molecule or the walls of the reactor.

Associated with Reaction (5) is a recombination length, L_r , which gives the average distance that an atomic hydrogen travels before it recombines in a trimolecular collision. For typical filament-method process conditions of $T = 1500$ K and $P = 10$ torr, the recombination length L_r is 13 cm[24]. Matsumoto and coworkers[12] in the original filament paper found that the filament-substrate separation must be less than 3 centimeters to get diamond growth.

The loss of hydrogen by recombination can be decreased by reducing the filament-substrate separation distance. Hirose used tiny filaments that were very close (<1 mm) to the substrate as well as oxygen additions to attain growth rates of 10 microns/hr which is 10 times the usual diamond growth rate for the filament process[25]. Presumably, the small separation between filament and substrate decreased the loss of atomic hydrogen and other active hydrocarbon species.

The quality of diamond produced by the filament technique can vary widely. Problems with contamination of the diamond films by filament material can affect electronic and thermal properties[26]. Also, filaments as discussed above are in effect point sources of atomic hydrogen and heat and the diamond films produced under a

filament or filaments will reflect this nonuniformity. The thickness, grain size and quality of a diamond film produced by a filament system will vary from place to place. Finally, because of a finite filament life, the maximum thickness of a diamond film that can be produced by the filament technique is limited. The construction costs of a filament system are relatively low as it can be built with readily available simple equipment. However, because of the low diamond growth rate with a filament system, the capital costs per unit of diamond produced are in the midrange of the various CVD techniques. Because of the simplicity of a filament system, its labor costs are relatively low as it does not require highly-trained personnel to operate it. Its operating costs as far as gas consumption and energy consumption are moderate.

IIB HOT FILAMENT EACVD

The hot filament process has been modified by some investigators to include a positive or negative bias between the hot filament and the substrate[27] (Fig 4). The process has been named hot-filament EACVD (electron-assisted chemical vapor deposition). The applied bias has been reported to cause changes in the nucleation rate, the growth rate and the crystal quality of the deposited CVD diamond. A general remark that must be made here is that all filament processes have an EACVD character. Consider a filament with a current passing through it. One end of the filament is at ground potential and the other end is at some applied voltage that is needed to drive the current through the filament. If the substrate is at ground potential, then the entire filament is biased with respect to the substrate except for the very end of the filament at ground potential. If EACVD had a large effect on CVD diamond growth, one would see a change in diamond growth along the substrate parallel to the filament. The lack of such reports in the literature imply that EACVD effects are not striking.

Generally, an increase in the nucleation and growth rate of the deposited diamond has been reported if the filament is held at a negative bias with respect to the substrate. Alternatively, if the filament is held at a positive bias with respect to the substrate, the diamond nucleation and growth rate decrease while the diamond crystal quality increases [28,29] In both cases, the bias potential must be kept below the breakdown point of the gases since the formation of a plasma seems to erase these favorable effects. There

has been some confusion in the literature because some researchers heat their filaments with AC and others heat their filaments with DC. Identical filament-substrate biases with AC and DC heated filaments, respectively, can cause very different results on CVD diamond growth. Six separate cases should be documented: 1) AC heating, positive DC bias; 2) AC heating, negative DC bias; 3) DC heating, positive DC bias; 4) DC heating, negative DC bias; 5) AC heating, AC bias; 6) DC heating, AC bias.

The negative effects[28] of plasma formation in hot-filament EACVD is somewhat surprising since the next section will show that plasmas have been effectively used for CVD diamond growth. This contradictory evidence is not uncommon in CVD diamond deposition. Generally, it is not the result of erroneous experiments. Rather there are dozens of independent parameters in an experiment and changing one parameter unavoidably changes other parameters and makes a clear interpretation of the data difficult. As an example, let us list some of the important parameters in a simple process such as hot-filament EACVD: 1). Filament composition; 2). Filament temperature; 3). Filament size and geometry, ie, wire, strip, mesh, etc; 4). Substrate composition; 5). Substrate temperature; 6). Substrate geometry; 7). Filament-to-substrate distance; 8). Gas pressure; 9). Gas temperature; 10) Gas flow rate; 11). Gas flow geometry; 12). Gas temperature gradient above substrate; 13). Gas temperature gradient near filament; 14. Hydrocarbon concentration in gas; 16). Impurity concentration in gas, ie, oxygen, water, nitrogen; 17). Filament-to-Substrate bias: positive, negative, AC; 18). Filament-to-Substrate current; 19) Filament Heating: AC or DC

If an experimenter changes the filament-to-substrate bias, he will also change the gas temperature, the substrate temperature, the temperature gradient in the gas, the filament temperature and the filament-to substrate current. He may then report an increase of growth rate with increasing bias that may be just an increase in growth rate arising from an increase in substrate temperature rather than a new filament-to-substrate bias effect. Banholzer has, in fact, recently carried out a very careful study investigating reports that EACVD increases the CVD diamond growth rate[30]. He finds that there is no such effect when he keeps the filament and substrate temperature constant as he applies a filament-substrate bias. What previous investigators were seeing were effects caused by an increased filament temperature and/or an increased substrate temperature when the EACVD bias was turned on. Banholzer,

however, did see an increased nucleation density of diamond with a negative bias applied to a DC heated filament.

Much of what was said about the cost of a filament system could be repeated here for a hot-filament EACVD system. A hot-filament EACVD system will cost more than a filament system. In most cases, a more costly DC power supply must be substituted for an AC power supply. Also a separate DC bias supply must also be provided. Biasing can decrease filament life by causing unwanted electric arcs or plasma discharges which physically erode the filament. Contamination of the growing diamond film is more of a problem because of the chance of bias sputtering of the filament, reactor wall or substrate material into the diamond film. Finally, the added complication of biasing inevitably reduces the percentage of successful runs.

IIC. PLASMAS

Another popular method to generate atomic hydrogen is with gas plasmas. Plasmas can be formed by many methods. Typically, a gas is ionized by exposure to high temperatures or high electric fields to form a neutral mixture of electrons, negative ions and positive ions. In plasmas exposed to high AC electric fields, hydrogen dissociation occurs by electron impact. Although the dissociation energy of hydrogen is only 4.5 ev, the electron impact dissociation of hydrogen requires electrons with energies above 9.5 ev because of the large mass difference between the electron and a hydrogen molecule (Fig 5). Such hydrogen dissociation by electrons reaches a peak at electron energies of 25 ev. Atomic hydrogen with a very high kinetic energy is consequently produced in plasmas since the difference between the dissociation energy and the electron impact energy must be taken up by the kinetic energy of the atomic hydrogen. This situation contrasts with thermal methods of generating atomic hydrogen where low kinetic energy atomic hydrogen is formed since a direct transfer of thermal energy breaks the hydrogen molecule apart without imparting additional excess energy that would appear as the kinetic energy of the atomic hydrogen product.

The typical charge density in a plasma is very low(Fig 6). Most molecules remain as molecules which are not reactive and do not take part in CVD diamond deposition. About 1% of the molecules in a plasma are converted to neutral radicals that are chemically reactive

molecules with a dangling unsatisfied bond. These radicals are the main component of the gas that is active in CVD deposition. Finally, about 0.01% of the molecules in a plasma are ions. Like radicals, these ions are chemically reactive and can take part in CVD diamond deposition. However, the extremely small concentration of ions indicates that they are not the important depositing species in diamond deposition. Although charged ions have a very low concentration and are not the principal depositing species during CVD deposition, it is possible that they may have some catalytic effects.

Plasmas can be conveniently divided into low-pressure and high pressure plasmas (Fig 5). At low pressures in a gas excited by an alternating electric field, the electrons and molecules are not in thermal equilibrium. Although electrons and molecular ions have the same charge, the mass of the molecular ion is typically 40,000 times that of an electron. Hence, the electron can accelerate rapidly in an alternating electric field and gain energy while the ion is too massive to accelerate quickly and lags behind the electron in energy gain from the alternating electric field. If the mean-free path for collisions between electrons and molecules is large as in a low pressure gas, there will not be a redistribution of energy between the high energy electrons and the slowly moving molecules and they will have different temperatures. As a result, a low-pressure plasma typically has a relatively cool gas temperature. Generation of atomic hydrogen and reactive molecular radicals will be accomplished principally by collisions with high energy electrons. As a consequence of the scarcity of electrons in the plasma and the large mean free path for collision with gas molecules, the absolute concentration of atomic hydrogen and molecular radicals will be low in a low pressure plasma.

In high pressure plasmas on the other hand, the mean free path for collisions between electrons and molecules will be small and any excess energy absorbed by the electrons from the electric field will be quickly redistributed to the more massive molecules by electron-molecule collisions. Hence, the temperature of the gas molecules and electrons will equilibrate at a relatively high temperature. Generation of atomic hydrogen and molecular radicals can now occur as the result of either high-energy molecular or electron collisions in the plasma. Thus, the absolute concentration of atomic hydrogen and molecular radicals will be high in a high-pressure plasma.

Because of the higher concentration of atomic hydrogen and hydrocarbon radicals in a high-pressure plasma, the CVD diamond growth rate will be greater in a high-pressure plasma than in a low-pressure plasma. Such a correlation is observed experimentally where CVD diamond deposition rates in a high-pressure plasma are typically 500 microns/hour whereas the deposition rate in low-pressure plasmas are 0.2 microns/hour.

If the growth rate was the only parameter of interest in diamond deposition, low-pressure plasmas would be ignored. However, high-pressure plasmas have a very high energy content which necessitates elaborate cooling schemes for the substrate to prevent substrate melting. Furthermore, high pressure plasmas tend to be unstable and difficult to control. For many applications, these problems rule out the use of high-pressure plasmas.

IIC1. Low-Pressure Glow Discharge

A common low-pressure plasma method of atomic hydrogen generation is based on the Wood's Tube method[31] where a stream of low-pressure molecular hydrogen is passed through a glow discharge between two metal electrodes (Fig 7). Over a pressure range of 0.1 to 20 torr, up to 25% atomic hydrogen can be generated by this method. The substrate is placed in this glow discharge or one electrode serves as the substrate so that atomic hydrogen is generated close to the substrate surface. Although AC or DC can be used to form the discharge, DC is advantageous if an electrode is used as a substrate since diamond growth rates are higher on the positive electrode. This method has been used to produce very fine-grain CVD diamond films by Crystallume of Palo Alto, California for such applications as diamond windows. Disadvantages of this process include the limited pressure range of operation, the erosion of and contamination from the electrodes and the generally high film stress, the high hydrogen content in the resulting diamond films and the low rate of diamond film growth. Construction costs for a low-pressure glow-discharge system are moderate. However, because of the very low diamond growth rates, the capital costs are relatively high per unit of diamond produced. Labor costs are low as it is a simple stable system that can be run for long periods without operator intervention. Material costs such as gas and electricity are also low.

IIC2. Low-Pressure Microwave Discharge

Low-pressure microwave discharges have been used more than any other method to generate atomic hydrogen for CVD diamond synthesis (Fig. 8) [32-52]. Since microwave discharges are electrodeless, electrode erosion problems are avoided. Microwave discharges are also very stable and provide up to 25% H atoms under typical CVD diamond growth conditions[7]. Moreover, microwave sources are very economical because of the mass production of microwave sources for microwave ovens. During CVD diamond deposition, the plasma must not contact the walls of the reactor since diamond and/or graphite can deposit on the walls. This carbon deposit will couple with the microwaves and heat up causing more deposition and the walls of the reactor (usually quartz) will gradually become opaque to microwaves. Under other operating conditions, the plasma can seriously erode the reactor walls by atomic-hydrogen reduction of the quartz. These problems can be avoided by magnetic confinement of the plasma.

A common magnetic confinement method uses an axial magnetic field in a cylindrical cavity with a microwave window and substrate, respectively, on opposite ends of the cylindrical cavity[32,36,50]. A gradient in the axial field is adjusted so electron-cyclotron-resonance (ECR) conditions exists near the substrate end of the cavity but not near the microwave window (Fig. 9). Circularly polarized microwave electric fields drive free electrons in circular orbits around the axial field lines. Near the substrate, the ECR resonance conditions allow the electrons to receive resonance impulses during each orbit so these electrons acquire a higher energy than electrons elsewhere in the cavity. Thus, the plasma forms preferentially in the region of these high energy electrons adjacent to the substrate. No plasma forms at the microwave window at the opposite end of the cavity where ECR conditions do not exist and electrons do not receive the added boost in energy. Hence, the microwave window is kept free of carbon deposits or erosion. An interesting observation in ECR experiments is that as the chamber pressure is lowered, the substrate temperature for diamond formation tends to decrease[32].

Similar to the work of Aikyo and Kondo for hot filaments[22], Martin and Hill have introduced the hydrocarbon downstream from a microwave plasma hydrogen discharge and successfully grown

diamond[47]. These experiments again demonstrate that the only necessary condition for CVD diamond growth is a source of atomic hydrogen. Much work has been done on the morphology of films grown in microwave discharges under varying conditions[41-43,46,48]. Low substrate temperatures and low hydrocarbon concentrations favor the development of (111) facets on the diamond crystals, indicating that the $\langle 111 \rangle$ direction is the slowest growth direction under these conditions. High substrate temperatures and high hydrocarbon concentrations favor the development of (100) faces showing the $\langle 100 \rangle$ direction as the slow growth direction. At intermediate hydrocarbon concentrations and temperatures, (110) facets will develop.

The lowest temperatures (365-500 °C) for CVD diamond deposition have been reported for microwave plasma deposition techniques[40,51]. Additions of oxygen carrying species such as alcohols, water, etc can increase the diamond film growth rate or lower the pressure necessary for diamond growth[33,40,44,45,49]. Lower gas pressures are particularly important as they allow the plasma to spread and make a more uniform deposit over a wider area[33,50]. The electromagnetic waves used in microwave discharges are launched into the deposition chamber from outside sources. The penetration length of these waves into a low pressure chamber varies inversely with the intrinsic plasma frequency of the gas[53]. The plasma frequency, in turn, is directly proportional to the square root of the gas pressure. Consequently, lowering the gas pressure will result in a greater penetration length and a more uniform discharge. For a pressure of about 10 torr, the penetration length of microwaves in a plasma discharge is only a few centimeters[54].

The quality of diamond produced by the microwave technique can vary widely. If the plasma is in contact with the walls or substrate of the reactor, the diamond film can become contaminated with this material. Because of the exponential decay of microwaves into a plasma, nonuniformities can develop in plasmas larger than the microwave plasma penetration length and the diamond films produced under such a nonuniform plasma will reflect this nonuniformity with the thickness, grain size and quality of a diamond film varying from place to place. The microwave penetration length also puts a limit on the maximum size of a diamond film that can be grown under a microwave discharge. The maximum thickness of a diamond film that can be produced by the

microwave technique is limited by the surprisingly low (in view of the high atomic hydrogen concentration) diamond growth rate of microwave reactors. The construction costs of a microwave system are moderate because of the widespread availability of microwave magnetrons. However, because of the low diamond growth rate with a microwave system, the capital costs per unit of diamond produced is in the higher range of the various CVD techniques. The microwave system has a low energy consumption because most of its energy goes into producing atomic hydrogen rather than heat or radiation. Its operating costs as far as gas consumption are also low. Finally, microwave discharges are easy to use and are very stable and can be run for long periods without much attention. Therefore, labor costs for a microwave system are expected to be low.

IIC2. Remote Low-Pressure Microwave Discharge

One way to avoid the microwave penetration length limit on the size of the microwave reactor is to generate atomic hydrogen by a microwave discharge in a small volume with dimensions less than the microwave penetration length and then to quickly distribute this atomic hydrogen to a much larger-area substrate by convective gas flow. This method requires very high gas velocities on the order of 10,000 cm/sec in order to transfer the atomic hydrogen from its remote source to the substrate before the atomic hydrogen can recombine[55]. As a result, the process uses such a large quantity of gases that the process is uneconomical unless the gases are recirculated. Gases must not only be recirculated but their composition must be constantly adjusted. In addition, it may be necessary to remove some gas products produced in the microwave discharge if they build up in a recirculating system and tend to poison the diamond growth process. Currently, Astec Corp of Woburn, Mass is designing and building a CVD diamond machine of this type complete with a gas recirculating system, all of which should be commercially available in 1992-93 time frame. The advantages of a remote discharge system with its larger area of deposition will have to be balanced against the complications and costs of the required gas recirculating system. Labor costs and energy costs are both expected to be higher than with a simple microwave discharge system. The cost per unit area of diamond films will probably be higher with this reactor but the films will be

more uniform, possibly of higher quality and much larger in area than they could be with a simple microwave system. Consequently, this machine may fill a market need where uniform large-area diamond films are necessary in a particular application.

IIC3. Low-Pressure RF Discharge

There has been much less work[56-62] done with low pressure RF discharges than with microwave discharges for CVD diamond growth (Fig 10). At first glance, this is somewhat surprising as RF is easier to scale to large volume and high power. Moreover, large RF plasma discharge units have been used in the semiconductor industry for some time. The scarcity of reported work in the RF area in CVD diamond growth may be the result of many unreported failures to achieve good quality diamond films rather than the result of not trying RF sources. The deposition rate of CVD diamond is closely correlated with the generation of atomic hydrogen and hydrocarbon radicals. The generation of such radicals seems to be more efficient in a microwave plasma than in an RF plasma. This is probably caused by both the higher energy and higher density of electrons in a microwave plasma. Average electron energies in a microwave plasma at 2450 MHz and 1 torr pressure average about 10 ev [63,64] which is enough energy (8.5ev) to dissociate hydrogen. On the other hand, average electron energies in an RF discharge at 13.56 MHz at 1 torr are about 4 ev [65] which is insufficient to dissociate hydrogen. In addition, electron densities are higher in microwave discharges[66].

Nevertheless, low-pressure electrodeless radiofrequency discharges have also been used to grow CVD diamond [56-62]. Depending on the pressure, atomic hydrogen concentrations of 10 to 65% can be produced in a RF discharge[7]. These discharges are less stable than microwave discharges and Ar sometimes has to be added to the hydrogen-hydrocarbon mixture to stabilize the discharge. Similar to the microwave discharge, deposits of carbon on the walls of the reactor can be a problem with an RF discharge. In addition, the RF can electromagnetically couple with any electrically conductive body in the reactor chamber and heat it. Finally, RF power sources are more expensive than microwave sources per watt of delivered power.

Diamond made by RF discharges has been of poorer quality than diamond made by microwave discharge[56]. In addition, large well faceted diamond crystals are usually not obtained.

RF generators are more expensive and less efficient in generating atomic hydrogen than microwave generators. The quality

of diamond produced by the RF technique has been generally poor. Because of the RF has a much lower frequency than microwaves, the penetration length problem discussed above with microwaves is absent with an RF discharge. Thus, larger areas of diamond could be made with an RF discharge than with a microwave discharge. Attempts to make remote RF discharges (where the atomic hydrogen is generated at one place and transported by gas flow to the substrate) work have been unsuccessful although they were one of the first techniques tried. The maximum thickness of a diamond film that can be produced by an RF discharge is low because of the very low diamond growth rate in RF reactors. The low diamond growth rate puts the capital costs per unit of diamond in the higher range of the various CVD techniques. RF system operating costs as far as gas consumption and energy are relatively low. Finally, labor costs for a RF system not expected to be as low as for a microwave system because the RF discharge is not as stable as a microwave discharge.

IIC4. High-Pressure DC Discharge

High-pressure DC discharges between fixed electrodes at atmospheric pressure have been used to grow CVD diamond from hydrogen-hydrocarbon mixtures at very high rates of up to 200 microns/hour and thickness greater than 1 mm (Fig 11) [67-71]. Because of technology developments over the years to make plasma torches, these DC discharges are now very stable. The substrate is biased positively in all cases. One disadvantage of this process is that the substrate must be directly cooled with running water to prevent it from melting because large amounts of power per unit of substrate area are used. Other disadvantages include the high power consumption, the erosion of the electrodes, the nonuniformity of the discharge and the small deposition area and the need for constant attention because of the large amount of power being used. Because of electrode erosion and the consequential contamination of the diamond film, it is expected that the diamond may not be suitable for applications in electronics. Also, with such high energy processes, overheating and degradation of the diamond film is a constant concern. Finally, all high intensity energy processes tend to be less reproducible from run to run. Because of the high rates of diamond growth, the capital cost per unit of diamond are expected to be moderate. Labor and operating costs for gases and energy will be relatively high.

IIC5. High-Pressure Microwave Discharge Jets

A high-pressure microwave discharge jet has also been used to grow CVD diamond at moderately high rates of 30 microns/hour at atmospheric pressure over a square inch of area[72]. A gas mixture of Ar-H₂-CH₄ is used with a CH₄/H₂ ratio as high as 10%. Sustained operation is difficult because of plasma instabilities and the need to vigorously cool the substrate. The plasma is initially ignited by electric breakdown around the central electrode and then sustained by microwave electromagnetic waves generated between the central electrode and chamber walls. One advantage of low-pressure microwave discharges is that they are electrodeless. However, with high-pressure microwave jets, this advantage has been lost by using electrodes that are immersed in the plasma and that therefore can erode. Operating costs tend to be very high with this process because of the large amounts and types of gases, particularly, argon that are required. Labor costs also are large as skilled personnel must keep a constant watch over the process.

IIC6. High-Pressure RF Discharge

High-pressure radiofrequency discharges have also been used to grow CVD diamond (Fig 12) [73]. These discharges are very unstable and large amounts of Ar are routinely added to the hydrogen-hydrocarbon mixture to increase the stability of the discharge. Nevertheless, the discharge must be monitored continuously and is typically only run for short periods of time. The danger associated with this arc instability has restricted high-pressure RF discharge growth of diamonds to a few scientific laboratories. High rates of diamond deposition are possible during these short runs. As with other high-pressure discharges, the high power input requires that the substrates be cooled directly with running water.

IIC7. High and Low-Pressure Flames

Hydrogen atoms are created during the burning of hydrogen or hydrocarbons in an oxygen flame (Fig 13) [74-76]. With a suitable ratio of carbon, hydrogen and oxygen, Hirose[77] discovered that CVD diamonds can be grown with a simple plumbers torch at atmospheric pressures in the "feather" of the flame just downstream of the flame front [77-86]. High temperatures (2800-3400 C) in common flames

cause a plasma to form and atomic species to be generated at the flame front[87]. The flames are operated under fuel-rich conditions so atomic hydrogen and hydrocarbon radicals are abundant in the feather of the flame where the substrate is placed. Growth rates of 30 microns/hr are attained.

Hydrogen atoms can also be generated in low-pressure hydrogen and hydrocarbon flames.[75,76] Advantages of low-pressure flames may be a higher carbon-to-diamond conversion rate, a wider spatial zone in the flame where diamond will grow and a much lower heat input to the substrate. Although work is underway at several laboratories, no successful CVD diamond growth has been reported yet in a low-pressure flame.

So far, work has been limited to hydrogen-hydrocarbon-oxygen flames. Flames with other chemical reactants may also generate CVD diamond growth. For example, hydrogen-hydrocarbon-fluorine, hydrogen-hydrocarbon-chlorine, hydrocarbon-fluorine, hydrocarbon-chlorine, halocarbon-fluorine and halocarbon-chlorine flames are promising candidates among many possibilities.

The capital cost of a flame system, particularly at atmospheric pressure, are very low. Its simplicity would also allow low labor costs. Furthermore, diamond is produced at high rates. However, deposition is only successful over a relatively small area. The restriction in area is a result of the structure of the flame. There is only a limited zone in the flame where conditions are favorable for diamond formation. Outside of this zone, diamond either will not be formed or will burn in the flame. These restrictions combined with the gas flow required to flow around the substrate produces an uneven and inhomogeneous diamond deposit on the substrate unless the substrate is very small in area. Scanning the flame may help but it also may smear out the problem and produce diamond of a uniformly poor quality. The high energy intensity of the flame method requires vigorous cooling of the substrate. The principal problem with the flame technique is its very low conversion rates of carbon to diamond (of the order of 0.01%). The very low conversion rate is not surprising as most of the carbon must be burned in the flame to produce the high temperatures necessary to generate a plasma and atomic hydrogen. At these low carbon-to-diamond conversion rates, the flame technique is the most expensive way to make diamond of the popular CVD diamond methods because of gas costs. If these low conversion rates can not be increased, the torch

method will only be economical in producing gem stones for the jewelry trade.

III OTHER LOW-PRESSURE DIAMOND PROCESSES

IIIA COMBINATION PROCESSES

Some investigators have used combinations of processes to see if any advantages would ensue. For example, a direct-current spiral hollow cathode combines features of the hot filament, electron beam and plasma process. Such a hollow cathode was used to grow CVD diamond in an Ar-H₂-CH₄ gas at a disappointing rate of one micron/hour[19,88,89]. The results of these experiments indicate that this particular combination of processes has no technical or economic advantage over a simple hot filament process.

IIIB THERMAL PROCESSES-SUBSTRATE ONLY

The thermal activated[90-92] growth of CVD diamond in various halogen-hydrocarbon or fluorochlorohydrocarbon-hydrogen-helium mixtures without the assistance of any external excitation such as a plasma or hot filament has been reported. In one case[92], only heating of the diamond substrate was required. In the other case[91,92], the gases at atmospheric pressure were preheated in a furnace tube at about 800-900 C and passed over a substrate at a temperature between 250-750 C (Fig 14). Diamond formed on the substrate at rates of 0.5-2 microns/hour.

Although halogens such as fluorine can stabilize the diamond surface in the same way that hydrogen does, the carbon-fluorine bond (108 kcal/mol) is much stronger than the fluorine-fluorine bond (38 kcal/mol). Thus, molecular or atomic fluorine can not produce vacant sites on a diamond surface covered with fluorine in the same manner[93,94] that atomic hydrogen produces vacant sites on a diamond surface covered with hydrogen. Without vacant sites, carbon deposition would cease. However, all of the gas mixtures used successfully contain hydrogen whose bond strength with fluorine (136 kcal/mol) exceeds the carbon-fluorine bond strength (108 kcal/mol). Thus atomic hydrogen can react with a monolayer of fluorine on the surface of diamond to form HF, thereby forming the vacant sites needed for additional carbon deposition and diamond

growth. This is an exothermic reaction with an energy release 28 kcal/mol and there would be no shortage of vacant sites. Starting from molecular hydrogen with a bond strength of 104 kcal/mol, a net expenditure of 24 kcal/mol must be spent to produce a mole of vacant surface sites on a surface of diamond covered with fluorine. Generation of vacant sites by molecular hydrogen would give a relatively low concentration of vacant sites but they may be sufficient to allow diamond growth if the kinetics of vacant site formation were rapid, ie as vacant sites were filled, new ones would form rapidly to maintain their equilibrium concentration.

There are potentially many chemical systems like the halogen based one discussed above that may produce diamond.[90,93,94]. Generally, one looks for a reaction scheme where carbon can be deposited in a series of exothermic reactions in the presence of chemical species that can form a single sp^3 bond to the diamond surface. The exothermic chemistry drives the reaction while the sp^3 bonding species stabilizes the diamond surface and prevents its reconstruction to a graphite-like surface.

There may also be reactions that are not quite exothermic but require a slight boost from an external energy source. Recently, Rudder and his coworkers at RTI have recently reported making diamond from a mixture of alcohol:acetic acid: water mixture of 20:20:60 in the presence of a graphite body. This gas mixture was subjected to RF excitation at a power level of 1/8 that required in conventional RF methane:hydrogen CVD system.[95]. Diamond was deposited on a silicon substrate at 300 Centigrade.

Most of capital costs of a thermally-activated process would be very modest, particularly for the systems[90] running at atmospheric pressure. For a fluorine-based system as discussed above, the reactivity of fluorine would require monel piping and tubing for the apparatus. For the other halogens, quartz or vicor would suffice. Expensive gas cabinets and safety systems are also be required with any system using the elemental halogens. In addition, because of environmental concerns about the ozone layer, the exhaust from this system could not be vented directly to the atmosphere as is now done for hydrogen-hydrocarbon systems but would have to be inactivated. Labor costs would be very low for a thermally activated

process as it is simple and does not require much attention once it is running. Energy costs would be the lowest of any current CVD diamond process. Depending on the halogen or fluorochlorohydrocarbon chosen, gas costs would range from low to high. Some fluorochlorohydrocarbons are expensive with prices ranging from \$10 to \$130 per kilogram. Halogens are even more expensive with fluorine costing almost \$1000 per kilogram. However, the more common dichlorodifluoromethane with which some of the best experimental results were obtained[90] sells for only \$2 per kilogram. These prices compare with hydrogen at less than \$1 per kilogram and methane from a natural gas tap. With current synthetic diamond prices of a few dollars/carat or \$10,000/kilogram, the conversion efficiency of nutrient gas to diamond could be very small before high gas costs would be a problem.

IIIC LASER EXCITATION

There have been some reports[96,97] of the deposition of CVD diamond using laser excitation. One of these reports was later withdrawn[97]. More recently, a group in India has been reported that diamond was made by subjecting an organic fluid to a laser pulse. Also, diamond has been made by directing a laser pulse onto a graphite layer on a copper slab[98]. Although these reports have generated wide-spread scientific interest, laser excitation does not seem to be a technologically viable method of diamond growth. Economically, lasers would be a poor choice for diamond production because of their high capital cost, their low rate of conversion of electrical power to laser light (typically, 3-10%) and low efficiency in converting nutrient carbon to diamond.

IID. ALTERNATING CHEMICAL REACTIONS

Recently, reports have circulated that diamond can be grown layer by layer by alternating exposures of diamond to different gases. No details are available about these experiments. However, the type of paired reactions that should work are shown in Equations 6 and Figs 15a and 15b for CF_4 and CH_4 :



where Diamond-F and Diamond-H represent, respectively, diamond covered with a monolayer of fluorine and hydrogen. This idea is an extension of the alternating reaction work of Eversole[5] shown in Equations 1 and 2. This reaction works because the bond strength of H-F exceeds the bond strengths of C-F and C-H. Both reactions are exothermic with an enthalpy of reaction of about 8 kcal/mole.

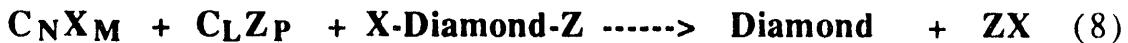
One can generalize this type of reaction in a number of ways. One way is to use compounds of the type C_NX_M and C_LZ_P :



where Diamond-Z and Diamond-X represent, respectively, diamond covered with a monolayer of Z and X. If the Z-X bond is stronger than the C-X and C-Z bonds, then alternate exposures of diamond to the respective gases will cause alternate exothermic chemical reactions where carbon is placed down during each exposure. These types of reactions inherently prevent the generation of double or sp^2 carbon bonds and thus stop graphite formation. Examples of gases that can be used in such reactions pairs are all of the fluorochlorocarbons, fluorochlorohydrocarbons, alcohols, halogens and hydrogen.

If C_NX_M and C_LZ_P do not react in the gas phase, then a gas mixture of them can be used to grow diamond instead of the alternating exposure of one and then the other depicted in Reactions

7. In this latter case, the reactions still alternate between (a) and (b) on a microscale but not on a macroscopic scale:



where X-Diamond-Z is diamond covered with a monolayer of a mixture of X and Z. A process like this may be what is actually taking place in the thermally activated diamond deposition experiments discussed above[90-92].

III.E. DEPOSITION FROM LIQUID SALT BATHS

Patel and Cherian [99,100] reported evidence of diamond growth on a diamond crystal that was placed in a small amount of liquid sodium hydroxide contained in a nickel crucible at 600 C. When the NaOH which is volatile and unstable at this temperature evaporated[101], a small deposit less than 1/2 micron thick was left on portions of the diamond crystals. Independent analysis of this deposit has not disproven that the deposit is ~~not~~ diamond[101]. All of the test that can be performed with such a small volume of material are consistent with the deposition of very thin and small particles of diamond. If this experiment is valid, we can speculate as to why it may have worked by using a NaOH bath as an example. There is an analogy between conventional CVD diamond growth from an acetyline-hydrogen gas mixture in the presence of atomic hydrogen and diamond growth from a NaOH salt bath containing sodium acetylide. Atomic hydrogen, sodium and hydroxyl form single bonds with carbon and prevent the formation of carbon double bonds which might lead to graphite growth. The stabilization of the diamond surface by atomic hydrogen is analogous to the stabilization by either sodium or hydroxyl ion in a liquid salt solution. The main difference between the two cases is that the bonding with diamond is predominantly covalent in the case of hydrogen and predominantly ionic in the case of sodium and hydroxyl ions. A simple extension of this method of diamond growth would involve a temperature gradient in a molten alkali salt bath containing graphite and a diamond seed. Alternatively, the graphite could be replaced with an alkali acetylide.

The amount of diamond produced by this process was extremely small and at present is not economically viable. Until the

process is modified and improved, it will remain a scientific curiosity somewhat like the early work of Eversole with CVD diamond.

IIIF. DEPOSITION FROM LIQUID METAL SOLUTIONS

Over the years, a number of patents have been issued claiming to have grown diamond from a liquid metal solution at low pressures. Many of these patents stemmed from the success of using metal catalysts in high-pressure, high-temperature diamond synthesis. Some of these patents are undoubtedly "paper" patents which were never really tried but which sounded logical and reasonable to a patent examiner. The success of using atomic hydrogen to stabilize diamond, however, reintroduces the question of whether a liquid metal bath can be used to grow diamond at low pressures. Diamond in a liquid metal bath may have its surface stabilized by metal atoms reacting with the diamond to form a carbide monolayer. If a metal with a metal-carbide bond energy equal to the hydrogen-carbon bond energy were used, one can argue that a low-pressure liquid-metal processes analogous to conventional CVD diamond deposition should be possible.

IV SUMMARY

Many innovative means of making diamond at low pressures have been developed in recent years. A number of these methods are only of scientific interest at the present time because of their high costs or impracticality. Even after these processes are eliminated from consideration, there remains a number of processes that are currently being used to make diamonds and which appear to be economically viable. Some applications are most easily addressed by a particular process and this is the reason for the choice of the process in such cases. In other cases, the previous background and experience of an individual or group of workers has dictated what diamond process was selected. People with no applicable experience have tended to select the filament process because of its simplicity or the microwave process because commercial equipment was available for purchase. After gaining experience with these techniques, they have graduated to other techniques which they find more suitable for their particular uses and applications. Currently, there are over 30 companies in the world actively pursuing CVD diamond research and trying to develop a diamond business from their research. Many

different methods of diamond making are being used by these companies which will be eventually sorted out by the marketplace. Currently, the advantages, disadvantages and economics of these various processes are closely guarded proprietary secrets. The determination of the "best" CVD diamond process, if one really exists, is not possible at this time from information available in the literature. Much more process research and development must be done before this determination will be possible.

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Figure 10. RF Low-Pressure Discharge Method of Making CVD Diamond.

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Figure 12. High-Pressure RF Discharge Method of Making CVD Diamond.

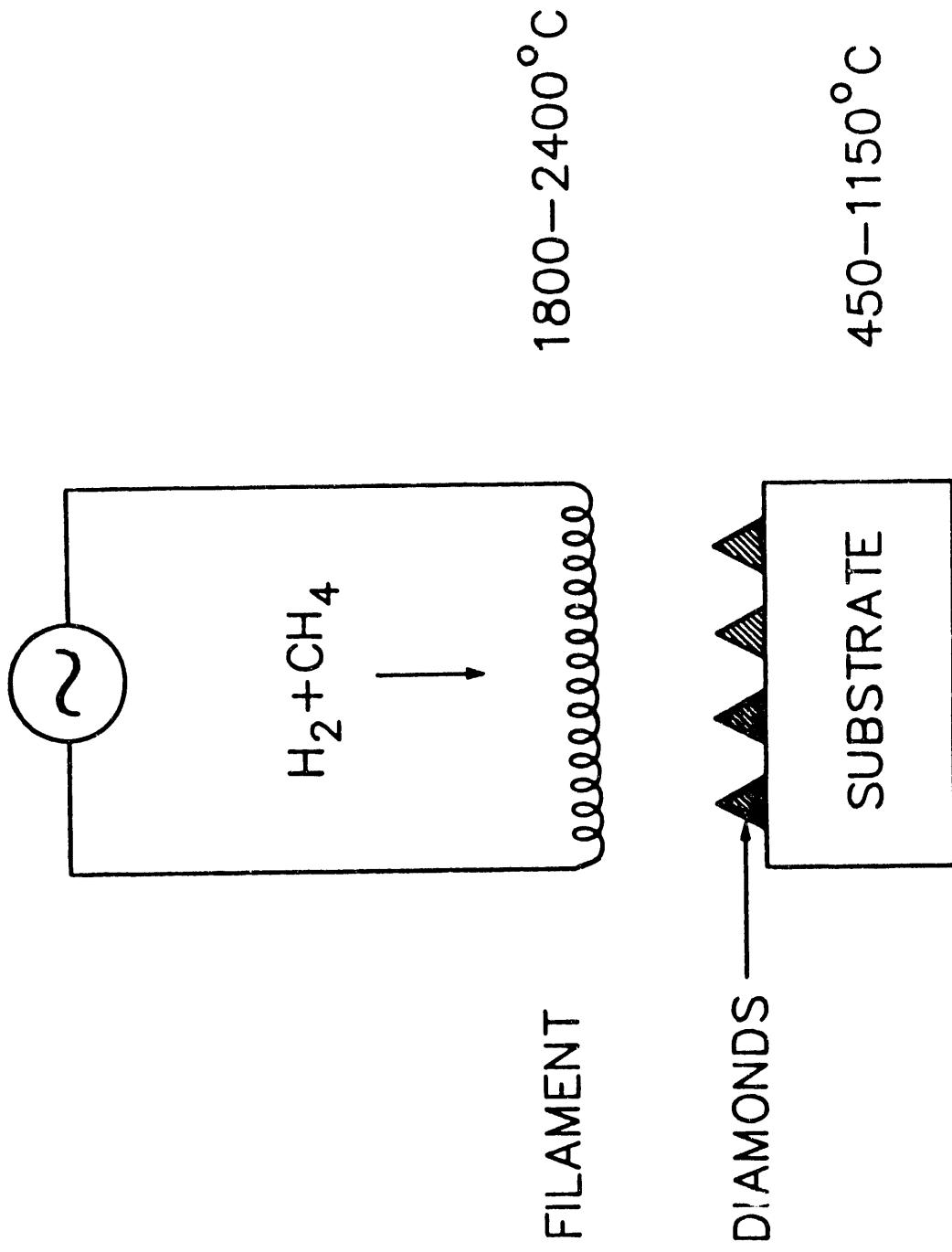
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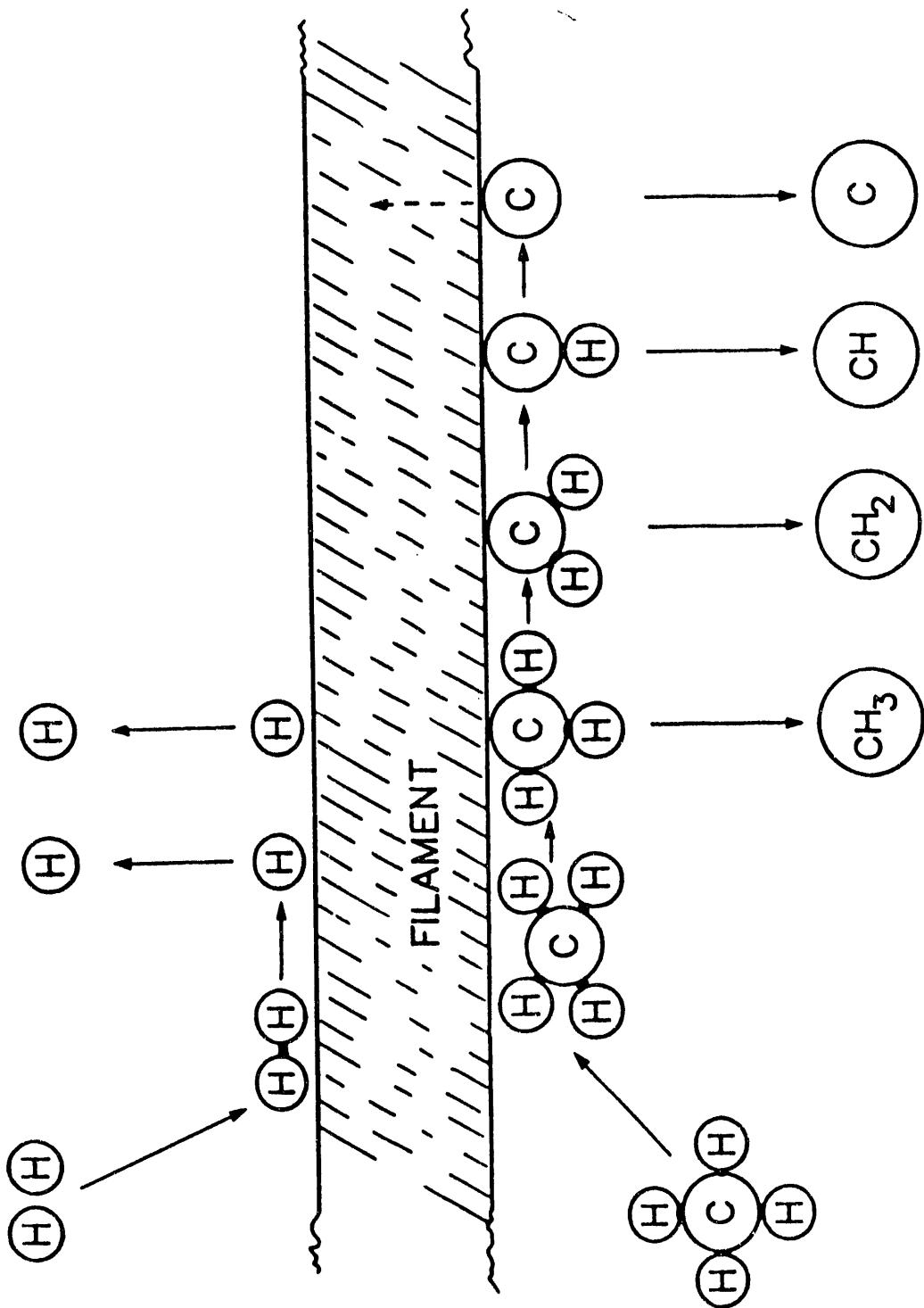
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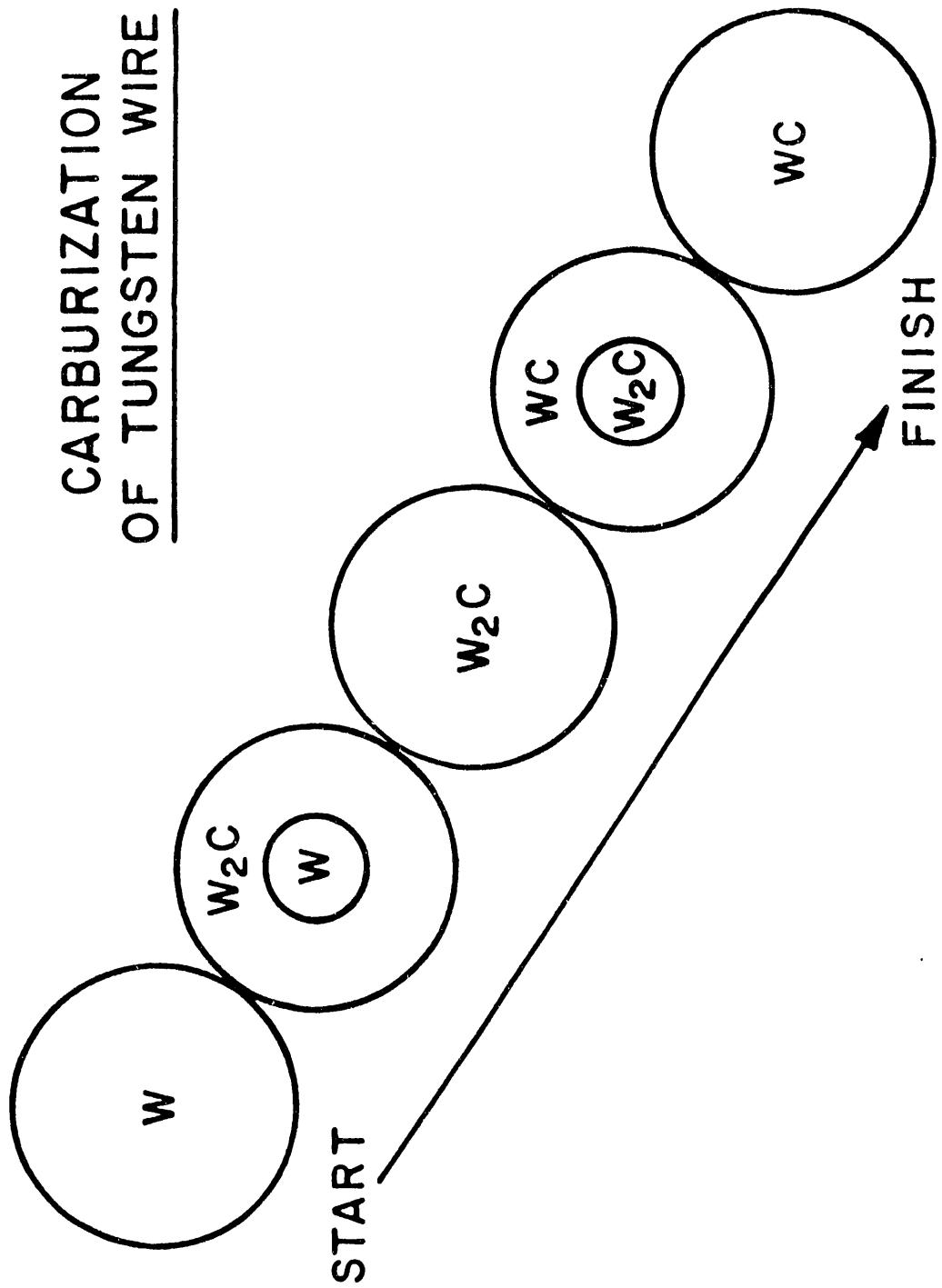
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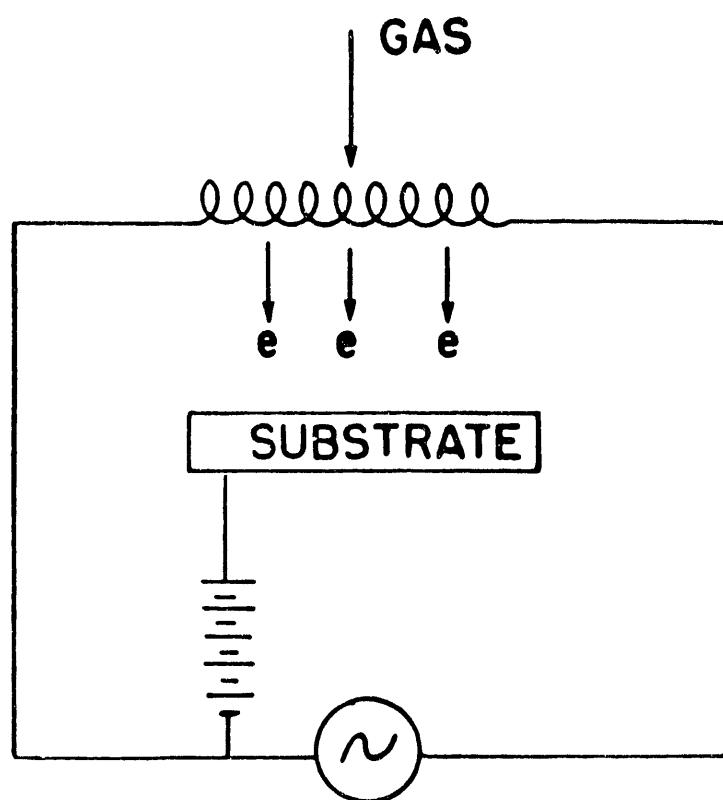
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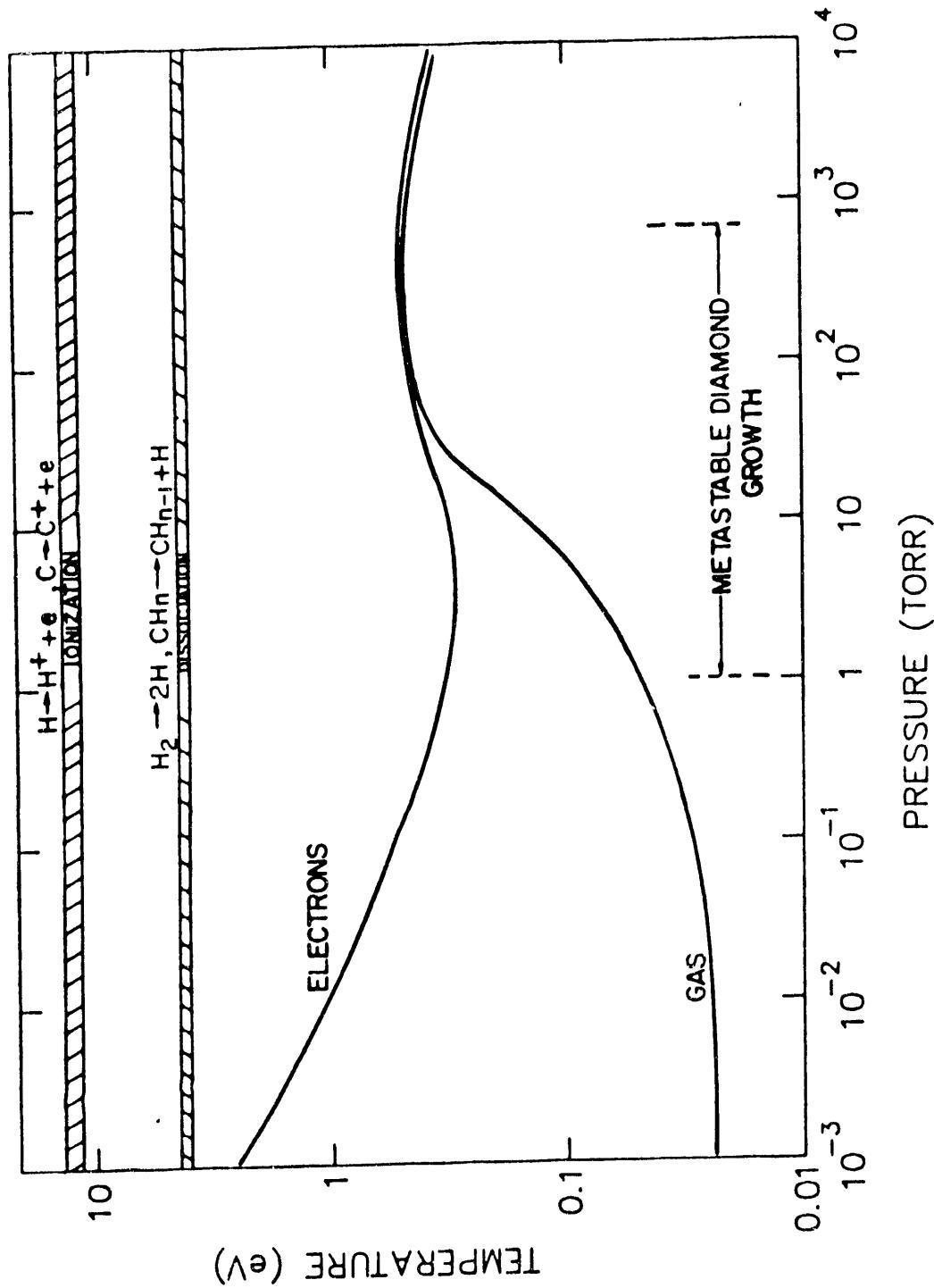
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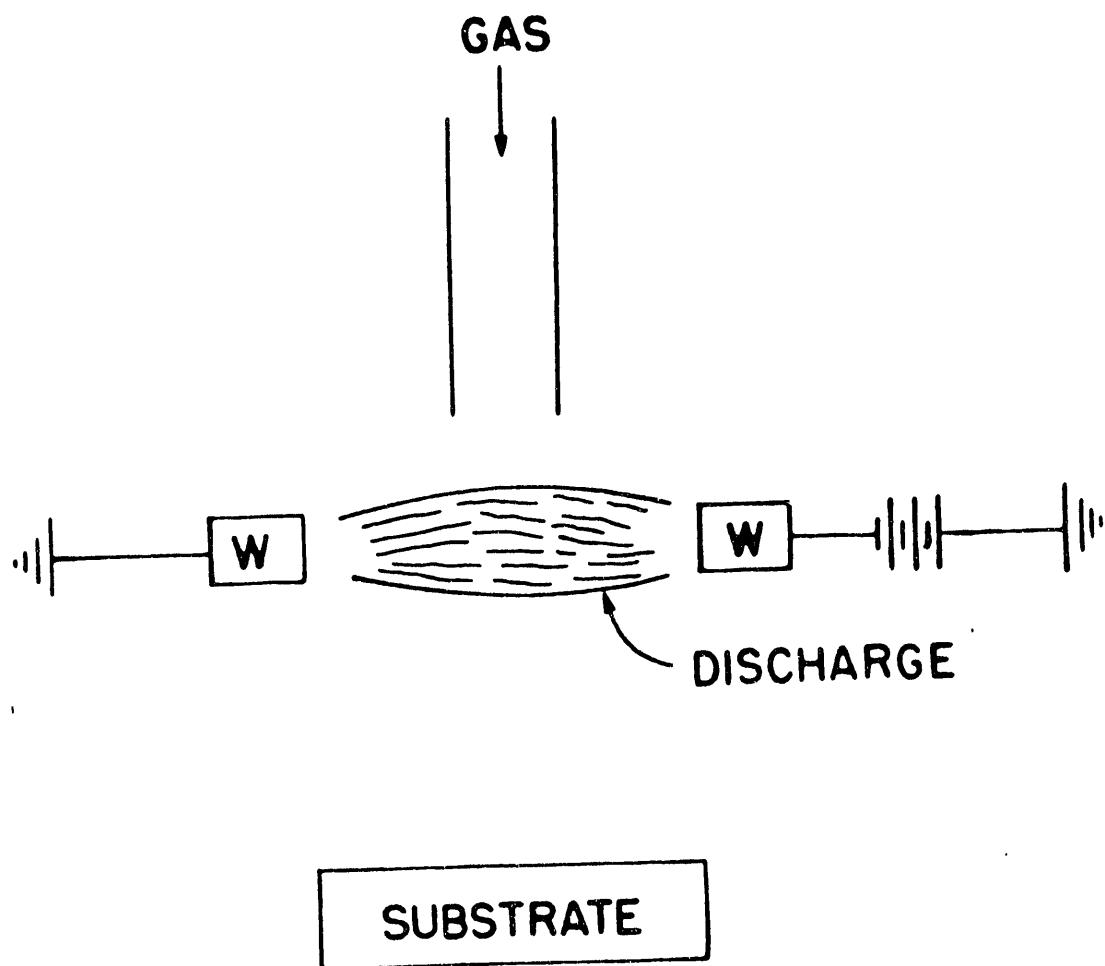
ELECTRON AND GAS TEMPERATURE VS PRESSURE IN A PLASMA



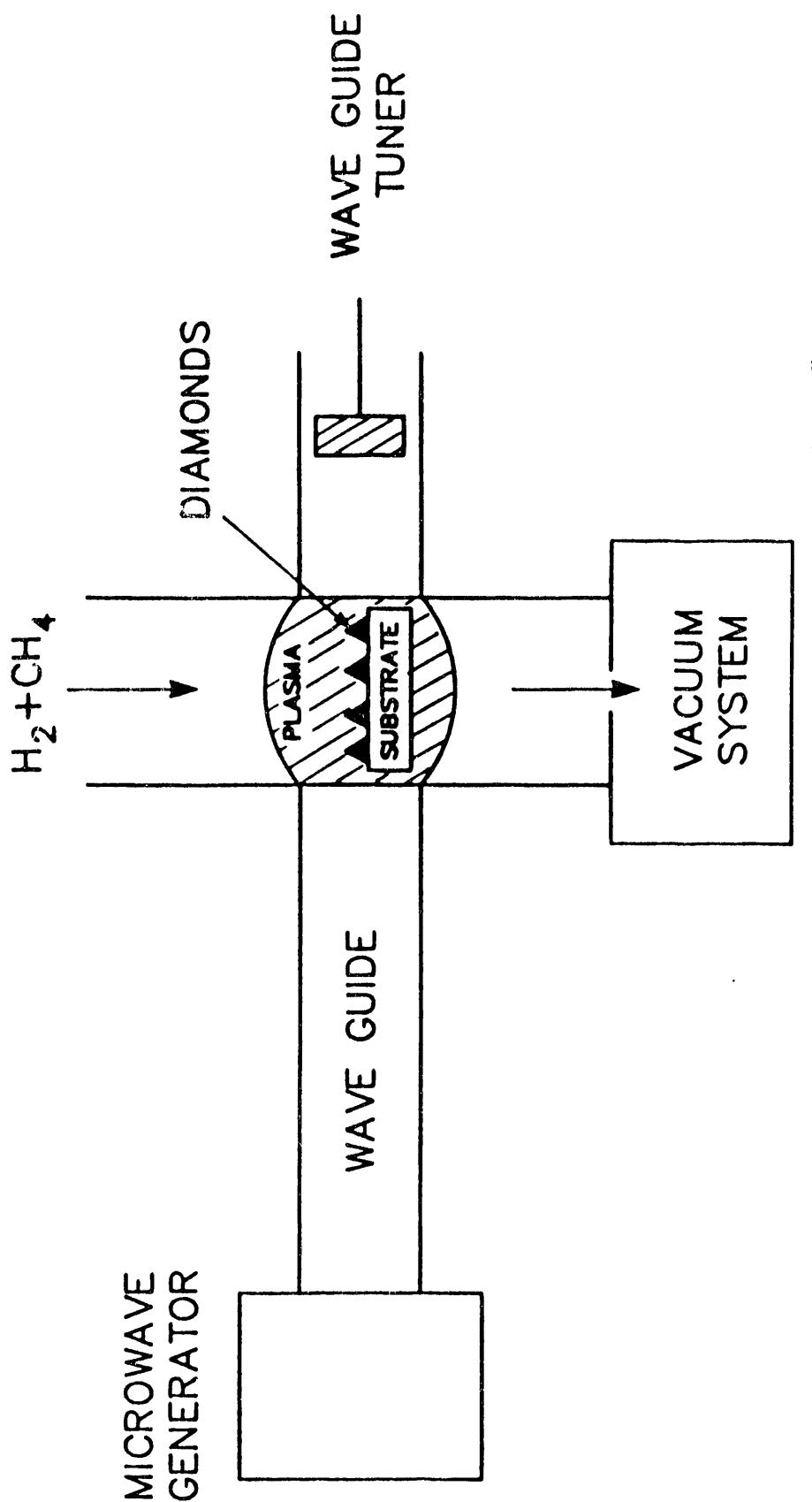
PLASMA COMPOSITION

SPECIES	RELATIVE CONCENTRATION	CONDENSABLE
MOLECULES (H_2, CH_4)	10,000	NO
NEUTRAL RADICALS ($\text{H}, \text{CH}_3, \text{CH}_2, \text{CH}, \dots$)	100	YES
IONS ($\text{H}_2^+, \text{CH}_4^+, \text{H}^+, \dots$)	1	YES

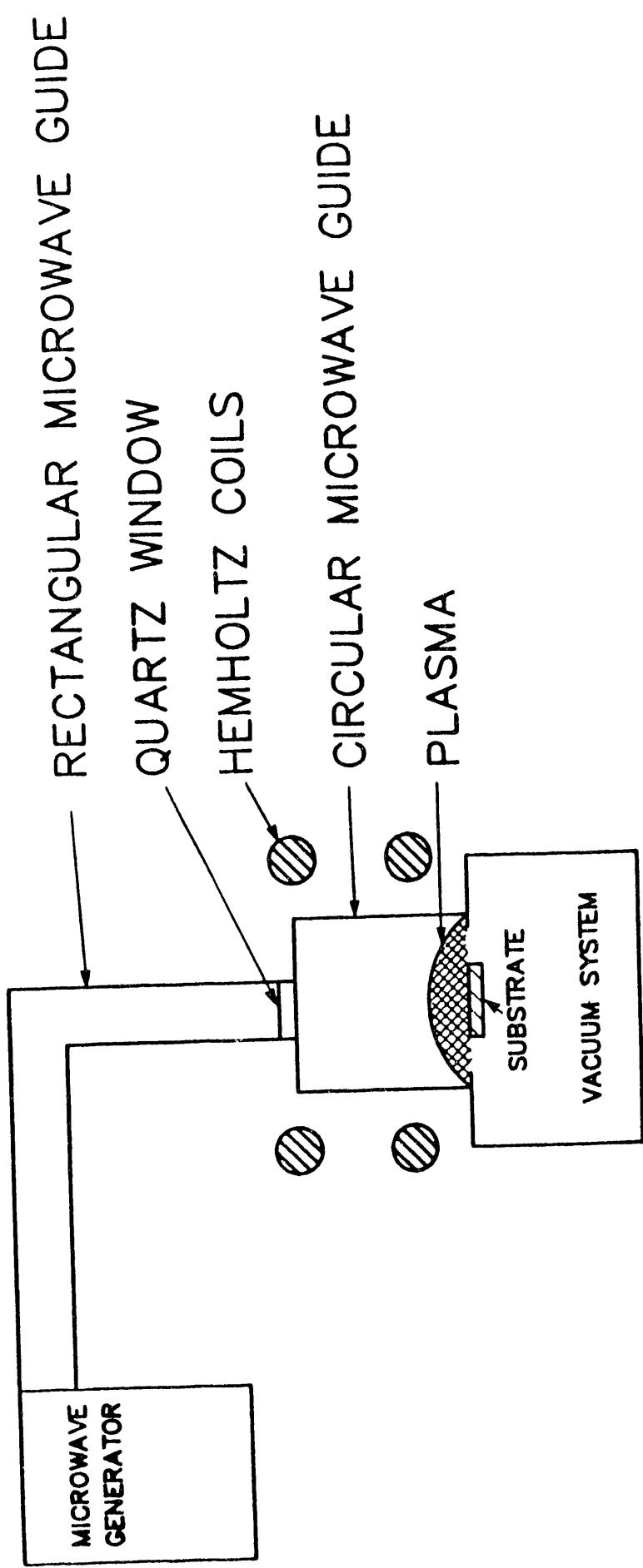
ARC DISCHARGE



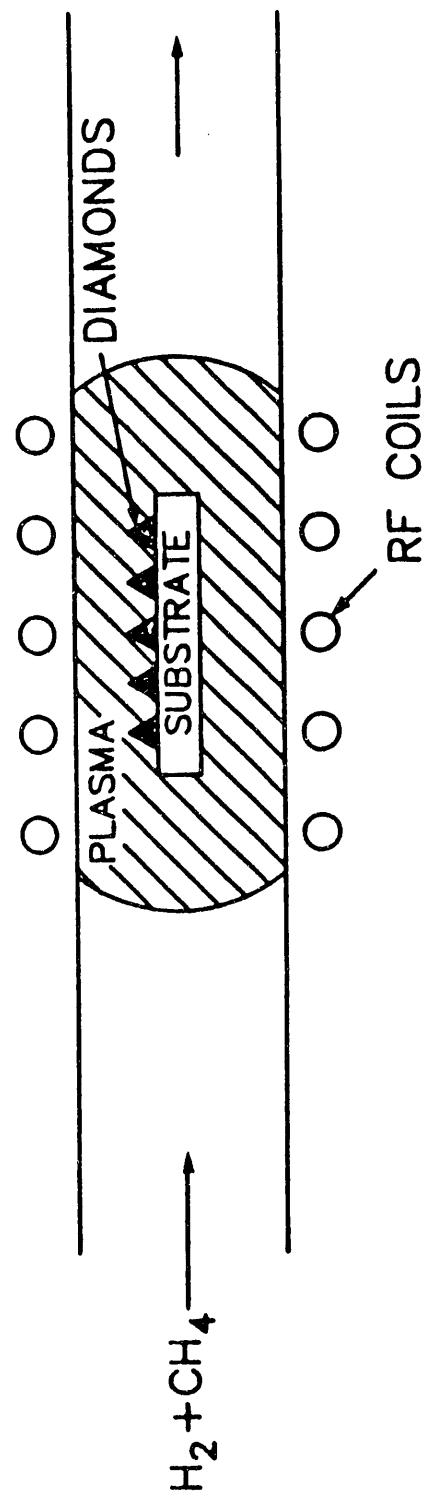
MICROWAVE-ASSISTED DIAMOND CVD



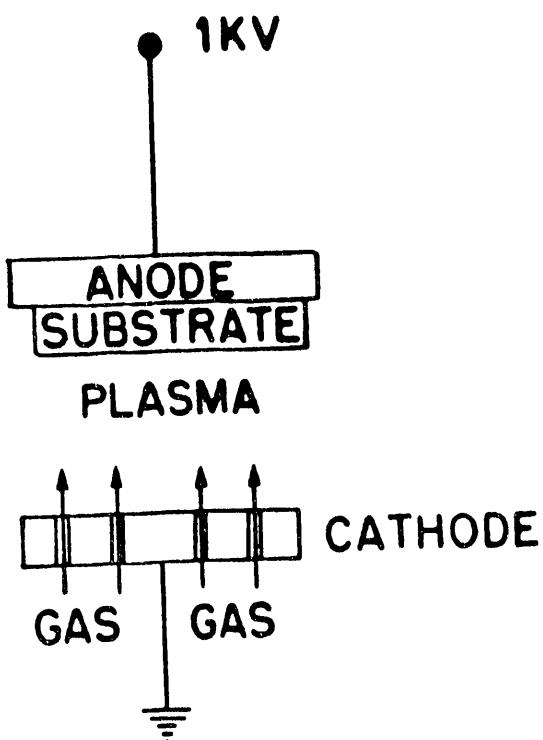
ECR PCVD DIAMOND GROWTH



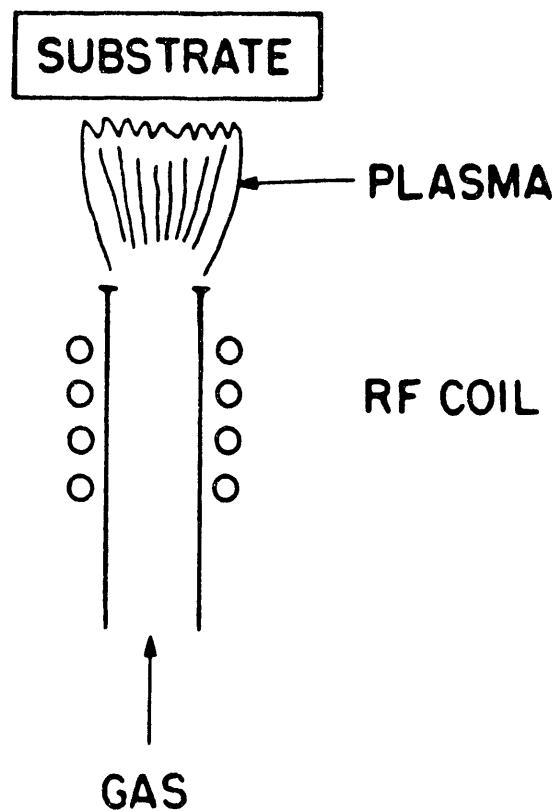
RF - ASSISTED DIAMOND CVD



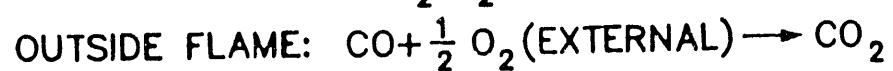
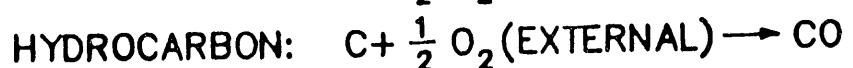
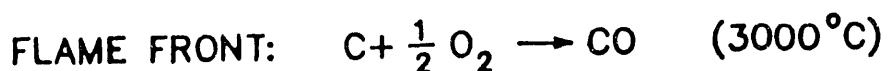
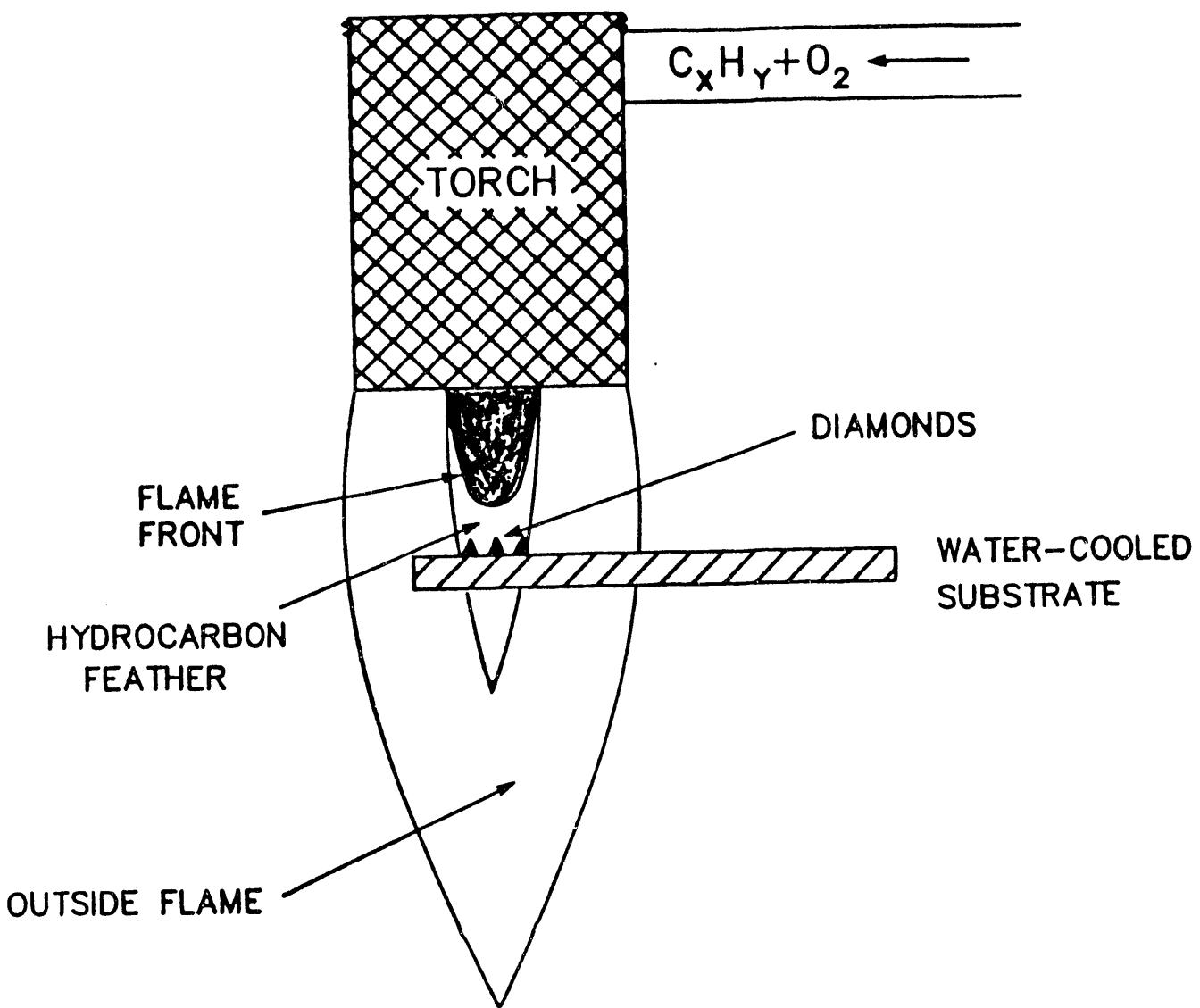
DC PLASMA CVD



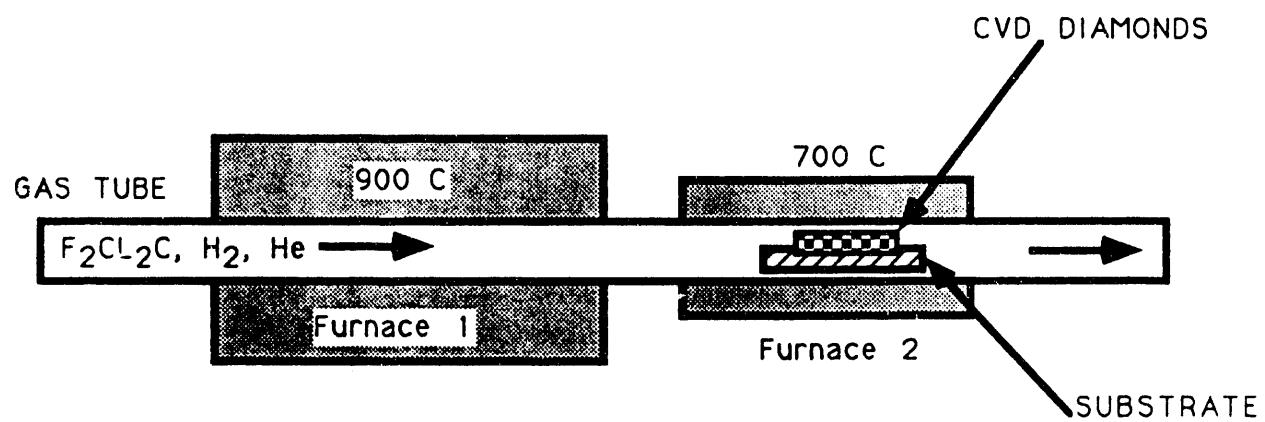
RF THERMAL PLASMA



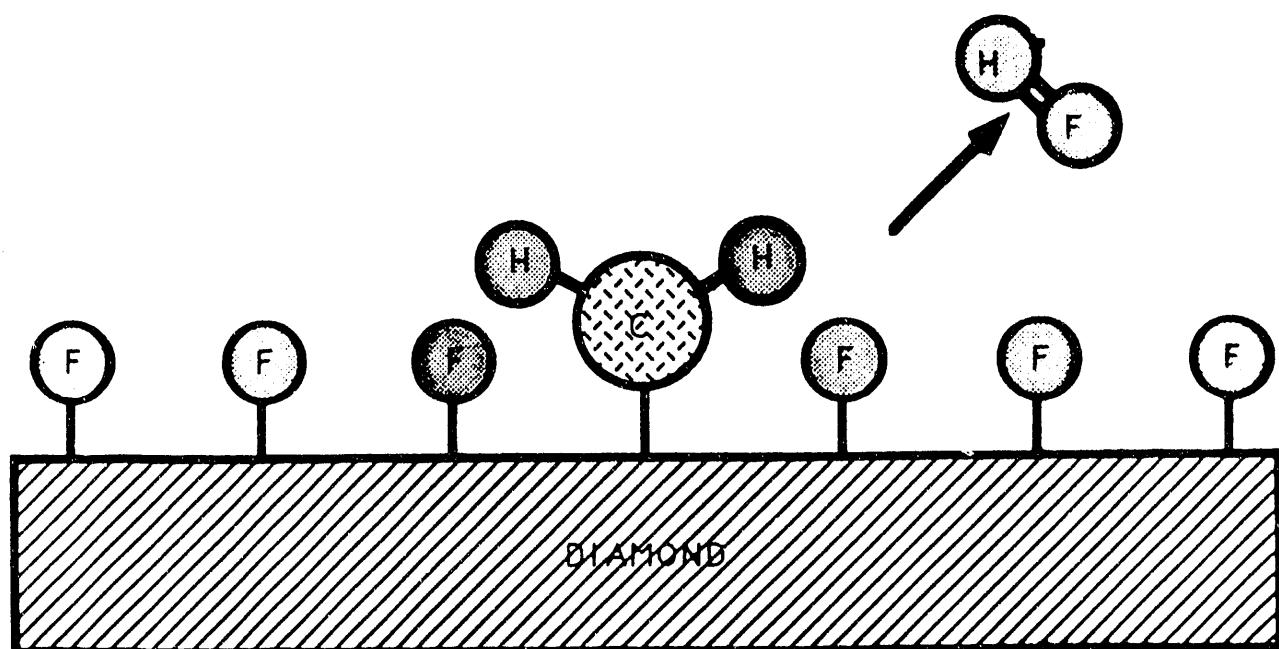
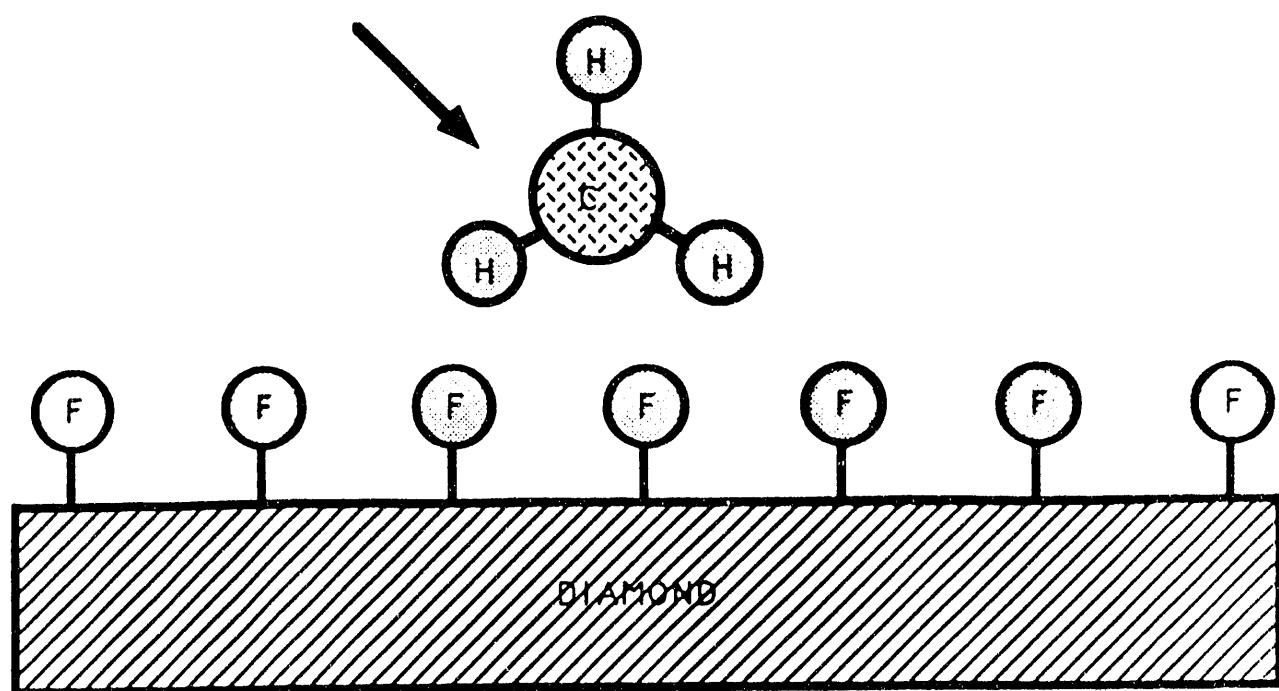
FLAME DIAMONDS



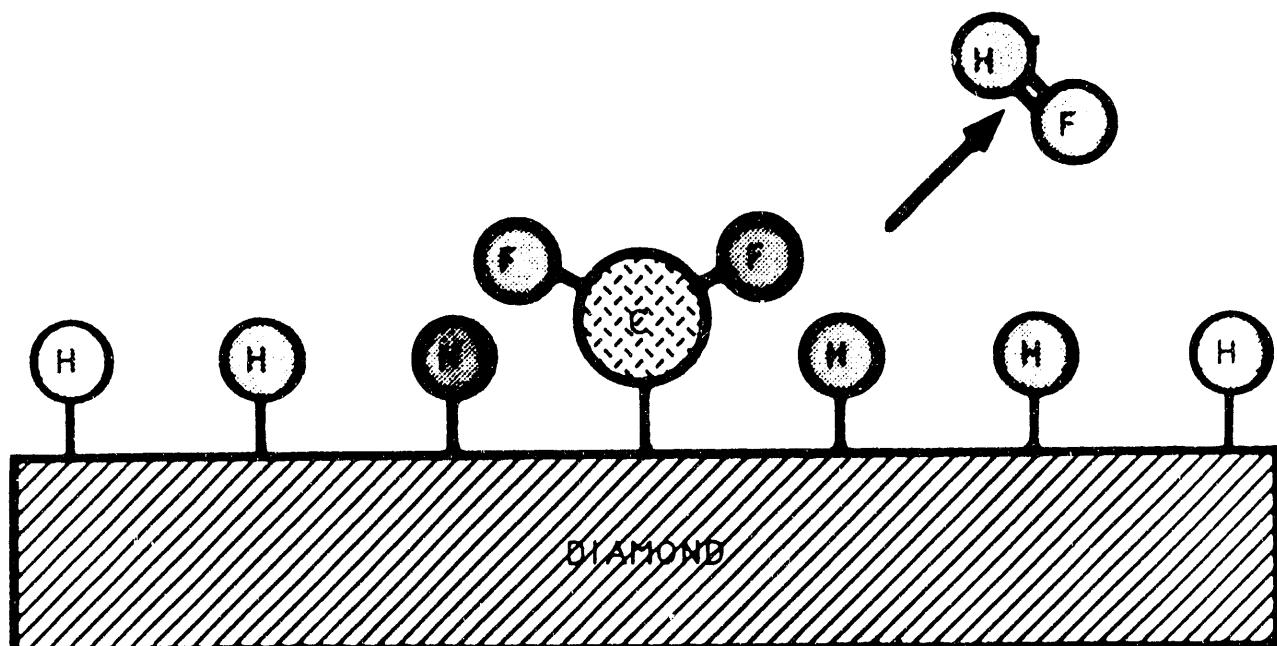
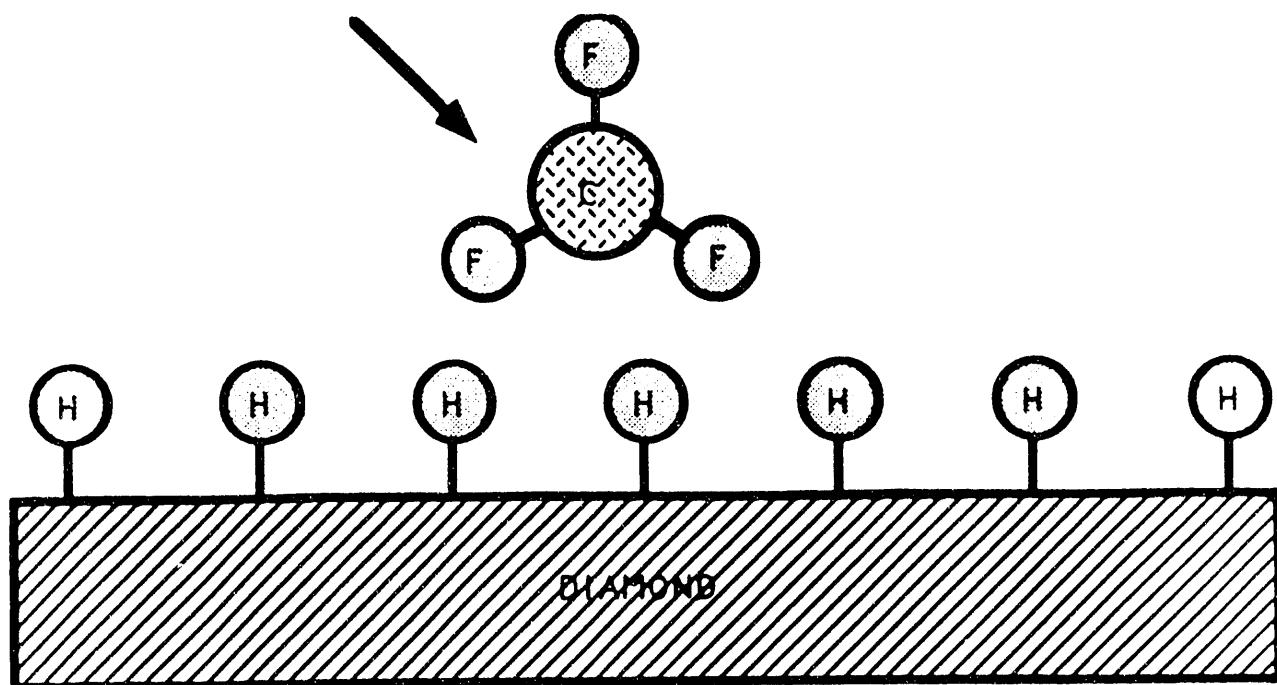
HALOGEN-ASSISTED THERMAL GROWTH OF CVD DIAMOND



ATMOSPHERIC PRESSURE



ALTERNATING REACTION ONE DURING DIAMOND GROWTH



ALTERNATING REACTION TWO DURING DIAMOND GROWTH

Ion-Beam Technologies

by

George R. Fenske

**Materials and Components
Technology Division**

Argonne National Laboratory

Presented at the DOE Tribology Program Workshop on
Diamond and Diamond-Like-Carbon Films, Argonne
National Laboratory, Argonne, IL, Feb. 4-5, 1992

Diamond/DLC Films

Why?

- High hardness
- High thermal conductivity
- Low thermal expansion coefficient
- Chemical stability (<500–1300°C)
- Low friction coefficient

Outline

- Review/description of deposition processes
 - CVD
 - PVD
 - IBD/IAD
- Properties of IBD/IAD
- Tribological performance of IBD/IAD Coatings
- Issues

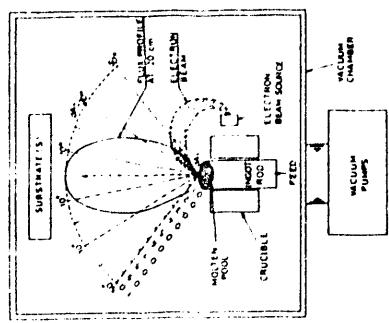
Deposition Techniques

- CVD (e.g., HFCVD, PACVD, etc.)
- PVD (plasma sputtering, ion beam sputtering, evaporation, etc.)
- IBD (low-energy ion implantation)
- Hybrid processes (biased sputtering, IBAD, biased HFCVD, etc.)

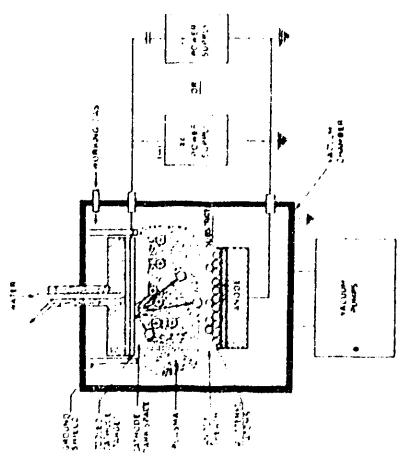
PVD Deposition Processes

- Evaporation (e.g., electron beam evaporation)
- Cathodic arc discharge
- Sputtering
- Ion beam sputtering
- Laser evaporation

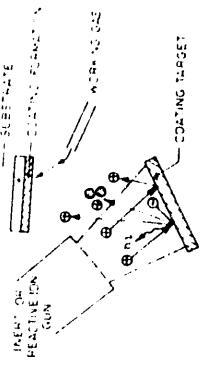
Electron Beam Evaporation



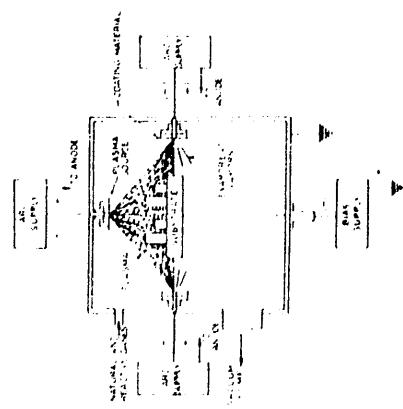
Plasma Sputtering



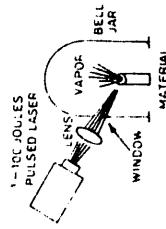
Ion-Beam Sputtering

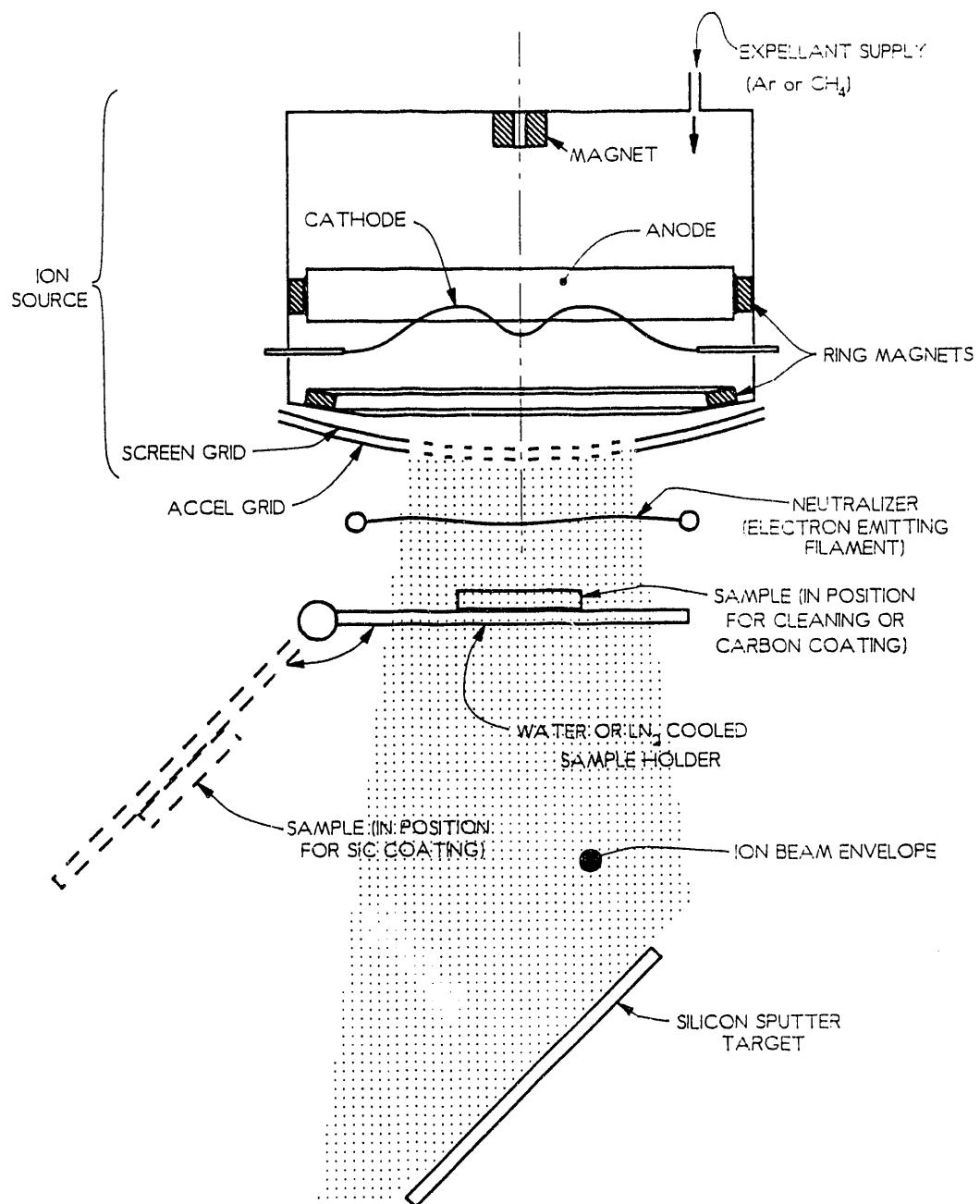


Cathodic Arc Deposition



Laser Evaporation



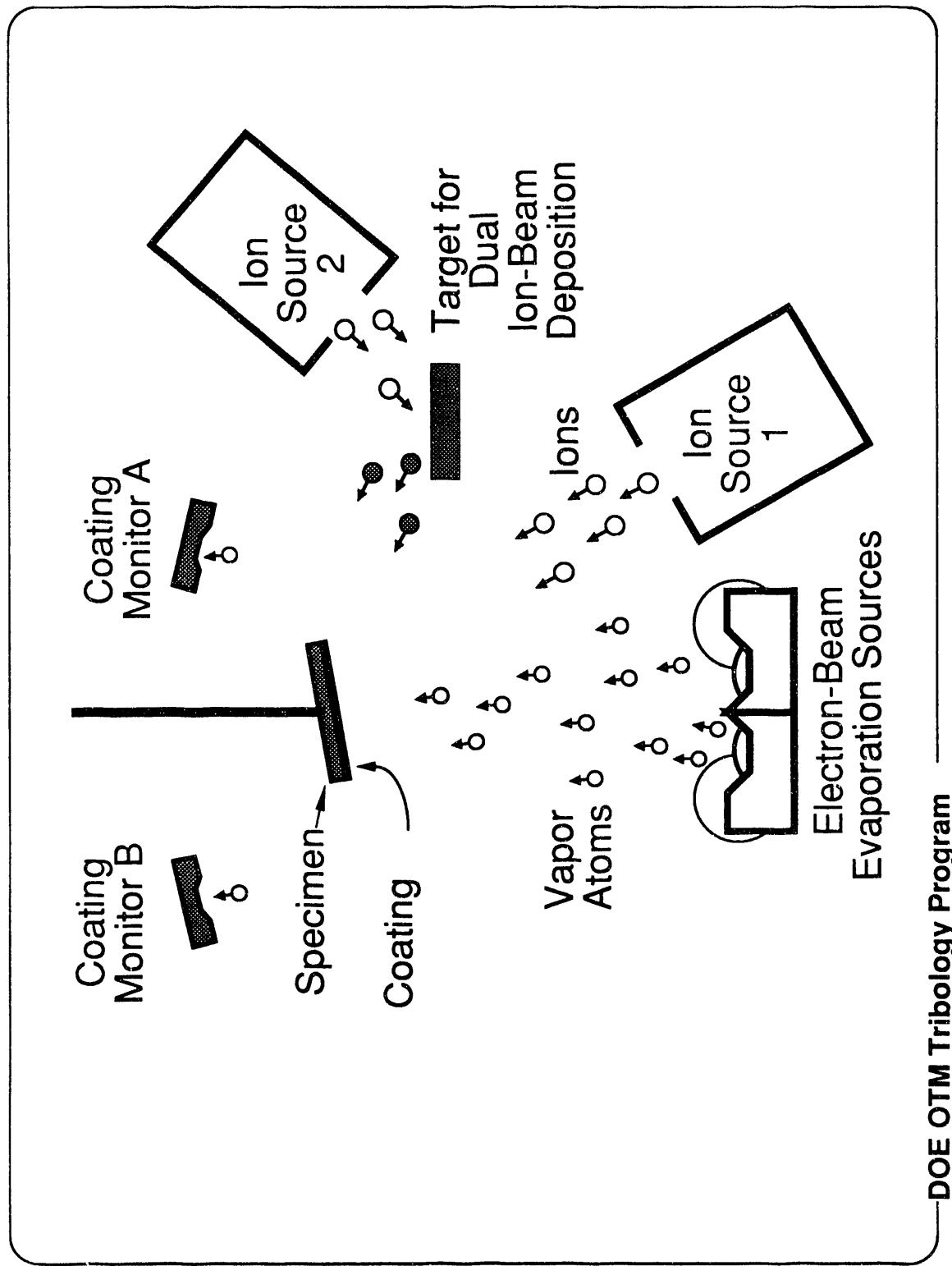


Paul Wilbur:
Colorado State University

DOE OTM Tribology Program

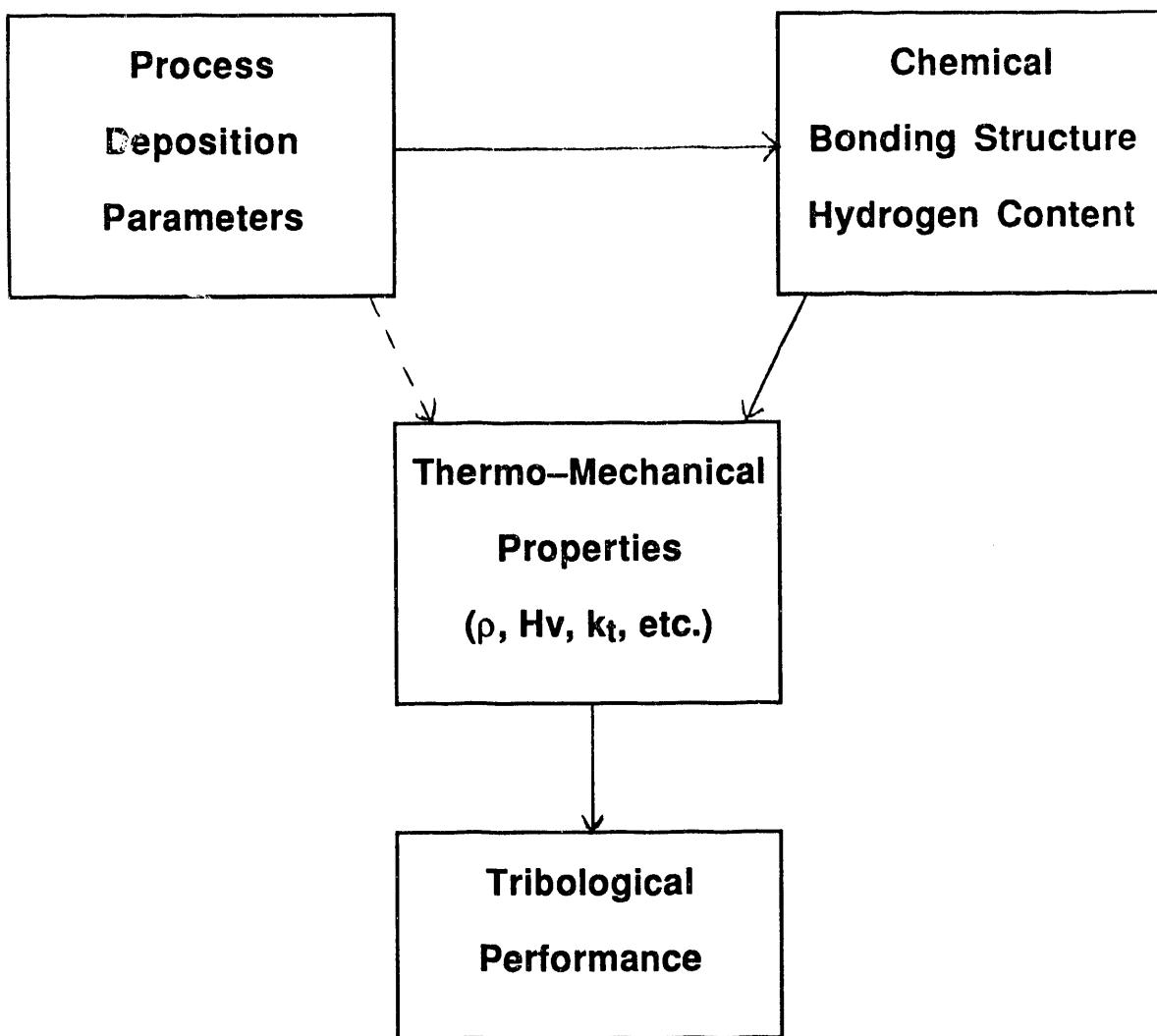
Hybrid Process

- Simultaneous
 - Ion Beam Assisted Deposition
 - e-beam evaporation
 - ion-beam sputtering
 - Biased Sputtering
 - Biased PECVD (Chang)
 - Ion Plating (hollow cathode, laser)
- Sequential
 - Laser/HFCVD
 - IBS/IBD

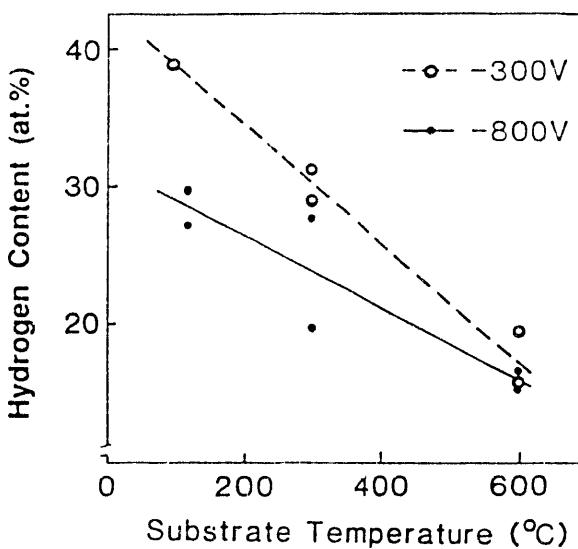
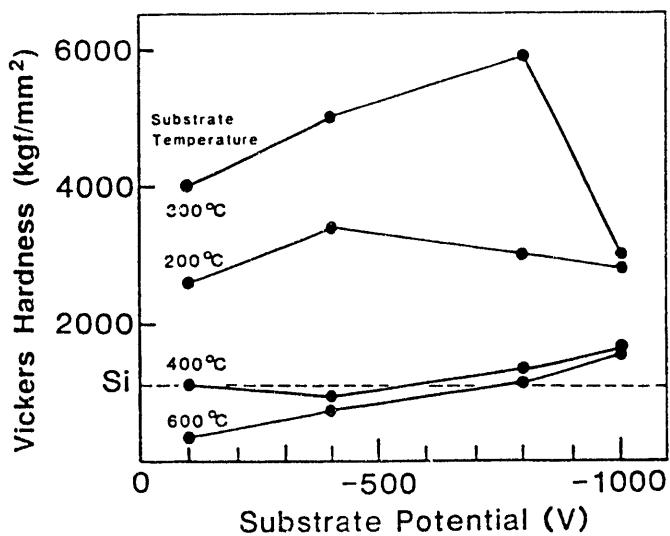


Comparison of Typical Deposition Conditions

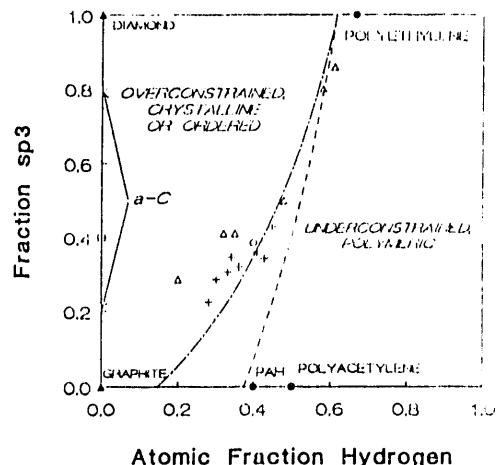
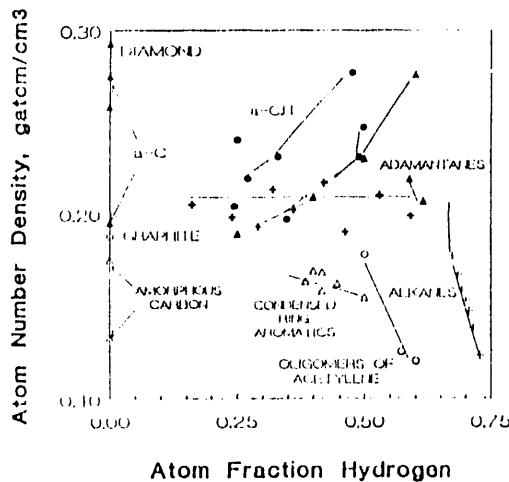
Process	Carbon Source	Particle Energy (eV)	Substrate Temperature °C	Film Characteristics
CVD	Dilute hydrocarbon gas in hydrogen	0.1–1 eV	Typical 800–1100°C (<500°C possible)	Poly-crystalline diamond & DLC/DLHC
PVD	Solid carbon	0.1–10 eV	R.T. and higher	DLC/DLHC
IBD	Gas (CH ₄ , H ₂ , etc.) (solid carbon)	0.1–100 keV	R.T. and higher	DLC/DLHC
Hybrid	Gas solid	0.1–10 keV	R.T. and higher	DLC/DLHC



Effect of Process Parameters on DLHC Properties



Okada et al.

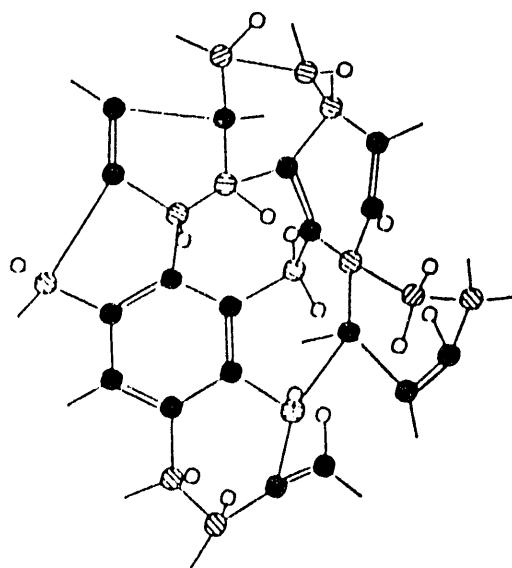


(Angus)

IBD/IAD processes typically produce amorphous carbon films with <1% hydrogen (denoted as a-c or DLC), or, amorphous hydrogenated carbon films with 20–60% hydrogen

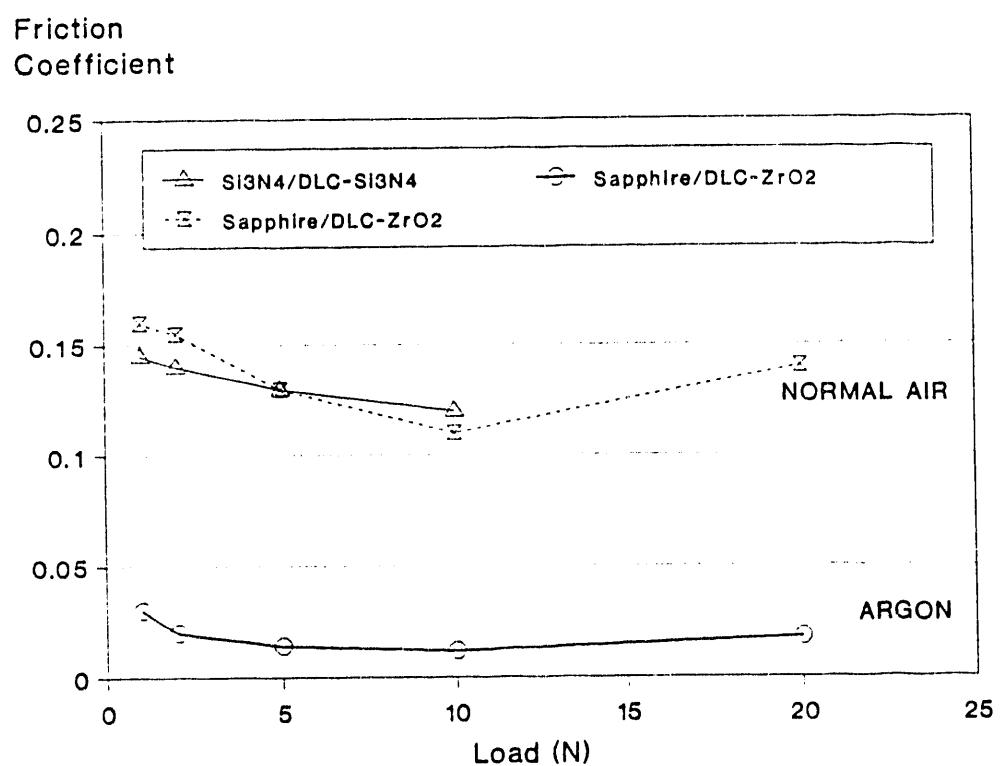
- amorphous (small crystallites)
- hydrogen content – ρ , sp^3 bonding

Structure of Amorphous Carbon Films (Angus et al.)

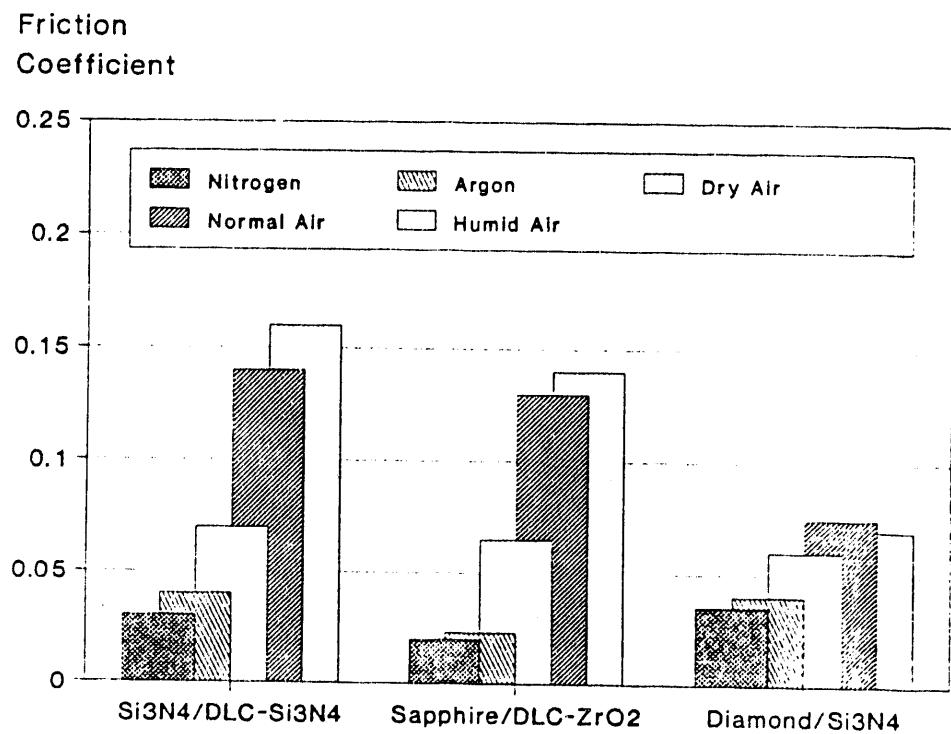


- Short range sp^2/sp^3 bonding
- No long-range order

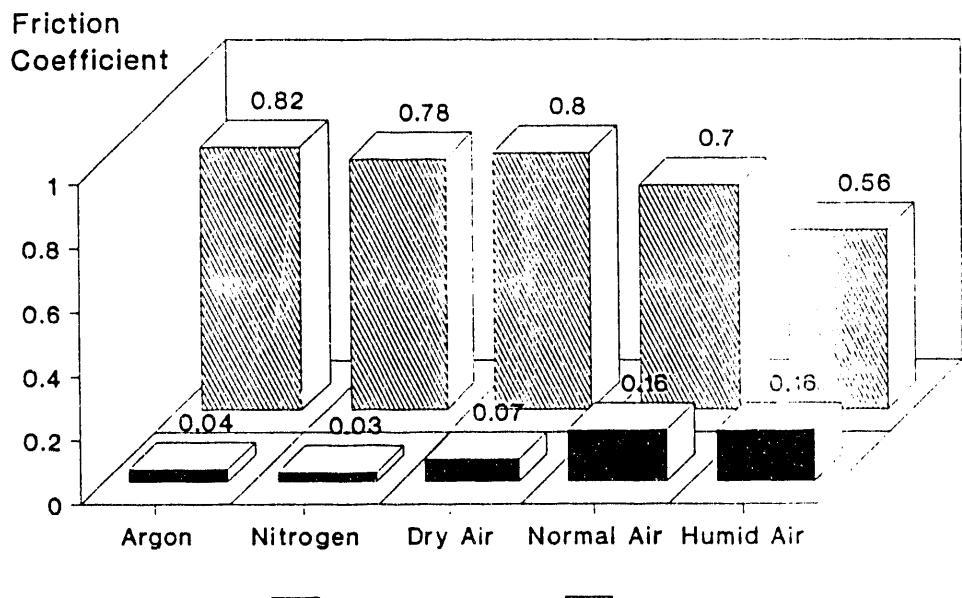
Friction Coefficient of DLHC Films on Ceramics (Erdemir, Wei, and Wilbur)



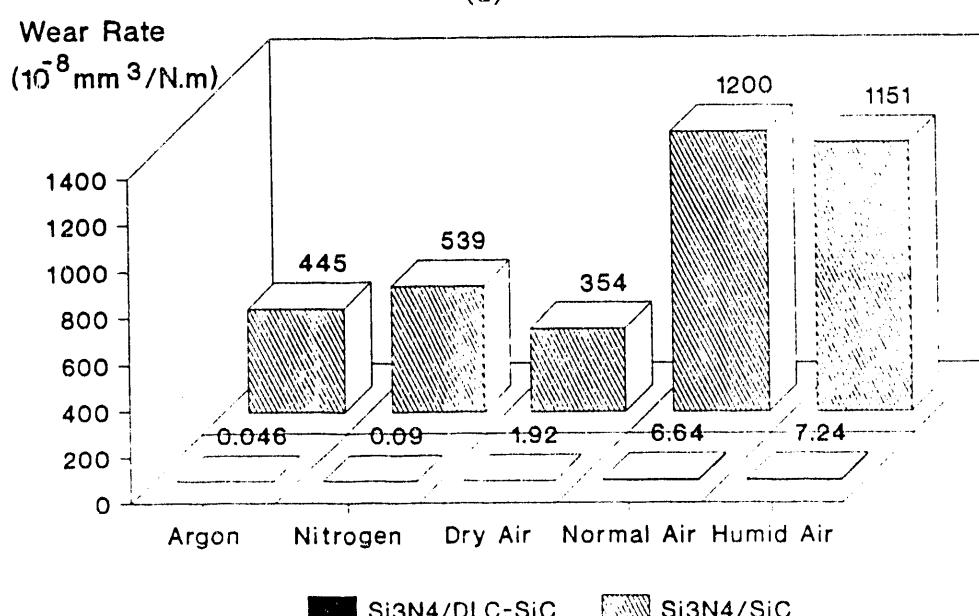
Friction Coefficient of DLHC Films on Ceramics (Erdemir, Wei, and Wilbur)



Friction and Wear of DLHC Films on Ceramics (Erdemir, Wei, and Wilbur)

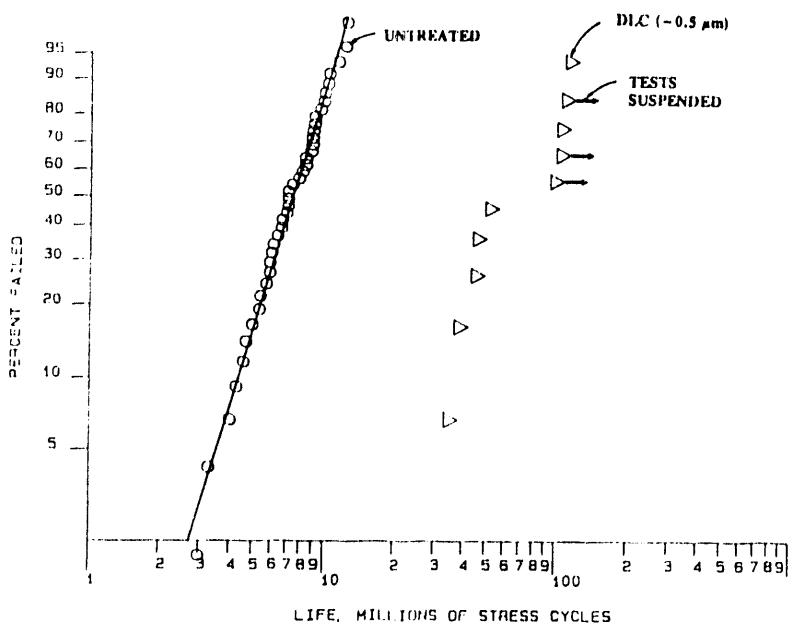
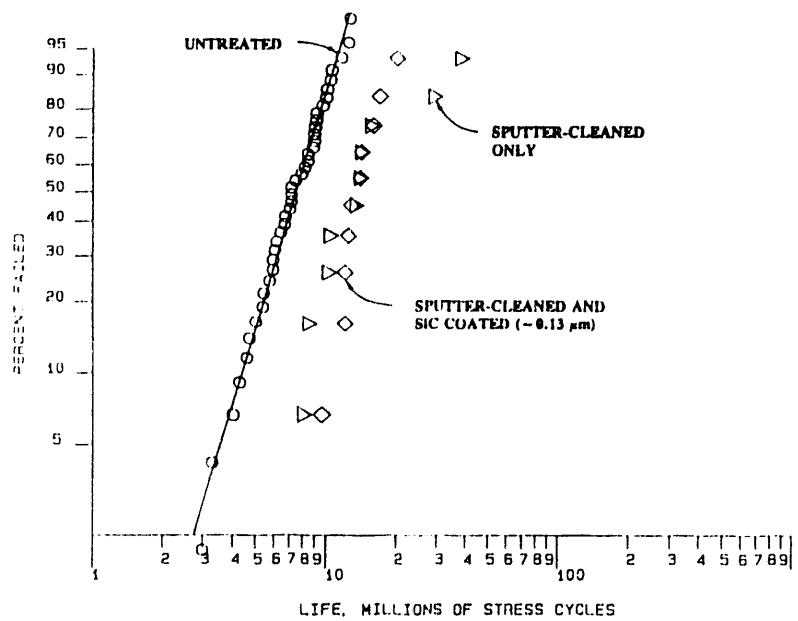


(a)



(b)

Rolling Contact Fatigue Tests of Thin DLC Films on M50 Steel (Wilbur, et al.)



Issues

- Film Stability
 - environment
 - temperature
 - mechanical loading
- Surface Finish
- Film Adhesion
- Deposition Rates
- Geometries
- Competing Processes
 - mature processes – TiN
 - emerging processes – c-BN
 - superlattices
- Cost

Department of Materials Science & Engineering
Diamond Deposition and Analysis Laboratory

CHARACTERIZATION METHODS

for

**DOE workshop on Diamond and Diamond-like
Carbon Films**

**February 4th & 5th
Argonne National Lab**

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Materials Sci. & Eng.
North Carolina State Univ.**



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* Current Employer: G E Superabrasives

Outline

Introduction

Raman Spectroscopy

SEM

TEM

Surface Analysis

Comparison of
Techniques

In-vacuo Analysis

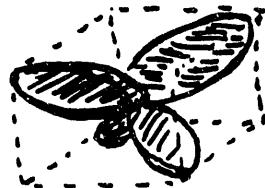
In-situ Analysis

Summary



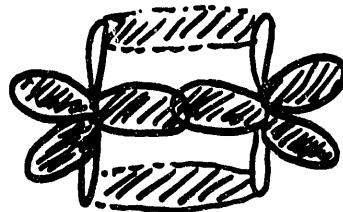
Carbon Bonding

$C - C$
 (σp^3)



$(1s^2) \underline{2s^1} \underline{p^3} (4\sigma's)$
 Diamond
 Tetrahedral

$C = C$
 (σp^2)



$(1s^2) \underline{2s^1} \underline{2p^1} \underline{2p^2}$
 $\uparrow \uparrow \uparrow$
 $1\pi \quad 3\sigma's$

Graphitic
 Planar

$C \equiv C$
 (σp^1)



$(1s^2) \underline{2s^1} \underline{2p^1} \underline{2p^1}$
 $\uparrow \uparrow$
 $1\pi \quad 2\sigma's$

Carbyne
 Linear

I. Identification of the Diamond Phase

A. Composition (Carbon)

Auger Electron Spectroscopy
X-ray Photoelectron Spectroscopy
Secondary Ion Mass Spectrometry
Rutherford Backscattering
Infrared Spectroscopy

B. Structure (Diamond, Fd3m space group)

X-ray Diffraction
Electron Diffraction

C. Bonding (sp^3 , tetrahedral)

Raman Spectroscopy
Auger Electron Spectroscopy
Electron Energy Loss Spectroscopy
X-ray Photoelectron Spectroscopy

II. Defects in Diamond Films

A. Scanning Electron Microscopy

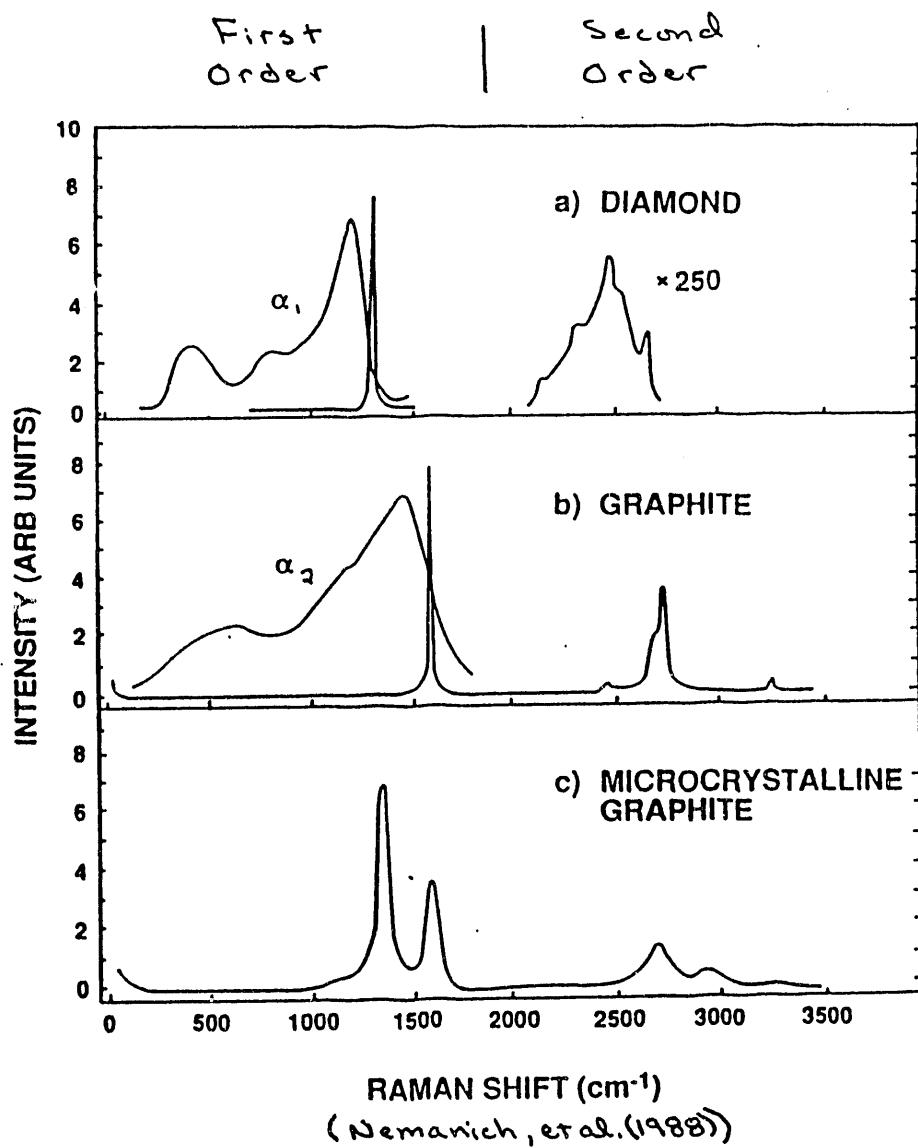
Grain Boundaries
Particle Morphology
Secondary Nucleation

B. Transmission Electron Microscopy

Dislocations
Stacking Faults
Twins
Grain Boundaries

C. Electrical Measurements

Impurities
Electrically Active Defects



1332 cm^{-1} - primary 1st order diamond peak

1580 cm^{-1} - primary 1st order graphite peak

1355 cm^{-1} and 1590 cm^{-1} - primary, 1st order
microcrystalline graphite peaks

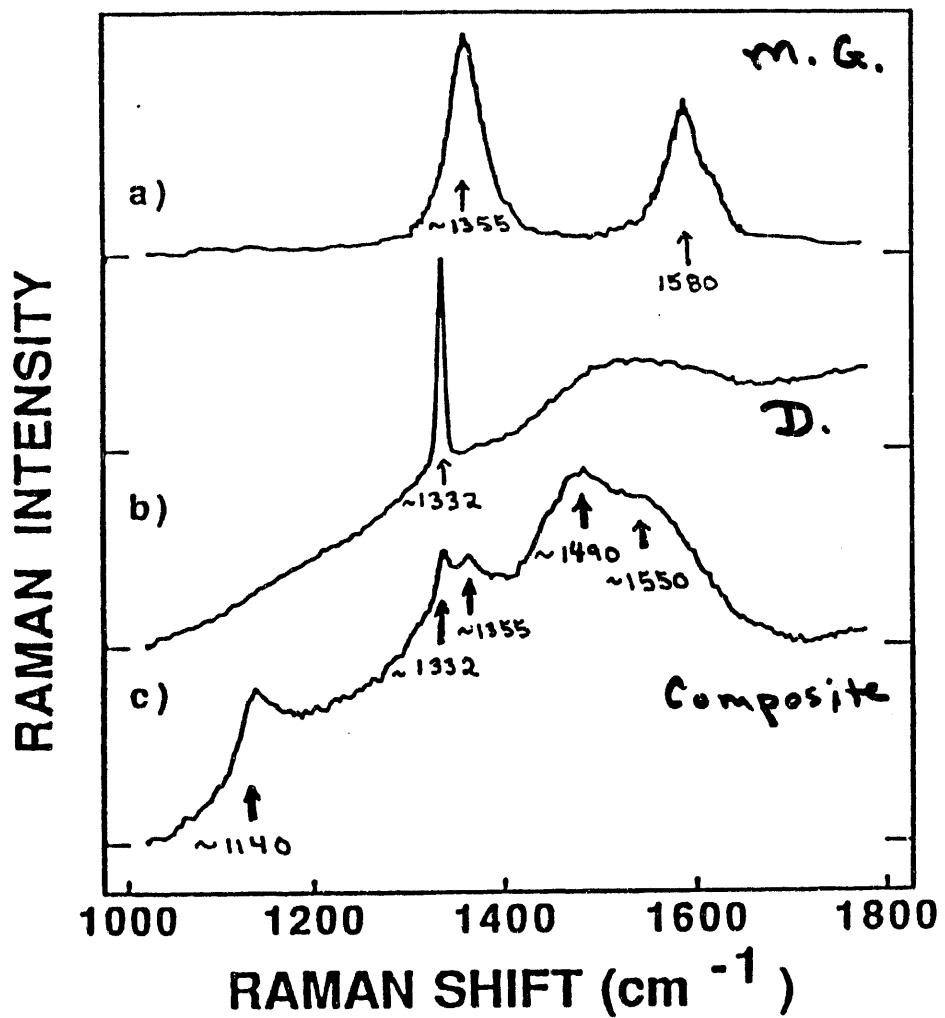
α_2 - amorphous graphite peaks

α_1 - amorphous Si spectrum scaled to the
diamond frequency to represent amorphous dia.

Note;

Amorphous "graphite" \Rightarrow 3-fold coordinated, sp^2 bonded
carbon with no long range order

Amorphous "diamond" \Rightarrow 4-fold coord, sp^3 bonded C



First-order Raman spectra of diamond thin films. (a) "diamond-like" film with features similar to microcrystalline graphite (b),(c) the sharp feature at 1322cm^{-1} is indicative of crystalline diamond while features between 1350 and 1600cm^{-1} are attributed to sp^2 bonded carbon. (Shroder (1988)).

1332 cm^{-1} - Diamond

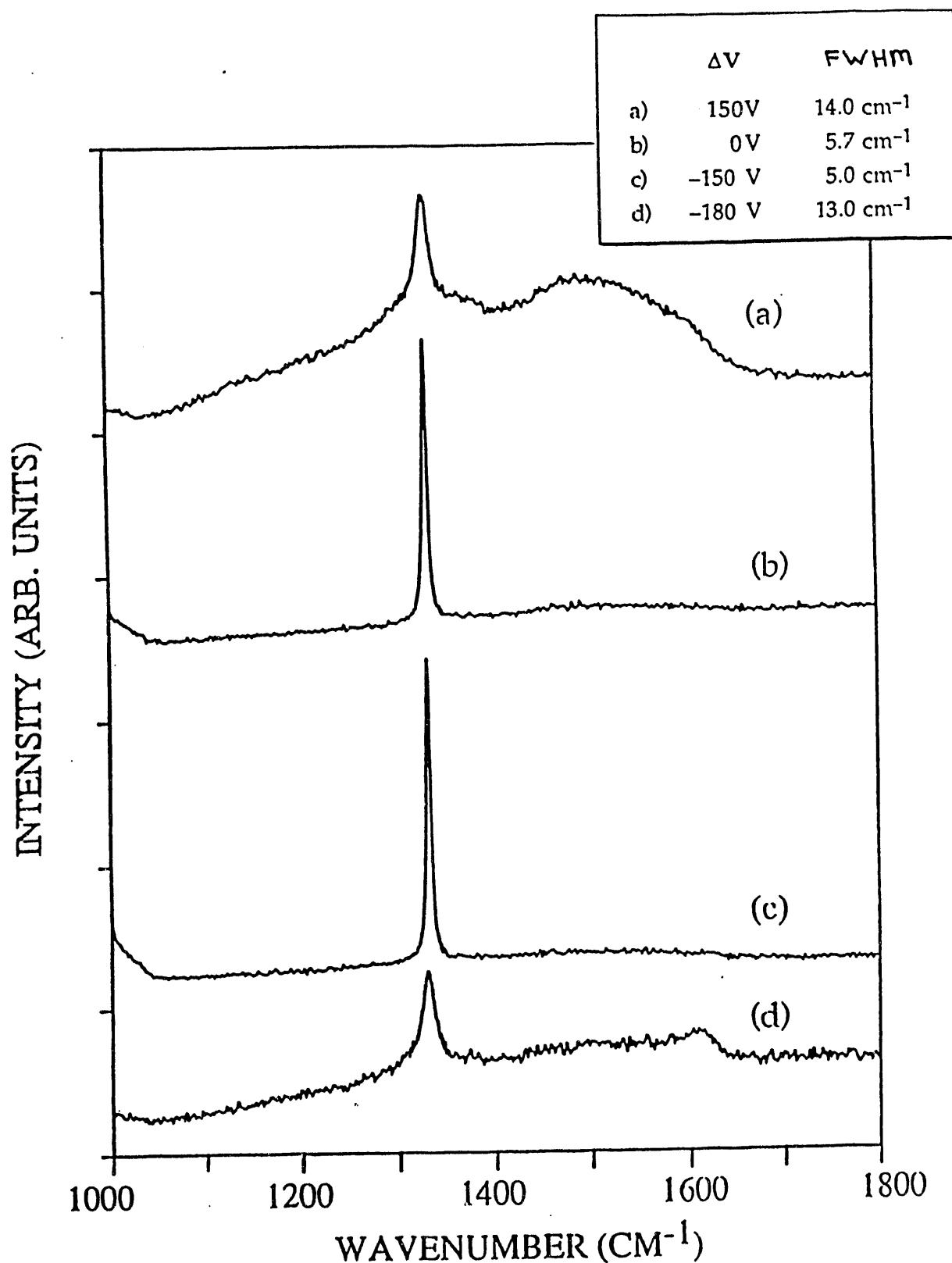
$1355 \& 1580\text{ cm}^{-1}$ - Microcrystalline Graphite

1490 cm^{-1} - Disordered (amorphous) Graphite

1550 cm^{-1} - Downshifted Microcrystalline Graphite

1140 cm^{-1} - Amorphous Diamond (?)

Note; $I_G \approx 50 I_D$



Raman spectra of diamond thin films grown under different biasing conditions. Appl. Phys. Lett. 56 (7), 12 February 1990.

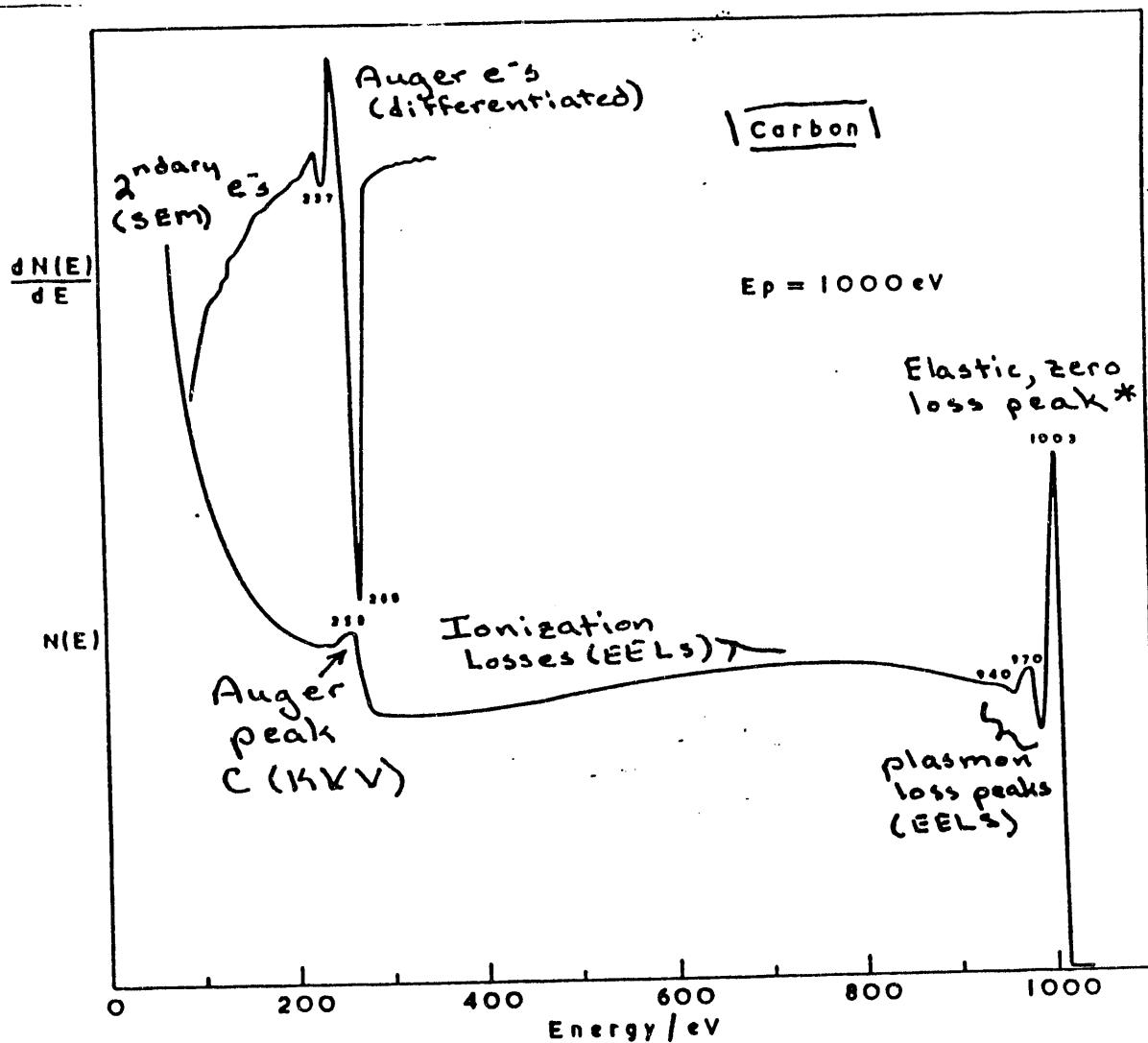
Department of Materials Science & Engineering
Diamond Deposition and Analysis Laboratory

Electron Spectroscopies

A. Auger Electron Spectroscopy

B. X-ray Photoelectron Spectroscopy

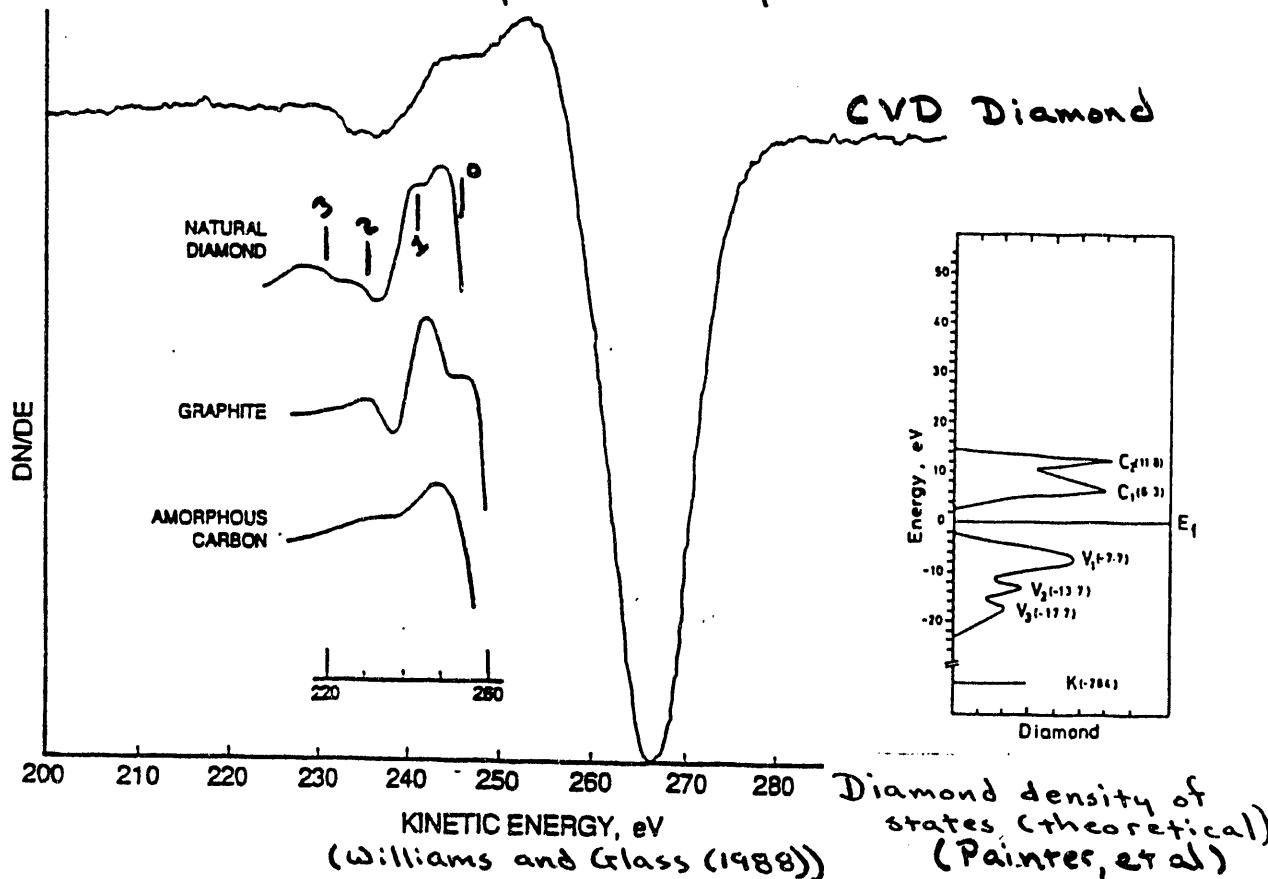
C. Electron Energy Loss Spectroscopy



Lower curve: distribution of energies of secondary electrons ejected from a graphite surface by incident electrons of energy 1000 eV. Upper curve: differential distribution over the energy range containing the carbon KLL Auger peaks. In the differential distribution the peak 'position' is taken to be that of the high energy minimum, by convention

* contains diffraction information

Narrow window AES scan about the C (KVV) peak showing fine structure



Diamond (Bulk)	$A_0 \pm 0.5$	$A_1 \pm 1$	$A_2 \pm 1$	$A_3 \pm 1$
Peak energy ^a	268	256	240	230
Peak position relative to A_0		12	28	38
Calculated energies (B.S.)	269	256	245	235
Identification	$(KV_1 V_1)$	$(KV_2 V_2)$	$(A_0 - \hbar\omega_s)$	$(A_0 - \hbar\omega_p)$
Calculated energies [19] (I.C.)	266	252	243	
Identification	$(^1D_2)$	$(^1P_1)$	$(^1S_0)$	

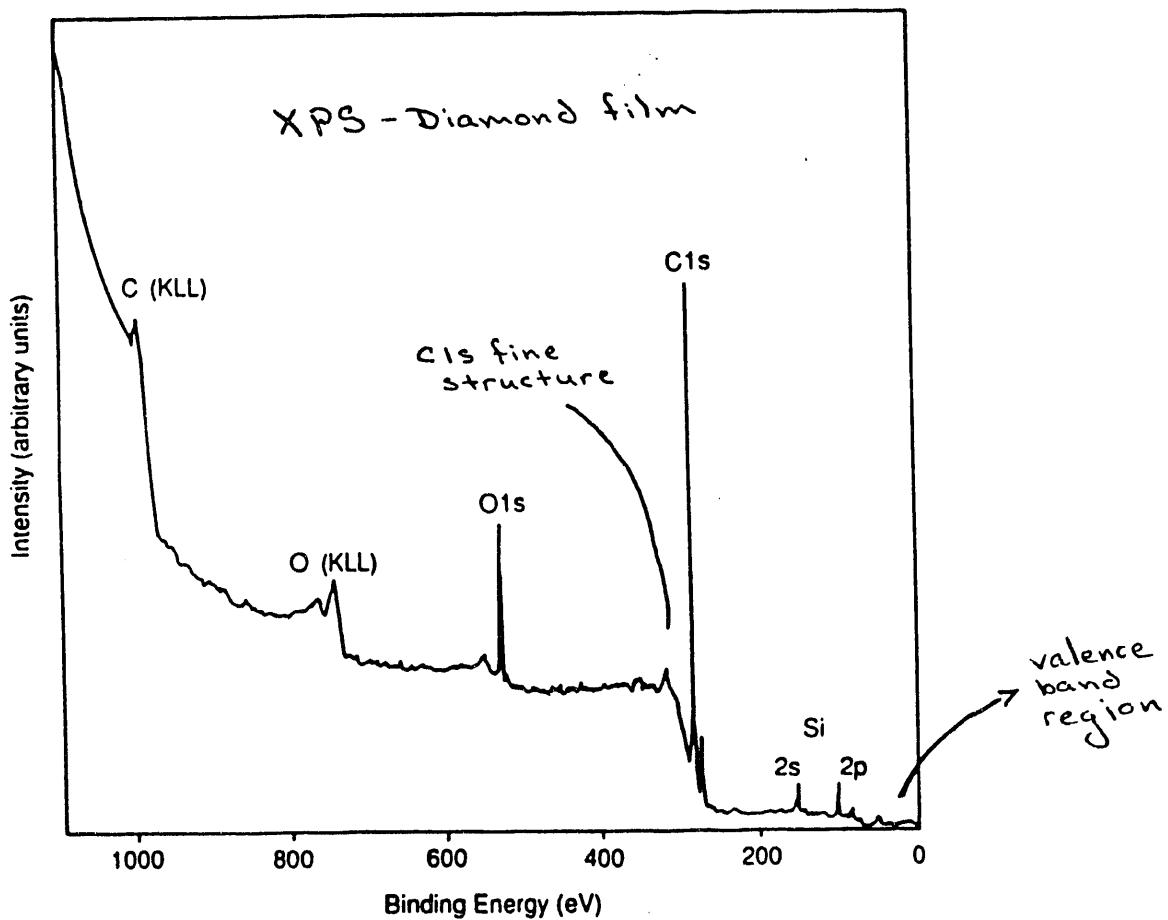
Graphite

Peak energy ^a	268	255	241
Peak position relative to A_0		14	27
Other [11]	270	253	239

Amorphous-carbon

Peak energy ^a	268	243
Peak position relative to A_0		25

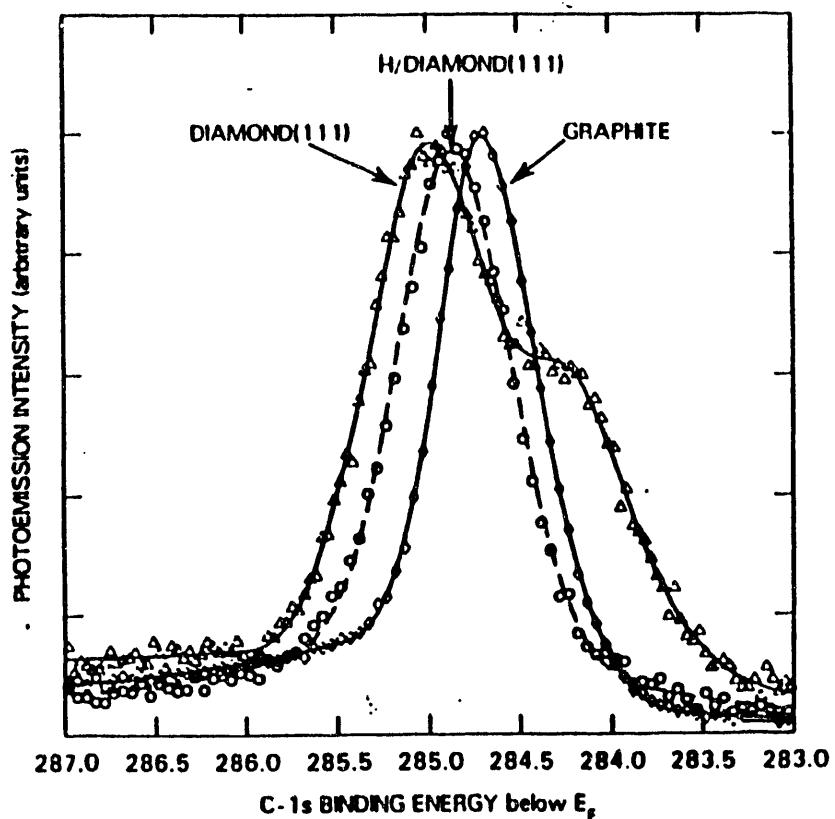
(Lurie and Wilson (1977))



Wide energy range XPS scan of a diamond film grown at 1% CH_4 in H_2 .

Note the x-ray excited Auger peaks for the O and C. Oxygen and Silicon impurities were generally confined to the surface, probably due to Quartz reaction chamber in the microwave plasma CVD system. (Glass, Williams and Davis (1988)).

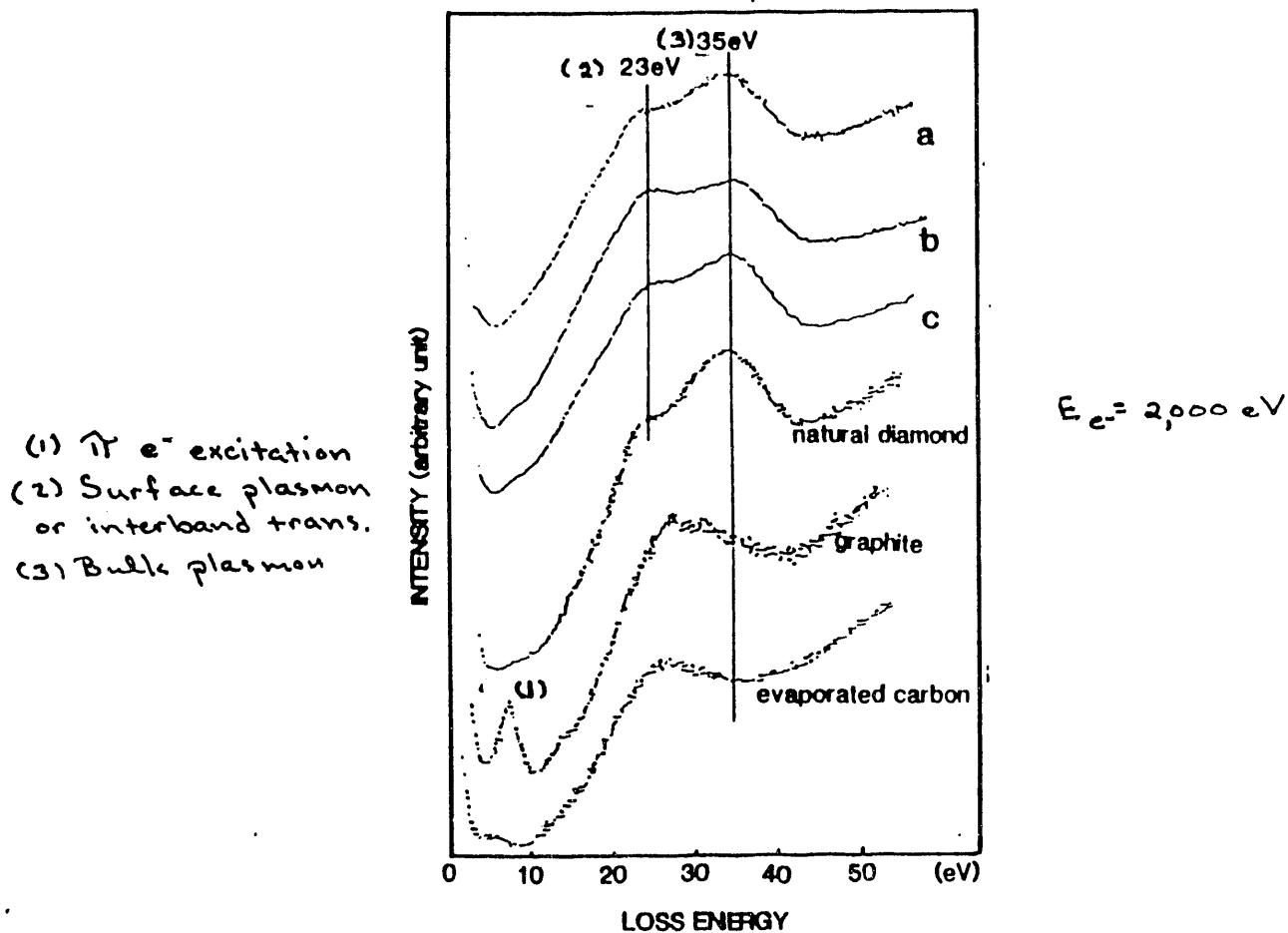
XPS, C_{1s} peak - Natural Diamond
and Graphite



Unprocessed photoemission spectra showing the peak positions for a clean diamond surface, a hydrogen-covered surface, and a graphite single crystal. The difference in binding energy between the hydrogen-covered and clean diamond bulk peak results from a shift in the Fermi-level pinning position when the hydrogen is removed from the surface. (Morar, et al. (1986)).

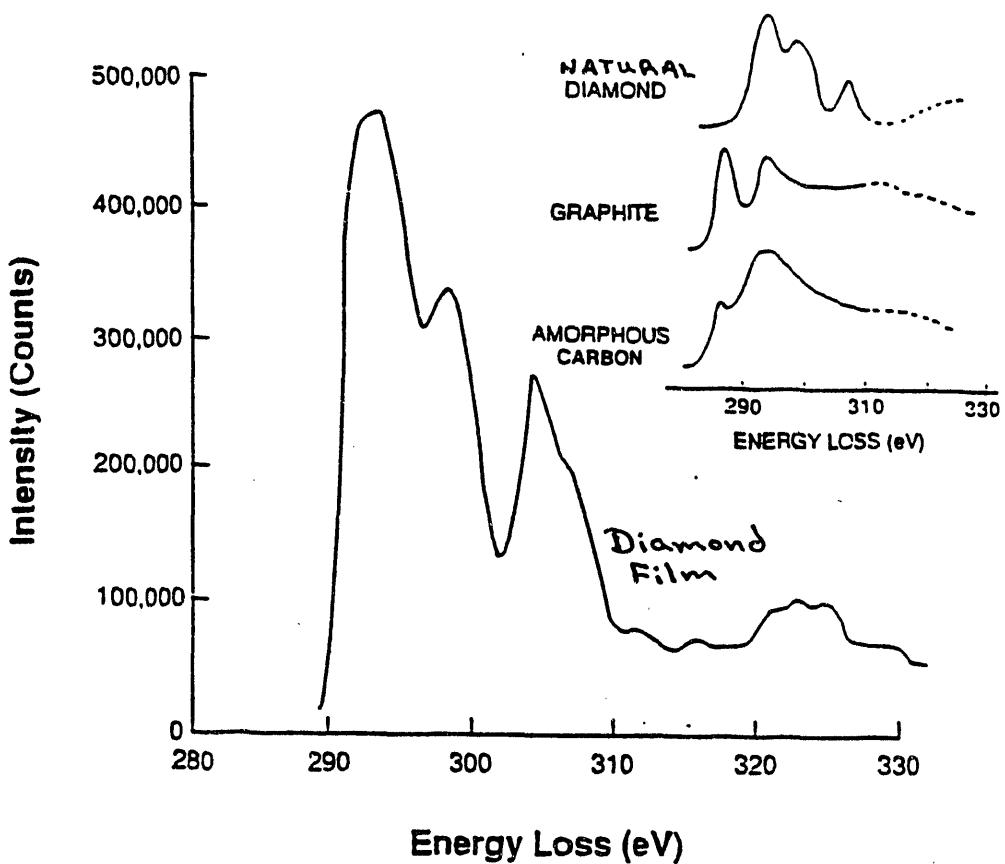
Note the relatively small binding energy shift between diamond and graphite. For detection, a monochromated x-ray source is necessary. Thus, for conventional, multi-technique surface analysis systems, the fine structure (AES or XPS) should be utilized to distinguish these phases, or electron energy loss spectroscopy, rather than E_F shift.

Electron Energy Loss Spectra from Carbon - plasmon loss region near zero loss peak



- EELS of Diamond films grown by EACVD;
- $\text{CH}_4 = 2.0\%$, $T_s = 1073 \text{ K}$
 - $\text{CH}_4 = 2.0\%$, $T_s = 823 \text{ K}$
 - Specimen (b) after acid wash
 - $\text{CH}_4 = 0.5\%$, $T_s = 823 \text{ K}$
(Sawabe and Inuzuka (1986))

Definition - A Plasmon is a collective excitation of conduction electrons. Frequency is determined by oscillation of lone electron plasmon with respect to the positive core.



K-shell ionization spectra from EELS
 in a Transmission Electron Microscope
 (note similarity between Diamond Film &
 natural diamond - edge and shape)

Advantage of transmission EELS in a TEM is the spatial resolution. Using a 200 Å spot size in this study grain boundaries and defects were examined for an sp^2 component. However, only sp^3 bonding was observed throughout the film.

(Williams and Glass (1988)).

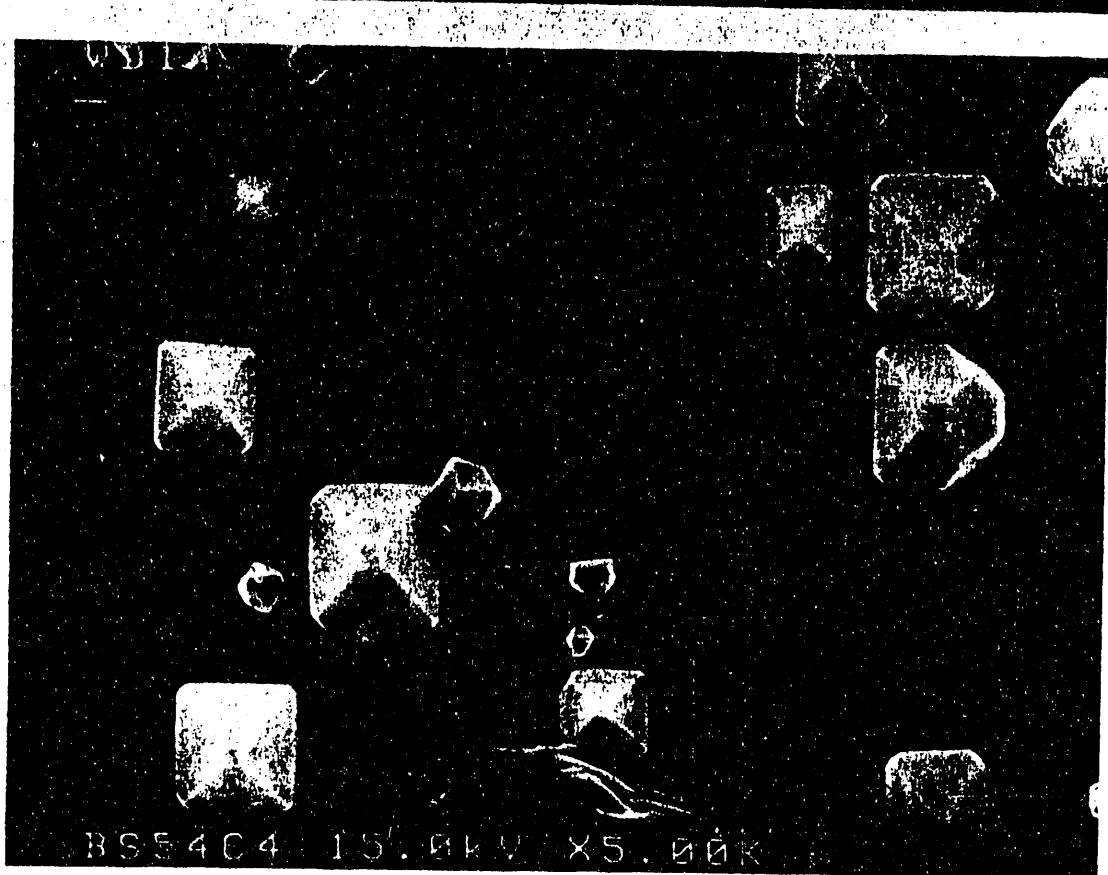
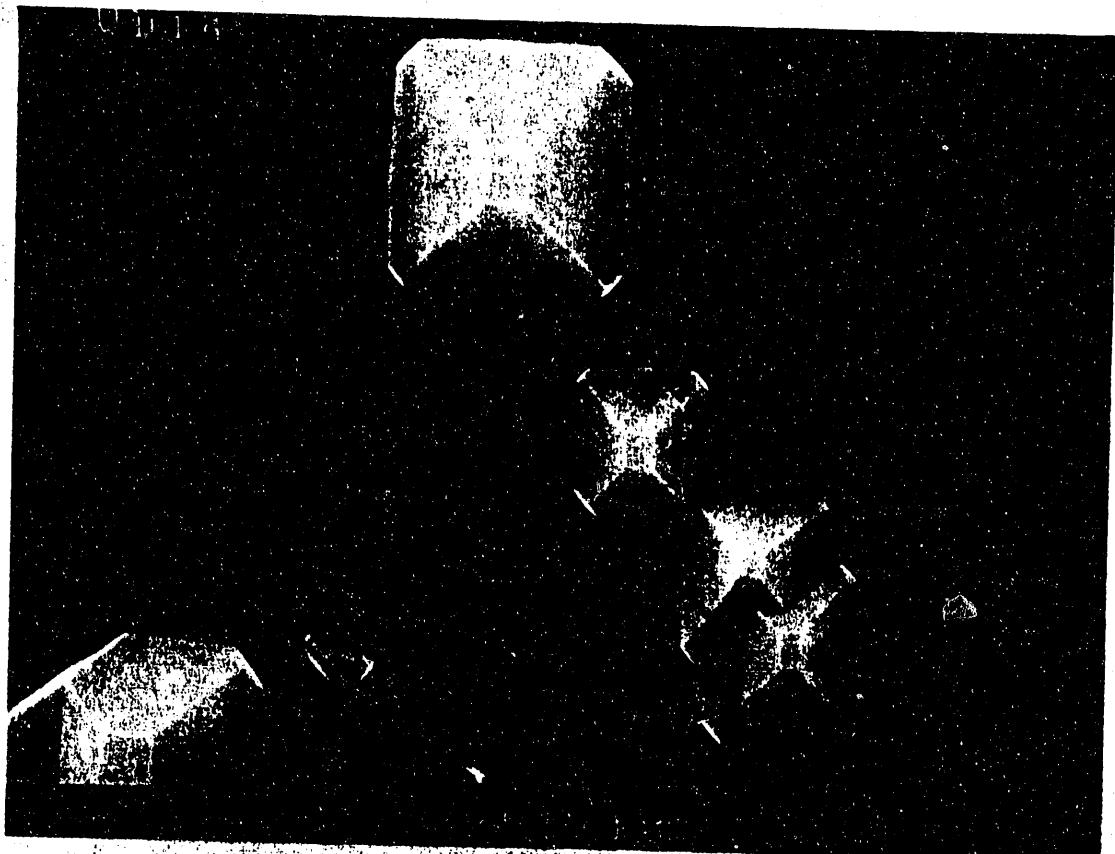
Electron Microscopies

A. Scanning Electron Microscopy

B. Transmission Electron Microscopy

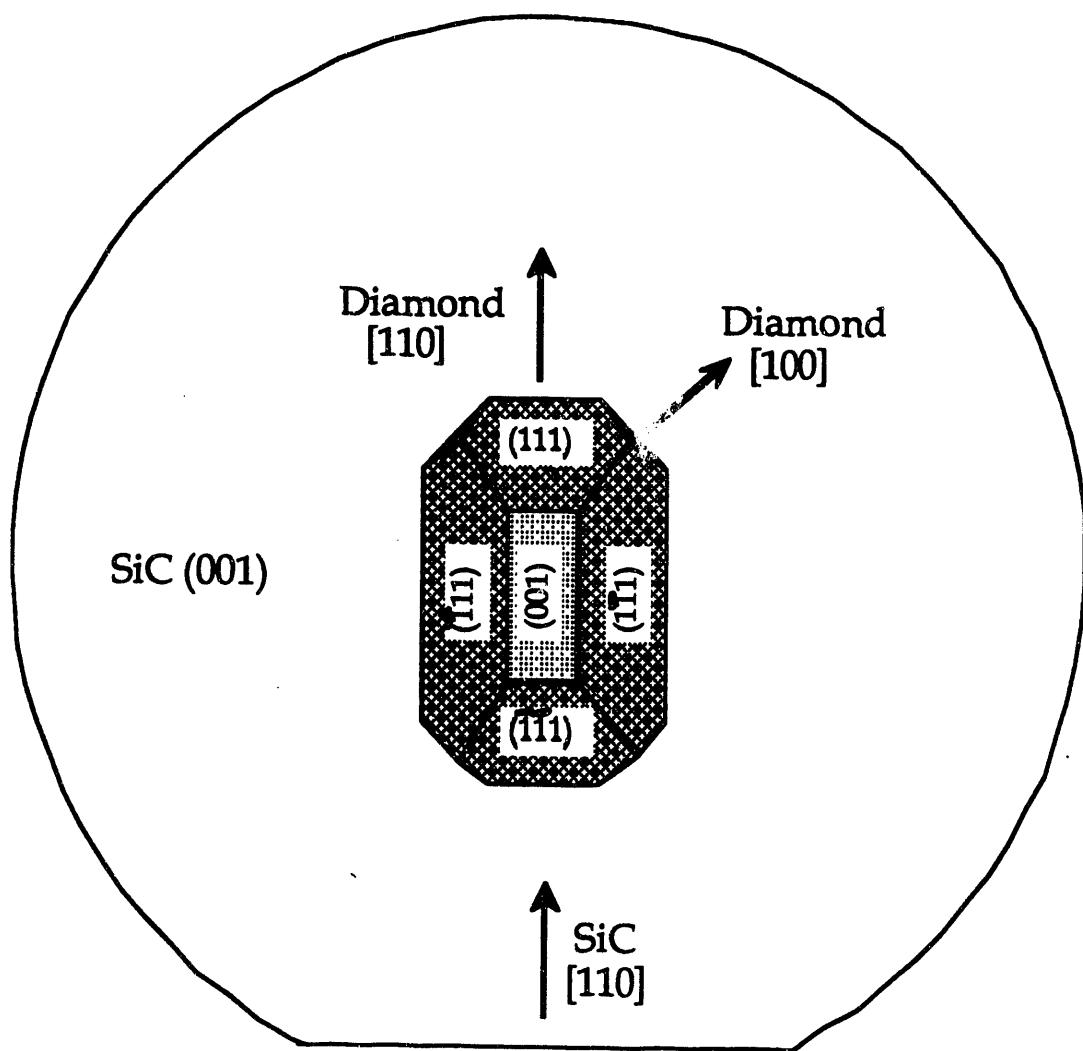
(C. Scanning Tunnelling Microscopy)





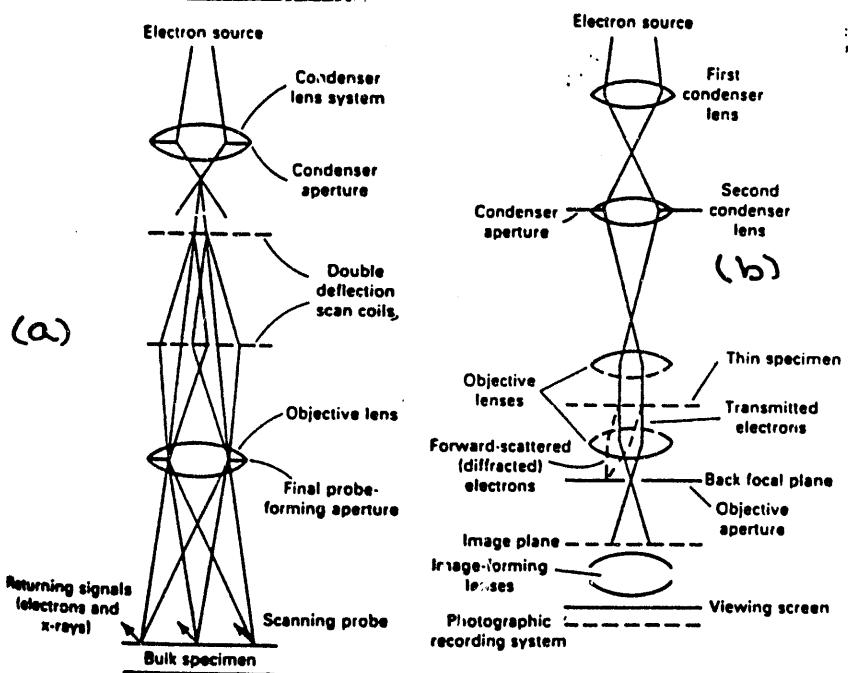
BS5404 15.8KV X5.50K

Schematic of Diamond Nuclei on β -SiC



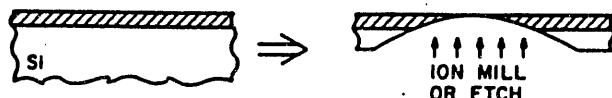


Transmission Electron Microscopy (TEM) - 55 -

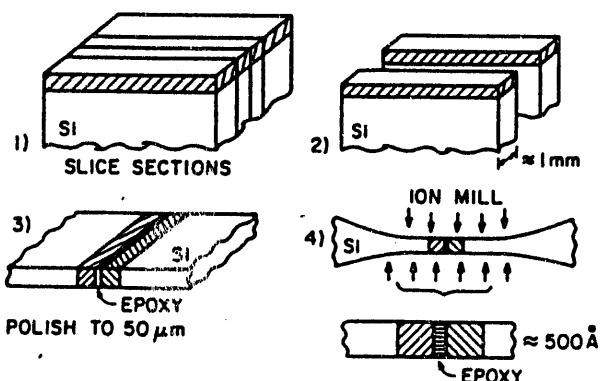


Schematics of electron optics for (a) SEM & (b) TEM

■ PLANAR TEM SAMPLE



■ CROSS-SECTION TEM SAMPLE



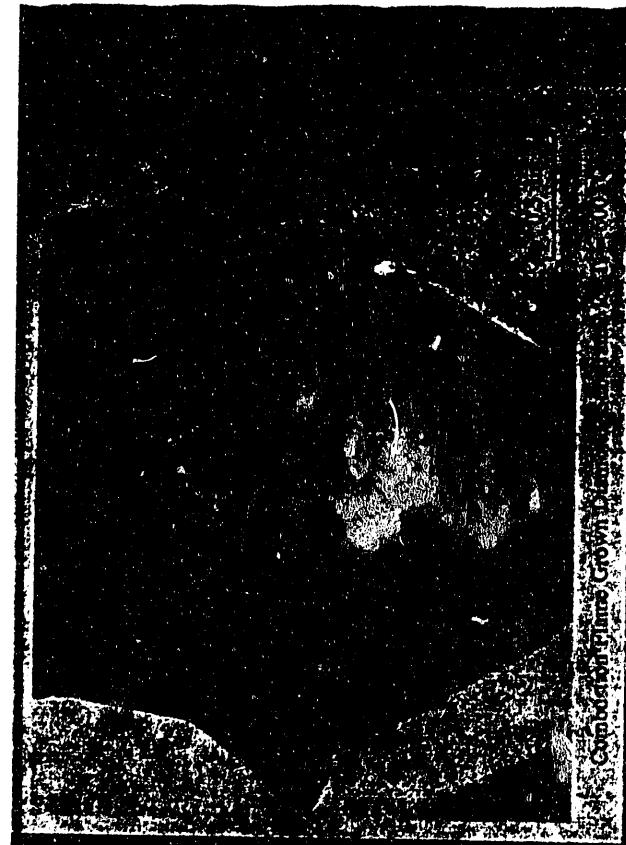
Sample preparation for transmission electron microscopy (TEM): (a) Preparation of standard planar samples involves polishing and a final etch or ion mill to thin the sample; (b) samples for cross section TEM involve (1) and (2) slicing sections about 1 mm thick, (3) using epoxy to hold two sections together and then polishing to about 50 μm thickness, and then (4) ion milling to produce the final sample thickness of about 500 \AA .

Advantages of TEM:

- * Resolution
- Diffraction info
- EELS, EDS attachments

Limitations:

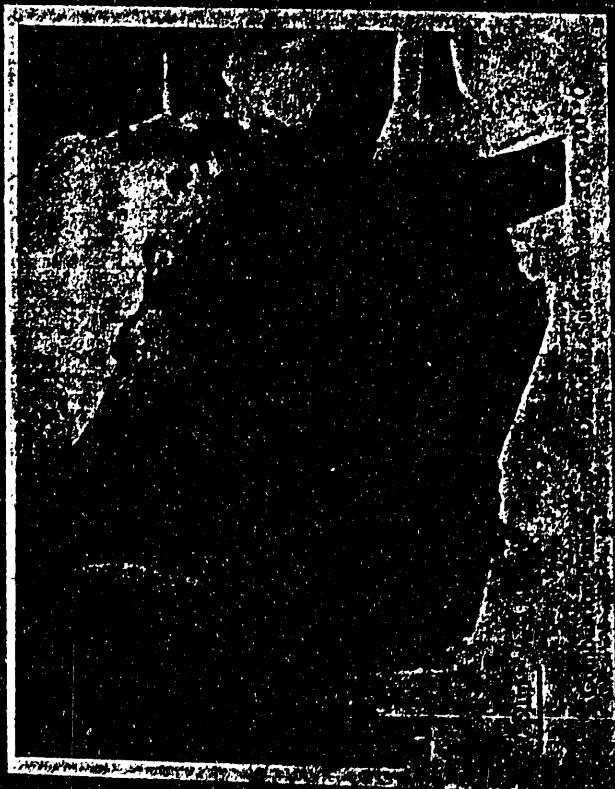
- Sample prep
- High vacuum
- e-beam damage
- Sampling volume

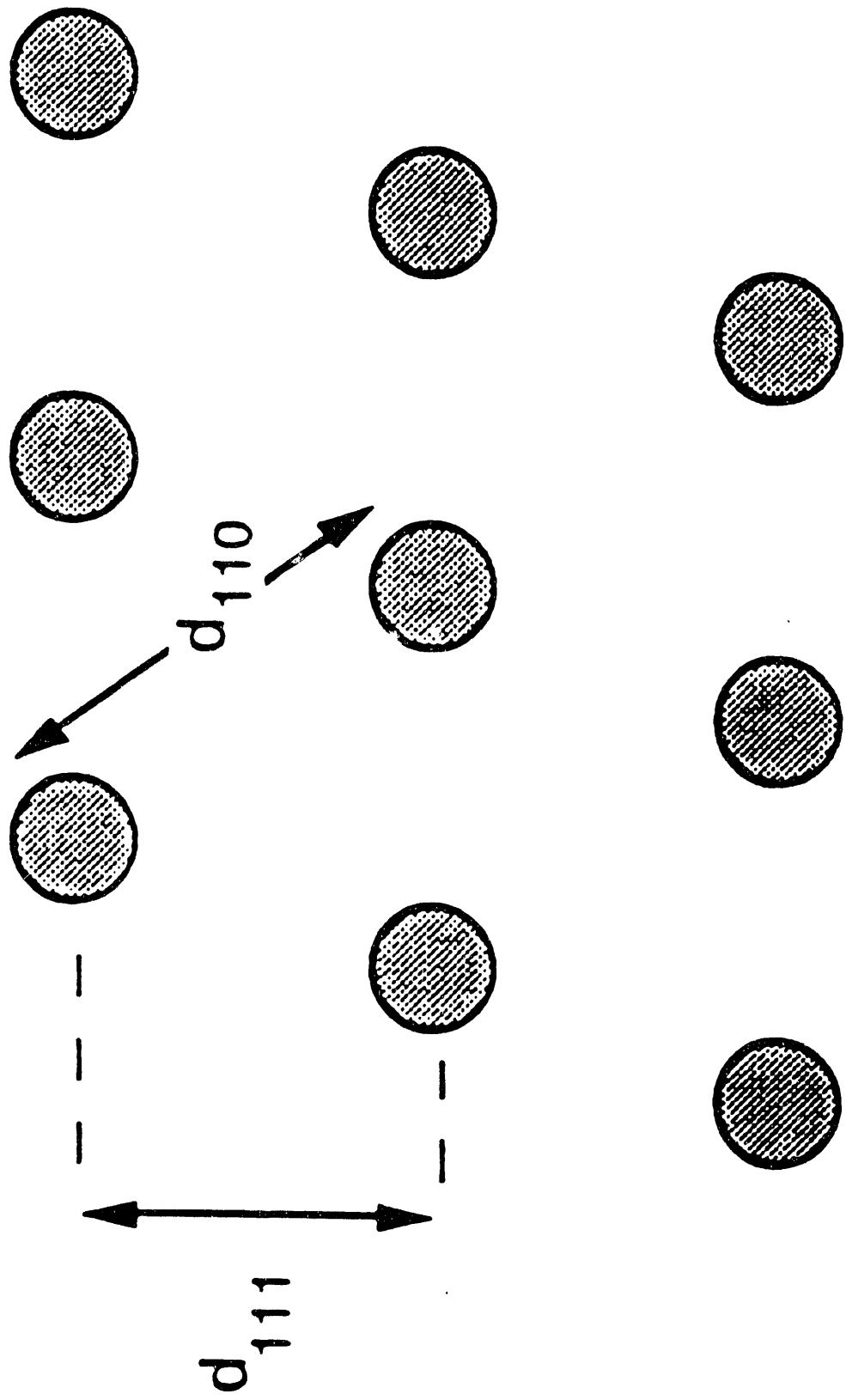


Comisión Ejecutiva
de la Ciudad de México

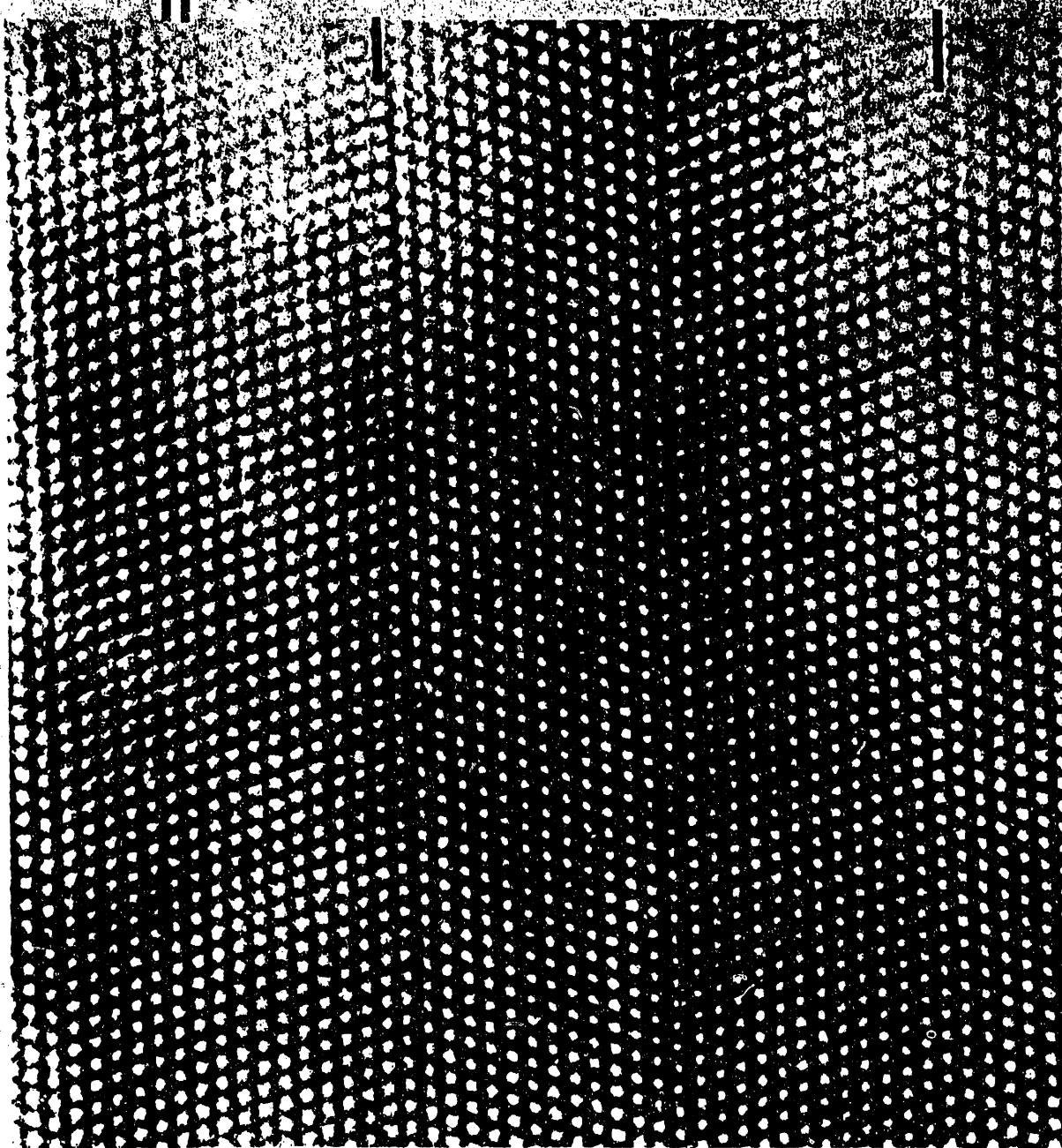


Comisión Ejecutiva
de la Ciudad de México





= Å 20.2



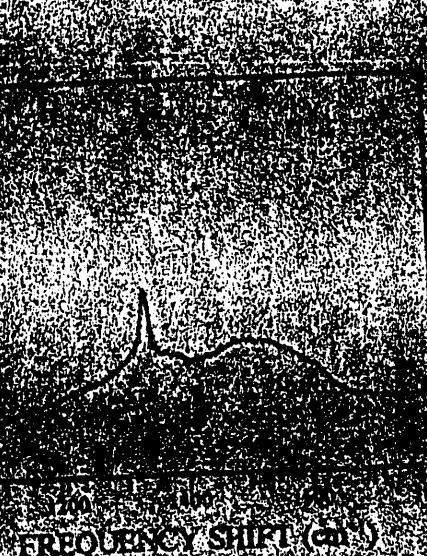
Comparison of Different Methods

- SEM • TEM • Raman
- XPS • AES • Raman



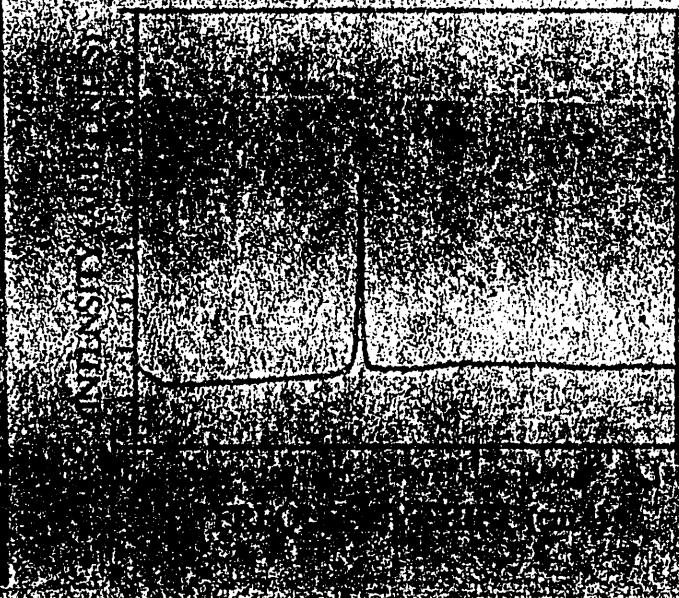
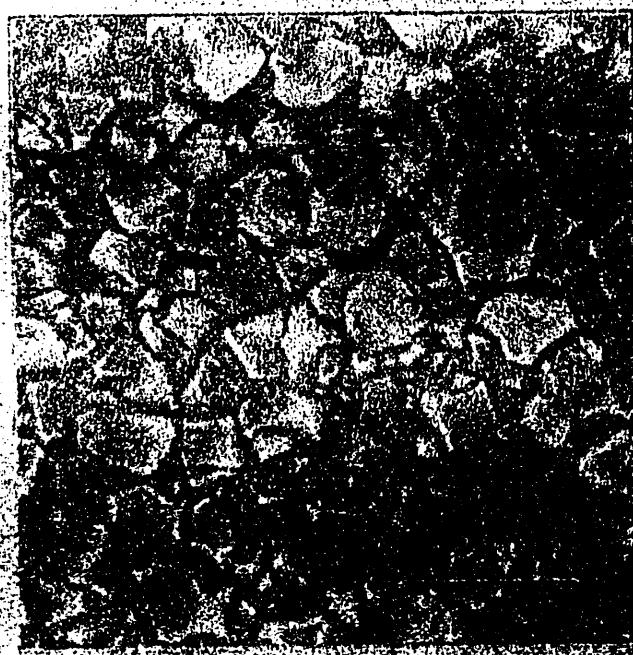


PLAN-VIEW TEM
MICROGRAPH



SCANNING ELECTRON
MICROGRAPH

Plan-view TEM micrographs of a single diamond grain grown under forward bias of 150 V and corresponding scanning electron micrographs and Raman spectra of diamond films



Plan-view TEM micrographs of a single diamond grain grown under zero bias, and corresponding scanning electron micrographs and Raman spectra of diamond films.

Comparative Sensitivities of AES, XPS-EELS, and Raman to sp₂:sp₃

Goal: Provide a comparison between techniques used by different researchers to evaluate the quality of diamond films.

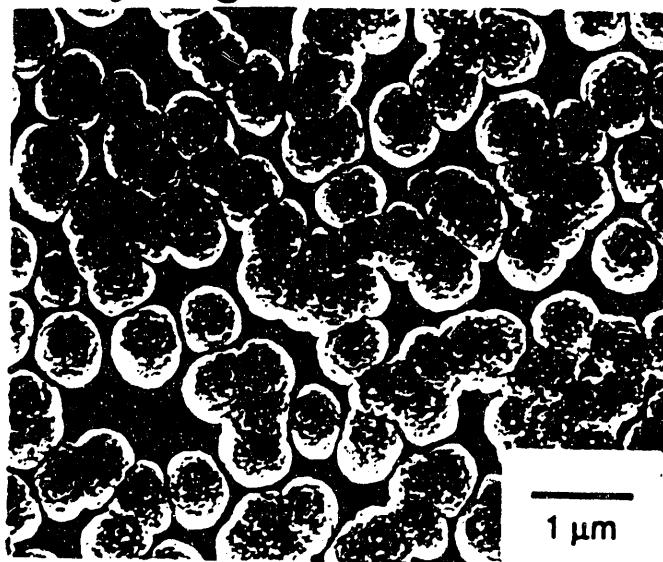
Approach:

- **Vary the methane concentration in the feedgas (1 to 50% in hydrogen) to increase/decrease the sp₂ component in the deposited films.**
- **Apply known correction factors (in the case of Raman) and qualitatively determine the amounts of phases.**

Surface Morphology: SEM

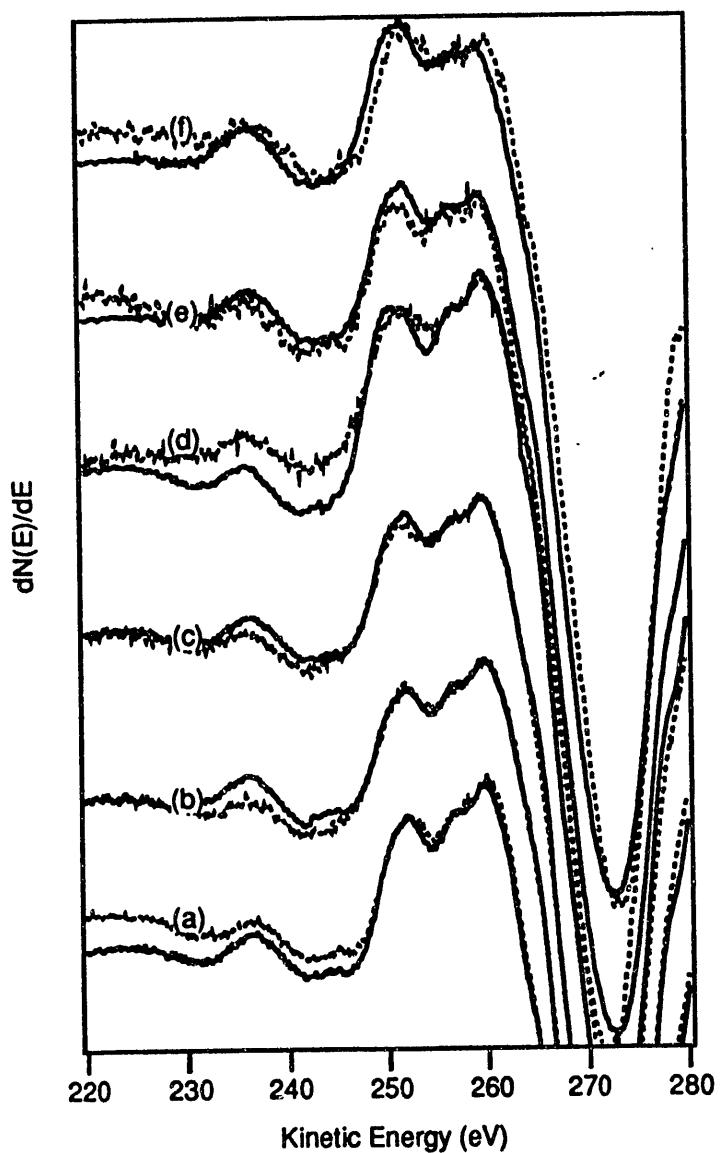


SEM micrograph of diamond film grown with 1% methane in hydrogen.



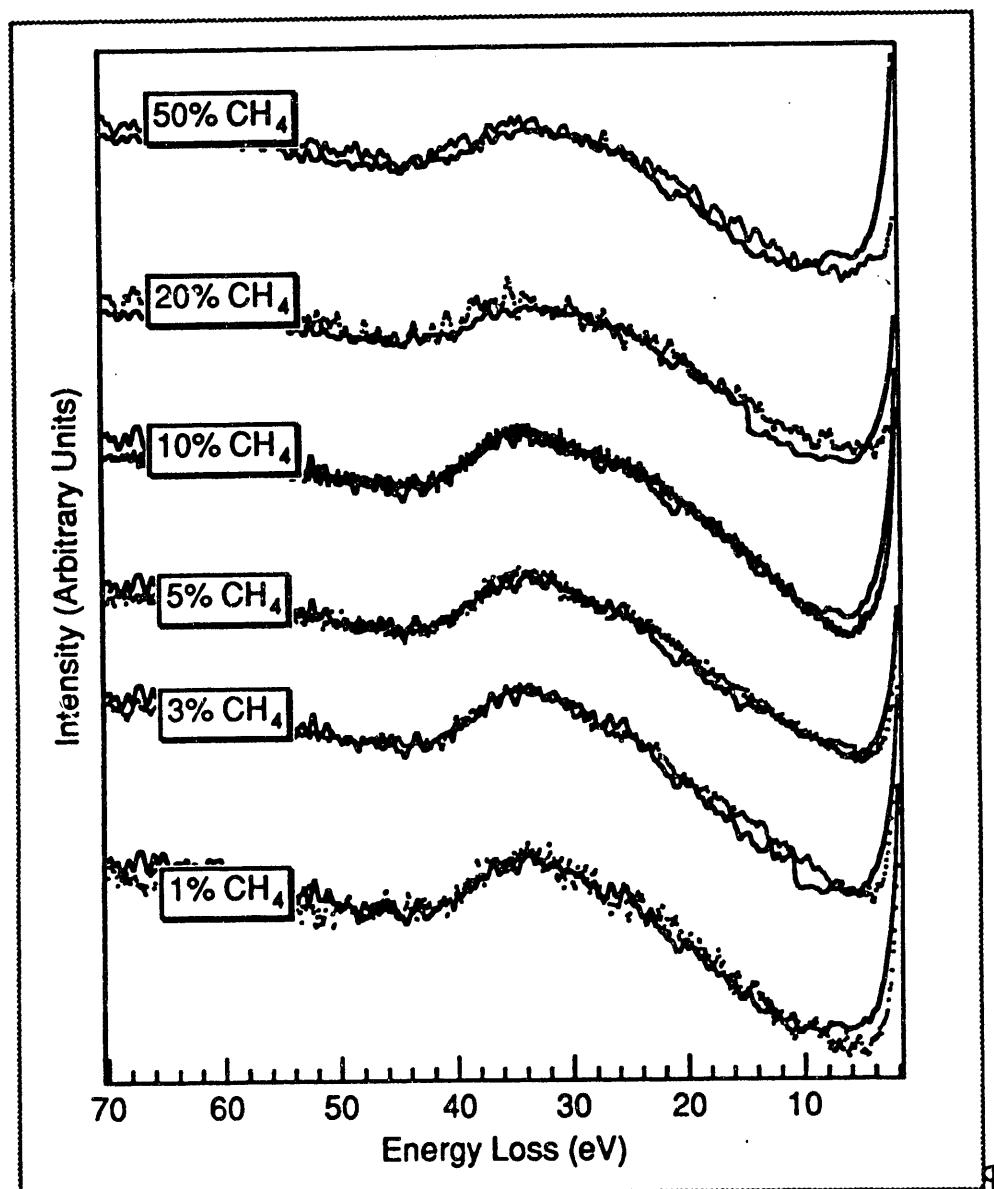
SEM micrograph of diamond film grown with 50% methane in hydrogen.

AES Spectra from Diamond Films

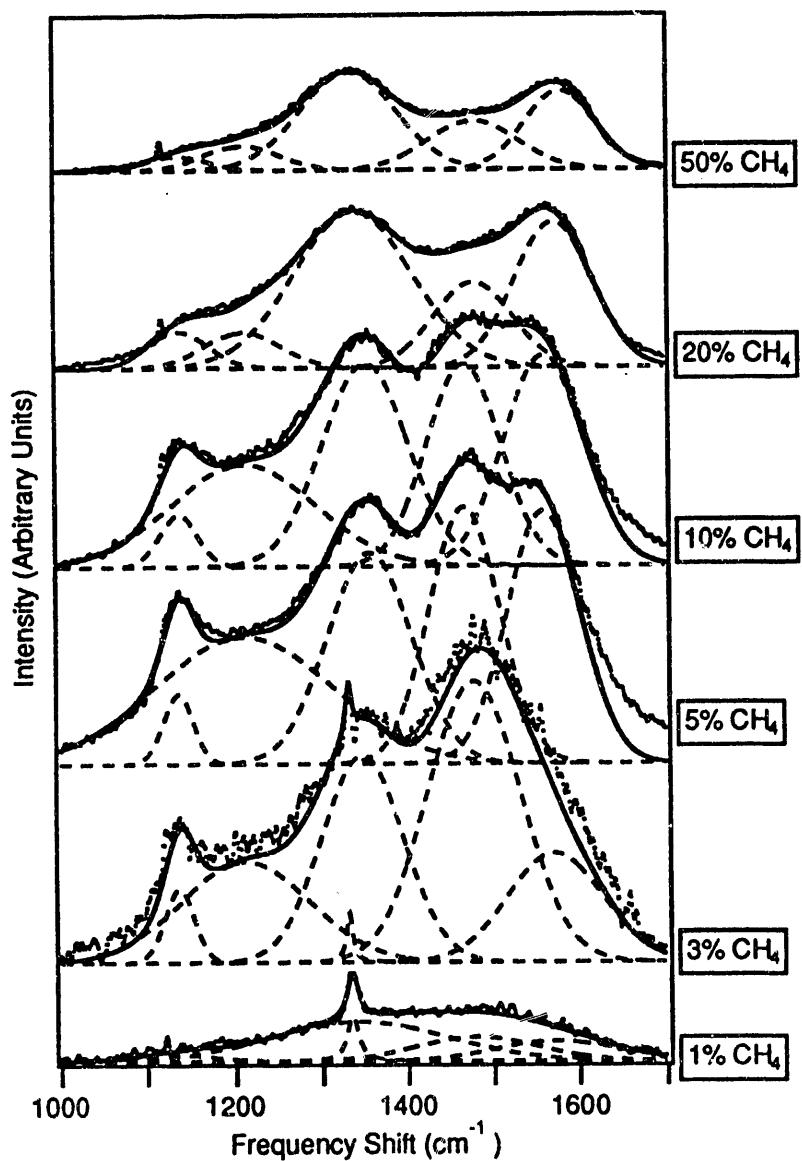


Auger spectra of diamond films grown with CH₄ concentrations of a) 1%, b) 3%, c) 5%, d) 10%, e) 20%, f) 50%.

XPS-EELS from Series of Diamond Films

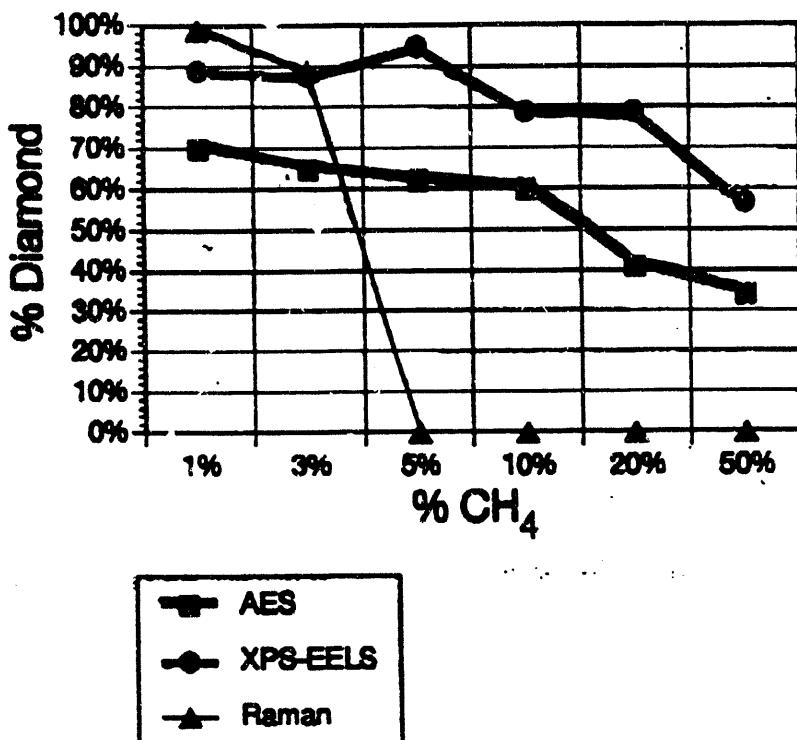


Raman Spectra of Diamond Films Grown with Different Methane Concentrations in the Feedgas



Department of Materials Science & Engineering
Diamond Deposition and Analysis Laboratory

Fraction of Diamond (sp3) Determined by
Deconvolution of AES, XPS-EELS, and Raman

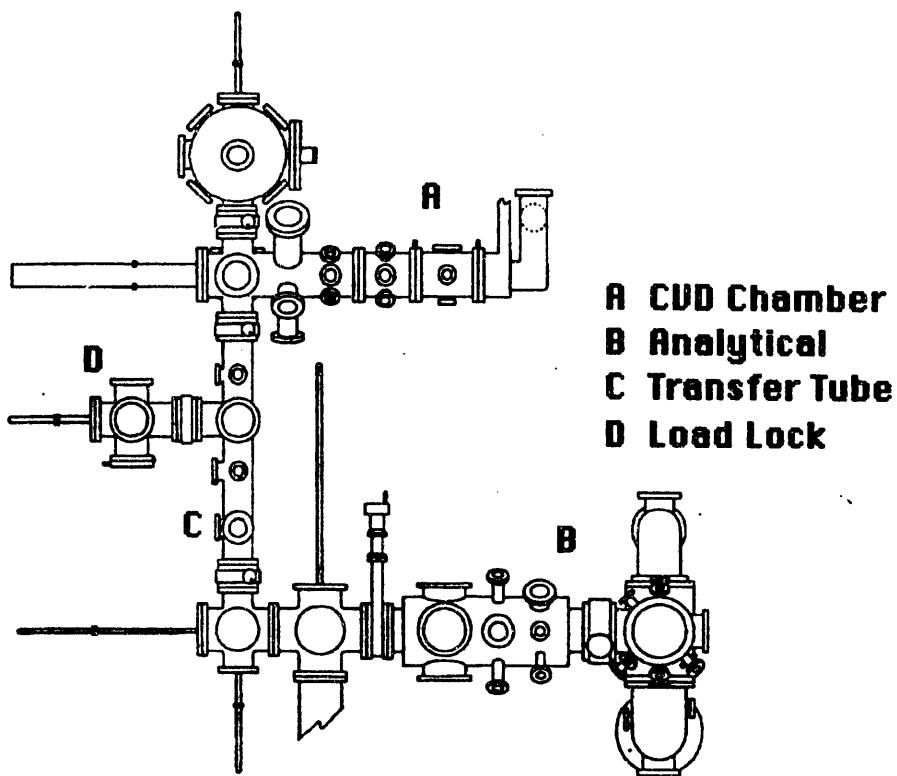


In Vacuo Analysis



Department of Materials Science & Engineering
Diamond Deposition and Analysis Laboratory

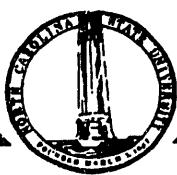
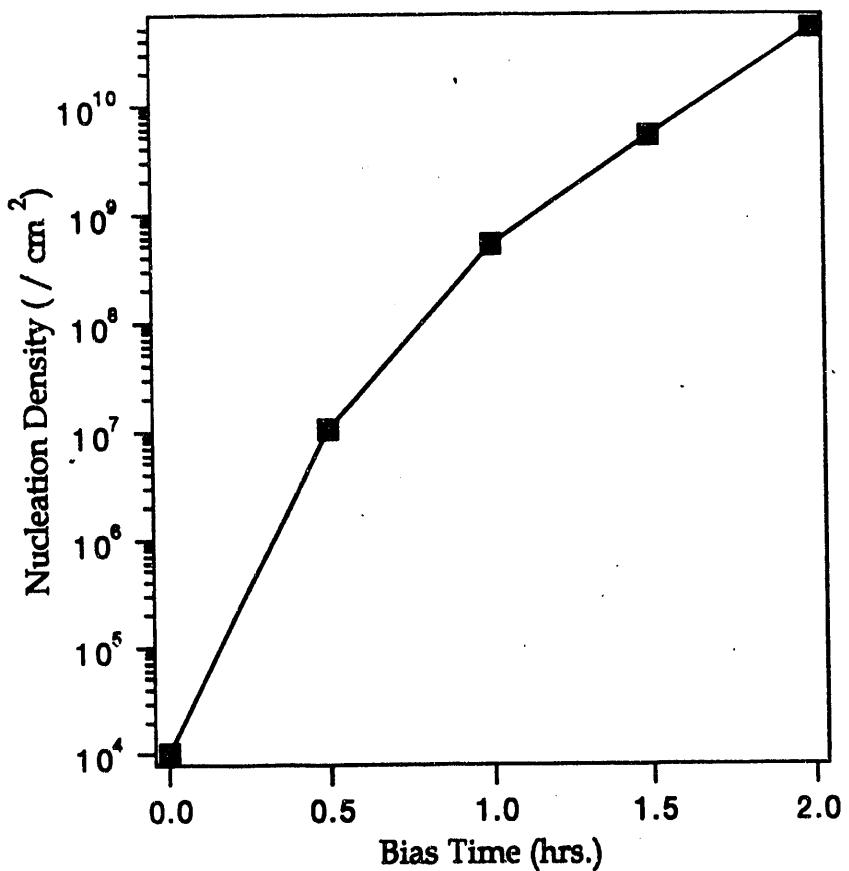
IN-VACUO CVD/ANALYTICAL CHAMBER



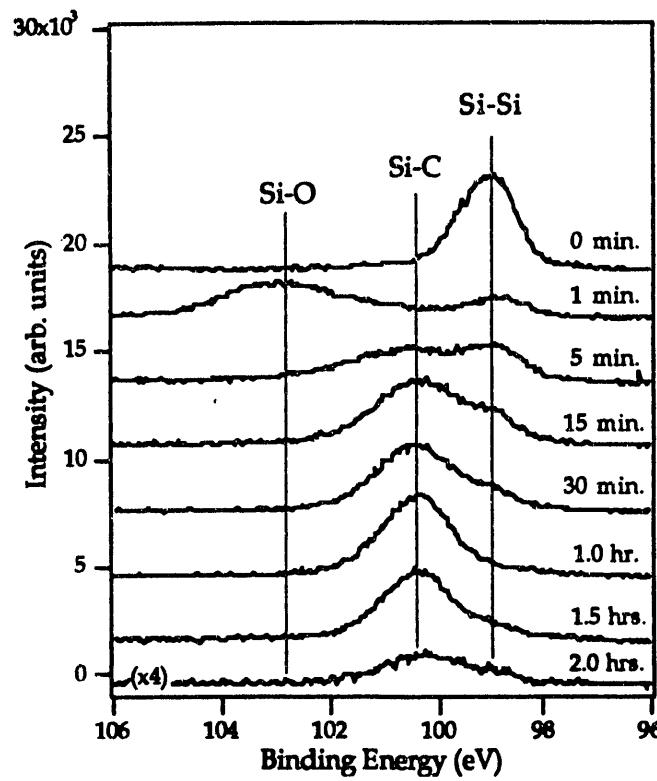
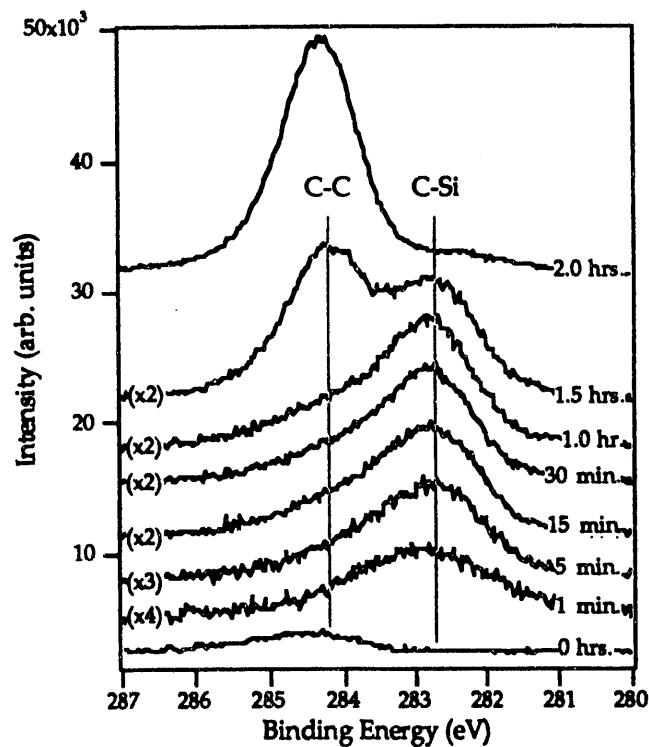
A CVD Chamber
B Analytical
C Transfer Tube
D Load Lock



Nucl. Density vs. Bias Time

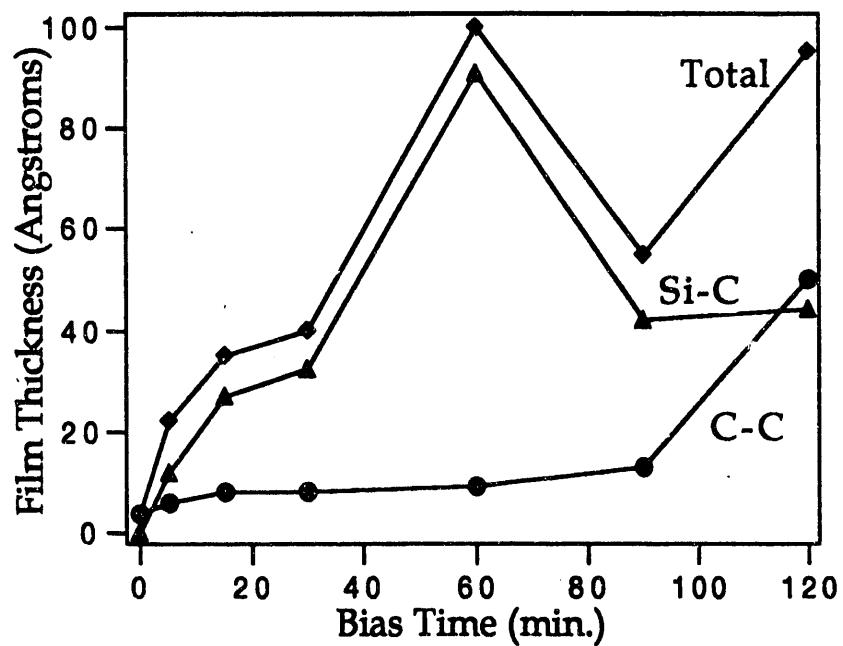


Surface Analysis During Biasing

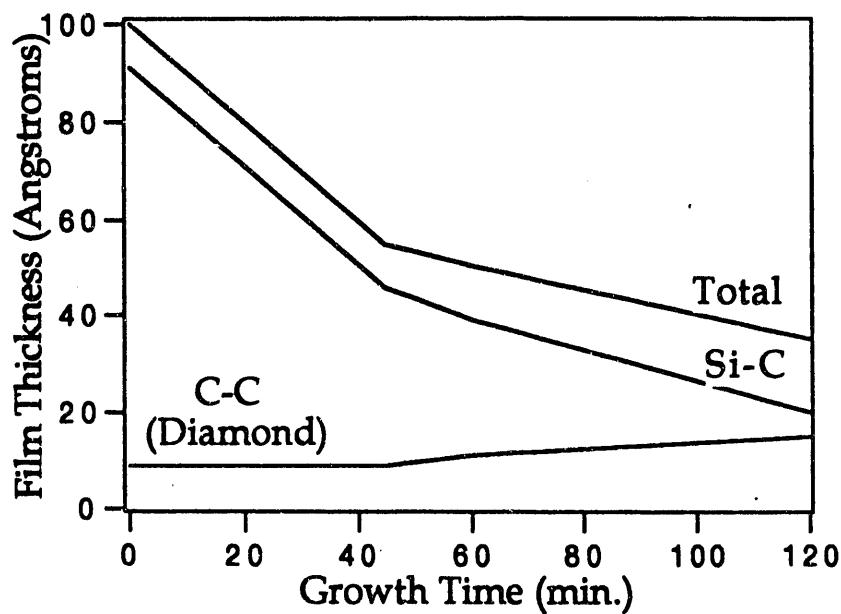


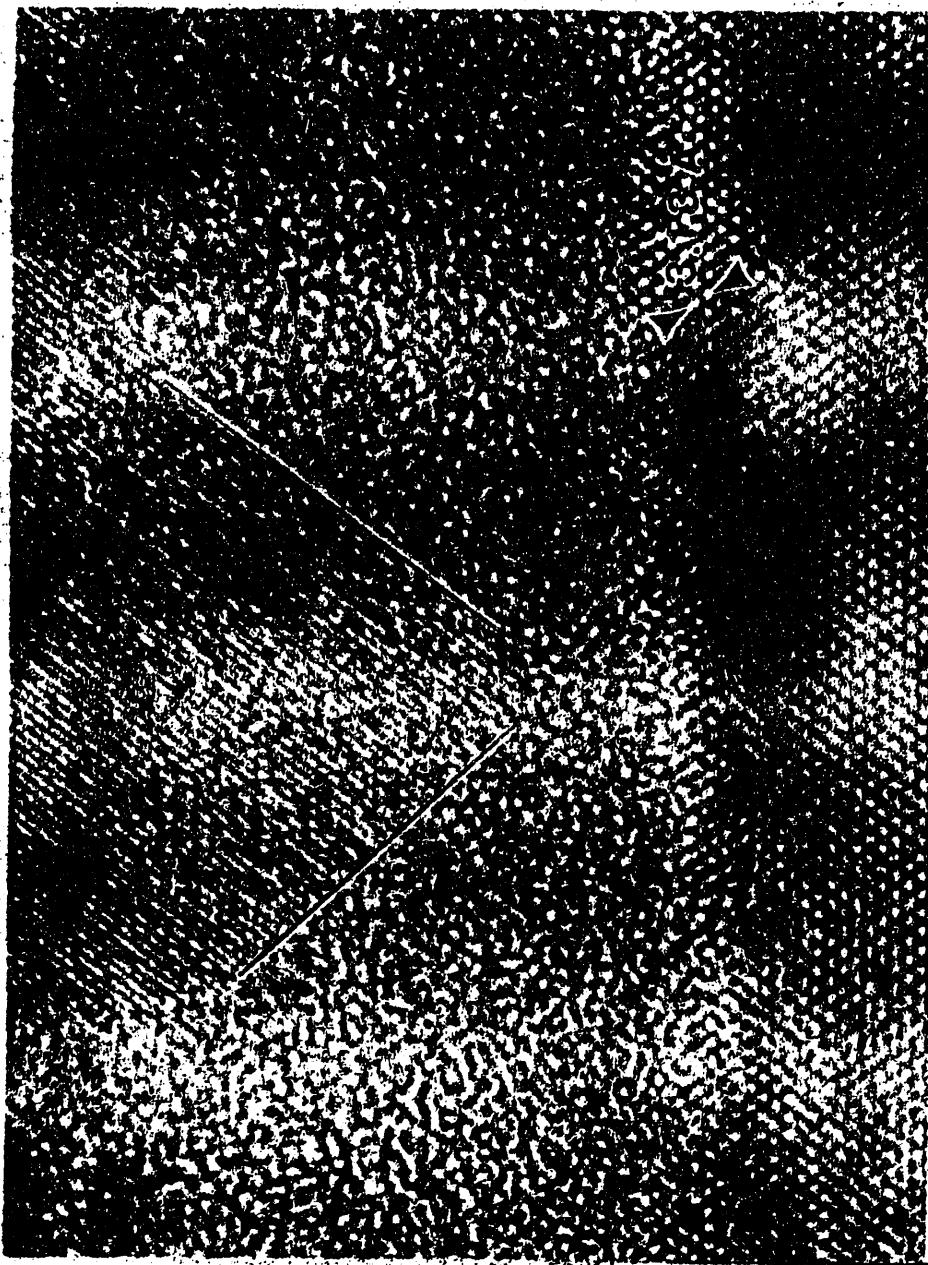
Calculated Film Thicknesses From XPS Peak Area Ratios

A: During Biasing Pretreatment

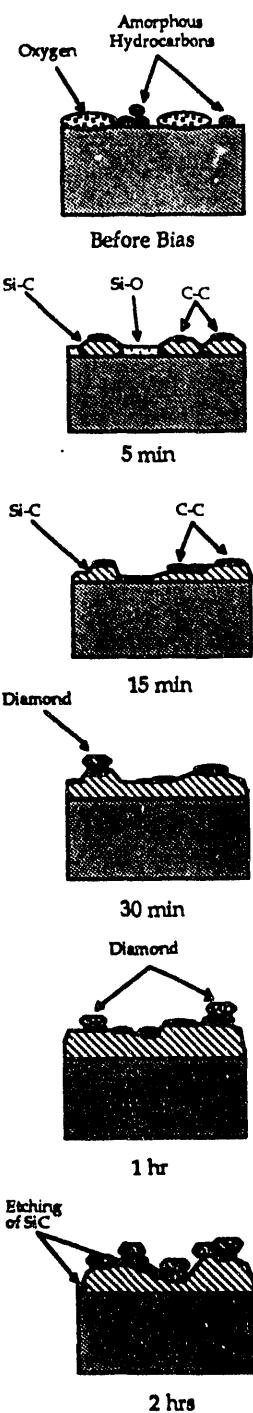


B: During Growth, After 1 hr. Bias





High magnification HRTEM showing an amorphous interfacial layer between the diamond and the silicon substrate.



Adsorbed oxygen and amorphous hydrocarbons on the substrate prior to biasing

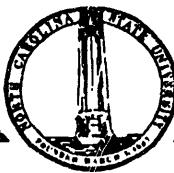
- Adsorbed carbon is either etched away or converted to Si-C.
- Physisorbed oxygen is converted into Si-O.
- C-C bonding is found on the surface of the Si-C.

- As biasing continues the oxide is etched away.
- Si-C islands continue to grow

- As local carbide islands reach critical thickness, excess carbon forms stable clusters.
- Some of the cluster become favorable for diamond nucleation.

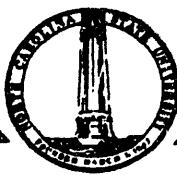
- As the rest of the carbide reaches critical thickness, more carbon becomes available to form diamond nucleation sites.

- As biasing continues, etching occurs, which allows diamond to nucleate closer to the Si surface.

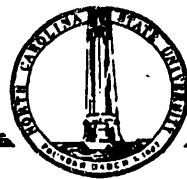
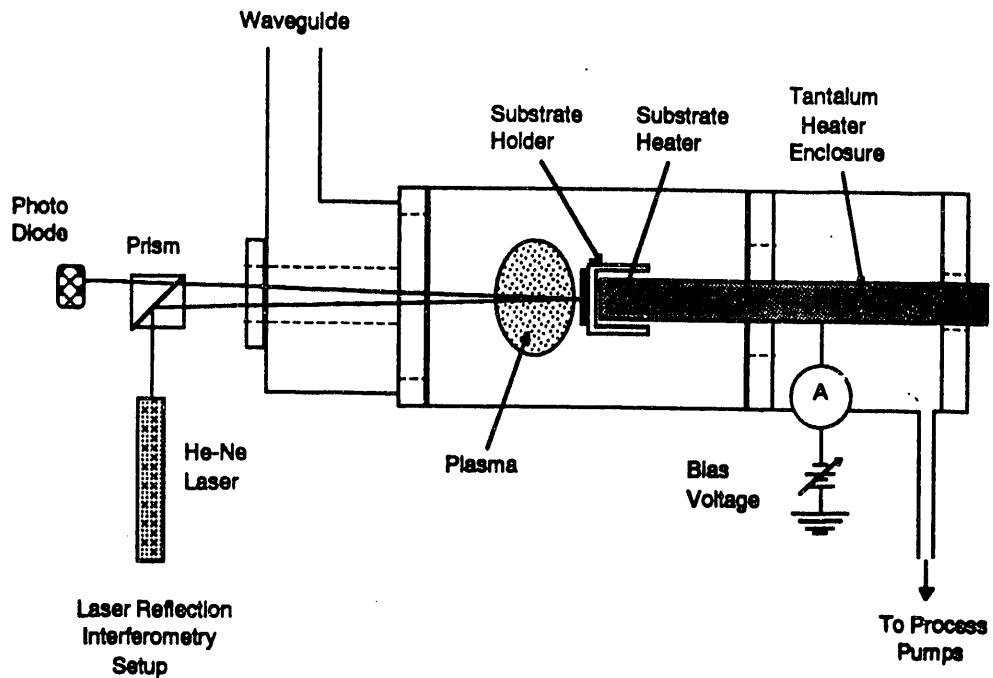


In Situ Analysis

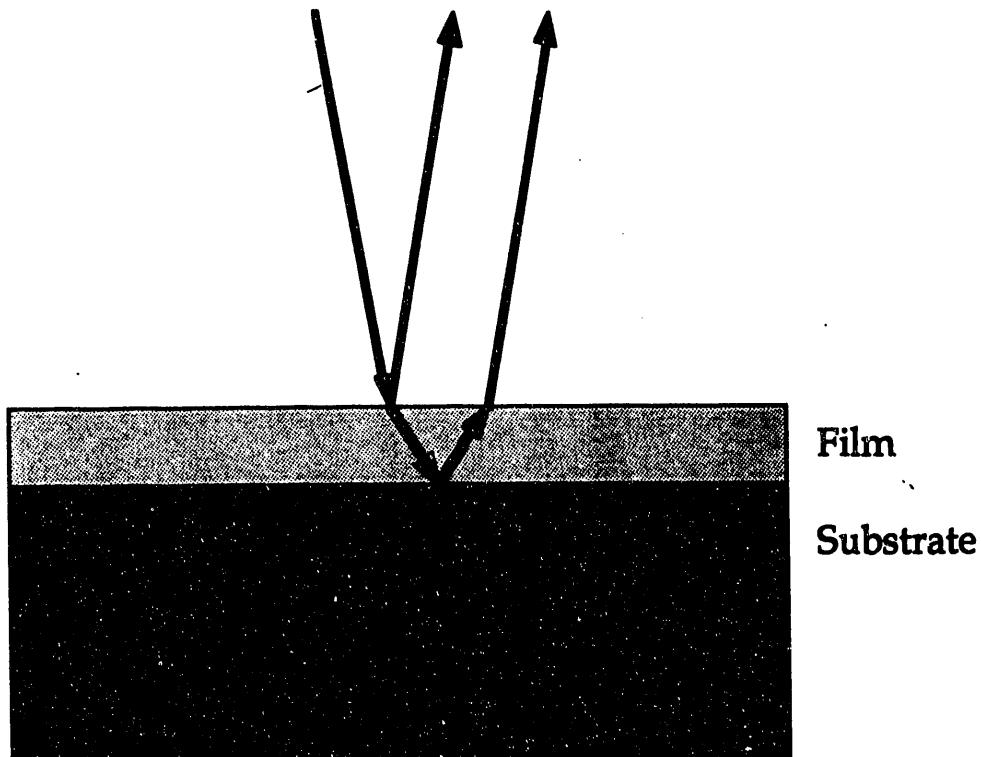
- LRI
- microbalance
- Ellipsometry
- IR absorption



MICROWAVE PLASMA CVD SYSTEM



LRI Theory



$$\text{Growth Rate} = (\lambda/2\eta)/T$$

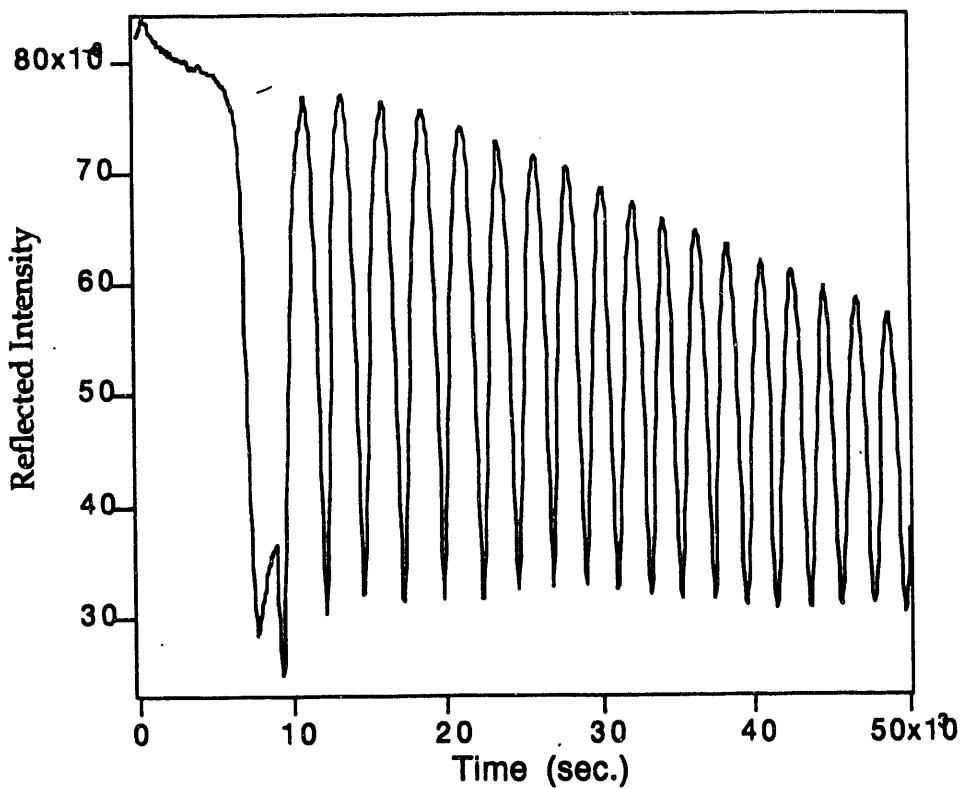
Where λ = laser wavelength

η = film refractive index

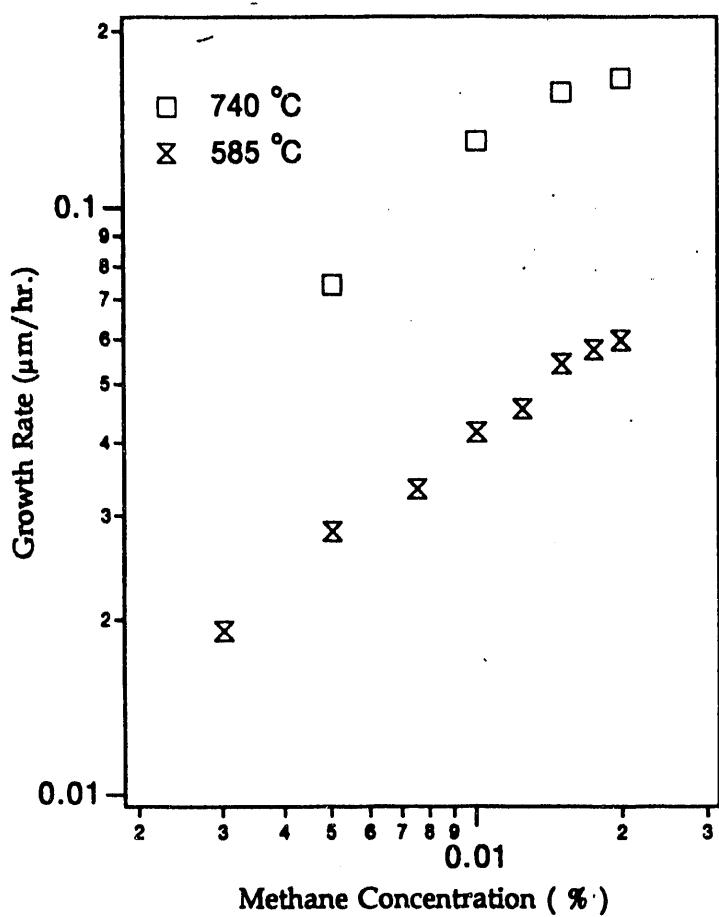
T = Period between interference cycles



LRI Scan



Growth Rate vs CH₄ Concentration



SUMMARY

- SEM & Raman Spectroscopy are the minimum techniques necessary (easy sample prep and relatively inexpensive)
- Strong correlations between surface morphology, defect density and Raman signal exist
- Various surface analysis techniques can be utilized and allow in-vacuo characterization of the growth process
- Quantification of nondiamond component is currently very difficult and needs further development
- True in-situ techniques are limited due to growth environment but are currently under development (LRI, Ellipsometry, ATR...)



**STRUCTURE AND PROPERTIES
OF
DIAMOND AND DIAMOND-LIKE FILMS**

R. E. Clausing

Metals and Ceramics Division,
Oak Ridge National Laboratory

Workshop

**on
DIAMOND FILMS FOR TRANSPORTATION
APPLICATIONS**

Sponsored by: DOE, Office of Transportation Technologies
and Argonne National Laboratory (ANL)
February 4-5, 1992

ornl

Structure and Properties of Diamond and Diamond-Like Films

- **Introduction**
- **Natural Diamond (The Standard)**
- **Importance of Structure and Composition**
- **Control of Structure and Properties**

SUMMARY

- Properties of CVD diamond films can compare favorably with natural diamond
- Properties are anisotropic, a strong function of structure and crystal perfection (including composition)
- Crystal perfection and morphology are functions of growth conditions and can be controlled.
- The manipulation of texture and thereby surface morphology and internal crystal perfection is an important step in optimizing CVD diamond films for applications.

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- The properties of DLC and CVD Diamond Films can be superlative
- The properties of DLC and CVD Diamond Films are strong functions of structure

Why Use Diamond?

- Hardness
- Strength
- Friction and Wear
- Thermal Conductivity
- Corrosion Resistance
- Optical Properties
- Electronic Properties
- Combinations of the Above

PROPERTIES OF DIAMONDS

- **Hardest Material:** Indentation Hardness of 14.2×10^6 psi
Scratch Hardness 10 on Mohs' scale
- **At Room Temperature Diamond is a Brittle, Elastic Solid**
Young's Modulus is 160×10^6 psi
(compared to Steels with 30×10^6 psi)
Theoretical Tensile Strength is $\sim 425,000$ psi
- **Low Coefficient of Friction of ~ 0.1 , Comparable to Many Lubricants**
- **Best Room Temperature Thermal Conductivity (20 W/(cm·K)) of Any Material**
- **Coefficient of Thermal Expansion is Low - 0.8×10^{-6} K $^{-1}$ (Room Temperature)**
- **Resistant to corrosion by All Acids, Even at High Temperatures.**
- **Transparent to Both Visible and IR Radiation**

SELECTED MECHANICAL PROPERTIES OF DIAMOND

Property	Value	Units	Note	Table Ref.
Elastic (Young's) modulus	1050.	GPa		1
	965.	GPa	Type Ia (nat.)	2
Bulk modulus	440.	GPa		1 (p. 8)
	440.-590.	GPa	Type IIa	3
Poisson's ratio	0.2	---	Type Ia (nat.)	2
	0.2	---	synth. polyxl.	2
	0.1-0.29	---	dep. on orient.	1
Tensile strength (theoretical)	190.	GPa	(<111> dir.)	1 (p. 285)
	2.94	GPa	(best value)	1
Shear strength (theor., <110> (111) system)	121.	GPa		1 (p. 285)
Compressibility	1.7×10^{-7}	cm^2/kg	Type IIa	3
Cleavage velocity	7.2	km/s		1 (p. 289)

References:

1. J. E. Field, ed., The Properties of Diamond, Academic Press, New York (1979).
2. R. M. Chrenko and H. M. Strong, "Physical Properties of Diamond," Gen. Electric Report #75 CRD 089, (1975).
3. W. G. Ebersol, U. S. Patents 3,030,187 and 3,030,188 (1962).

A COMPARISON OF THE ELASTIC MODULUS OF DIAMOND TO THAT OF OTHER MATERIALS

Material	E (GPa)*	(E _{diamond} /E)
Pyrex™ glass	70.	15.4
mild steel	206.	5.1
partially-stabilized zirconia	205.	5.1
titanium nitride	251.	4.2
α - silicon nitride	304.	3.5
α - silicon carbide	400.	2.6
titanium carbide	430.	2.4
α - alumina	380.	2.4

* Oak Ridge National Laboratory Datasheet on the Properties of Ceramics.

ELECTRICAL PROPERTIES OF DIAMOND EXCEED THOSE OF OTHER SEMICONDUCTORS

Excepting for electron velocity, the electrical properties of diamond exceed those of virtually all other semiconductors. Table I below provides the details.

Table I. Electrical Comparisons

Property	diamond	GaAs	silicon
Bandgap (meV)	5450	1430	1100
Hole mobility#	1800	400	600
Electron mobility#	2000	8500	1500
Resistivity (ohm-cm)	10^{16}	10^9	10^3
Breakdown (V/cm $\times 10^6$)	10	6	5
Dielectric constant	5.7	12.5	11
Work function (eV)	*	4.7	4.8
High field electron velocity (cm/sec $\times 10^7$)	2.7	1	1

$\text{cm}^2/\text{volt-sec}$

* 4.8 eV (p-type). Diamond is thought to exhibit a negative electron affinity on its (111) surface.

LISTING/UNDERSTANDING THE PROPERTIES OF BULK IIA DIAMOND IS NOT ENOUGH.

- Natural Diamond Properties Are Quite Variable
- Properties Vary With Crystal Direction
- Polycrystalline Diamond Behaves Still Differently
 - Sintered Compacts
 - Bonded Aggregates/Composites
 - CVD Films
- DLC Has Very Different Properties
 - a-C:H
 - a-C

DIAMOND FILMS AND DIAMOND-LIKE, HARD CARBON FILMS DIFFER SUBSTANTIALLY

DIAMOND	HARD CARBON
Crystalline	Amorphous
Hardness Material Known	0.1 Hardness of Diamond
Limited size (few cm ²)	Large Areas Possible
Thickness typically limited to <1mm	Thickness Limited to few μm
Growth Rate typically 1 $\mu\text{m}/\text{hr}$	Growth Rates of 10's $\mu\text{m}/\text{hr}$
Grown by Activated CVD	Grown by Plasma and Ion Techniques
Uniform Properties Possible	Variable Properties/Composition
Rapidly Moving Technology	Commercial Process

DEFINITIONS

- **Natural Diamond**
 - **Type I** - Impurity Absorption edge at 330 nm
 - **Ia** - Up to 0.3% Nitrogen Aggregated
 - **Ib** - Up to 0.05% Nitrogen in Single Substitutional Sites
 - **Type II** - Intrinsic Absorption Edge at 220 nm
 - **IIa** - Very Low Nitrogen, Insulator
 - **IIb** - Very Low Nitrogen, Semi-conductor
 - Contains Boron
 - **Mixed**
 - A Single Crystal May Contain Regions of Several Types

DEFINITIONS

- CVD Films
 - Long Range Order (Crystalline)
 - Crystalline Morphology
 - Faceted
 - Diffraction - Single Phase Diamond Structure
 - Raman - Narrow 1332 cm^{-1} Line
 - sp^3 Bonding
 - Currently Mostly Polycrystalline
 - Can Contain DLC Phase
- DLC Films
 - No Long Range Order
 - Mixed sp^2/sp^3 Bonding
 - a-C Films Contain Little Hydrogen
 - a-C:H Films Contain 16 a% to 60 a% Hydrogen
 - sp^3 Bonding Increases With Hydrogen Content
 - Reportedly Can Contain Crystalline Diamond Phase

HYDROGEN PROMOTES sp^3 BONDING

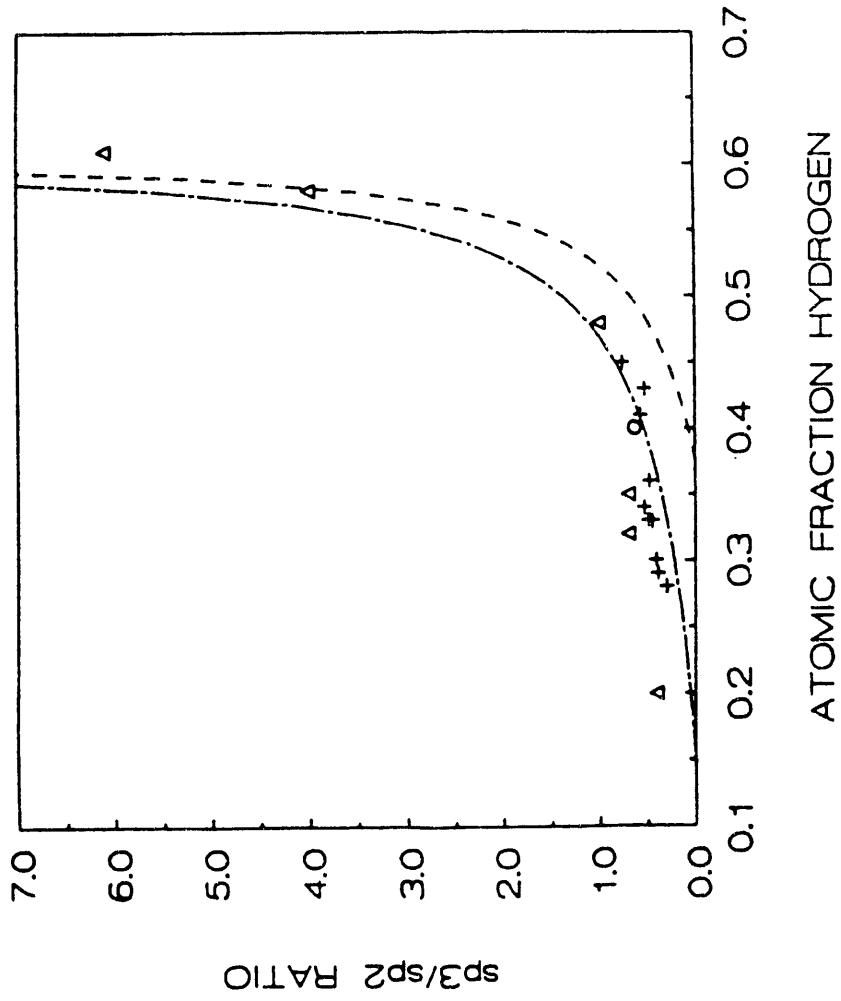


Figure 5

The ratio of sp^3 to sp^2 sites in a-C:H; The points labeled Δ are from reference (23), the point labeled \circ from reference (24) and the point labeled $+$ from reference (22). The first two were obtained from NMR measurements, the last one from analysis of the electron energy loss spectrum. The lines are the theoretical expressions for fully constrained, random hydrocarbon networks, i.e., equations (6) and (22). The right hand curve was derived assuming all sp^2 carbon atoms are present in single six-membered aromatic rings. The left hand was derived assuming the aromatic clusters contained 76 rings.

HYDROGEN PROMOTES sp^3 BONDING

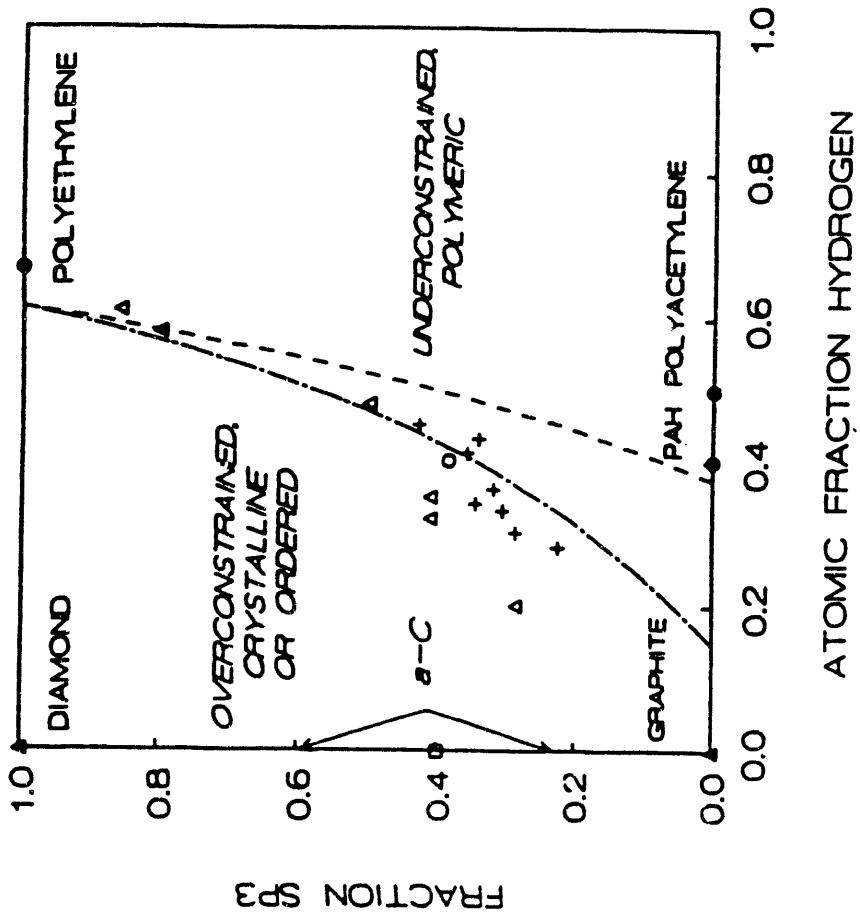


Figure 6
ATOMIC FRACTION HYDROGEN

Fraction of carbon atoms with sp^3 hybridization versus atomic fraction hydrogen. Conventional underconstrained (floppy) polymers are to the right of the lines. Overconstrained, crystalline or ordered solids are to the left. The data points are for hydrogenated diamondlike hydrocarbons (a -C:H). The points Δ and \circ were obtained by nuclear magnetic resonance²³ and the points $+$ by electron energy loss spectroscopy²¹. a -C refers to diamondlike carbons and PAH for polycyclic aromatic hydrocarbons. The point \square is for an a -C sample reported by Cuomo.⁴

CHARACTERISTICS OF DLC FILMS

- Tetrahedral bonding ,sp³, increases with hydrogen content
- Band gap and optical transmission increase with sp³ bonding/hydrogen content
- Hardness decreases with hydrogen content
- Hardest most dense films have least tetrahedral bonding
 - Hydrogenated (a-C:H) - 16-60 Atom % H
 - Density 1.4 - 2.0 g cm⁻³
 - Hardness 8 to more than 9 on the Mohs Scale
- Non-hydrogenated (a-C) - <1 Atom % H
 - Density up to 3.1 g cm⁻³
 - (Diamond = 3.51g cm⁻³, Graphite = 2.26 g cm⁻³)
 - Hardness reported to equal or exceed diamond

Why Use DLC Films?

- Hardness
- Abrasion Resistance
- Friction and Wear
- Corrosion Resistance (Inertness)
- Low Permeability
- Optical Properties
- Electronic Properties
- Large Area Films
- Very Smooth
- Cost
- Excellent Adhesion to Glass, Metals, Plastics etc.
- Adaptable to Manufacturing and Applications
- Combinations of the Above

Structure and Properties of Diamond and Diamond-Like Films

- **Introduction**
- **Natural IIa Diamond (The Standard)**
- **Importance of Structure and Composition**
- **Control of Structure and Properties**

Diamond Properties Depend On Structure

- Mechanical
- Thermal
- Corrosion
- Optical
- Electronic

EFFECT OF NITROGEN ON MECHANICAL PROPERTIES

**Strength, hardness, abrasion resistance of laboratory grade diamond
(after Chrenko and Strong²⁰)**

Diamond	Colour	Nitrogen/ ppm atomic	Cleavage/ pressure ^a /GPa	Hardness/ GPa	Abrasion resistance ^c
70	Yellow	70	20.3	95	0.84
12	Yellow	20	---	106	1.31
82	Pale green	~2	24.5	---	1.72
15	Colourless	~0.3	---	110	3.05
87	Pale green	~0.1	~30.0	131	3.11

- (a) Indentation on a (001) face with a spherical indenter
- (b) Vickers indenter on a (001) face, with the diagonals of the indenter parallel to <100> direction.
- (c) Grinding wheel test with 70 Al₂O₃ grit and with grinding ratio expressed as volume of wheel wear in m³ divided by weight of diamond lost in gm.

HARDNESS AS A FUNCTION OF CRYSTAL FACE AND INDENTER ORIENTATION

Knoop hardness (H_K) of diamond - GPa (after Brookes⁴⁸)

Plane	Direction	Type I	Type II
(001)	[110]	81.0	89.0
(001)	[100]	96.0	101.0
(110)	[110]	86.0	92.0
(110)	[001]	106.0	113.0
(111)	[110]	55.0	75.0
(111)	[112]	62.0	108.0

ABRASION RESISTANCE IS A STRONG FUNCTION OF CRYSTAL PLANE AND DIRECTION OF CUTTING

Depths of cuts made by bonded wheels, normalised to a depth of 10 ($\lambda/2$) in
the softest direction (Wilks and Wilks⁵⁴)

Plane and Direction

Plane	Dodecahedron (011)	Cube (001)	Octahedron (111)
Direction	[100] [011]	[100] [110]	[112] [112]
Depth of cut ($\lambda/2$)	10.0	1.8	8.5
		1.1	3.9
			2.1

ABRASION RESISTANCE IS A FUNCTION OF CRYSTAL PLANE AND DIRECTION

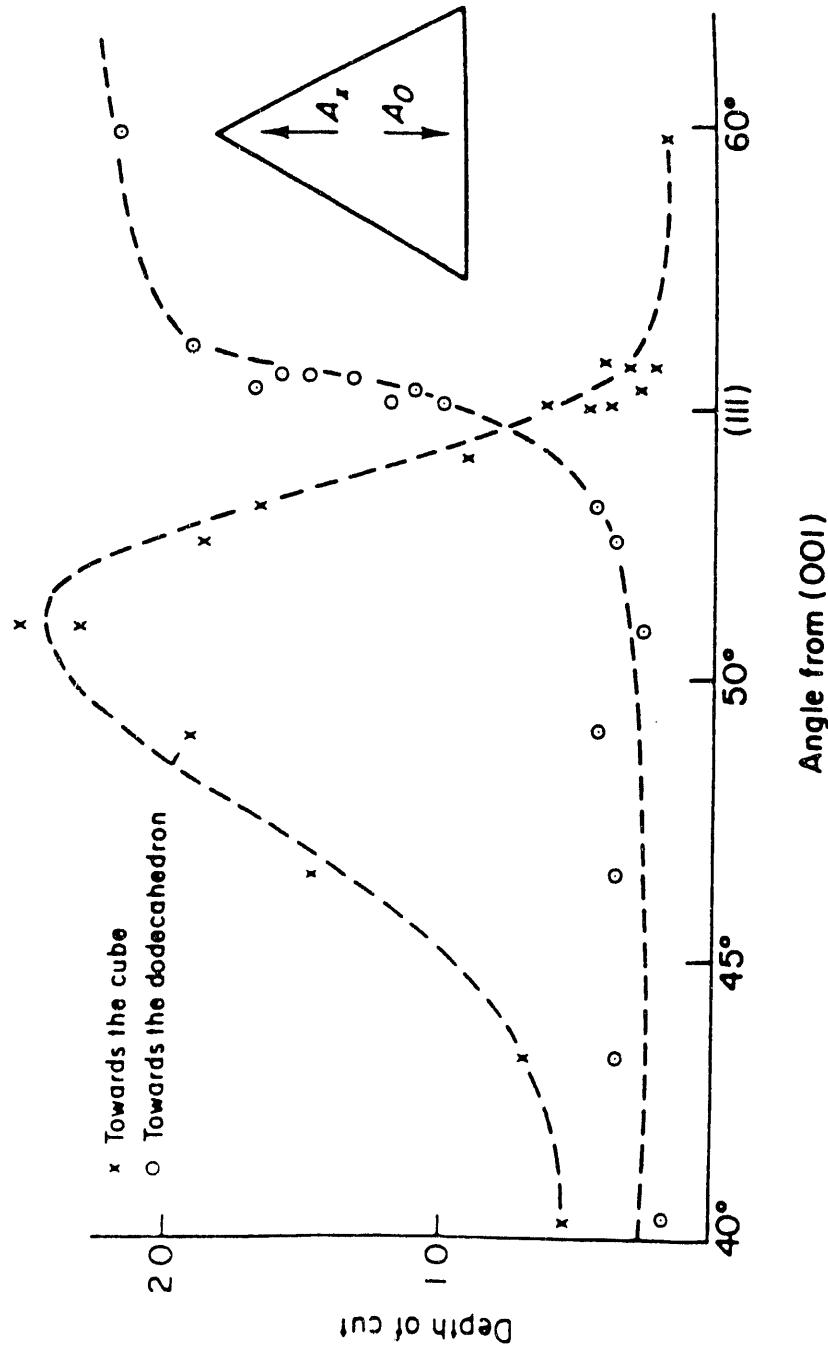


Fig. 11.1. The relative depths of cuts when abrading diamond facets near (111). The symbols o and x correspond to the directions shown in the inset.

CLEAVAGE ON {111} DOMINATES FRACTURE

Theoretical cleavage energy for diamond

Plane	Angle between plane and (111) plane	Cleavage energy/ J m ⁻²
111	0° and 70° 32'	10.6
332	10° 0'	11.7
221	15° 48'	12.2
331	22° 0'	12.6
110	35° 16' and 90'	13.0
322	11° 24'	13.4
321	22° 12'	14.3
211	19° 28'	15.0
320	36° 48'	15.3
210	39° 14'	16.4
311	29° 30'	16.6
100	54° 44'	18.4

Note: to obtain a fracture surface energy, γ , divide by 2.

Structure and Properties of Diamond and Diamond-Like Films

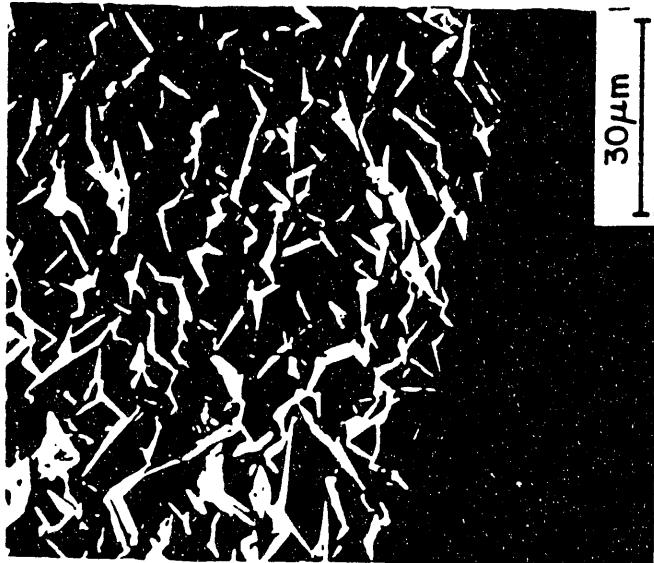
- Introduction
- Natural Ila Diamond (The Standard)
- Importance of Structure and Composition
- Control of Structure and Properties

PROPERTIES OF DIAMOND ARE SENSITIVE TO FILM STRUCTURE AND DEFECTS

- Structure Depends Strongly on Growth Conditions
- Mechanical and Physical Properties Correlate with Structure and Growth Conditions
- Films can be Designed and Grown for Specific Applications

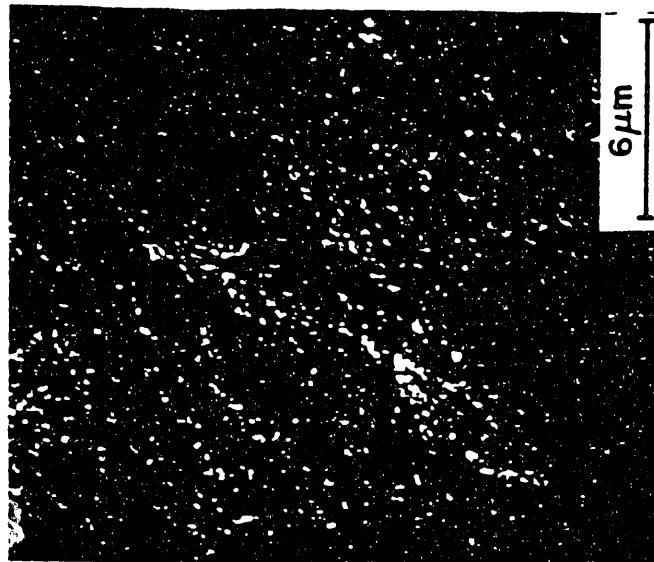
DIAMOND FILM MORPHOLOGIES

PYRAMIDS



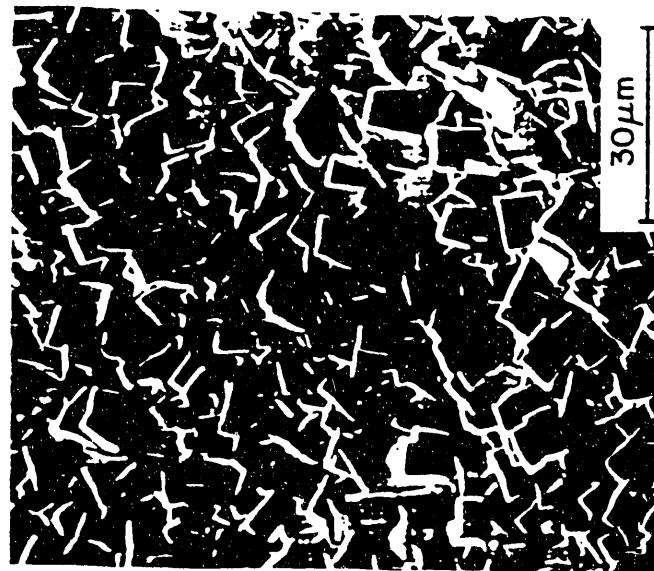
(a)

MICRO-CRYSTALS



(b)

PLATE-LIKE



(c)

omnl

DATA FOR SAPPHIRE SLIDERS ON DIAMOND FILMS

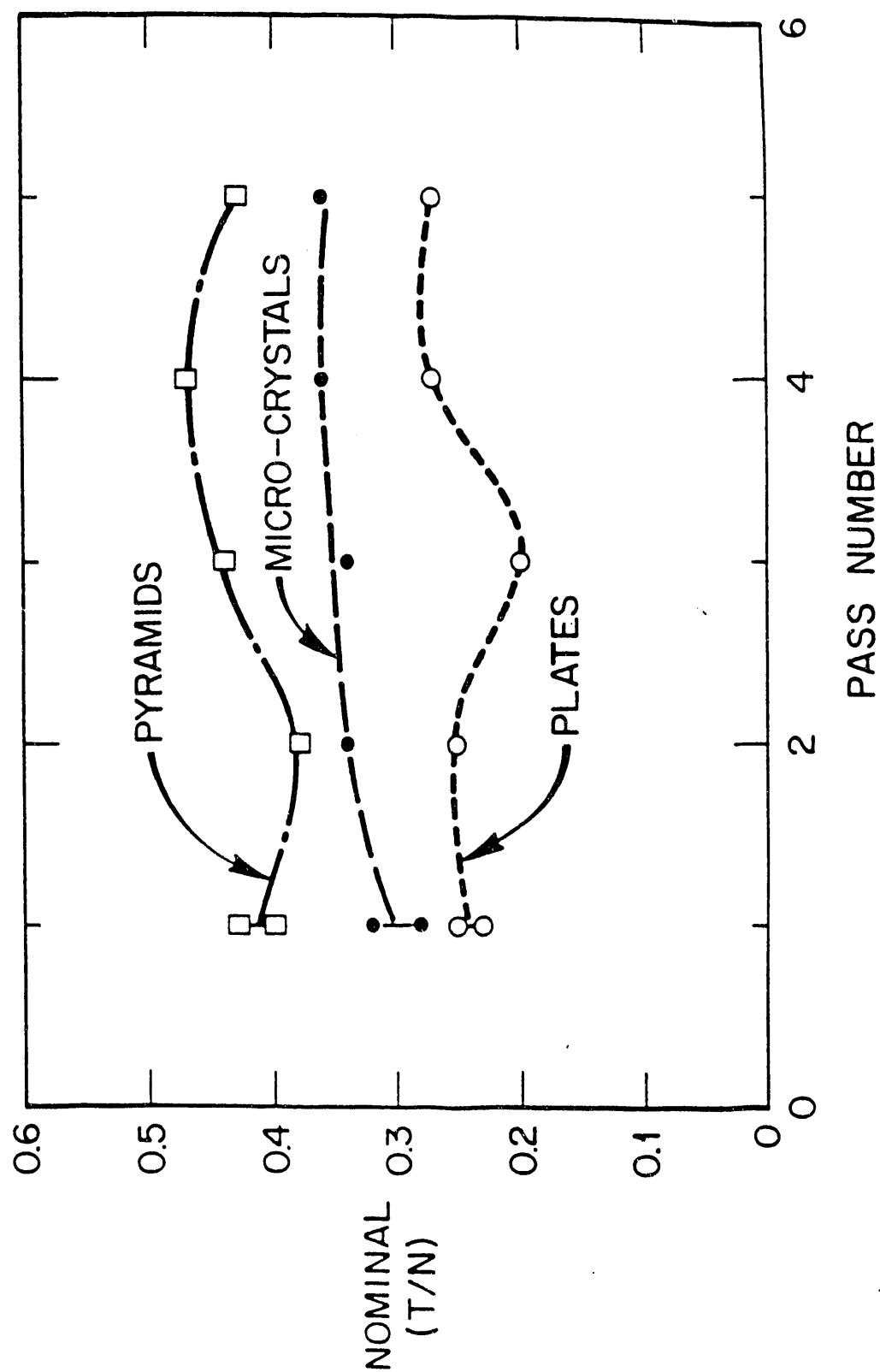




Figure 7. Scanning electron micrograph of a steel cutting chip removed as a steel ball slid against a diamond film with sharp facets.

FRICITION COEFFICIENTS OF DIAMOND AND DLC FILMS

Single Crystal IIa

- Typically 0.5 to 0.15, Except in Vacuum or at High Temperature

CVD Diamond Films

- After some Wear (Wong et al)
Blocky, $<100>$ 0.3>0.16 0.2
Pyramidal, $<110>$ 0.04> 0.11 0.035
Microcrystalline 0.04 0.035

DLC Films - Both a-C:H and a-C

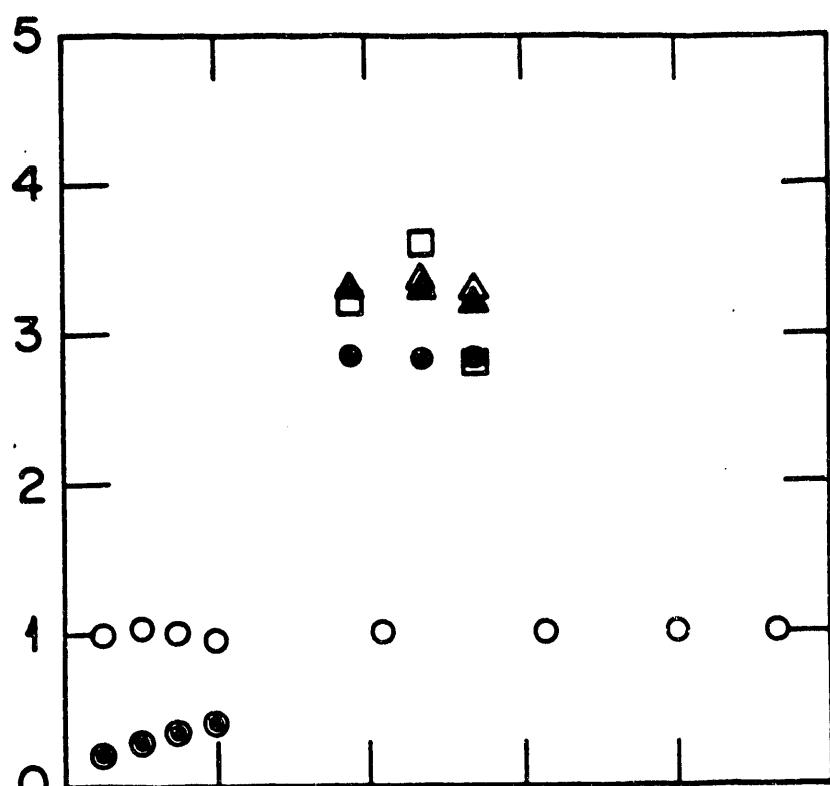
- Reported Values Range From 0.01 to 0.3, (Typically 0.1 to 0.2)
- Friction Coefficients Increase with High Humidity to 0.3 or 0.4
- Films Alloyed with Si Gave Values Near 0.05
- One Report W/O Data Said That Coating "Moving Parts Inside Automotive Engines" With DLC "Successfully Reduced Wear Rates"

Note: All above results depend on details of the test and materials

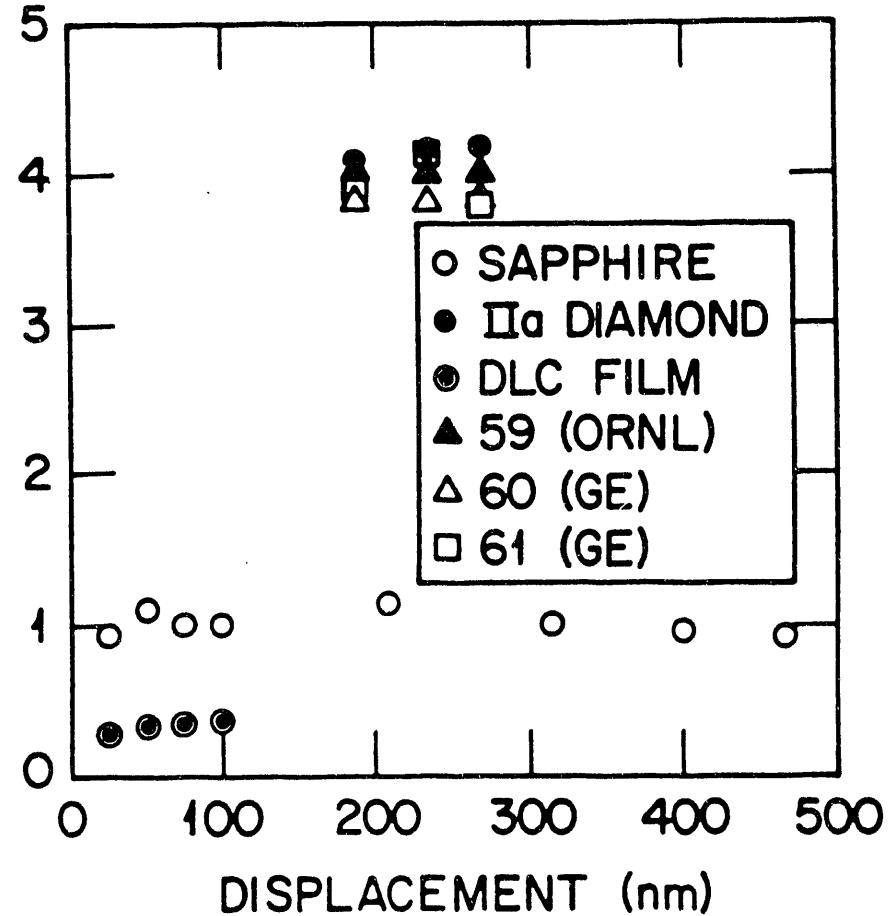
SOME OBSERVATIONS ON FRACTURE OF DIAMOND FILMS

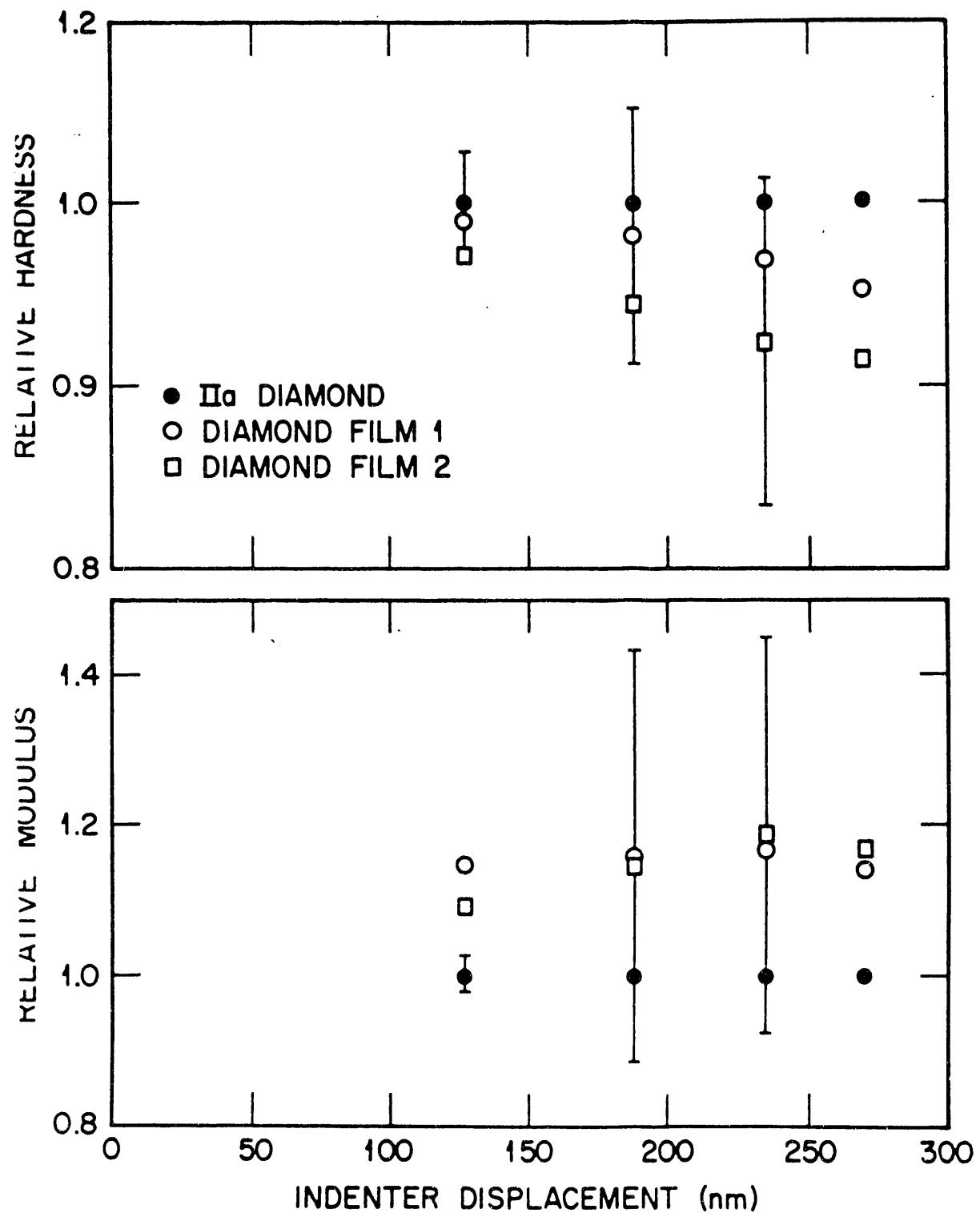
- CVD Films Usually Fail Transgranularly Implying Strong Grain Boundaries
- Torch Grown Films Usually Fail Intergranularly Implying Weaker Grain Boundaries
- Cracks in Polycrystalline CVD Films Branch Suggesting That They May Be Tougher Than Single Crystals
- Microcrystalline CVD Films Are Slightly Softer and Deform Slightly in Indentation Tests Suggesting That They May Be Tougher Than Coarser Grained Polycrystalline CVD Films

RELATIVE MODULUS



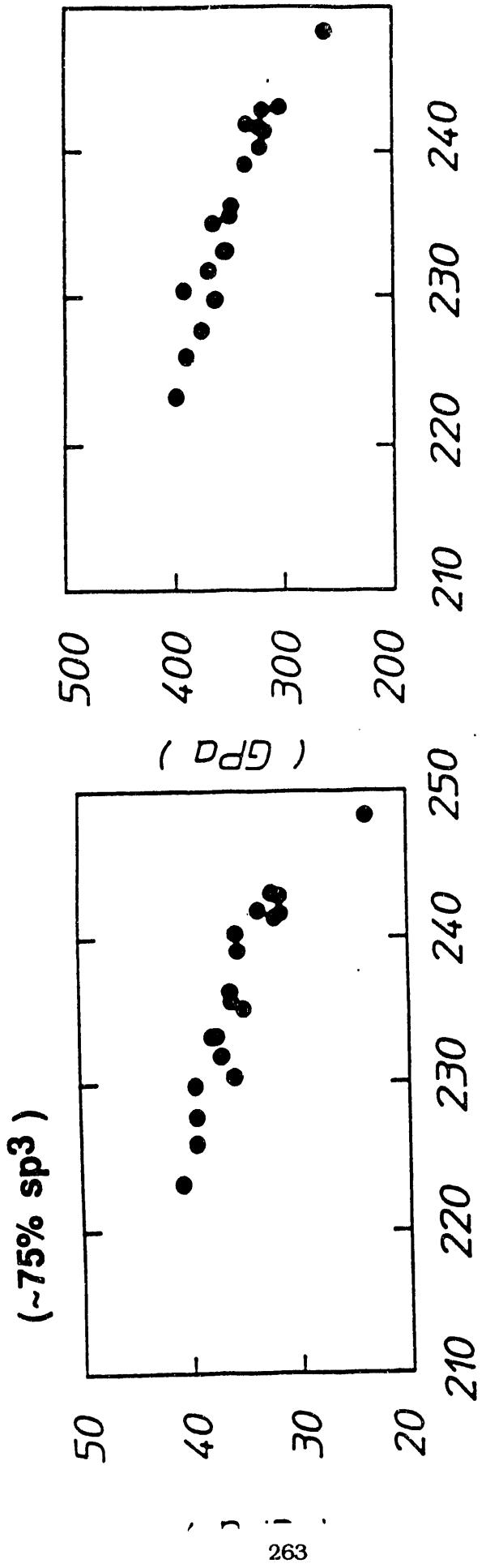
RELATIVE HARDNESS





"MICROCRYSTALLINE"

- Mixture of diamond and other bonding types



Displacement (nm)

Hardness = 37 GPa

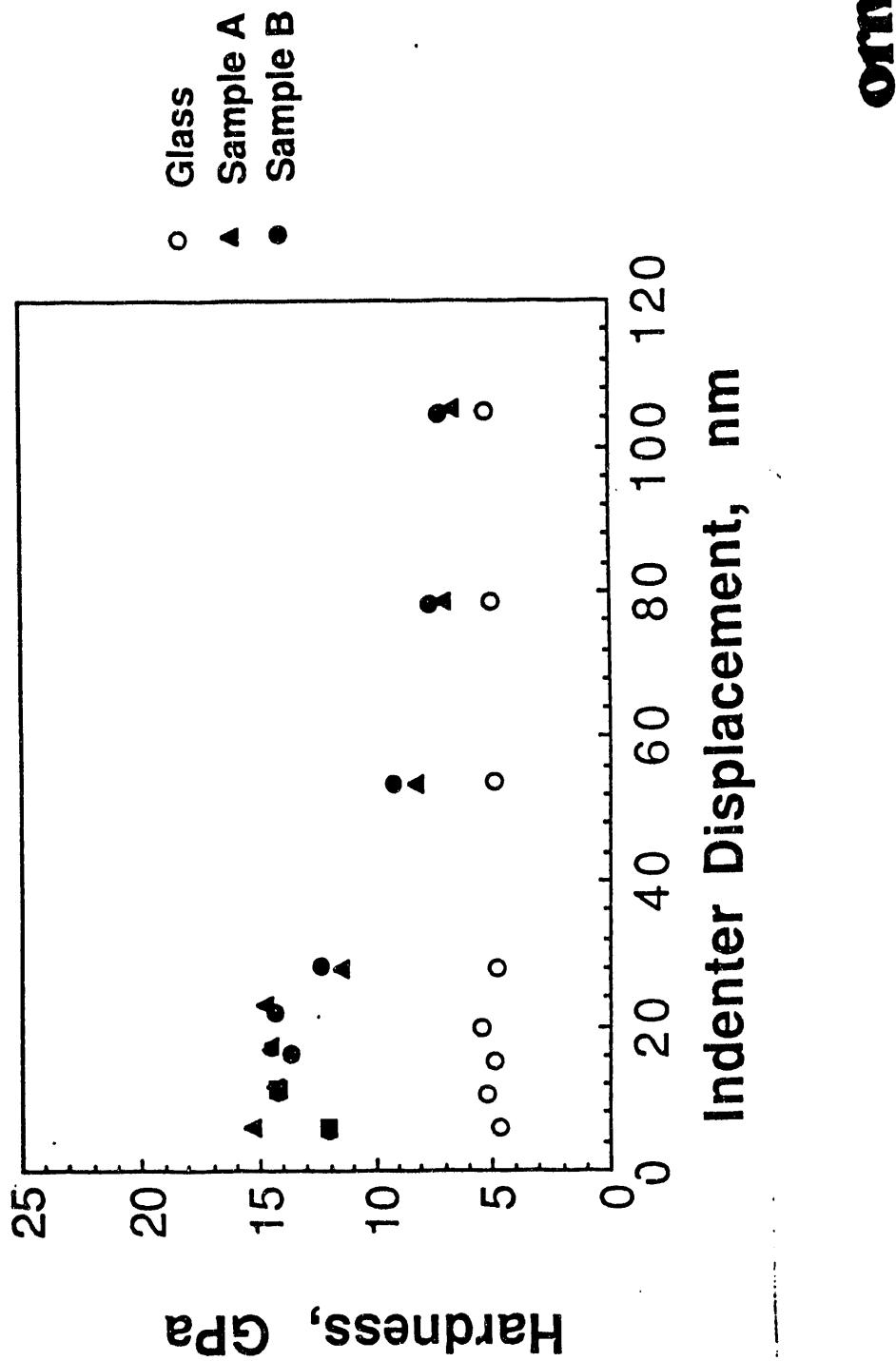
(Collins et al)

Displacement (nm)

Elastic Modulus = 370 GPa

THIN FILMS: DEPTH OF INDENT RELATIVE TO FILM THICKNESS

- Softer substrate - HCC on glass

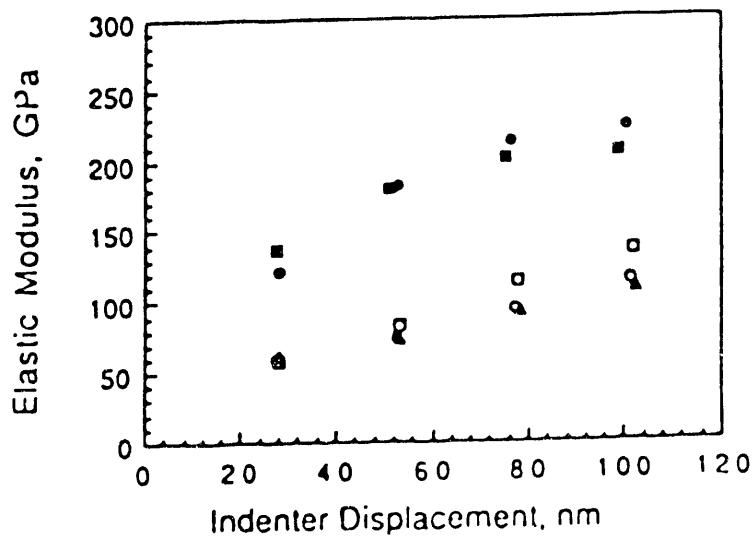
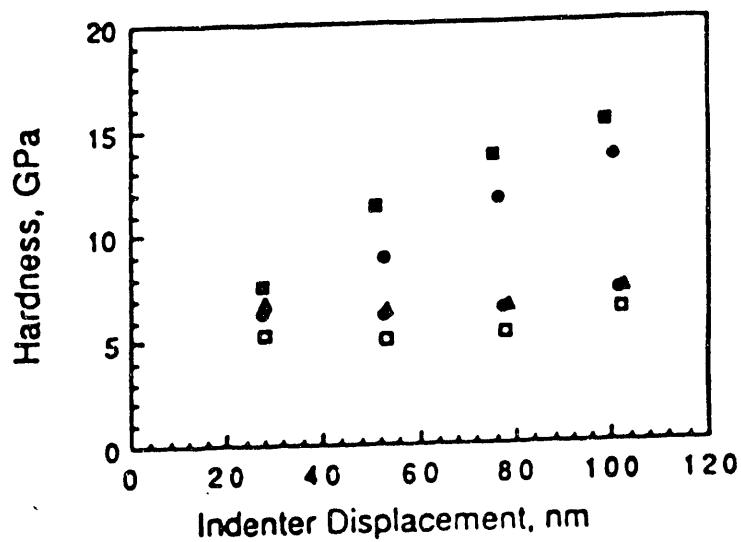


Adherent films

- DLC 10 (sapphire)
- DLC 11 (ALON)

Non-Adherent films

- DLC 2 (sapphire)
- ▲ DLC 4 (sapphire)
- DLC 5 (sapphire)



**RESULTS FOR
DLC FILMS**

"HCC" FILMS

HARDNESS (GPA)

5

10

15

37

370

ELASTIC MODULUS (GPA)

40 - 60

100 - 120

130 - 170

MICROCRYSTALLINE MIXTURE

SUMMARY

- DLC FILMS
- Substrate properties affect measurements

Film adherence affects measurements

Hardness = 5 - 15 GPa

Elastic modulus = 40 - 170 GPa

- DIAMOND FILMS

"Hardness" is same as Type IIa (100)

Elastic Modulus = 1280 GPa = Type IIa

GROWTH CONDITIONS CHANGE STRUCTURE AND THERMAL CONDUCTIVITY

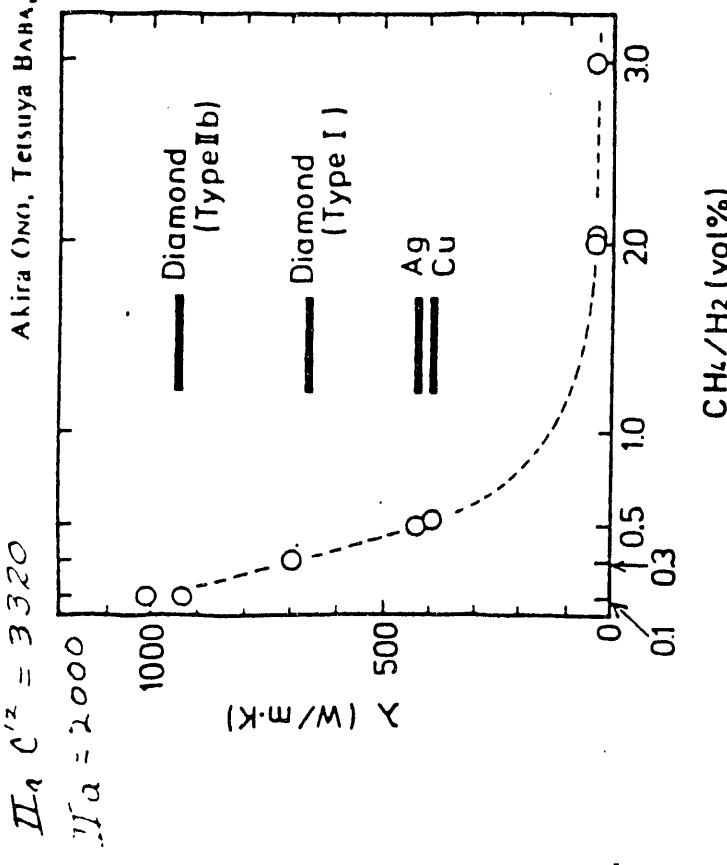


Fig. 3. Thermal conductivity of diamond films for different methane concentrations.

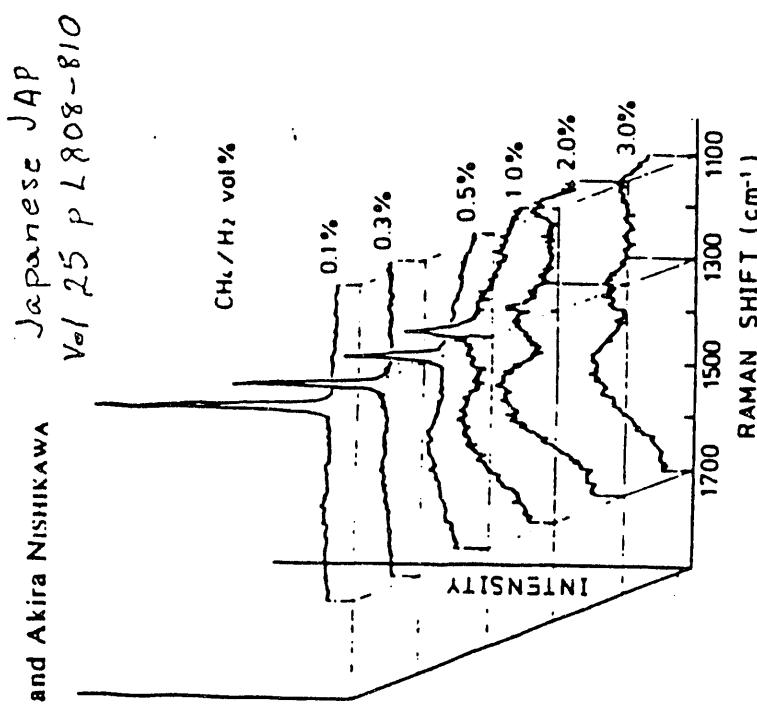
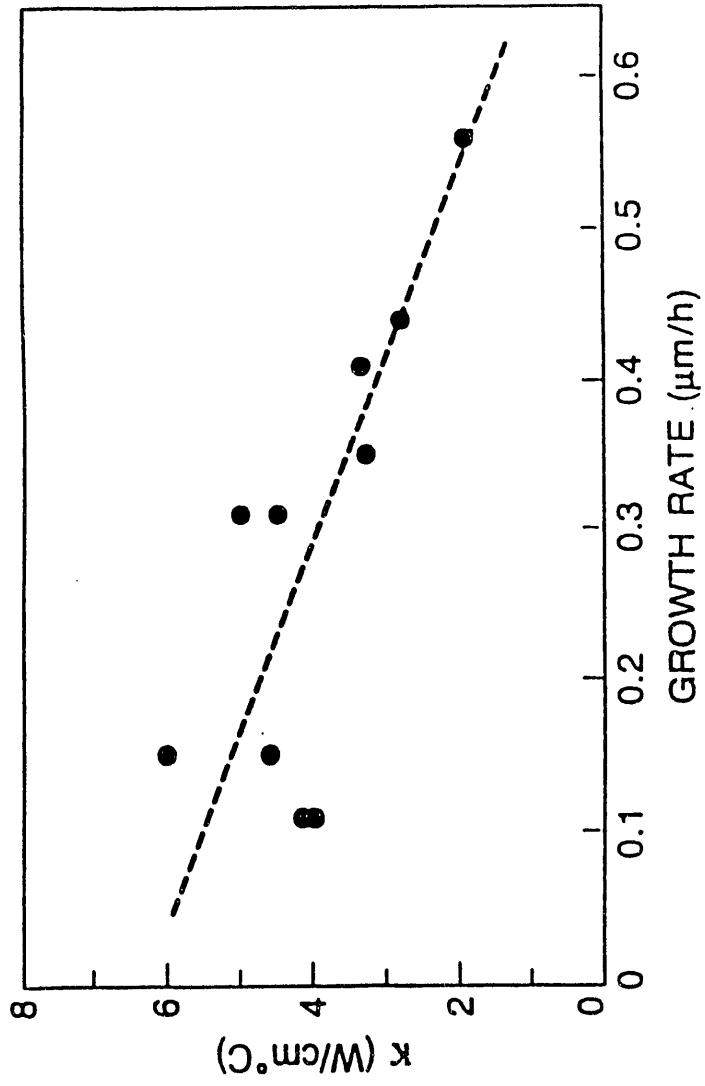


Fig. 4. Raman spectra of diamond films for different methane concentrations.

GROWTH CONDITIONS CHANGE STRUCTURE AND THERMAL CONDUCTIVITY



To BE PUBLISHED IN
JOURNAL OF APPLIED PHYSICS
The Thermal Conductivity of CVD Diamond Films on Silicon

J. E. Graebner

J. A. Mucha

L. Seibles

G. W. Kammlott

AT&T Bell Laboratories
Murray Hill, NJ 07974

CON 1W22449 03

THE THERMAL CONDUCTIVITY IS BETTER FOR FILMS WITH A NARROW 1332 CM⁻¹ RAMAN LINE

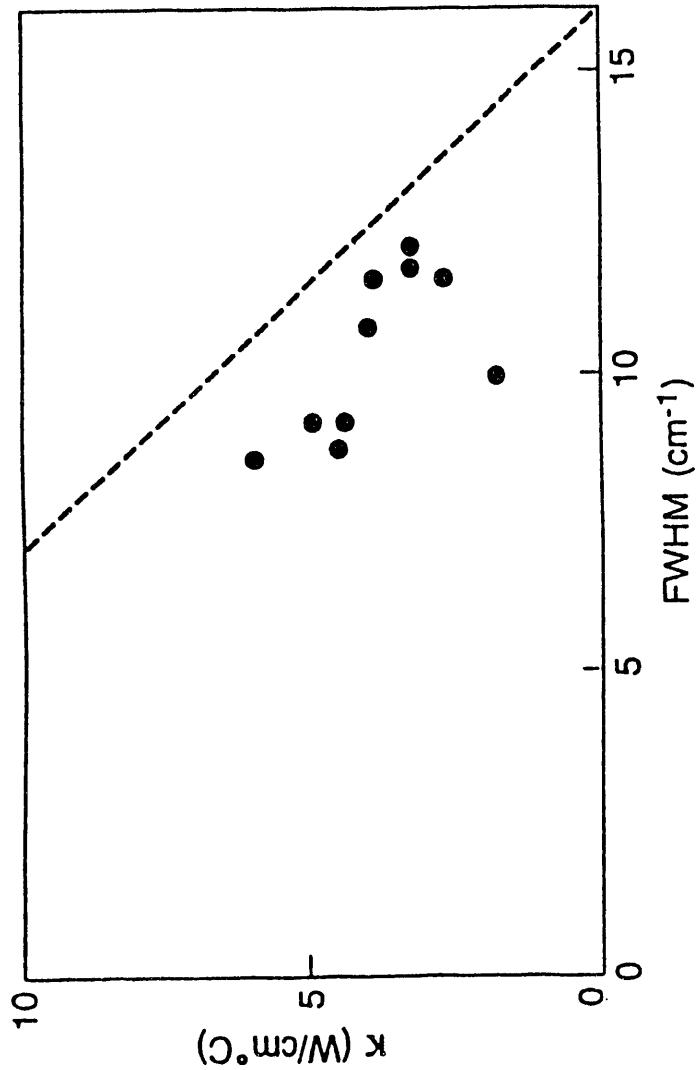
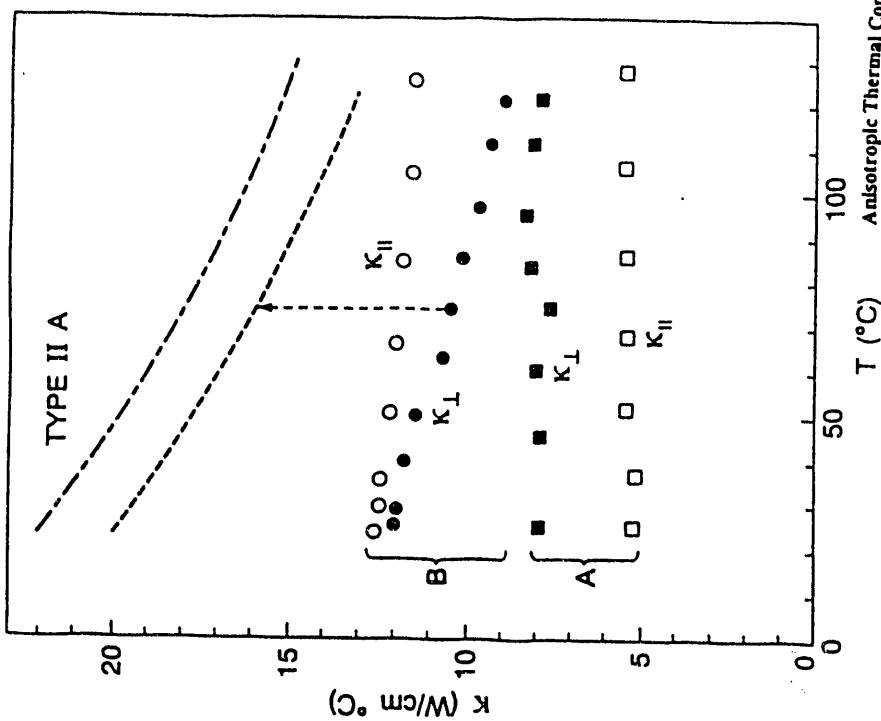


Figure 4. Thermal conductivity $\kappa(T = 25^\circ\text{C})$ vs. linewidth $\Delta\nu$ of the diamond-like Raman line at 1332 cm^{-1} for the CVD films listed in Table 1. The dashed line is to be published in *Journal of Applied Physics*.

To be published in
Journal of Applied Physics
"The Thermal Conductivity of CVD Diamond Films on Silicon
J. E. Graebner
J. A. Mucha
L. Seibles
G. W. Kammlott
AT&T Bell Laboratories
Murray Hill, NJ 07974

THERMAL CONDUCTIVITY OF DIAMOND FILMS CAN BE DIRECTIONAL BECAUSE OF STRUCTURE



in the text
conductivity of sample B is given by a dashed line, based on a model described
Type IIa diamond (Ref. 13) is shown by the dot-dashed line. The intrinsic
given by open symbols, perpendicular by closed symbols. As for single-crystall
The thermal conductivity for heat flowing parallel to the plane of the film is
Fig. 5 Thermal conductivity vs. temperature for samples A (squares) and B (circles).

5

Fig. 5 Thermal conductivity vs. temperature for samples A (squares) and B (circles).

J. E. Graebner

S. S. Jin

G. W. Kammlott

B. Bacon*

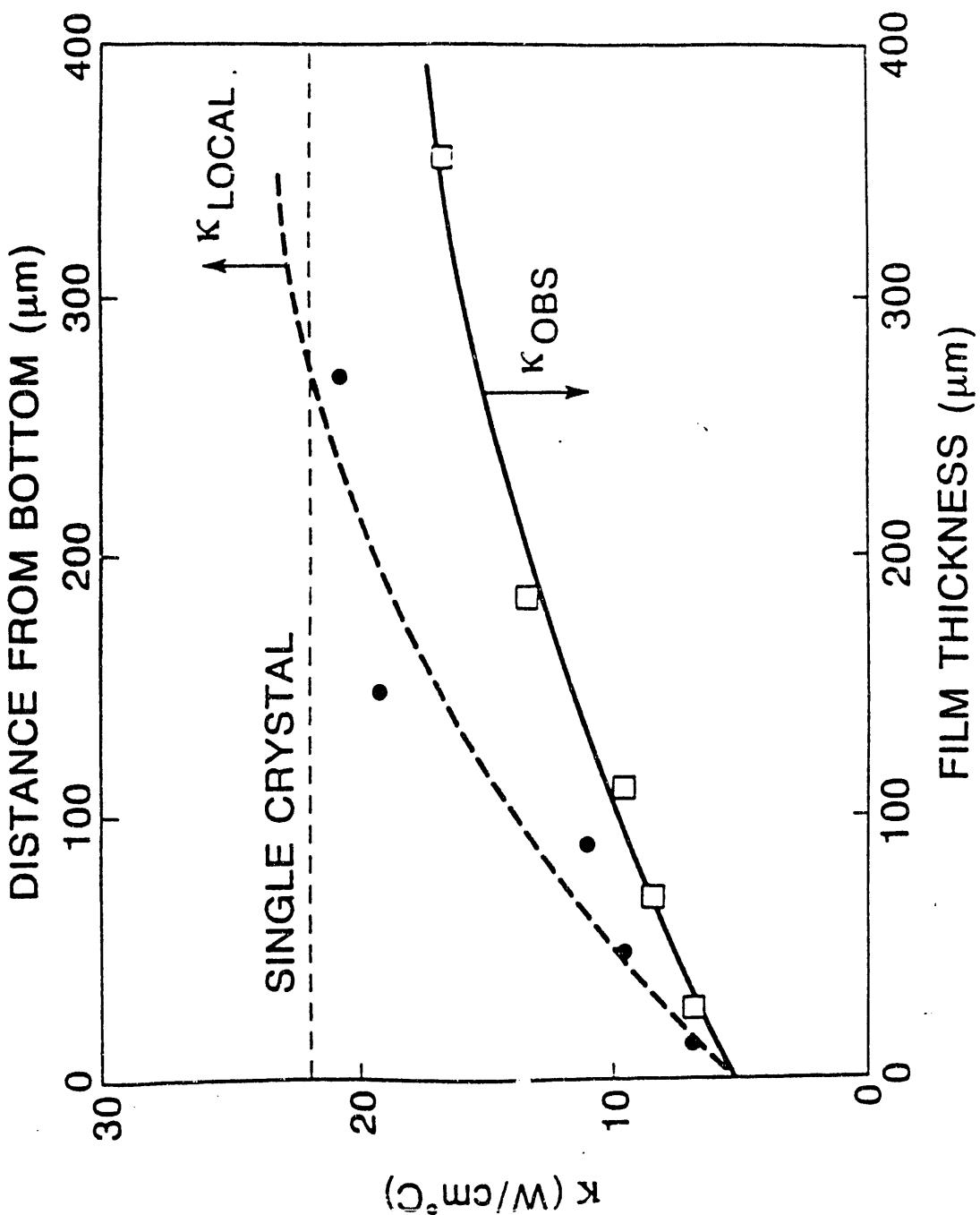
L. Sribles

AT&T Bell Laboratories
Murray Hill, New Jersey 07974

W. Bartholzer
General Electric Research Center
Schenectady, N.Y.

Thermal Conductivity of Diamond Films Can Be a Function of Thickness When the Structure Changes with Thickness

Typical conductivity reported for single-crystal high-quality (Type IIa) of position in the sample (Eq. 3). The horizontal dashed line indicates the data. The dashed curve is the derived local conductivity κ_{local} as a function line through the κ_{obs} data is a 3-term polynomial (Eq. 2) least-squares fitted to local conductivity as derived according to Eq. 2 is shown by solid circles. The measured thermal conductivity κ_{obs} at 25°C for five samples (squares). The



EFFECT OF GRAIN SIZE ON THERMAL CONDUCTIVITY

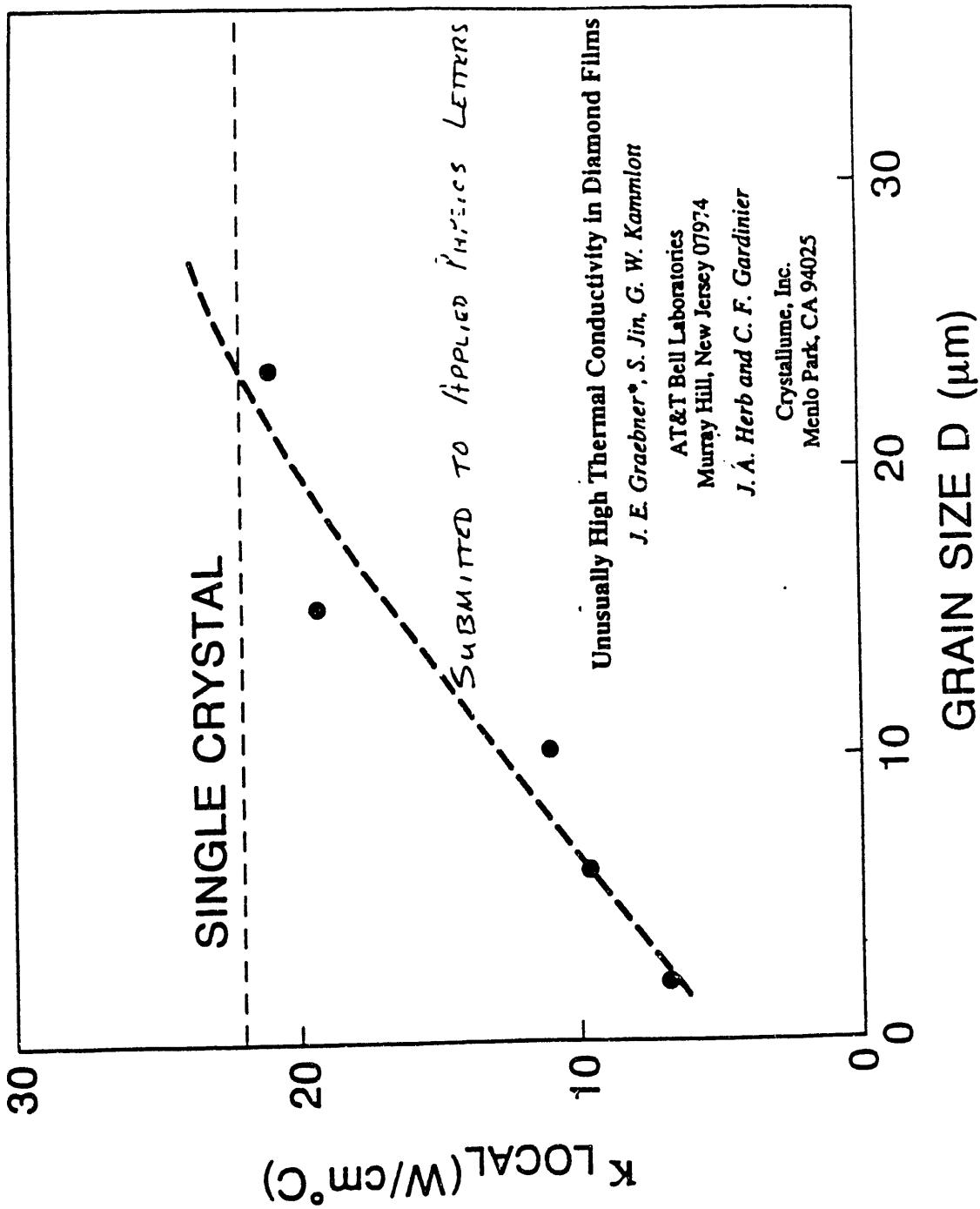


Fig. 5

SOME OBSERVATIONS ON OXIDATION OF DIAMOND FILMS

Single Crystal IIa

- Begins to be Significant at 700 C in air or Oxygen
 - (100) 0.15×10^{-4} mm min^{-1}
 - (110) 0.8×10^{-4} mm min^{-1}
 - (111) 01.5×10^{-4} mm min^{-1}
- Field p405

CVD Diamond Films

- Depends on Structure -- Consistent With Single Crystal Data
 - for Good Quality Films
 - Microcrystalline Films Oxidize Much More Rapidly (Usually Contain sp^2 material)

DLC Films - Both a-C:H and a-C

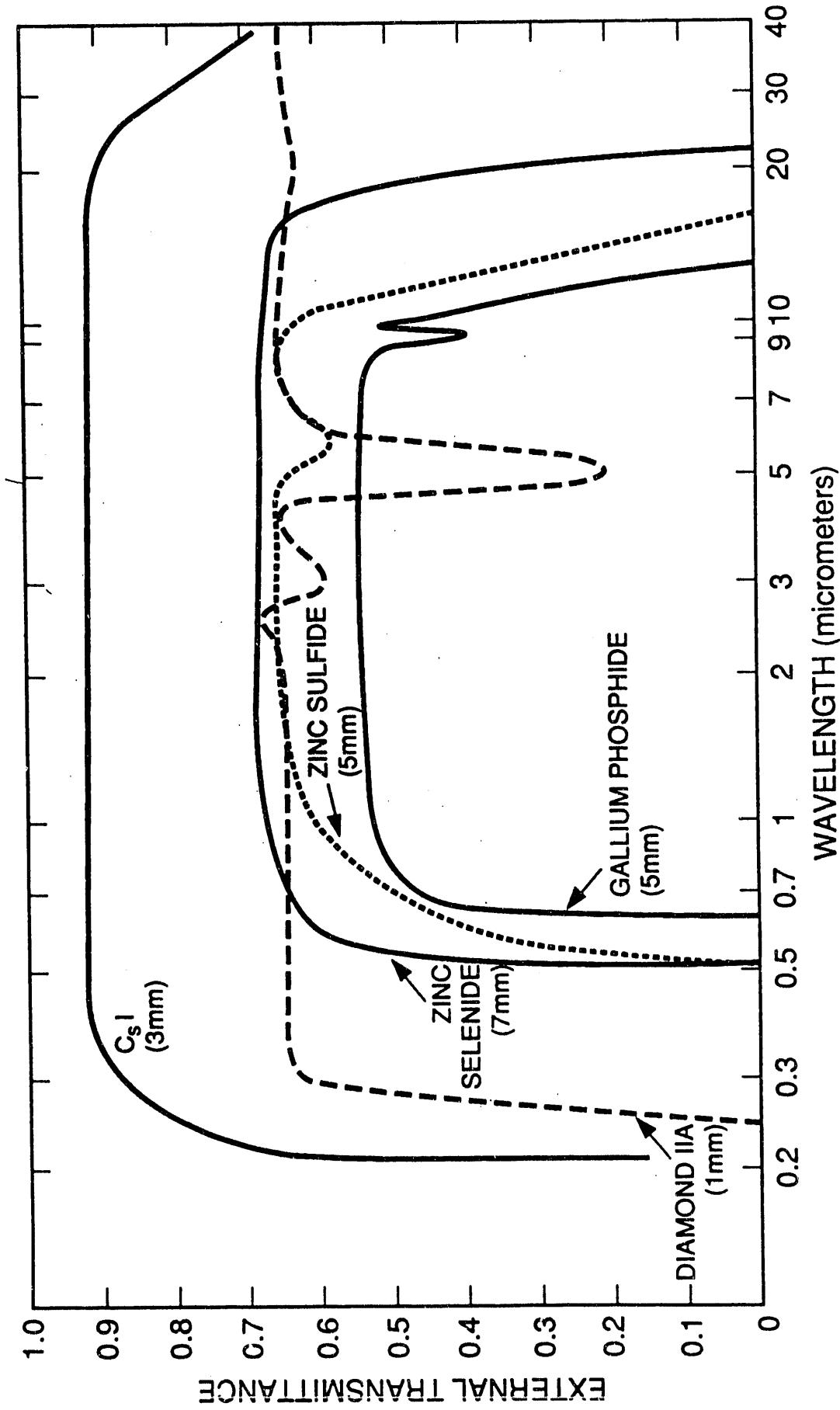
- a-C:H Loses Hydrogen and Decomposes Above 400 C
 - Estimated to be 10 Times Faster Than CVD Films

Oxygen Plasma Etching seems to follow qualitatively in the same order

Structure and Properties of Diamond and Diamond-Like Films

- Introduction
- Natural Ila Diamond (The Standard)
- Importance of Structure and Composition
- Control of Structure and Properties

TRANSMISSION SPECTRA OF BROAD BAND INFRARED OPTICAL MATERIALS



Structure and Properties of Diamond and Diamond-Like Films

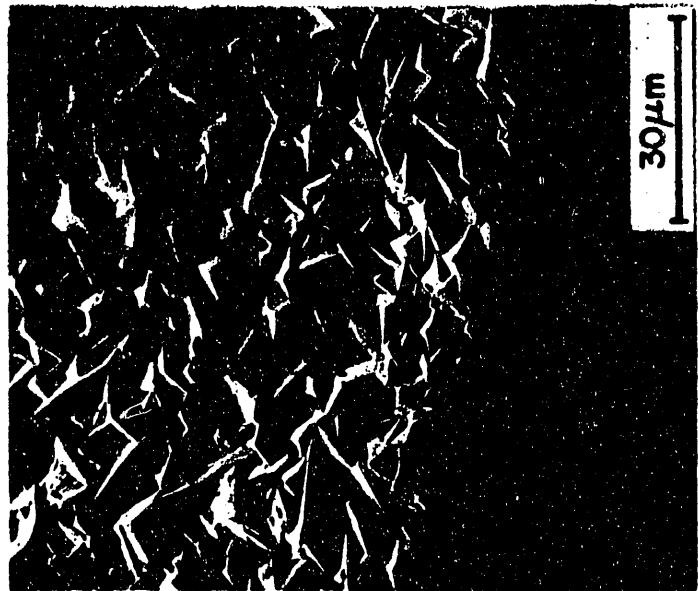
- **Introduction**
- **Natural Ila Diamond (The Standard)**
- **Importance of Structure and Composition**
- **Control of Structure and Properties**

Control of Structure and Properties

- Evolution of Microstructures
 - Amorphous
 - Microcrystalline
 - Torch Grown - Porous Material
 - Uniform Non-textured Fine Grained Material??
 - Mixed Size Equiaxed Grains
 - Columnar Textured Structure
 - Van der Drift
 - Homoepitaxial Crystals
 - Heteroepitaxial Crystals
 - Adhesion/Interfacial Properties
 - Planar
 - Chemical Bonding
 - Cobalt Problem
 - Thermal Coefficient of Expansion
 - Brazing
 - Sintering??
 - Mechanical
 - Uniformity and Quality Control

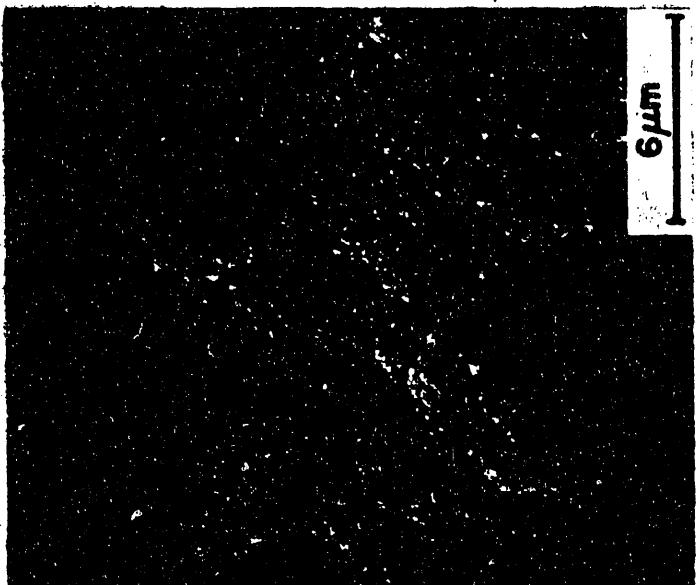
DIAMOND FILM MORPHOLOGIES

PYRAMIDS



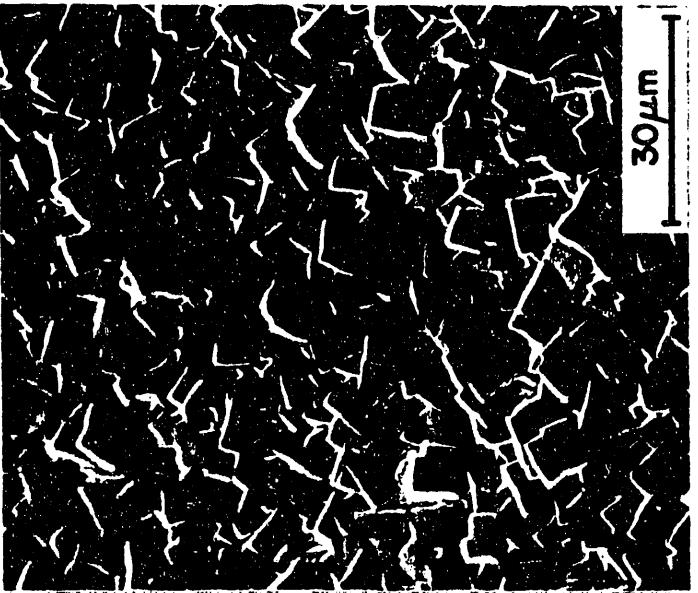
(a)

MICRO-CRYSTALS



(b)

PLATE-LIKE



(c)

cm

Thesis

THE GROWTH OF DIAMOND MATERIALS MUST BE CONTROLLED TO OPTIMIZE THEIR STRUCTURE FOR SPECIFIC APPLICATIONS.

- Crystal perfection/defects are important to properties.
- Crystal orientation and morphology are also important to the properties.
- Crystal perfection and morphology are functions of growth conditions and can be controlled.

WE HAVE MADE GOOD PROGRESS TOWARD THIS GOAL.

Final

Hypothesis #1

THE PERFECTION/DEFECTS INCORPORATED INTO THE CRYSTAL STRUCTURE DURING THE GROWTH PROCESS ARE RELATED TO THE STRUCTURE OF THE GROWING CRYSTAL SURFACE.

orm1

Hypothesis #2

THE DEVELOPMENT OF TEXTURES IN DIAMOND FILMS
IS THE RESULT OF "THE SURVIVAL OF THE FASTEST
GROWING CRYSTALLITES."

This is van der Drift's "Principle of Evolutionary Selection" and can explain the development of textured materials.

It serves as a guide for growing selected textures and the surfaces on which growth will occur.

orm1

van der Drift's "Principle of Evolutionary Selection"

- Random nucleation
- Competitive growth
Nuclei with the fastest growing crystallographic direction
direction perpendicular to the substrate
envelop and over-grow the less favorably oriented ones.

THIS LEADS TO A TEXTURE (CRYSTALLITE ORIENTATION)
WITH THE FASTEST GROWING DIRECTION
PERPENDICULAR TO THE SUBSTRATE.

ormal

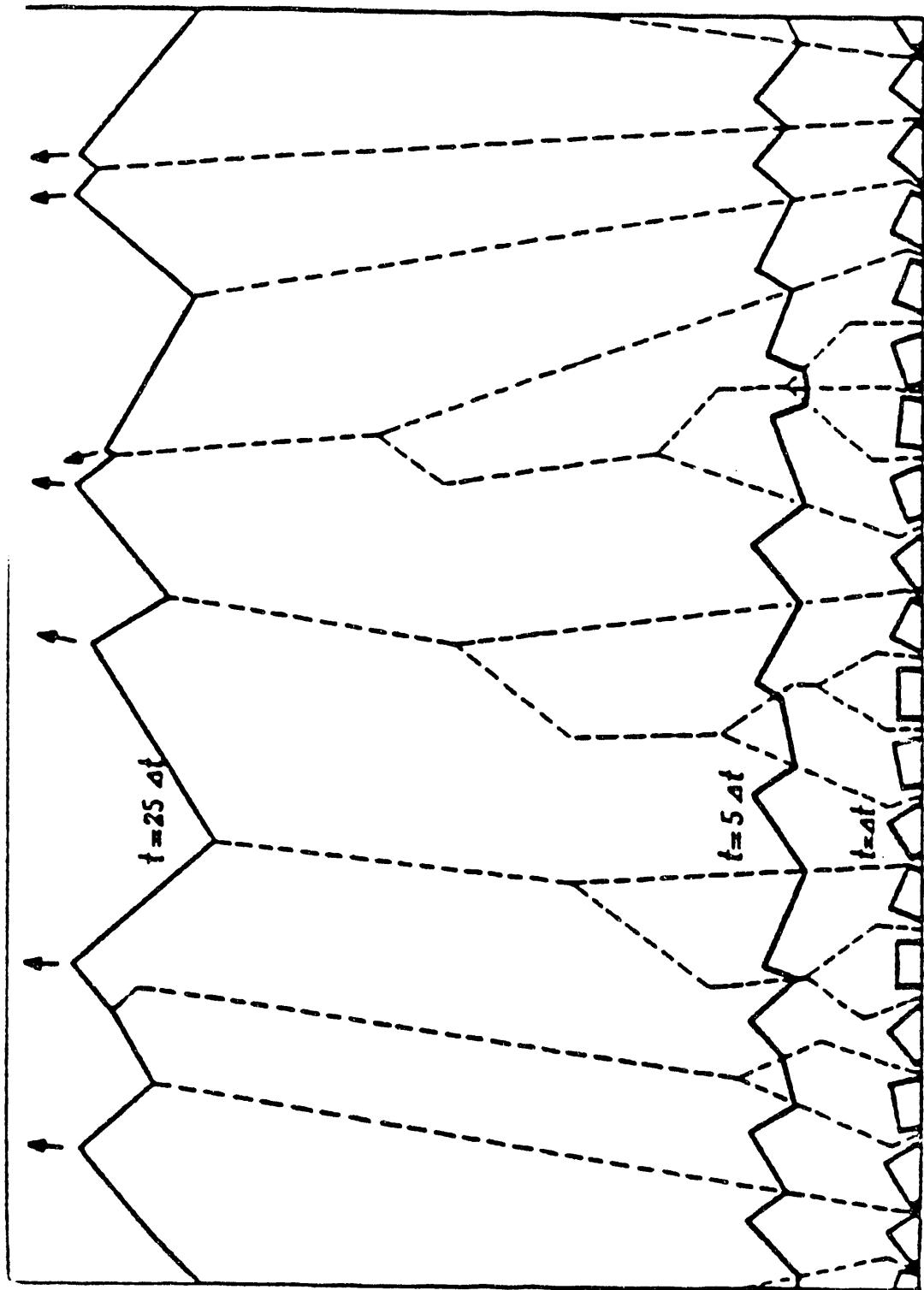
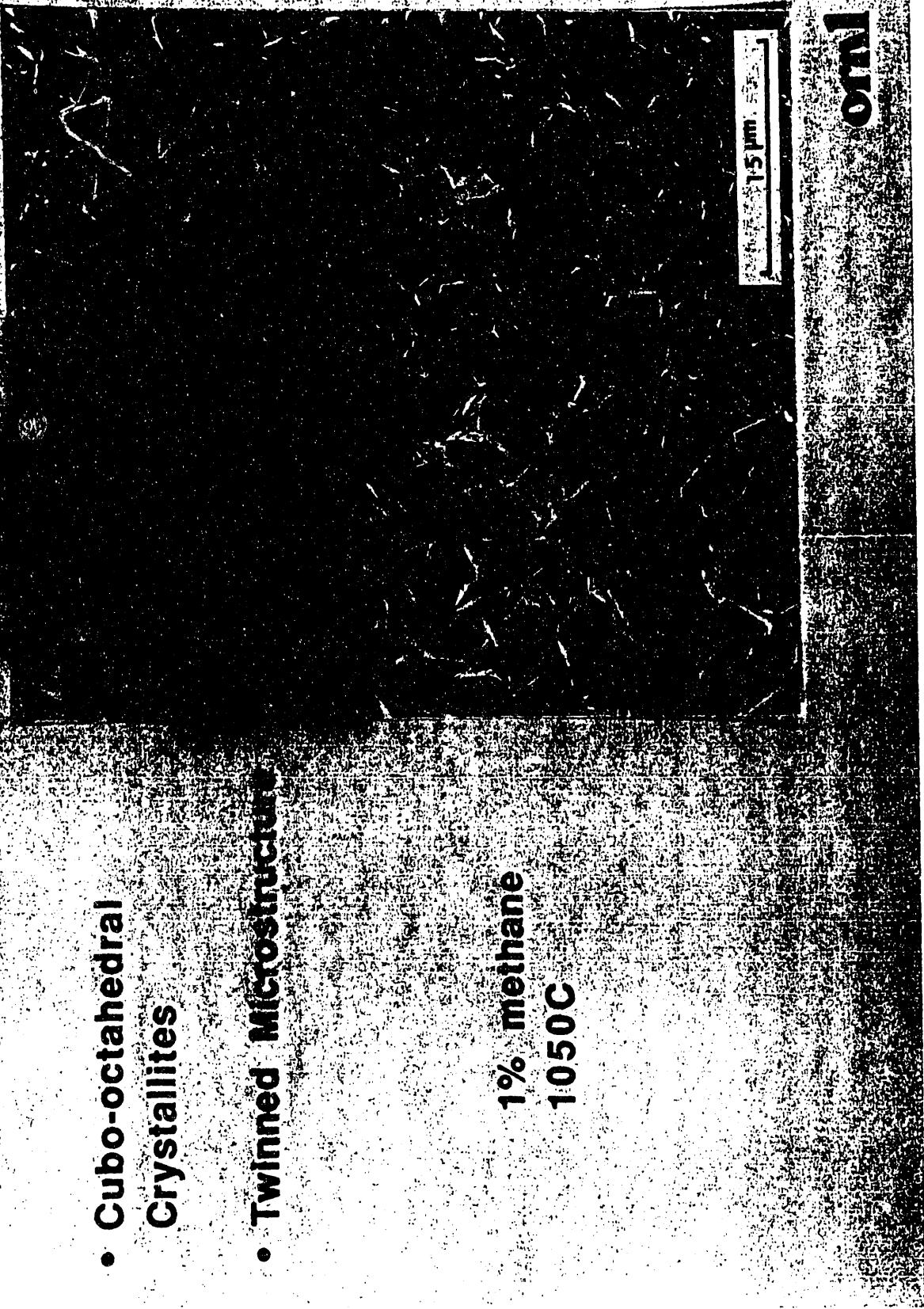


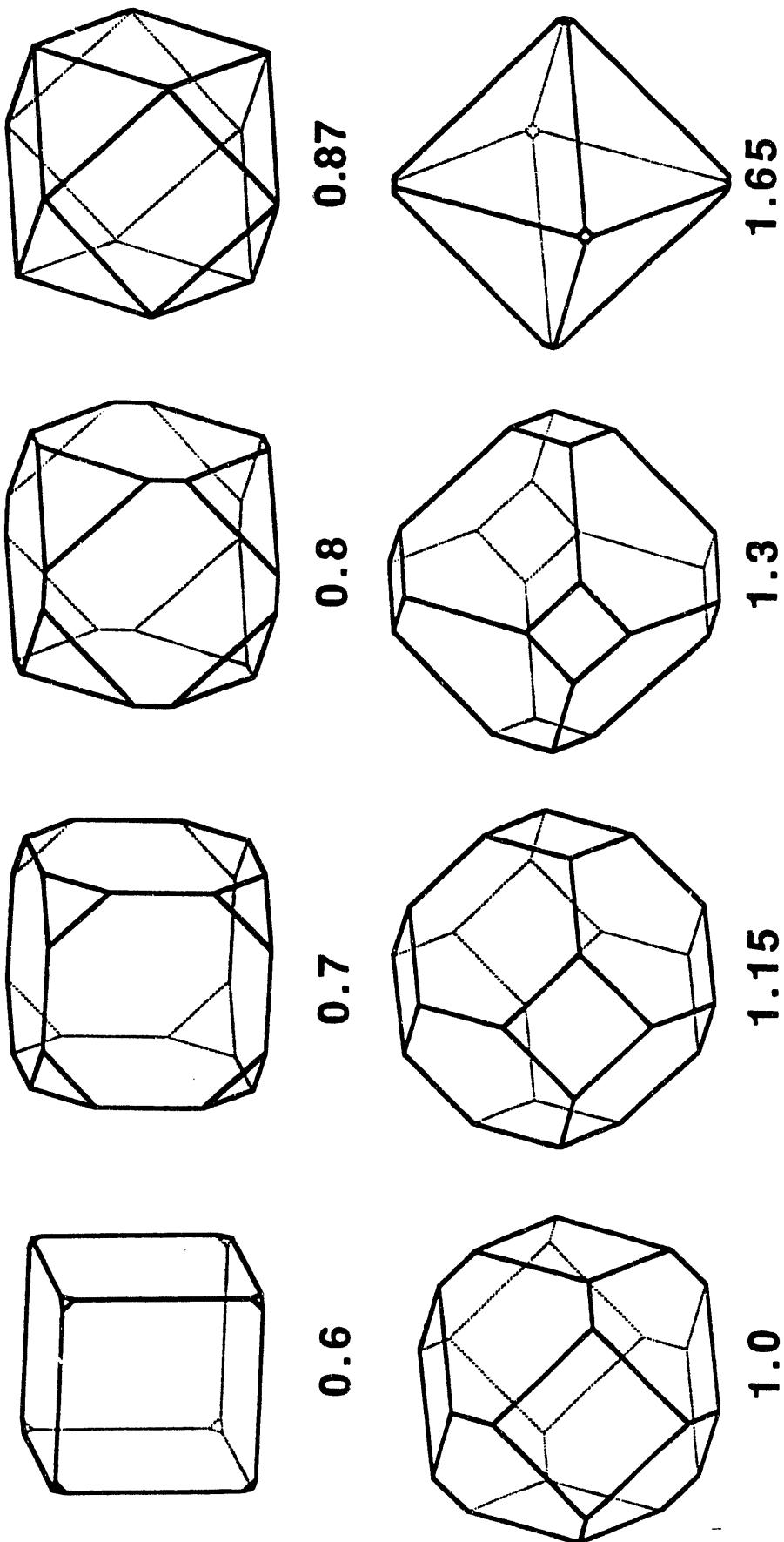
Fig. 4u. Starting from random-orientated equidistant (10)-bounded "cubic" crystals in a two-dimensional space and assuming infinite surface diffusion even along the substrate, the inter-crystal boundaries (dashed lines) as well as the crystal front at different times (at $t = 1\Delta t$, $t = 5\Delta t$ and $t = 25\Delta t$ in which Δt is the shortest time required for two neighbouring nuclei to meet one another) are constructed. It is shown how the evolutionary selection leaves the crystals with their $\langle 11 \rangle$ -direction (arrows) nearly perpendicular to the substrate.

FILMS EXHIBIT TYPICAL PYRAMIDAL "({111})" MORPHOLOGIES

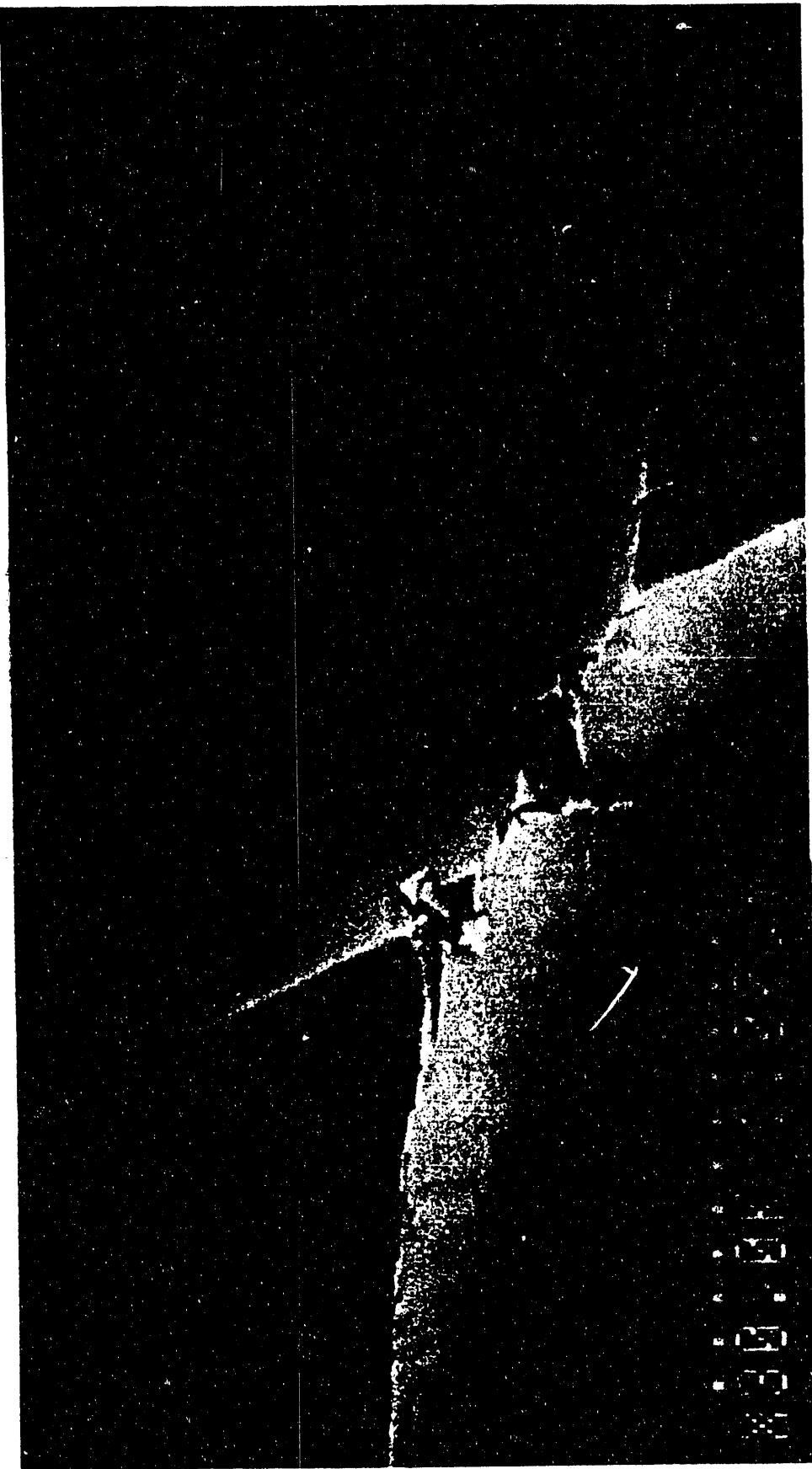


- Cubo-octahedral Crystallites
- Twinned Microstructure

Cubo-octahedral shapes reveal the ratio of growth rates in the $<100>$ and $<111>$ directions. The $<100>/<111>$ value is given.



[111] faces have rough micro-faceted surfaces
[100] faces are smooth



ornal

1323 15KU X58-169100m

oral

The fractured edge of a free standing film shows the rough faceted surface and the columnar grain structure



TEM shows ubiquitous twinned structures



ormal

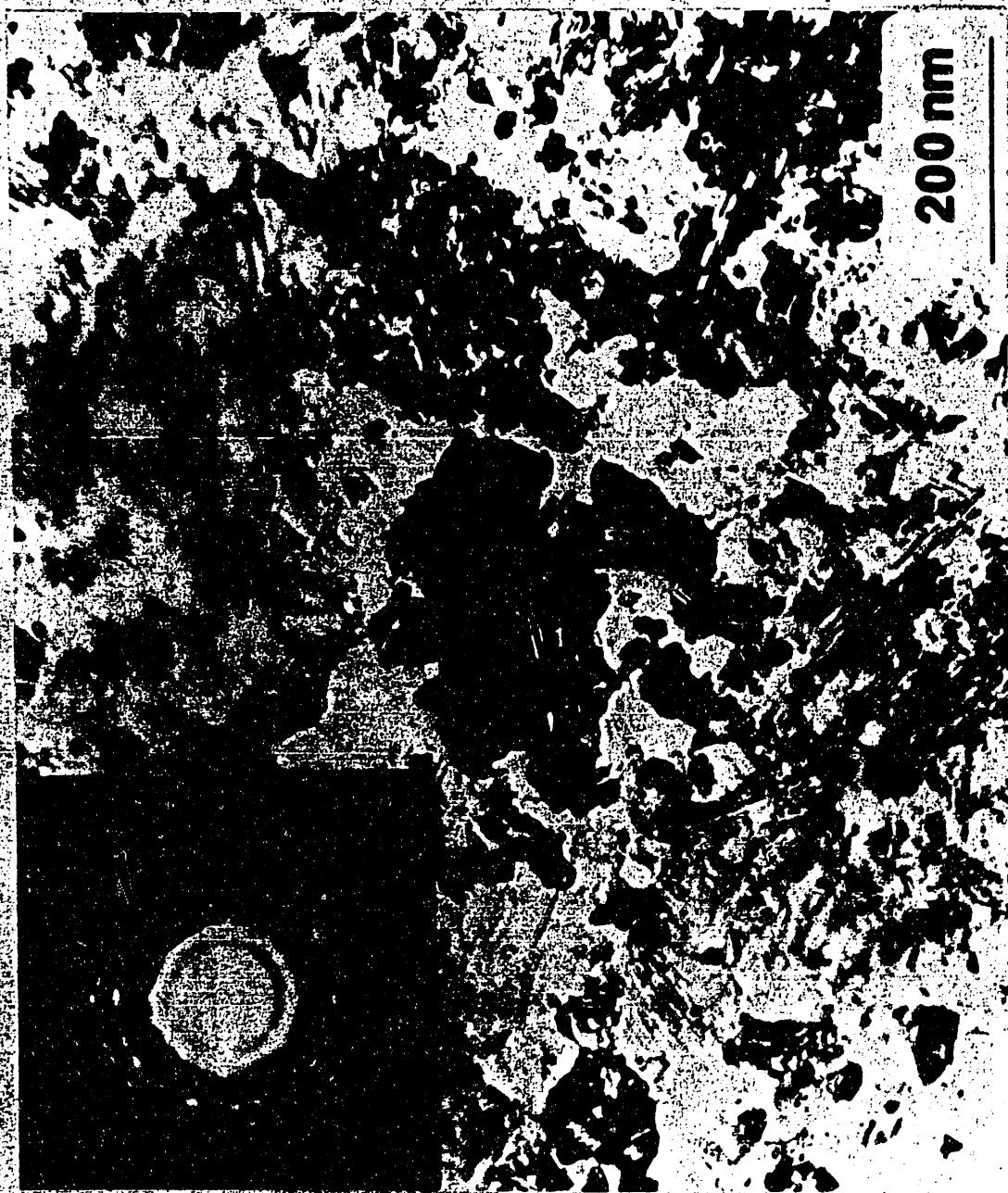
4010186

OM1



At 920C and below films are microcrystalline.

Microcrystalline material is full of micro-twins and defects.



200 nm
0.1 nm

In a narrow range near 950°C square [100] Facets develop

4P10182

om1



The grains contain no twins or stacking faults



90138

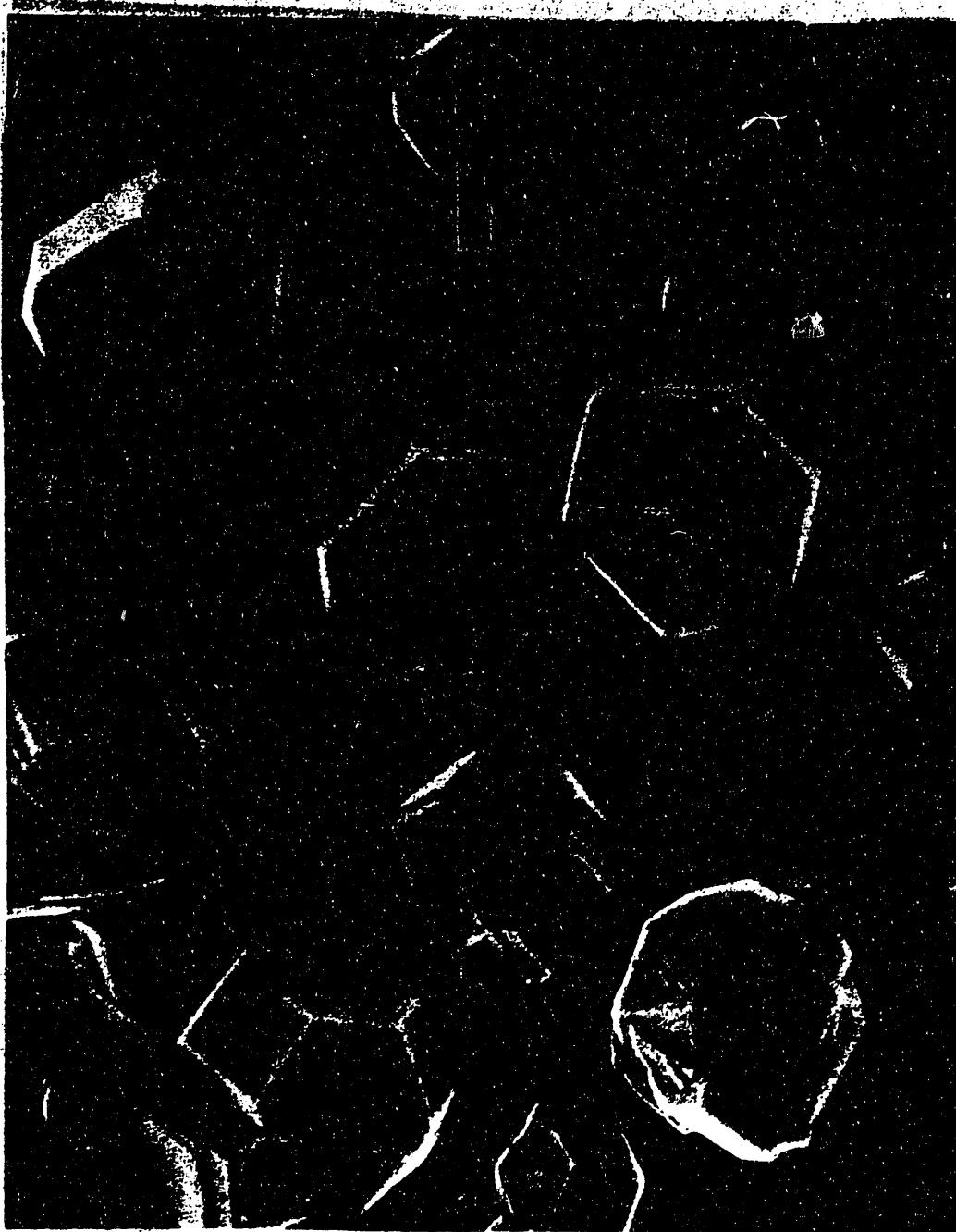
omi

Grainboundary regions included very defective material.



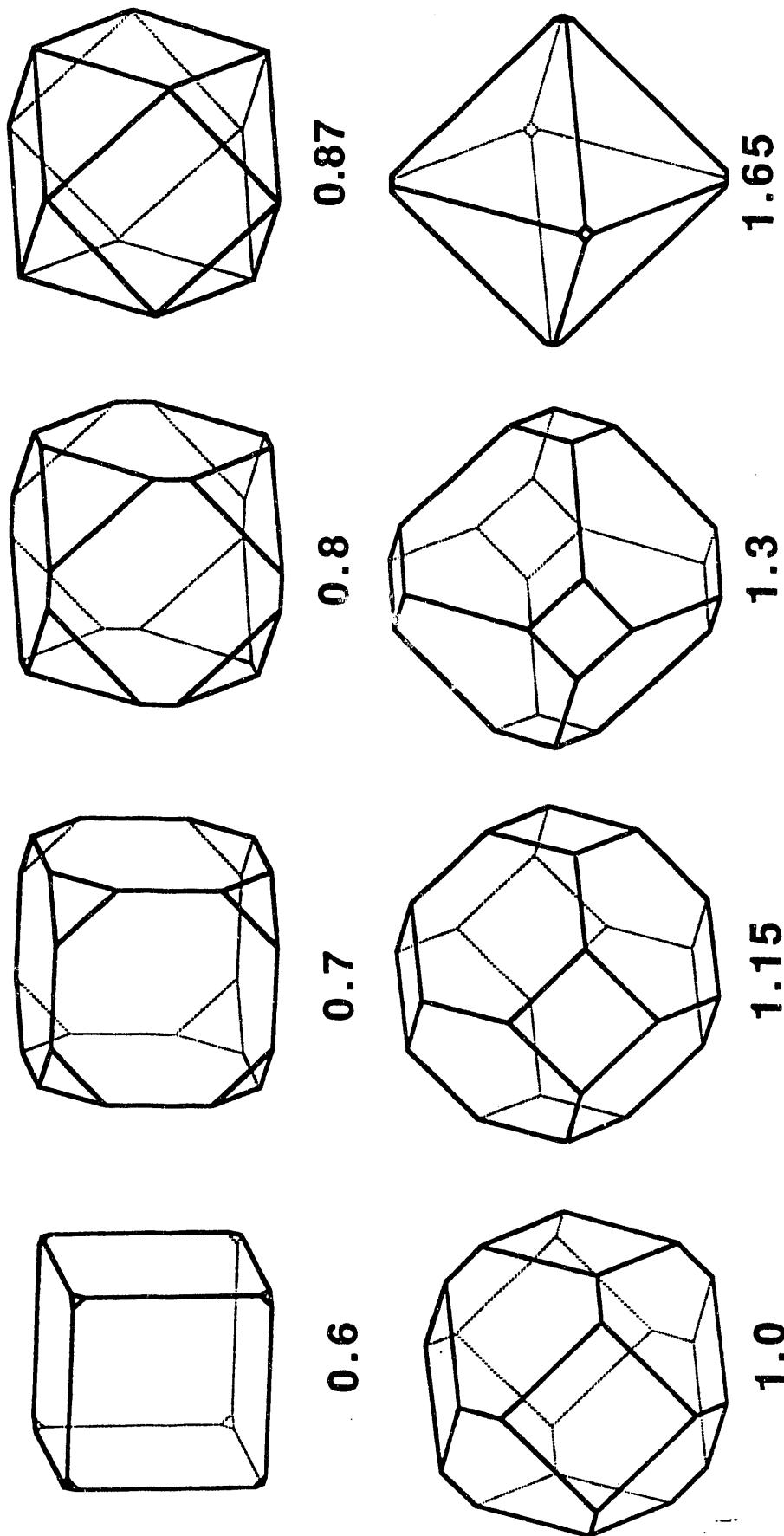
orm1

The initial nuclei are randomly oriented cubo-octahedra.

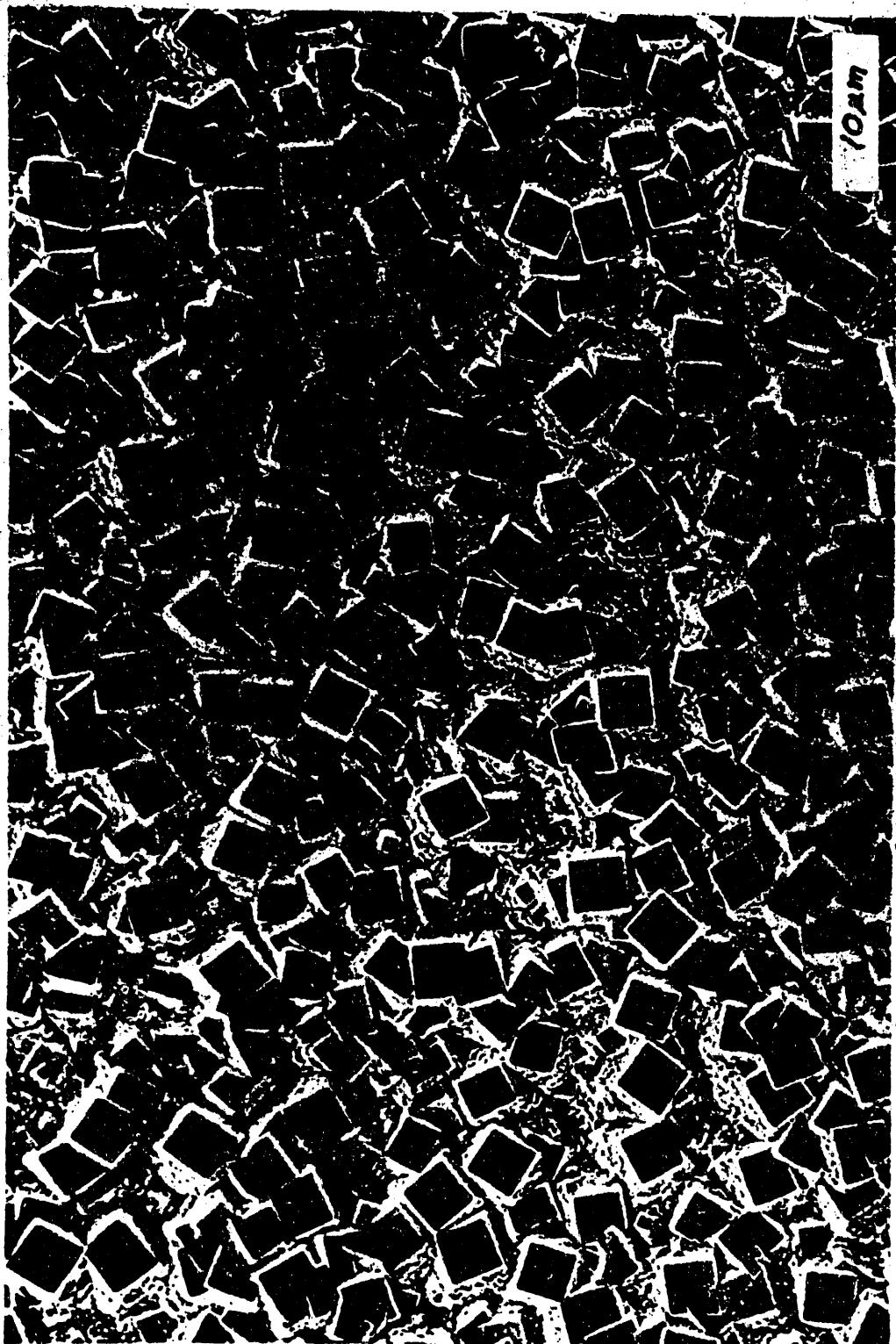


$R \approx 1.05$
normal

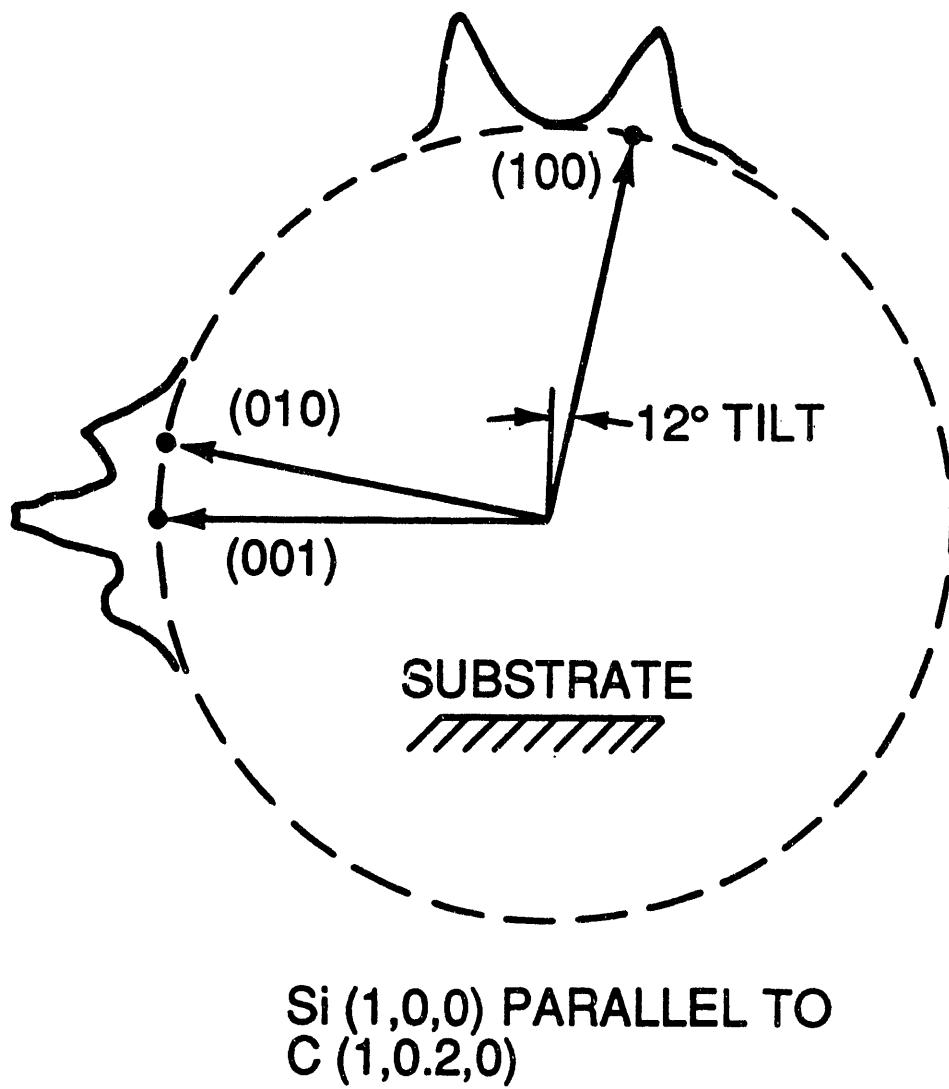
Cubo-octahedral shapes reveal the ratio of growth rates in the $<100>$ and $<111>$ directions. The $<100>/<111>$ value is given.



After 20 hours the $<100>$ texture is clearly developed.



omi

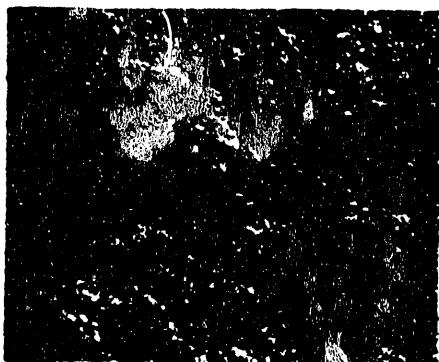


**X-RAY TEXTURE DIAGRAM FOR DIAMOND
FILM GROWN AT 930–950°C USING
1% CH₄ IN HYDROGEN**

Growth Conditions Determine the Internal and External Morphology of Diamond Films

SEM

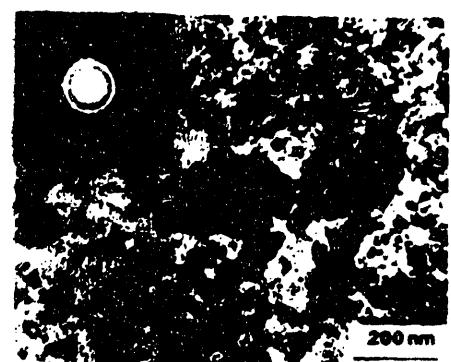
900°C



Microcrystalline

- smooth surface
- very fine grain size ($<0.2\text{ }\mu\text{m}$)
- poor crystal perfection

TEM



1050°C



(100) & (111) Facets

- sharp angular faceted surfaces
- grain size of 2-30 μm
- good crystal perfection but twins and stacking faults

930°C



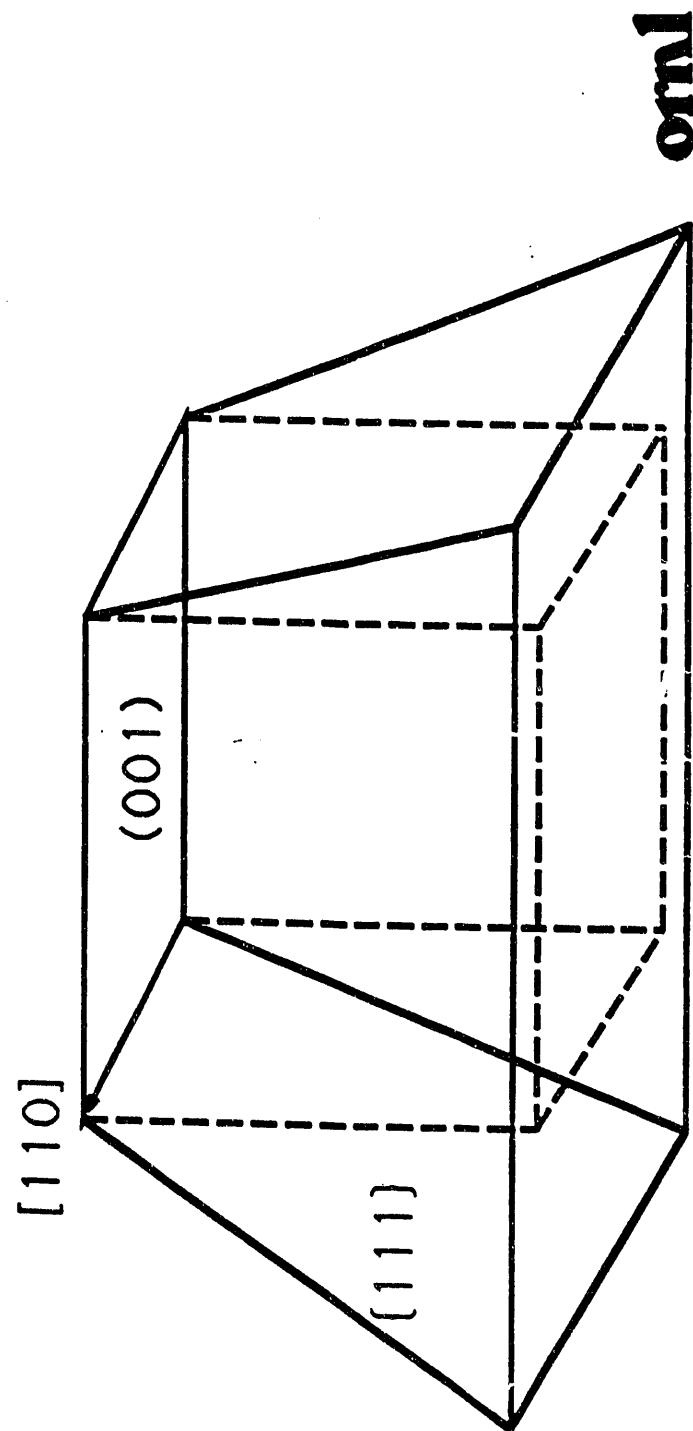
(100) Facets

- flat, square facets
- grain size of 2-30 μm
- very good crystal perfection, no twins or stacking faults
- grain boundaries contain some less perfect material
- tends to be highly textured

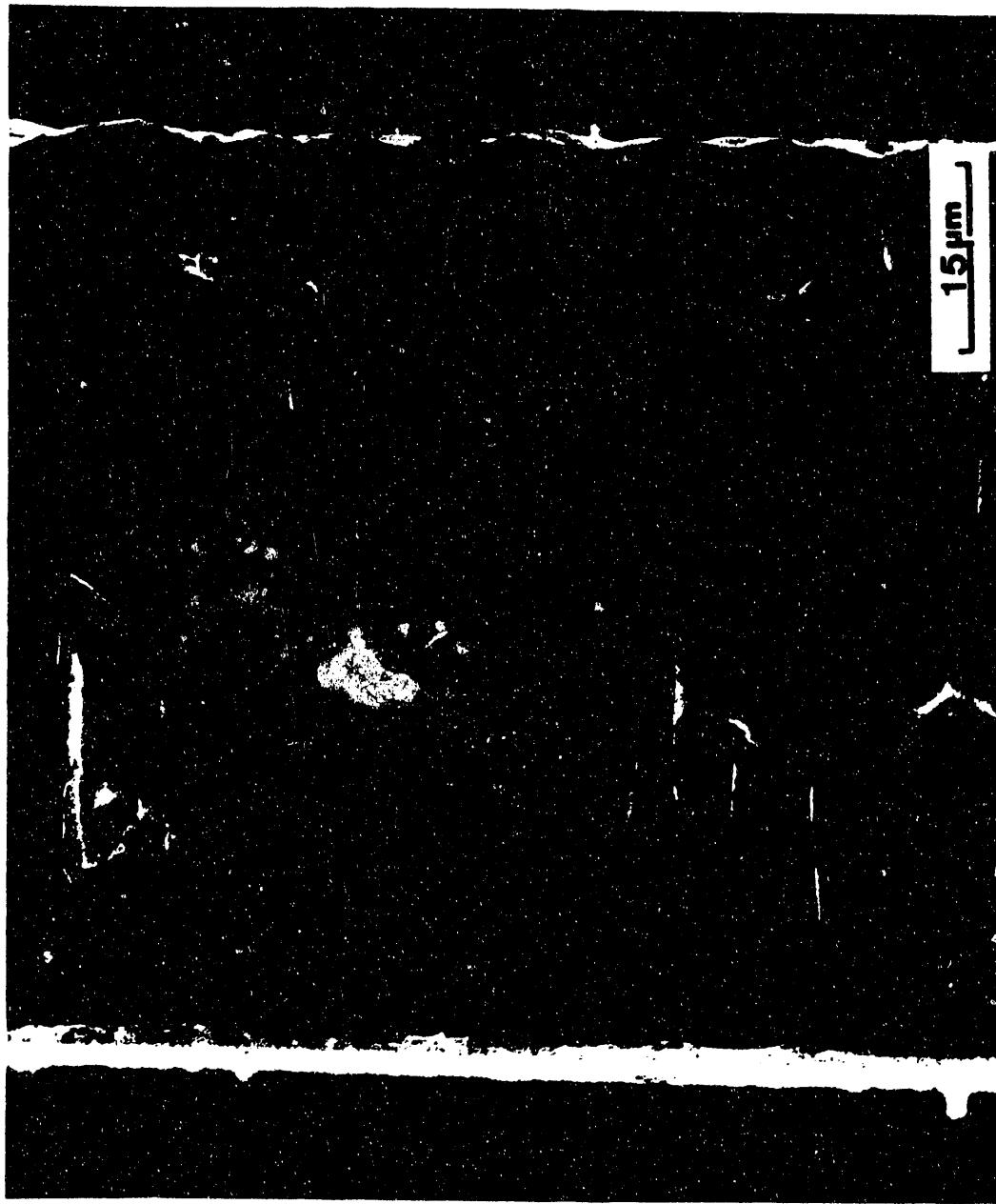
TEM



<100> TEXTURED MATERIAL GROWN WITH BOTH (001) AND
{111} FACES HAS A CENTRAL VOLUME GROWN FROM A
(001) FACE SURROUNDED BY MATERIAL GROWN FROM {111}
FACES.



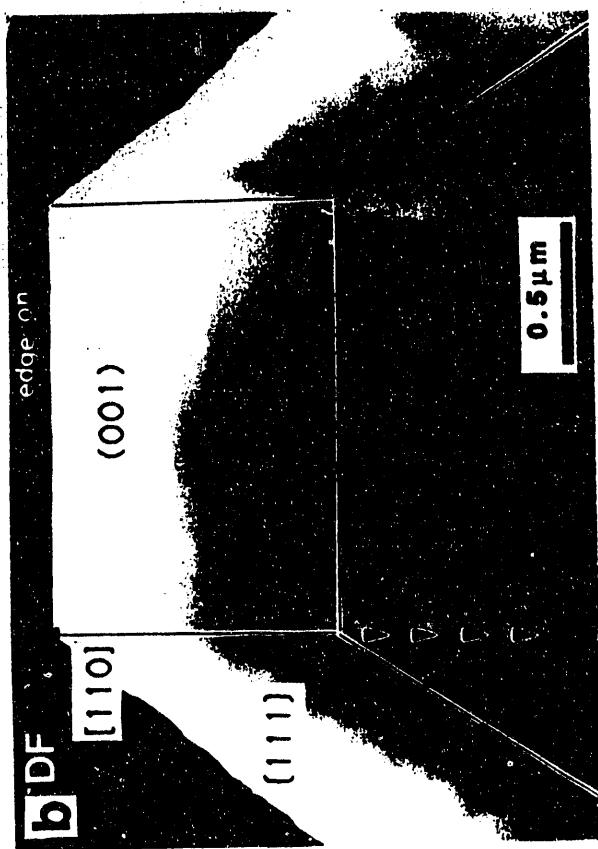
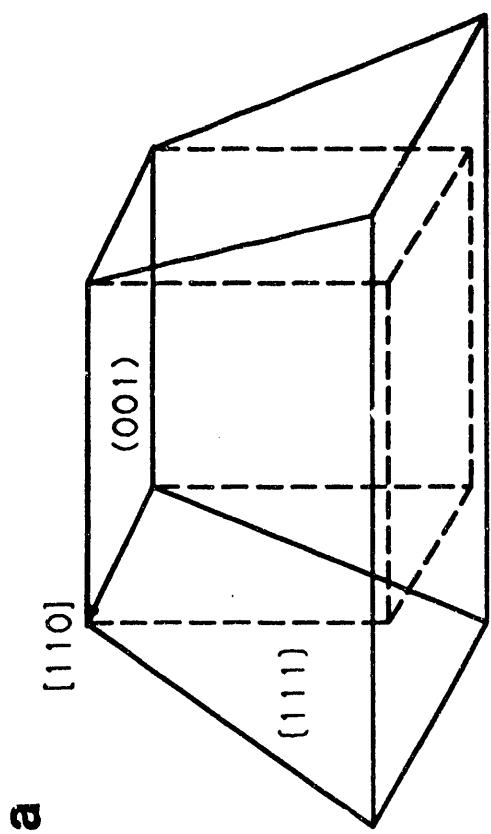
<100> textured films with (100) facets have smooth surfaces and columnar grains.



YR10170

omni

Y013223



$R \approx 1.6$

It is possible to change the growth conditions
to produce a $<100>$ texture with (111) facets.

4010177

omni



CVI DIAMOND GROWTH CONDITIONS CAN BE CONTROLLED
TO PRODUCE THE FULL RANGE OF CRYSTAL HABITS



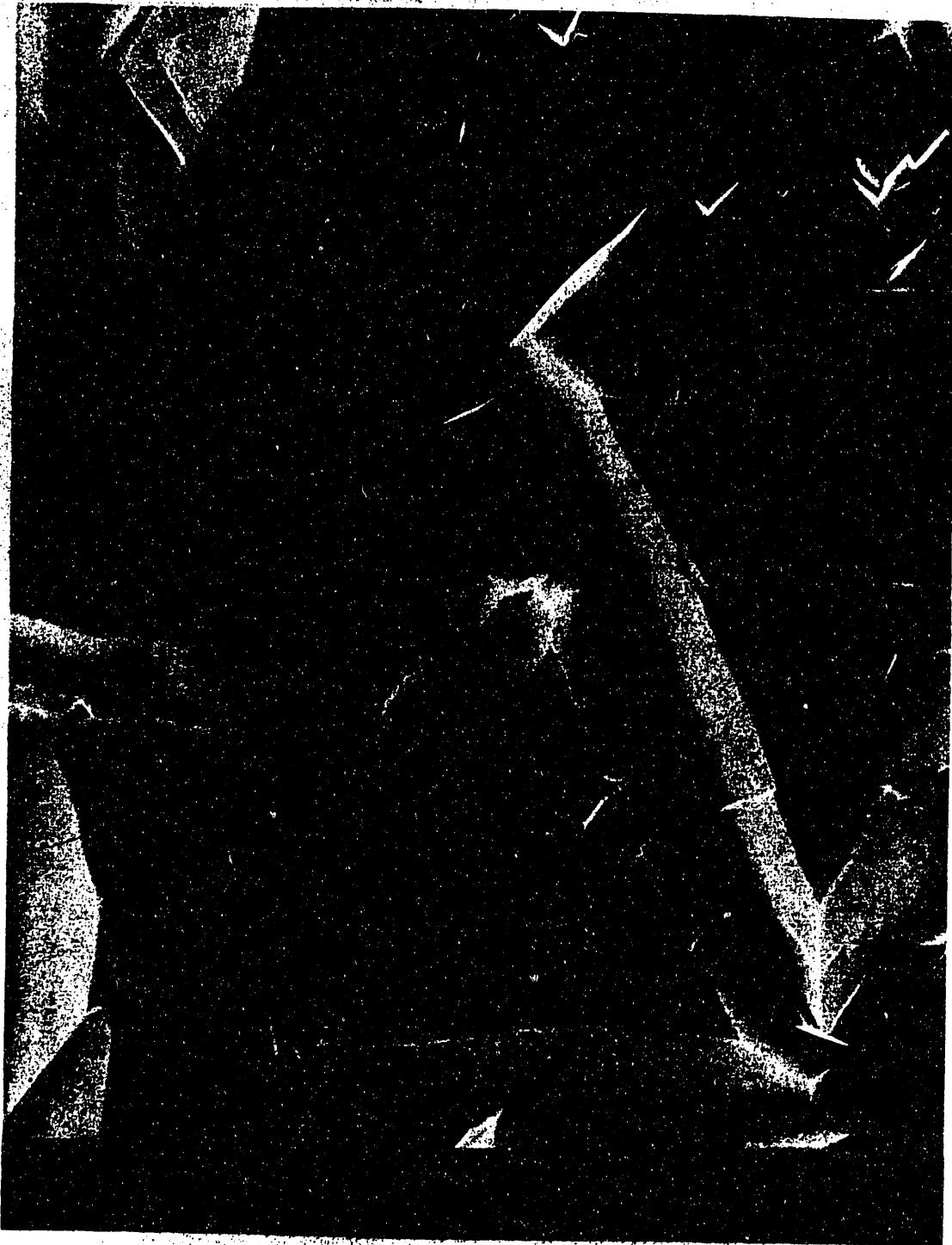
$R = 1.7$

$R = 0.6$

ornal

Yp/1988

FILMS CAN BE GROWN WITH A $<111>$ TEXTURE AND LARGE
 $\{111\}$ FACETS PARALLEL TO THE SUBSTRATE.



ori

Y011692

FILMS GROWN WITH THE RATIO OF GROWTH RATES OF
THE $\langle 100 \rangle / \langle 111 \rangle$ NEAR 0.6 PRODUCE $\langle 111 \rangle$ TEXTURED
MATERIAL WITH $\{100\}$ FACETS.



SUMMARY

- Crystal perfection and morphology are functions of growth conditions and can be controlled.

Crystallite shape indicates the relative rates of growth in the $<100>$ and $<111>$ crystallographic directions

The van der Drift model predicts texture development

The growth face is very important to control twinning

- The manipulation of texture and thereby surface morphology and internal crystal perfection is an important step in optimizing CVD diamond films for applications.

SUMMARY

- Unique new Diamond-Like Carbon (DLC) products are possible.
- Some properties of DLC films may approach those of natural diamond
- Properties are a strong function of structure and hydrogen content and can be controlled over a wide range by the growth processes
- Hard DLC films are generally limited to a few microns in thickness but are relatively easy to make and can be applied at room temperature to a wide variety of substrates.

om1

SUMMARY

- Unique new CVD diamond products are possible.
- Properties of CVD diamond films can compare favorably with natural diamond
- Properties are anisotropic, a strong function of structure and crystal perfection (including composition)
- Crystal perfection and morphology are functions of growth conditions and can be controlled.
- The manipulation of texture and thereby surface morphology and internal crystal perfection is an important step in optimizing CVD diamond films for applications.

Ornl

Control of Structure and Properties

- Evolution of Microstructures
- Amorphous
- Microcrystalline
- Torch Grown - Porous Material
- Uniform Non-textured Fine Grained Material??
- Mixed Size Equiaxed Grains
- Columnar Textured Structure
 - Van der Drift
 - Homoepitaxial Crystals
 - Heteroepitaxial Crystals
- Adhesion/Interfacial Properties
- Planar
 - Chemical Bonding
 - Cobalt Problem
 - Thermal Coefficient of Expansion
 - Brazing
 - Sintering??
- Mechanical
- Uniformity and Quality Control

SUMMARY

- Unique new Diamond-Like Carbon (DLC) products are possible.
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ornal

SUMMARY

- Unique new CVD diamond products are possible.
- Properties of CVD diamond films can compare favorably with natural diamond
- Properties are anisotropic, a strong function of structure and crystal perfection (including composition)
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- The manipulation of texture and thereby surface morphology and internal crystal perfection is an important step in optimizing CVD diamond films for applications.

only



Potential Transportation Applications for Diamond Films

Robert A. Hay and Patrick M. Stephan

Norton Diamond Film
Northborough, MA

Overview Of Diamond Films and Diamond-Like Coatings

Y. S. Raja and S. S. Raja

Size

Properties



NORTON



Overview of Diamond Films and Diamond-Like Coatings

- Geometric Capability
- Size Capability
- Substrate Selection

NORTON -

Overview Of Diamond Films and Diamond-Like Coatings

Diamond-Like Coatings

Capabilities

Properties

Adhesion

Substrate	CVD Diamond	DLC
Silicon Nitride	Yes	Yes
Silicon Carbide	Yes	Yes
Aluminum Oxide	No	Yes
Steels	Maybe	Yes
Aluminum	No	Yes
Plastics	No	Yes
Tungsten Carbides	Maybe	Yes
Other Carbide Formers	Maybe	Yes
Glass	Maybe	Yes

Characteristics Of Diamond Films

- High Hardness (Wear Resistance)
- High Corrosion Resistance
- High Thermal Conductivity
- Low Friction Coefficient
- Low Thermal Expansion
- High Stiffness
- Low Mass
- Thermal Stability
- Thermal Shock Resistance

Properties



Properties	Natural Diamond	CVD Diamond	PCD	DLC	Tungsten Carbide (ISO K10)
Hardness GPa	56-102	70-100	50-80	25-50	18
Young's Modulus GPa	400-1000	1000	840	-	630
Thermal Conductivity W/m K	600-2000	600- 1400	560	-	110
Temperature Limit Deg. C	600-650	700	600	200-400	600

Potential Transportation Applications

■ Automotive

Aeronautics

Space

Rail

■ Special Defense Needs



Potential Benefits

Longer Component Life

Fuel Savings

Noise Reduction

Better Thermal Management

Higher Package-Specific Output

Potential Component Applications for Diamond Films

Valve Train Components

Piston Rings

Piston Pins

Cylinder Liners

Gears

Bearing Surfaces

Window Coatings

Fuel Nozzles

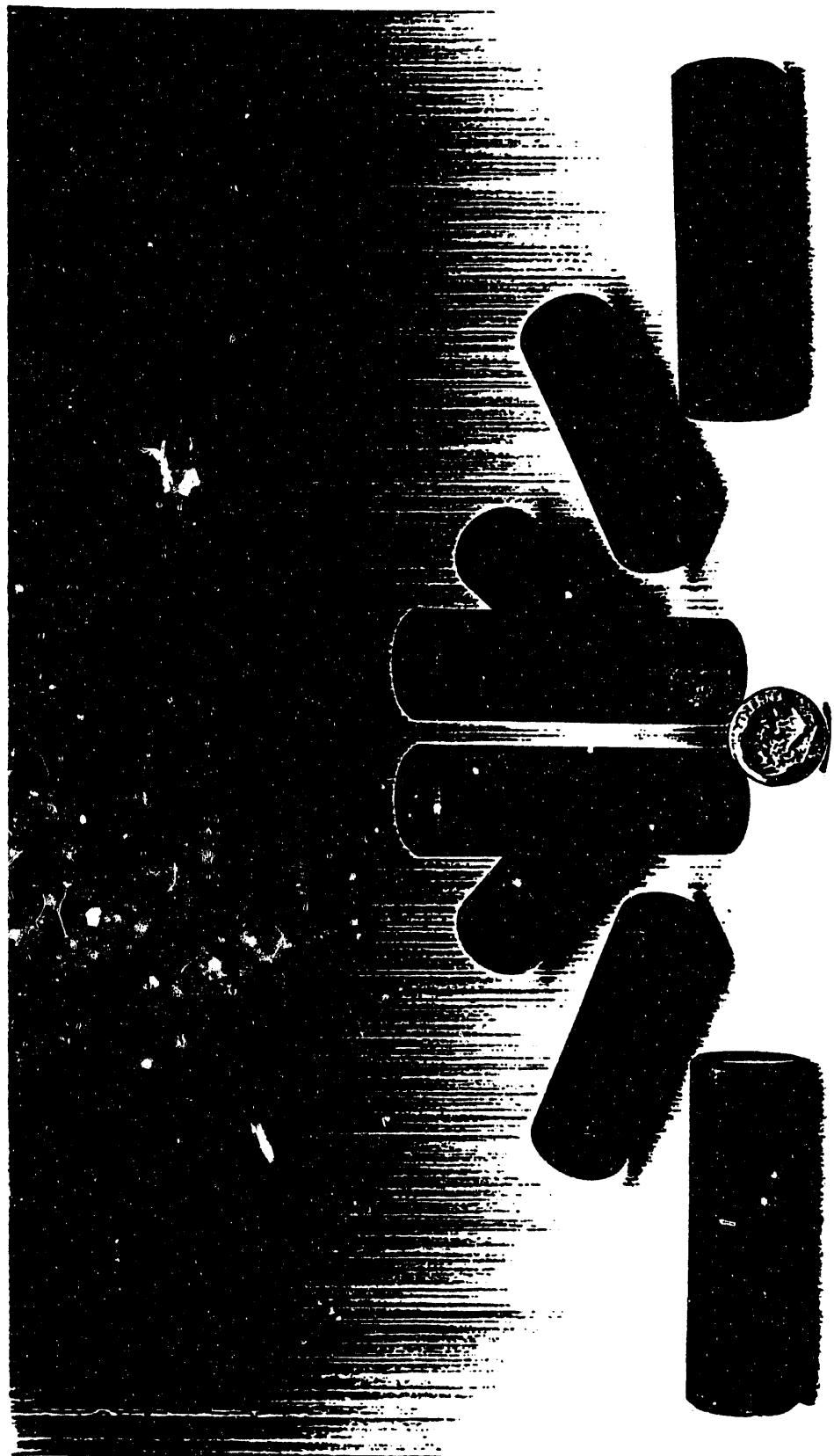
Heat Sinks

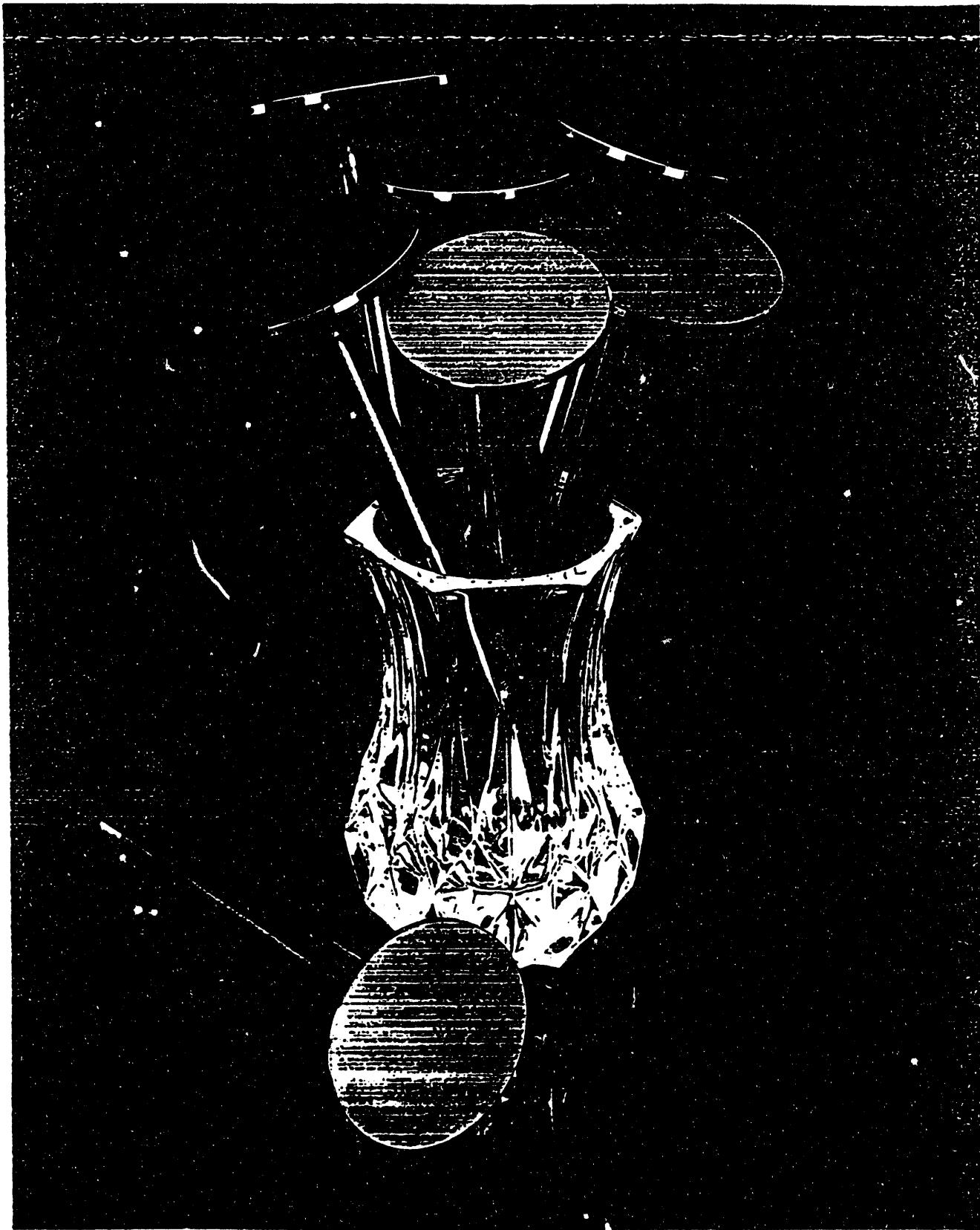
How Do We Get There From Here?

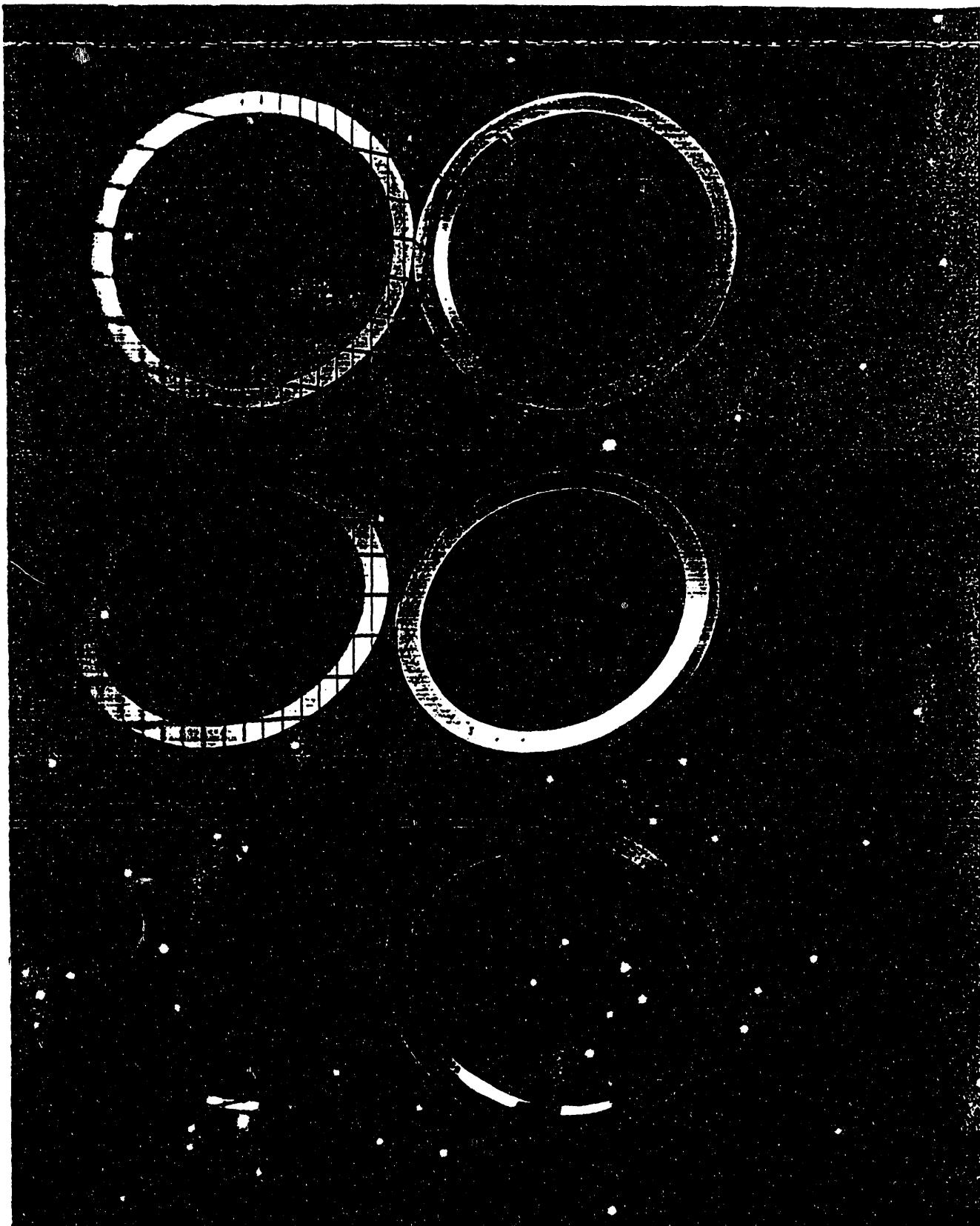
Diamond Thin Film
Nozzles, Valve Train

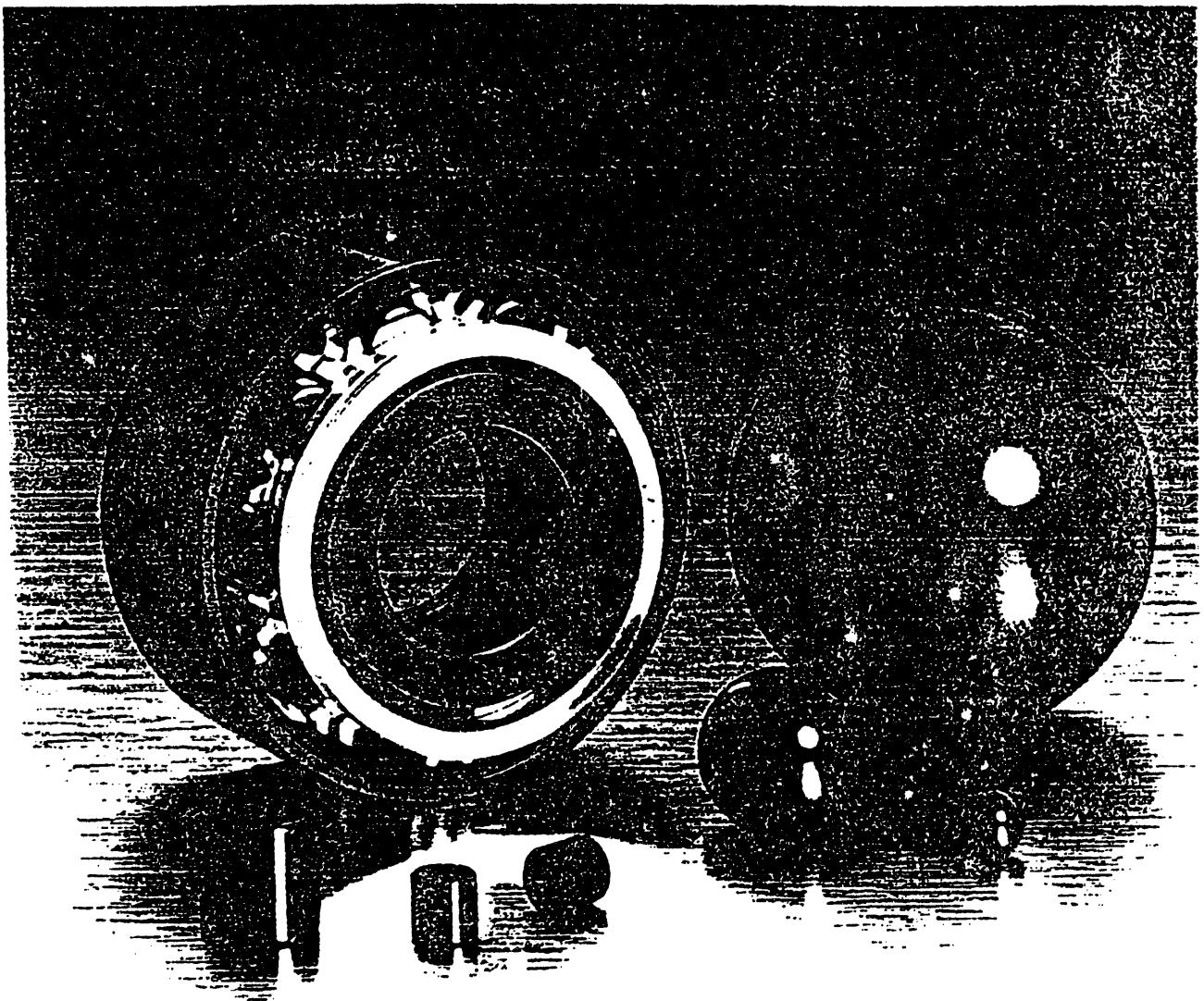
Diamond Re-coating - Gears, Valve Train

Firestanding Diamond Nozzles, Heat Sinks









NORTON



How Do We Get There From Here?

Surface Characteristics

Adhesion Strength

Wear Resistance

Temperature Capability

Thickness and Coverage

How Do We Get There From Here?

- Benefits Analysis
- Cost/Price Relationships
- Barriers Analysis
- Technical Feasibility

Technical issues

- Nucleation on different substrates
 - Adherence
 - Film growth mechanisms
 - Film structure and quality
- ## Scaling-up
- Large sizes
 - Complex shapes
- Different capacities
 - Different ranges
 - Different systems

Conclusions

Three Viable Technologies
Needs Considerable Amount of Development
Near-Term Commercial Applications

4.0 REPORTS FROM WORKING PANELS

Panel 1 – Comparative Evaluation of Deposition Technologies

Panel Members:

Chairman: George R. Fenske, Argonne National Laboratory

David K. Benson	National Renewable Energy Laboratory
Deepak Govind Bhat	GTE Valenite Corporation
Yu-Lin Chen	Allison Gas Turbine Division, GM
Roy Gat	Case Western Reserve University
Mike Kelly	Stanford University
James E. Lawler	University of Wisconsin
Dennis C. Nagle	Martin Marietta Labs.
Duane Outka	Sandia National Laboratories
Roland J. Pitts	National Renewable Energy Laboratory
Gopal Subray Revankar	Deere & Co.
Frank Stodolsky	Argonne National Laboratory
Vish V. Subramaniam	Ohio State University
Mahendra Kumar Sunkara	Case Western Reserve University
Paul J. Wilbur	Colorado State University
Ming-Show Wong	Northwestern University
William E. Woolam	Southwest Research Institute

This working group attempted to evaluate/compare the different types of deposition techniques currently under investigation for depositing diamond and diamond-like carbon films. Table I lists the broad types of techniques that were considered for depositing diamond and diamond-like carbon films. After some discussion, it was agreed that any evaluation of the various techniques would be dependent on the end application. Thus the next action was to list the different areas where diamond and DLC films could find applications in transportation. These application areas are listed in Table II. Table II intentionally does not go into great detail on applications because that subject is dealt with specifically by Panel #4 - APPLICATIONS TO TRANSPORTATION. The next action concentrated on identifying critical issues or limitations (see Table III) that need to be considered in evaluating the different processes. An attempt was then made to rank different broad categories of deposition techniques currently available or under development based on the four application areas (Table II) and the limitations (Table III). These rankings/evaluations are given in Tables IV and V for diamond and DLC techniques, respectively. Finally, the working group tried to identify critical development and research issues that need to be incorporated into developing a long-term program that focuses on diamond/DLC coatings for transportation needs.

Deposition Technologies

Techniques for depositing diamond and diamond-like-carbon films are listed in Table I. For diamond films, CVD processes that were considered include: laser-assisted, hot-filament, plasma-assisted (microwave), and halogen-based CVD. Two other techniques considered were combustion-flame processes and plasma (arc)-jet processes. While this is not a complete list of all of the techniques/processes (and variants thereof) known to be under investigation for depositing diamond films, the working group felt that these were the more prominent ones and that techniques/processes not listed (e.g. biased hot-filament, low- or high-pressure rf-discharge, etc.) would be similar to those listed. For example, the LANL process currently under development to combine hydrogen and carbon at elevated temperatures in a fluidized-bed reactor to deposit diamond coatings would come under the combustion-flame process in Table I.

Techniques for producing DLCs are also listed in Table II. Again, not all processes are listed. The DLC processes are primarily based on PVD and energetic-beam technology (or combinations of both).

Application Areas

The first action was to list the different areas where diamond and DLC films could find applications in transportation. These application areas are listed in Table II. Table II intentionally does not go into great detail on applications because that subject is dealt with specifically by Panel #4 - APPLICATIONS TO TRANSPORTATION. The first application area on thermal management takes advantage of the high thermal conductivity of diamond films to help dissipate heat generated either by mechanical means (e.g. brakes or cutting operations), or ohmic heating (high-power-density electronic components). It was also noted that diamond/DLC films could be used to control the thermal loading of the interior compartment by controlling the amount of light transmitted.

The second application area identified, Optics, is concerned with the use of diamond (and perhaps DLC) films as optical coatings for windows.

The third area deals not only with the use of diamond/DLC films in end-use tribological applications (e.g. cylinder liners, fuel injectors, etc.), but also with manufacturing practices (e.g. machining, etc. of components)

The fourth application area deals with using diamond/DLC coatings in fabricating sensors used in transportation, e.g., pressure, temperature, and emission sensors.

Comparative Limitations

The discussion in this section focused on determining the critical factors that need consideration in ranking/evaluating the different processes listed in Table I for the application areas listed in Table II. Substrate preparation refers to special pre-deposition treatments (such as scratching the surface with diamond or some other abrasive material) to enhance the nucleation of diamond crystals during the initial stages of film growth. While these steps may be required for diamond films, they are not required for DLCs. Growth rates may also be a limiting factor for some of the processes (e.g. PA-CVD) but not for others (Arc-Jet). The size of the component for currently available diamond techniques may be an issue depending on the application, but not necessarily for many of the DLC processes which are more mature.

Substrate deposition temperature is currently a major limiting factor for most diamond deposition processes (depending on what one would consider as being an acceptable growth rate). Deposition temperatures below the annealing temperature of steel components are highly desirable. Cost is always a critical factor particularly if these techniques will be used in treating components produced in large quantities. Surface finish is another critical factor particularly for tribological applications that demand smooth surfaces to prevent severe wear of the mating surface. In some instances (e.g. material cutting, grinding, etc.), however, a smooth surface may not be as critical.

The maximum thickness that can be deposited may be critical depending on the process and type of film (diamond or DLC). Thick diamond coatings (in excess of 3-4 mm thickness) are commercially available today. For DLCs, the thickness is usually less than several micrometers.

Adhesion is another critical factor that limits applications. If the coating does not adhere to the surface under typical operating conditions, the coating is useless. Adhesion appears to be more of an issue for diamond coatings than for DLCs. Diamond films are often difficult to nucleate and grow on all but a few materials (typically strong carbide formers), while DLCs can be applied on a wider range of materials particularly if an intermediate bond-coat is employed.

Thermal conductivity is not a limiting factor for diamond films; in fact the thermal conductivity of diamond films is one of its outstanding properties. DLCs on the other hand, because of their amorphous nature, have very poor thermal conductivities, and thus are inappropriate for thermal-management applications.

The geometry limitation in Table III refers to the capability of the different techniques to coat components with complicated shapes. Line-of-sight processes such as the ion-beam techniques would have difficulty coating interior surfaces. CVD processes on the other hand may be more appropriate for interior surfaces provided activated species can be transported to the interiors.

Finally, thermal oxidation of the coatings needs to be considered. Diamond films are stable up to temperatures of approximately 800°C (depending on the environment) while DLCs start to crystallize (to graphite) at temperatures above 300-400°C .

Ranking/Evaluations

Tables IV and V summarize the ranking of the different techniques identified in Table I for the 4 application areas listed in Table II. The critical limiting factors that the working-group members felt were crucial in evaluating the different techniques are listed for each application area. For thermal-management applications, the limiting factors include: growth rates, substrate temperatures, cost, thermal conductivity, and thermal oxidation. Based on these factors, the group felt that the Arc-Jet technology is most promising as a proven technology for thermal-management applications. Plasma-assisted CVD (microwave) and hot-filament CVD processes were rated as the next two most promising proven technologies. The columns denoted by "Pot" denote technologies (PA-CVD, halide-assisted CVD, and Arc-Jet) that the group felt had significant potential for thermal-management applications.

For optics applications, the more promising, proven technologies include PA-CVD, Arc-Jet, and HF-CVD, while halide-CVD and combustion-flame processes offer potential.

Under tribological applications, PA-CVD, Arc-Jet, and HF-CVD were noted as most promising techniques (these three techniques are the most mature of the different techniques listed, and thus it is not surprising to see them listed in the top of the "Proven" processes). PA-CVD was listed as having potential because it may be possible to form cubic-BN films. Halide-based CVD techniques were also listed as having potential because of their potential ability to deposit films at low substrate temperatures.

For sensor applications, the PA-CVD and HF-CVD were noted as being the most promising proven technologies. Arc-Jet technologies were not considered because of high deposition temperatures. Laser-assisted CVD techniques have potential because of their ability to develop complex diamond patterns that may be incorporated into the sensors.

The results of the ranking exercise for DLC processes are given in Table V. Because of the poor thermal conductivity and thermal oxidation properties of DLCs, it was felt that these types of films (and hence their deposition processes) should not be considered at all for thermal management and sensor applications. Consequently, all of the processes listed in Table V received a "0", signifying that they should not be considered. For optical coatings, sputter-deposition techniques were considered to be very mature, and thus were rated as most promising of the proven technologies. Ion-assisted techniques and PA-CVD were also noted as being promising "proven" processes.

For tribological applications, all of the processes, with the exception of laser-ablation-PVD appeared to be equally promising as proven technologies.

Recommendations

After evaluating the different processes for depositing diamond and DLC coatings, the working group attempted to identify key issues that need to be addressed in furthering the utilization of diamond and DLC films in transportation applications. These issues fell into one of two categories: one dealing with research issues and the other dealing with technology-development issues.

The research issues that need to be addressed in bringing diamond and DLC coating technologies to the point where they can solve the thermal-management, optic, tribological, and sensor needs of advanced transportation systems are as follows:

- 1) **Growth Rates:** The growth rates of the current processes used to produce diamond and DLC films are not sufficiently high to make them economically attractive for transportation applications. Growth rates are typically on the order of several micrometers per hour (with the exception of plasma arc-jet processes). Increases in the range of two to three orders of magnitude are needed.

In order to increase the overall growth rates of the deposition processes, research is needed to understand the nucleation and growth of diamond and DLC films and how the multitude of process parameters influence these processes.

- 2) **Substrate Temperature:** The substrate temperatures required for diamond-film growth are too high for many materials. Typical deposition temperatures for diamond films are in the 800 to 1000°C range. Deposition temperatures (without reduced growth rates) below 400 to 500°C are desirable for use on heat-treated steel components (assuming adherent diamond coatings can be deposited on steels).

Research on nucleation and growth at low substrate temperatures is needed to address this issue.

- 3) **Adhesion:** Adhesion is a critical factor that limits the application of diamond films. A general (but not necessarily sufficient) criterion for good adhesion is to use a material that is a strong carbide former (iron and steels are an exception).

Research is needed to identify the properties that determine the adhesion of diamond films and how the different deposition processes can be modified to improve the adhesion of diamond and DLC films.

- 4) **Surface Finish:** Polycrystalline films deposited by many of the techniques listed in Table I are comprised of faceted crystals. The resulting surfaces can be rough and thus unacceptable for some applications. Research on the nucleation and growth mechanisms of diamond films would provide information on controlling the surface roughness. Post-deposition surface-finishing procedures may offer an alternative approach to obtain the desired surface morphology.

Once the technological barriers have been overcome, a number of process-development issues need to be addressed. These issues include:

- 1) Scalability: Can the desired process be scaled up in size to coat not only prototypic components, but also eventually be adapted for long-term and potentially high-volume manufacturing runs?
- 2) Controllability: Is the desired process controllable, and if so what are the critical process parameters that need to be monitored and controlled?
- 3) Cost/Marketability: Can the cost be brought down to reasonable levels acceptable to industry? Precisely what are the markets for these diamond/DLC film processes?

Summary:

Within the time allotted, a number of practical deposition processes that currently exist for forming diamond and DLC coatings were evaluated with respect to 4 application areas (thermal management, optics, tribology, and sensors). The group identified a number of promising technologies that currently exist for diamond-film deposition. These include processes based on hot-filament and microwave-plasma CVD and arc-discharge. For DLC coatings, it was noted that this is a relatively more mature field in terms of processes than the deposition of diamond films. There are a number of applications where DLCs are routinely used, particularly in the magnetic recording field. It was also noted that although the group considered 4 application categories in assessing the different processes, a more thorough assessment needs to be performed for each specific application once it has been identified.

The group also noted that there are a number of significant differences between diamond and DLC coatings that place limitations on the end-use of these coatings. Notable are the low thermal-conductivity and thermal-oxidation properties of DLCs compared to diamond films that limits the applicability of DLCs for sensors and thermal management. The surface roughness of DLCs make them very attractive for tribological applications compared to diamond films.

It was further noted that new/novel processes and deposition chemistries (e.g. halogen-assisted CVD) need to be explored particularly for diamond-film deposition.

Specific development and research goals were identified. Research and development effort is strongly needed to obtain higher growth rates, to lower the deposition temperature, improve the surface roughness, and the adhesion of diamond and DLC films.

TABLE I: Deposition Techniques

Diamond Films

Chemical Vapor Deposition Processes

- laser assisted CVD (LA-CVD)
- hot filament CVD (HF-CVD)
- plasma-assisted (micro-wave) CVD (PA-CVD)
- halogen activated CVD (hal-CVD)

Combustion Flame (FLAME)

Plasma (Arc-Jet)

Diamond-Like Carbon Films

Physical Vapor Deposition

- electron-beam evaporation (EB-PVD)
- sputtering (SPT-PVD)
- CVD (CVD-PVD)
- laser ablation (LA-PVD)

Ion-Beam Deposition (IBD)

Ion-Assisted Deposition (IAD)

Plasma-Assisted CVD (PA-CVD)

TABLE II: Transportation Application Areas

1) Thermal Management

- heat dissipation (hot spots)
- electronic components (high power density)
- heat loading through windows
- manufacturing (cutting tools)

2) Optics

3) Tribology

4) Sensors (e.g., mechanical devices to measure pressures and temperatures)

TABLE III: Comparative Limitations

		PCDs	DLCs
A	substrate preparation (nucleation)	x	
B	growth rates	x	x
C	component size	x	
D	substrate temperature	x	
E	cost	x	?
F	surface finish	x	
G	maximum coating thickness		x
H	adhesion	x	?
I	grain-size, crystallites, heteroepit.	x	N/A
J	thermal conductivity		x
K	geometry	x	x
L	thermal oxidation		x

TABLE IV: Ranking of Diamond-Deposition Processes

	Thrmal- Mngmnt		Optics		Tribology*		Sensors	
	(B, D, E, J, L)		(F, G, H, I)		(C, D, F, H, K, L)		(H, J, L)	
	Prvn**	Pot**	Prvn	Pot	Prvn	Pot	Prvn	Pot
LA- CVD	-	-	-	-	-	-	-	*
HF- CVD	3	-	3	-	3	-	2	-
PA- CVD	2	+	1,2	-	1	c-BN	1	-
hal- CVD	-	+	-	+	-	low-T _s	-	-
FLAME	-	-	-	+	-	+	-	-
Arc- Jet	1	+	1,2	-	2	-	-	-

*Also includes wear-resistant coatings for optics.

**"Prvn" - refers to proven technologies for specified field.

"Pot" - refers to technologies that have significant potential in specified field.

⁺Denotes technologies that have potential.

TABLE V: Ranking of DLC-Deposition Processes

	Thrmal- Mngmnt		Optics		Tribology		Sensors	
	(B, D, E, J, L)	(F, G, H, I)	(F, G, H, I)	(C, D, F, H, K, L)	(C, D, F, H, K, L)	(H, J, L)	(H, J, L)	
	Prvn	Pot	Prvn	Pot	Prvn	Pot	Prvn	Pot
EB- PVD	0*	0	-	-	1	-	0	0
SPT- PVD	0	0	1	-	1	-	0	0
CVD	0	0	-	-	1	-	0	0
LA- PVD	0	0	-	-	-	**	0	0
IBD	0	0	-	-	1	-	0	0
IA	0	0	2,	a	1	-	0	0
D			3					
PA- PVD	0	0	2,3 ^b	-	1	-	0	0

*A '0' denotes these techniques should **not** be considered.

**Refers to technologies that have potential.

^aProtective coatings for low-heat-load windows.

^bIR windows.

Panel 2 – Properties of Diamond and Diamond-Like-Carbon Films

Panel Members:

Chairman: P. J. Blau, Oak Ridge National Laboratory

O. O. Ajayi	Argonne National Laboratory
P. F. Bartelt	Deere & Co.
R. H. Baughman	Allied Signal
B. Bhushan	Ohio State University
R. E. Clausing	Oak Ridge National Laboratory
C. V. Cooper	United Technologies Research Center
M. T. Dugger	Sandia National Laboratories
A. Freedman	Aerodyne Research, Inc.
J. Larsen-Basse	National Science Foundation
Y. Y. Liu	Argonne National Laboratory
N. R. McGuire	Caterpillar
R. F. Messier	Penn State University
G. L. Noble	John Crane, Inc.
M. H. Ostrowski	John Crane, Inc.
A. Purohit	Argonne National Laboratory
B. D. Sartwell	Naval Research Laboratory
R. Wei	Colorado State University

Goals of this Panel

This panel attempted to identify and prioritize research and development needs in determining the physical, mechanical and chemical properties of diamond and diamond-like-carbon films (D/DLCF). Three specific goals were established. They were:

1. To identify problem areas which produce concern and require a better knowledge of D/DLCF properties.
2. To identify and prioritize key properties of D/DLCF to promote transportation applications.
3. To identify needs for improvement in properties-measurement methods.

Each of these goals is addressed subsequently.

Problem Areas

Problem areas delineated by the panel were identified as being either short-term (ST) issues (urgent needs), long-term (LT) issues (requiring significant times for effective solution), or as having elements of both (S/LT). These problem areas are summarized as follows:

1. There was general agreement that there is a need for specific guidance from the transportation industry (i.e., engine manufacturers, parts manufacturers, materials suppliers) as to which specific properties need to be improved. This guidance is critical for those developing new methods to produce D/DLCF. [ST]
2. A need was expressed for a comprehensive data base for the properties of D/DLCF. This activity should begin at once and be continued as the technology matures. [S/LT]
3. There is a lack of standard tests (e.g., ASTM test methods) for use to determine the properties of D/DLCF. [S/LT]
4. Standard reference materials on which to validate D/DLCF property-measurement methods are not available but should be developed. [ST]
5. There is a need for better quality-control (QC) methods which can use one or two key properties to qualify products for use. Often it is not possible, economically and/or technically, to perform a large number of tests on each lot of material. Key QC tests, which are well-correlated to performance, should be developed. [S/LT]

Considerations Bearing on Problem Areas

There was a sense that certain factors affect the degree to which government laboratories should be involved with industrial efforts to promote and develop D/DLCF technology. These considerations included the following:

1. There is no question that property requirements will be driven by end use. Applications information arising from the other panels should be considered in setting priorities.
2. Pending the identification of specific target applications, R&D should be directed at generic technical issues.
3. Research is needed to link D/DLCF properties with their microstructures and the underlying mechanisms of material behavior.
4. Combinations of key properties may be more important than individual properties alone.
5. The properties of D/DLCF must be taken in the context of a total materials system which contains the substrate-material properties as well.

Prioritization of Needs for D/DLCF Properties

A poll of the panel members indicated the following order (1=highest) of importance in properties determination for D/DLCF used in transportation applications:

1. tribological properties
2. mechanical properties
3. thermal properties
4. chemical properties
5. electro/optical properties.

It is recognized that the above priorities may be different for specific applications (for example, thermal management for circuit chips may rank much higher in regard to automotive microcomputer-system needs). Therefore, the list resulted from a consensus on applicability to the general area of transportation technology.

There was an attempt to further break down the top two properties needs on the above list into more specific areas. Those tribology areas receiving at least three votes from panel members were the following:

<u>Subject</u>	<u>No. of Votes</u>
1. friction	13
2. wear	13
3. better surface-morphology characterization	10
4. rolling-contact-fatigue characterization	5
5. lubrication of D/DLCF	4
6. scuffing-reduction properties	3

Similarly, mechanical-properties areas receiving the most votes were as follows:

<u>Subject</u>	<u>No. of Votes</u>
1. adhesion	15
2. hardness	8
3. residual stress	4
4. fracture toughness	3
5. elastic properties	2

Prioritization in Needs for Better Properties-Measurement Methods

There were five areas in which better D/DLCF properties-measurement methods were felt to be needed. These are:

- 1) Better methods for reporting (i.e., improved completeness of methodology) are needed for friction and wear data, including the more consistent use of units.
- 2) Several areas of adhesion testing were identified as being significant. These included development of standard reference materials for adhesion testing, better means to develop quantitative rankings, more repeatable and reproducible methods for adhesion testing, better methods to discriminate between shear and tensile properties of D/DLCF, and better tests for scratch, pull, bend, bulge and indentation.
- 3) Thermal-conductivity test methods should be developed aimed at specific applications (as ASTM test methods). Special test methods are needed for films under 0.1 micrometer in thickness.
- 4) The hardness of thin films is very difficult to measure. New methods to prepare surface for hardness tests without altering properties should be developed.
- 5) Indentation fracture-toughness testing methods have serious drawbacks. Improved methods for D/DLCF are needed.

Recommendations

In summary, Panel #2 on Properties had the following recommendations:

1. Properties data for D/DLCF cannot stand alone. Data must be accompanied by an understanding of materials fundamentals.
2. Special techniques, tailored for measuring the properties of D/DLCF, are urgently needed. Some of these techniques should be standardized, for example, as ASTM test methods, and reference materials to validate new standard test methods are needed as well.
3. The panel recommended establishing an initial round-robin program to develop a D/DLCF properties data base.
4. Tribological behavior, mechanical properties, and thermal properties have high priority for D/DLCF in transportation applications. A series of specific property rankings were developed.

Panel 3 - Characterization

Panel Members:

Chairperson: Robert A. Erck, Argonne National Laboratory

Ali Erdemir	Argonne National Laboratory
Albert Feldman	Natl. Inst. of Standards and Technology
Jeffrey T. Glass	North Carolina State University
Jang-Hsing Hsieh	Argonne National Laboratory
Rick Kleiner	Coors Ceramics
Emil A. Lawton	JPL/Caltech
Richard H. Lee	Argonne National Laboratory
Carl J. McHargue	Univ. of Tennessee-Knoxville
Xian Zheng Pan	Argonne National Laboratory
Diane E. Peebles	Sandia National Laboratory
Deming Shu	Argonne National Laboratory

This task of this panel was to identify and prioritize needs in the area of characterization of diamond and diamond-like-carbon (DLC) films for use in the transportation industry. Diamond has been extensively studied for many years, and DLC has been known and studied for two decades. Until recent advances in producing diamond and DLC films that were both inexpensive and suitable for covering large areas, it was not considered feasible that these materials could be mass-produced.

The physical properties of diamond have been well characterized. However, because diamond and DLCs have been extremely expensive and difficult to produce, especially in large quantities or over large areas, little work has been done to apply these materials to non-traditional applications. Thus, little work was done (aside from diamonds for abrasive applications) on investigating and determining how best to apply diamond and DLCs to solving problems in transportation technology. The deposition technologies (e.g., CVD diamond) are themselves very new, and much more work needs to be done on understanding how the processes operate on the molecular scale.

After some discussion, it was agreed that the Characterization panel should restrict itself to identifying needs in areas that would be of most use to manufacturers and users in producing and utilizing diamond and DLC coatings in industry. These characterization needs include:

- 1) in-situ monitoring during growth
- 2) relation of structure to performance
- 3) standards and definitions

The performance of any diamond or DLC surface depends critically on the properties of the surface of the film, the film itself (bulk), any interfaces that are contained in the film or between film and substrate, and the substrate. The Panel addressed three questions. What

were some of these general systems that needed to be characterized, *why* is the information needed, and *how* will this information be obtained? Table I is a summary list of items identified by the Panel.

The Panel intentionally avoided discussing specific properties of diamond and DLC films; that topic is dealt with by Panel #2, *Properties of Diamond and Diamond-Like Carbon*. Nor did the Panel enumerate the various techniques for deposition; these are addressed by Panel #1, *Comparative Evaluation of Deposition Technologies*.

For any successful commercial utilization of diamond and DLC films, it was thought vital to be able to know which parameters are critical for the maintenance of quality and reproducibility during deposition. In addition, any practical production process will require *in-situ* monitoring of the deposition process. Without real-time "feedback," quality during manufacturing is put in jeopardy. Thus, the Panel placed emphasis on process control, and on determining the relation between measured parameters, structure and performance. The following section lists some of the concerns expressed by panel members.

- It was felt that the characterization question should span the range from fundamental to applied. Fundamental research was needed to determine which parameters (and thus which techniques) would give the most useful (significant) information about the control of a particular technique. Applied research was needed to relate properties to performance during use.
- Characterization methods should be developed which allow monitoring the growing film during deposition. Because practical CVD methods of growing diamond and DLC films have only recently been discovered, the kinetics of these interactions, especially gas-gas and gas-solid interactions, is just beginning to be understood. It became clear that any practical deposition technology involves understanding and controlling reactions between molecular and atomic species existing in the gas phase and between the gas phase and the surface. Thus, the characterization task requires a means of measuring properties of molecular, atomic or excited species, and characterizing the interactions between these species and the growing surface.
- Any practical use of diamond and DLC coatings under mechanically loaded conditions will require good adhesion of the film to the substrate. A film that detaches will be worthless. Diamond's thermal-expansion coefficient is a poor match to many common engineering materials, and good adhesion is necessary for film integrity under thermal cycling. At present, good bonding of diamond can be obtained to only a few classes of materials. Thus a means of assuring film/substrate bonding is needed, as well as a way of controlling film stresses during growth.
- It was emphasized that characterization techniques can be classified as destructive or non-destructive. For process monitoring, suitable non-destructive tests need to be developed.

- A suitable characterization technique must be sensitive to the parameter or parameters that critically affect the performance of the product. Much work is still needed to clearly understand which characterization techniques would be most appropriate to study the particular film property to be measured. For example, Raman spectroscopy is highly sensitive to graphite impurities that are sometimes found in diamond films grown by CVD techniques. Thus, Raman spectroscopy would be extremely useful as a characterization tool if knowledge or control of the presence or absence of graphite were critical. However, if film properties were found to be critically related to grain size, for example, and the presence of graphite was immaterial, then Raman would be unsuitable. A characterization technique sensitive to grain size would need to be found.
- A clear need was felt for the development of basic and applied understandings of the chemistry and structure of diamond and DLC films in order to engineer specific (desirable) properties. Many of the basic physical properties of these materials are well-measured and understood. However, because diamond and DLCs have been very expensive and difficult to produce, especially in large quantities or over large areas, it was never thought practical to apply these materials on a large scale to manufactured parts. Thus, little work has been done on understanding diamond and DLC films in terms of those specific properties useful for application to transportation. Thus, a gap in knowledge was seen in the relation of chemistry and structure to properties such as wear resistance, friction or compatibility with other materials.
- For any production of diamond and DLC films on a commercial scale, some reliable and robust means of monitoring and feedback will need to be developed for use during production. At the present time, we lack knowledge and tools to monitor and characterize the production of films of diamond and DLC *in-situ*. This includes both monitoring of film nucleation and monitoring of growth. The initial nucleation of the film will be a critical step, so that characterization and feedback may be necessary to attain acceptable yields. It was thought that deposition rates would probably be slow and that some means of assuring film quality *in-situ* would be necessary to avoid lengthy deposition of a fatally flawed film.
- Much additional work and understanding are needed to relate structure to performance. The term structure was not restricted to physical structure, but also includes chemical composition and impurities. The panel included in the "performance" category not only tribological aspects such as wear, environmental and high-temperature properties, but also radiation resistance and electrical properties. Information is needed about not only the film itself, but also about the surface, interfaces and substrate, as shown in Table I.
- An experimental means of adhesion testing that is reproducible is needed for diamond and DLC films. However, no widely accepted direct means of testing thin films in general exists, making this challenge more difficult. A non-destructive means of ascertaining film adhesion would be ideal. An indirect test, in which a particular property that is related to adhesion is measured may be one way of approaching the problem, but much work needs to be done in this area.

- The extent of the information database for diamond, and especially DLC, is still very limited. It was speculated that some of the data published to date may have been obtained under poorly controlled conditions as researchers initially strove to understand the new deposition processes. A strong desire was expressed by panel members representing industry for a study and compilation of a database concerning critical process parameters and performance. It was felt that a published database, perhaps similar to the ACTIS tribology database, would be useful.
- A strong need for standards and standardized characterization procedures was felt. At present, no industry-wide specifications or procedures seem to have been developed for diamond or DLC that were designed for use by the transportation industry. A need exists for specifications that are practical and useful and that facilitate meaningful communication between all parties. Materials standards for microelectronic and thermal-management application were known to be available, but these were thought to be unsuitable as standards for tribological use. There was no consensus, though, as to which organization or organizations should be responsible for producing the standards.
- In addition to standards, it was felt that a round-robin testing program should be initiated, similar to the programs developed to characterize other materials. The results would be compared and potential problems identified. This would aid in assuring high standards and consistency.
- The topics of surface roughness, its effect on wear and friction, its means of measurement, and ways to polish diamond, were raised. It was felt that this topic was more properly addressed by Panel #2, *Properties of Diamond and Diamond-Like Carbon*.
- A film of high "quality" is always desirable. However, a good working definition of quality for various applications does not exist, although this term is often used in the area of diamond and DLC films. This lack of a good definition is particularly evident for DLCs, which, because very little is known about their atomic structure, poses greater challenges for understanding the relationship of structure to properties. It was felt that any definition of quality of a film must take into account not only bulk properties such as structure, composition, phase distribution, residual stresses, and so on, but also adhesion of the film to the substrate.
- Another parameter that affects film performance is the relative amount of sp^2 and sp^3 bonding and the hydrogen content of a DLC film. The performance of DLC films is poorly known in relation to these quantities, and means to measure these properties are not readily available.
- Because no transportation industry can afford to invest in all possible characterization tools, panel members felt a need for more information on the strengths and weaknesses of various characterization methods for different tasks. Because tight control on process parameters is difficult and expensive, it is necessary to know which parameters are most vital for growing reproducible

films. The desire was also expressed for information concerning which kinds of characterization techniques could be relied upon to maintain tight process control.

- Although there is much interest in diamond films for microelectronic applications, good mechanical or tribological properties may not require high-purity diamond. Indeed, DLC or hydrogenated DLC films can be grown which are very smooth and hard, and which can exhibit low friction. DLC films can be deposited at low temperatures. Thus, there is great need to find useful characterization techniques for these amorphous materials, of which very little is known at present of the structure. Progress is needed for defining nomenclature for evaluating and describing amorphous carbonaceous phases, whether they be DLC or hydrogenated DLC.

The Panel summarized and prioritized these concerns according to the following criteria:

1. Identify areas for characterization
2. Identify critical needs
3. Rank needs by priority
4. Recommendation

The following items are a prioritized summary listing of critical characterization needs:

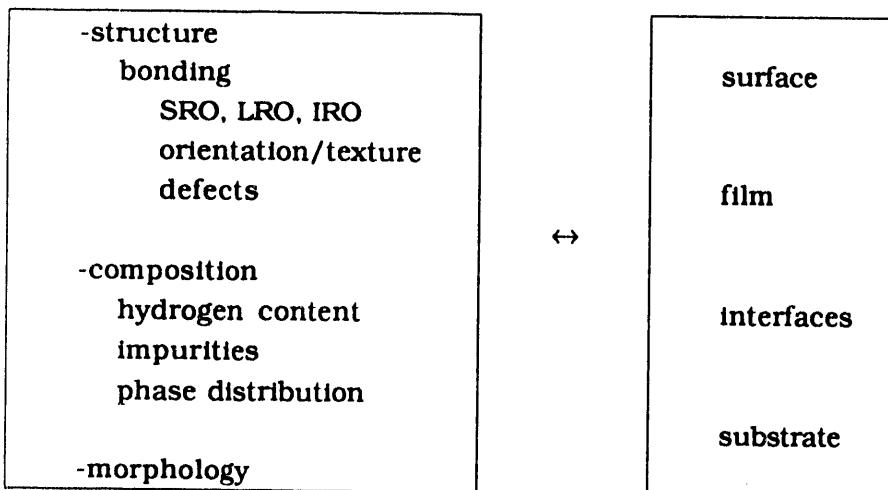
1. Development of in-situ surface/near-surface characterization (and quality control) techniques.
2. Determine the relation of structure, impurities, etc. to performance, tribobehavior, environmental, high-temperature, etc. properties.
3. Understanding of nucleation/adhesion mechanisms.
4. Establish criteria for evaluating amorphous carbonaceous phases.
 - nomenclature for non-crystalline materials.
 - relationship between hydrogen content and sp^2/sp^3 bonding.
5. Determine the nature of diamond/DLC interaction with other surfaces (wear/polishing).
6. A working definition of "quality" for various uses.
7. A correlation of various characterization techniques.

A final recommendation was given by members of the Panel:

"Diamond and diamond-like materials have been identified as enabling technologies for increasing U.S. competitiveness in the transportation sector. Critical issues in characterization must be addressed to enable the transfer of these materials from research labs to end-users in manufacturing. The successful use of diamond and diamond-like materials in the transportation sector will require solutions of critical issues identified by this panel for characterizing the production of these materials, the materials themselves, the interactions of these materials with other materials and the development of suitable standards."

Table I

a) **What** properties/regions can be characterized?



b) **Why** is characterization needed?

- need to develop basic and applied understanding of chemistry and structure to engineer specific properties
- need for specifications useful to manufacturers and users

c) **How** can properties be characterized?

- stylus
- interferometer
 - STM
 - SFM
 - light scattering
 - SEM
 - TEM
 - Raman
 - other existing techniques
- other future techniques

Panel 4 – Applications to Transportation

Chairman: Fred Nichols, Argonne National Laboratory

Joseph Au	Sundstrand Aerospace
Rabi Bhattacharya	Universal Energy Systems, Inc.
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After considerable discussion, it was decided that the most effective manner in which this working group could serve the aims of the workshop was to compile a listing of current and anticipated future problem areas in the transportation industry where the properties of diamond and DLC films make them especially attractive and where the group as a whole could strongly endorse the establishment of DOE/Transportation Industry cooperative research efforts. It was further decided that it would not be fruitful at this time to attempt to create a prioritized ranking.

The problem areas identified for possible applications of diamond/DLC technology are compiled in the following pages, together with indications of current approaches. Also we have given brief indications of specific needs and the type of research program envisioned. We have attempted to give some idea of time scale required for the various efforts. Finally, we have indicated foreseeable payoffs if the technologies are successfully implemented.

They should demonstrate cost-effectiveness and transferability to production. Finally, successful processes should be sufficiently robust for day-to-day production-line variations.

Area #1

1. Problem

Valve guide/stem wear at high temperatures in advanced diesel and developmental low-heat-rejection engine.

2. Current Approach

4140 Steel valves/cast iron guides at 300–350°C

3. Needed

Diamond or DLC coating on either or both surfaces to extend operating temperature to 300–500°C and to reduce liquid lubricant requirement.

4. R&D Program Envisioned

Investigation of coating/material combinations with high-temperature, 20,000-hour capability; should provide lubricious interface.

5. Time – Scale

5–7 years.

6. Payoff

Maintain international competitive advantage, better fuel efficiency, reduced emissions.

Area #2

1. Problem

Piston ring/bore tribosystem needs improvement to decrease wear, oil consumption and emissions for gasoline, diesel and alternative fuels.

2. Current Approach

Coated piston skirts and rings/cast-iron or Al bores at $\approx 150^{\circ}\text{C}$ for 500,000 miles (diesel), 100,000 miles (automobile).

3. Needed

Heavy-Duty Diesel: Serviceable ring/bore combination at $\approx 300^{\circ}\text{C}$ for approximately 1,000,000 miles, 20% increase in cylinder pressure, reduced friction.

Automotive: Friction reduction at current temperatures for 200,000 miles.

4. R&D Program Envisioned

Identify/develop diamond/DLC materials (coatings)/processes for high-temperature ($\sim 300^{\circ}\text{C}$) tribological interfaces, e.g., plasma deposition, cvd/pvd. Develop improved piston ring/cylinder wall tribological computer models to guide research.

5. Time - Scale

5-7 years.

6. Payoff

Maintain international competitive advantage, better fuel efficiency, reduced emissions.

Area #3

1. Problem

Need increased load-carrying capacity for gears, power train and bearings in spark-ignited/diesel engines and vehicular drive trains, as well as in manufacturing.

2. Current Approach

Gears: Steel (various) with some type of wear-life-enhancement process.

Bearings: Typically lead-tin bronze bushings cast or sintered onto steel backs, with Pb-Sn overlay. Oil-lubricated.

3. Needed

Improvements in power-throughput capability to allow components with lower cost or smaller size to be used. Increase oil temperatures from ~120°C to ~150°C.

4. R&D Program Envisioned

Investigate diamond/DLC coatings or new surface treatments that offer reduced pitting/contact fatigue/abrasion, scoring or galling in comparison with conventional materials. Improved computer modeling of gears and bearings.

5. Time - Scale

8-10 years.

6. Payoff

Enhanced international competitiveness, improved reliability and design flexibility. Improved fuel economy/emissions due to higher cylinder pressure, injection pressure. Reduced friction from (possibly) higher sump temperatures. Decrease Pb in environment.

Area #4

1. Problem

Electric fuel pumps and fuel pump gears operate immersed in fuel. Potential wear areas include the commutator/brush interface. Concerns include potential abrasion and arcing. The effect of methanol fuel on these phenomena has not been established. Other rubbing contacts are potential concerns because of the poor lubricating ability of these (low-viscosity) fuels.

2. Current Approach

Issues are in the early stages of investigation.

3. Needed

Identification of materials/coatings (diamond/DLC) appropriate for commutator, brush and other applications with gasoline, methanol and admixtures.

4. Payoff

Improved reliability and design flexibility.

Area #5

1. Problem

Accelerated or bench tests used for selection of tribological materials do not always accurately model the effects of actual service. This deficiency may lead to unrealistic failure modes during testing, or conversely to unexpected failures during service. No widely accepted, quantitative adhesion evaluation method is presently available for bond strengths in excess of 69 MPa (10 ksi).

2. Current Approach

Test simulation: varies widely from case to case, ranging from well-defined and verified accelerated wear tests to arbitrary screening tests for wear and/or adhesion.

Modeling: Empirical experimental methods are used, unreliable for predicting wear under typical operating conditions.

3. Needed

Systematic procedures for defining appropriate tests, especially for adhesion. Accurate modeling methods and properties of coatings, especially adhesion.

4. Payoff

Rapid material screening and validation, reduced costs and improved performance, shorter cycle time. Ability to predict component life and forestall premature failures.

Area #6

1. Problem

Injector plunger-barrel scuffing (adhesive wear) with diesel fuel, but especially with alternative (low-lubricity) fuels. Potentially also a problem with spark-ignition engines utilizing alternative fuels.

2. Current Approach

Typically, electroplated hard-chromium plunger with hardened steel bore, or nitrided plunger and bore. Very tight clearances required, e.g., $2.5 \mu\text{m}$ ($100 \mu\text{in}$) diametral. Fuel-lubricated, approximately 93°C (200°F). Axial load to 12 kN (2600 lbf), injection pressure $\approx 172 \text{ MPa}$ (25 ksi). Required life $>500,000$ miles. Typically, tool-steel plunger, carburized steel injector cup with multiple holes formed by electro-discharge machining (EDM). Hole diameter approximately $200 \mu\text{m}$ (0.008 in). Diesel fuel contaminated with sulfuric acid/organic acids/combustion products, $150\text{--}315^\circ\text{C}$ ($300\text{--}600^\circ\text{F}$). Required life $>10,000$ hrs or $700,000,000$ cycles.

3. Needed

Injection pressure $\approx 207 \text{ MPa}$ (30 ksi), up to $1,000,000$ miles for heavy-duty engines. Greater tolerance to low-lubricity fuels (e.g., low-S, low-aromatics fuel, arctic fuel, methanol, etc.). Reduce corrosion/erosion rates of spray holes by factor of 5.

4. Payoff

- a) Develop scuffing- and wear-resistant coatings, as well as those for corrosion/erosion resistance.
- b) Develop solid lubricating coatings.
- c) Evaluate diamond-like-carbon coatings – need improved adhesion to steel.
- d) Develop coating process for long, narrow bores ($1/d > 3$), e.g., conformal-plasma ion implantation.
- e) Bench/screening tests and engine tests required.

5. Time – Scale

3–5 year R&D program to develop and evaluate processes.

6. Payoff

- a) Improved emissions/fuel economy (higher injection pressure).
- b) Improved durability & reliability with low-lubricity fuels.
- c) Improved international competitiveness.

Area #7

1. Problem

Improved rolling-contact-fatigue (RCF) life of valve and injector cams and cam-roller followers is needed, for gasoline, diesel and gas-turbine engines.

2. Current Approach

Induction-hardened steel, powder-metallurgy and cast-iron cams, steel or ceramic rollers. Required life >500,000 miles (heavy duty) and 100,000 miles (automotive); oil-lubricated. Hertz stress approximately 1.4–2 GPa (200–300 ksi).

3. Needed

Increase injection pressure 20% without reducing RCF life. Improve lifetime for ceramic rollers.

4. R&D Program Envisioned

- a) Evaluate thin-film ceramic PVD coatings on cam lobes.
- b) Evaluate thin-film solid lubricating coatings on roller pin to reduce roller-pin friction, hence cam-roller traction.

5. Time – Scale

3 yr. R&D program.

6. Payoff

Increased fuel-injection pressure capability (improved emissions/fuel economy). Improved international competitiveness.

Area #8

1. Problem

Surfacing of light-weight materials for self-lubrication and resistance to scuffing.

Examples: Aluminum-block engine – cylinder-bore surface
 Valvetrain components (valves, tappets, etc.)
 Transmission case "hot spots"
 Light-weight brake rotors
 Air conditioning (A/C) compressor hardware

2. Current Approach

Use of inserts – e.g., bore liners (cast iron), valve seats, etc.

Use of heavier, wear-resistant (usually ferrous) alloys

3. Needed

Understanding of adhesion of surfacing layers, e.g., diamond/DLC to metals such as aluminum; modeling for mechanical surface behavior of bi-material couples; understanding of methodologies for selecting composite surfaces.

4. Time – Scale

3–5 years

5. Payoff

Reduced friction and energy consumption; manufacturing simplification (in some cases).

Area #9

1. Problem

The wear life of non-ferrous die materials is insufficient for medium-volume applications.

2. Current Approach

Hard-chromium plating is being evaluated for non-ferrous dies; for ferrous dies ion (plasma) nitriding mid-chrome coating and flame-hardening are used.

3. Needed

A wear-life-enhancement process that can be easily applied, give increased tool life, be repaired, stripped and retreated if needed.

4. R&D Program Envisioned

Hard-chromium plating and plasma-source ion implantation appear to be potential solutions. Could also employ diamond/DLC films.

5. Time – Scale

Process could be used immediately. R&D program could require 2-3 years.

6. Payoff

Benefits to U.S. auto-makers and other U.S. manufacturers.

Would obtain:

- cheaper tooling
- faster time to market; reduced lead time
- enhanced competition with foreign companies

Area #10

1. Problem

Develop diamond and/or DLC sensors and associated packaging systems, for harsh, transportation-related environments, for sensing temperature, force and various chemical conditions.

2. Current Approach

Usual approach has been simply to push silicon devices harder and harder; at present, we are up against the limits for Si sensors and further progress to more severe conditions requires a new material.

3. Needed

Operation at 500 to 800°C in exhaust environments. Many barriers to progress exist at ≈300°C, e.g., coolant, lubricant, air, fuel inlet.

4. R&D Program Envisioned

Integration of fragmented R&D in diamond electronics and sensors, as active and passive devices for on-board diagnostics.

5. Time - Scale

4-5 years

6. Payoff

Essential for selling automobiles in California with new emission/environmental requirements; enhance U.S. competitiveness in international markets.

Area #11

1. Problem

Abrasion/erosion of compressor blades, stator vanes in gas turbines, turbochargers, etc., where small amounts of wear can have drastic, deleterious effects. (Trouble in Saudi Arabia)

2. Current Approach

Replacement of components. This results in very costly loss in effective utilization.

3. Needed

Increase in abrasion resistance. Elimination of heavier materials which are now required for adequate abrasion resistance.

4. R&D Program Envisioned

Identify/develop diamond/DLC technology/processes for surfaces subject to highly abrasive conditions.

5. Time – Scale

4-5 years

6. Payoff

Reduced maintenance costs. Reduced down-time. Increased efficiency.

Area #12

1. Problem

Abrasion of windows on aircraft and automobiles.

2. Current Approach

Mostly uncoated windows are used.

3. Needed

Enhanced abrasion resistance, possibly combined with optical improvements, e.g., low heat transmission.

4. R&D Program Envisioned

Should include investigation of feasibility of float-line or post-line processes. Should also include possibility of non-glass windows.

5. Time – Scale

2-3 years

6. Payoff

Improvements in product, durability and safety.

Area #13

1. Problem

Efficient utilization of electrical power/power transmission (power management) for electric vehicles and communications equipment.

2. Current Approach

Si is used, with its low power capability.

3. Needed

Higher-power switching and management.

4. R&D Program Envisioned

Develop mosaic diamond, diamond-base sample and switch devices.

5. Time – Scale

6-7 years

6. Payoff

Extended vehicular range; improved safety, reliability and performance.

Area #14

1. Problem

Thermal fatigue from hot spots in combustion chamber, especially cylinder head.

2. Current Approach

Increase back-side (coolant side) flow rates and heat transfer. Increase material strength and thermal-fatigue resistance. Limit specific power.

3. Needed

Thin layer on top of firedeck surface to serve as heat distributor/spreader.

4. R&D Program Envisioned

Develop methodologies for practical applications of durable diamond coatings with very high thermal conductivity to eliminate "hot spots" within the combustion chamber. Validate same.

5. Time - Scale

2-4 years

6. Payoff

Enabling technology for increased specific power output for current and future-generation products. Improved emissions through elimination of radical sites.

Area #15

1. Problem

Machine/cutting tools for advanced materials, e.g., composites, ceramics.

2. Current Approach

Current programs on diamond-coated tools exist but are limited to non-ferrous substrates.

3. Needed

Diamond-coated tools for various substrates.

4. R&D Program Envisioned

Fill in gaps of current programs to cover all needs. Coordinate with National Center for Machining Sciences (NCMS).

5. Time – Scale

4-5 years

6. Payoff

Instantaneous productivity increase. Enabling technology for ceramics industry.

Area #16

1. Problem

Brake heating is critical problem for heavy-duty trucks and aircraft.

2. Current Approach

Fins, radiators, water cooling, etc.

3. Needed

More efficient thermal management to eliminate overheating failures.

4. R&D Program Envisioned

Diamond heat pipes and/or spreaders would be developed.

5. Time - Scale

4-5 years

6. Payoff

Improvement in safety and durability; weight reduction.

Area #17

1. Problem

Surfaces coated with diamond or DLC in the engine may not be compatible with the (conventionally) formulated engine oils. Also true for transmissions, gears, etc.

2. Current Approach

Diamond and DLC coatings are avoided in these systems.

3. Needed

Lubricants compatible with diamond and DLC that will not drastically alter other systems, materials, functions, etc.

4. R&D Program Envisioned

Develop practical lubricant (base-stock and additives) in the context of diamond/DLC coatings, applicable for tribological interfaces of real-life, near-term and advanced systems. Coordinate with current work on lubricants for ceramics.

5. Time – Scale

3-7 years

6. Payoff

Enabling technology for the utilization of diamond/DLC coatings in engine and power-transmission systems.

Area #18

1. Problem

Seals in many areas.

Note: Time did not permit elaboration on this area.

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